



Product Change Notification: CENO-16EGCZ399

Date:

22-Jul-2025

Product Category:

16-Bit - Microcontrollers And Digital Signal Controllers, 16-Bit Microcontrollers, 32-Bit Microcontrollers, Development Tools, 8-Bit Microcontrollers, Access Networks, Analog Multiplexer/Switch ICs, Analog Temperature Sensors, Analog to Digital Converters, ARCNET-Circlink Controllers, Battery Management and Fuel Gauges - Battery Chargers, Battery Management and Fuel Gauges- Battery Management Devices (Powersmart), Bluetooth Silicon, Broadband Gateway, CAN Controller, CAN Controller With Integrated Transceiver, CAN PN Transceiver, CAN/LIN SBC, Capacitive Touch Sensors, Car Access, Charge Pump DC-To-DC Converters, Clock And Timing - Clock And Data Distribution, Clock And Timing - Clock Generation, Clock And Timing - High Speed Communication, Clock Buffers, Computing I/O Controllers, Crypto Authentication, Current And Power Measurement Ics, Digital Potentiometers, Digital Signal Controllers, Digital Temperature Sensors, Digital to Analog Converters, Driver / Interface ICs, Equalizers, Ethercat, Ethernet Bridges, Ethernet Controllers, Ethernet Phys, Ethernet Switches, General Purpose Fpgas, General Purpose LED Drivers, High Reliability, High-Side Current Sense Amplifiers, Hybrid Controllers, Inductive Position Sensors, INIC, Instrumentation Amplifier, Interface- Controller Area Network (CAN), Interface- Infrared Products, Interface- LCD Drivers, Interface- LIN Transceiver, Interface- Passive-Keyless-Entry Analog Front End, Interface- Serial Peripherals, KEELOQ® Encoder Devices, LIN System-In-Package, LIN Transceiver With Vreg, LIN Transceiver With Vreg And Watchdog Timer, Line Drivers, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Linear Regulators, MCUs with transmitters, Memory, Motor Control Sips, Motor Drivers, Photoelectric/Ionization Smoke Detector, Piezoelectric Horn Drivers And CO Detector, PoE PSE, Power Line Communications, Power Management - PMIC, Power Management - Power Switches, Power Management - PWM Controllers, Power MOSFET Drivers, PWM Controllers, Random Number Generator, Real-Time Clock/Calendar, Security Computing Embedded Controllers, Simple and Complex Programmable Logic, Smart Energy SOC, Smart Energy Wireless Communications, Special Purpose Analog to Digital Converters, Switching Regulators, Temperature Sensors, Touch Controllers, Touchscreen Controllers, Transceivers, USB Bridge, USB Hubs, USB Port Power Controller, USB Power Delivery, USB Products, Voice Audio, Wireless IC, Wireless Modules, Wireless Power And USB-PD Controller

Notification Subject:

CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

Affected CPNs:

CENO-16EGCZ399_Affected_CPN_07222025.pdf
CENO-16EGCZ399_Affected_CPN_07222025.csv

Notification Text:

PCN Status:

Final Notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

Pre and Post Change Summary:

For PIC16F182xx, PIC16F151xx, PIC16F193xx, PIC16F726xx, PIC16F178xx, PIC18F24Kxx, PIC16F722xx, PIC16F723xx, PIC18F23Kxx, PIC16LF19xx, PIC16LF15xx, PIC16F171xx, PIC16F188xx, PIC16F191xx, PIC16F153xx, PIC18F26Kxx, PIC18F25Kxx, PIC16F184xx, PIC16F150xx, PIC16F145xx, PIC16F161xx, PIC16F157xx, PIC16F170xx, PIC16F183xx and MTCH108 device families available in 16L, 20L and 28L UQFN (3x3x0.5mm, 4x4x0.55mm and 4x4x0.5mm) packages

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	8600	QMI519*
Molding Compound Material	G700	G700
Lead-Frame Material	EFTEC64T	EFTEC64T

For ATmega328PB, ATmega88PB, ATmega48PB, ATMEGA4808 and ATmega168PB device families available in 32L TQFP (7x7x1mm) package.

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material	Au	CuPdAu
Die Attach Material	3280	QMI519*
Molding Compound Material	G700	G700
Lead-Frame Material	C7025	C7025

For remaining device families and packages.

	Pre Change			Post Change		
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Inc. (MPHIL-3) (MP3A)
Wire Material	Au / CuPdAu			Au / CuPdAu		
Die Attach Material	3280 / 8600 / 2200D			QMI519*		
Molding Compound Material	G600 / G700			G600 / G700		
Lead-Frame Material	A194 / C151 / CDA151/ EFTEC64T / C7025			A194 / C151 / CDA151/ EFTEC64T / C7025		

*Note 1: *PFAS free material*

Impacts to Data Sheet:

None

Change Impact

None

Reason for Change:

To improve manufacturability by qualifying QMI519 as a new die attach to standardize the use of PFAS free material and CuPdAu as a new bond wire material.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 03, 2025 (date code: 2536)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2025					>	September 2025				
Workweek	27	28	29	30	31		36	37	38	39	40
Qual Report Availability				x							
Final PCN Issue Date				x							
Estimated Implementation Date							x				

Method to Identify Change:

Traceability code

Qualification Report:

Available upon request.

Please open the attachments included with this PCN labeled as PCN_#_Qualification Report List.

Revision History:

July 22, 2025: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_CENO-16EGCZ399_Qualification Report List.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PIC18F2420T-I/ML

PIC16F876AT-I/ML

24LC08BT-I/MC

24AA08T-I/MC

MCP73837T-FCI/MF

MCP73837T-FJI/MF

MCP73837T-NVI/MF

MCP73838T-FJI/MF

ATMEGA48PB-MN

ATMEGA324PB-MN

ATMEGA164PA-MN

ATMEGA328PB-MN

ATMEGA32A-MN

AT90PWM81EP-16MN

AT90PWM81-16MN

ATMEGA164P-20MQ

ATMEGA324PA-MN

ATSAMD21G17L-MN

RE370V28

SHA104-MAVMD-BCZ

ECC204-MAVMD-BCZ

SHA105-MAVMD-B

SHA104-MAVMD-B

LAN9253-V/R4X

RE46C305Q16

ATECC608C-MAVMD-B

M1A3P250-VQ100I

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M1A3P250-VQG100I

DSPIC30F3011-20I/PT

DSPIC30F3011-30I/PT

A3P060-1VQ100I

A3P060-1VQG100I

A3P060-2VQ100I

A3P060-2VQG100I

DSPIC30F6015-30I/PT

DSPIC30F6010A-30I/PT

A3P060-VQ100I

A3P060-VQG100I

DSPIC33CK64MP105-I/PT

DSPIC33FJ64MC508A-E/PT

PIC24HJ128GP510A-E/PF

DSPIC33FJ64MC710A-E/PT

DSPIC33FJ64MC506A-E/PT

DSPIC33FJ64MC706A-E/PT

PIC24HJ128GP510A-E/PT

DSPIC33FJ128MC710A-E/PF

DSPIC33FJ128GP306A-E/PT

DSPIC33FJ128GP706A-E/PT

DSPIC33FJ128GP710A-E/PF

DSPIC33FJ64MC506A-E/PFC23

PIC24HJ64GP210A-E/PT

PIC24HJ64GP510A-E/PT

ATMEGA644RFR2-ZFR

ATMEGA2564RFR2-ZFRP01

ATTINY427-MFR

PIC18F57Q84T-E/6MX

MCP48CVD01T-E/MG

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MCP48CVD02T-E/MG

MCP48CVD11T-E/MG

MCP48CVD12T-E/MG

MCP48CVD21T-E/MG

ATTINY827-MFR

MCP48CVD22T-E/MG

MCP47CMD01T-E/MG

MCP47CMD02T-E/MG

PIC12F1572T-E/RF

PIC16F1939T-E/MV

PIC16F1784T-E/MV

PIC16F1789T-E/MV

24LC024-I/MC

24AA024-I/MC

24LC025-I/MC

24AA025-I/MC

DSPIC33CK512MP605-I/M7

24LC014-I/MC

24AA014-I/MC

PIC16F1824-I/ML

PIC32MK0512GPK064-I/MR

PIC32MK0512MCM064-I/MR

PIC32MK1024GPK064-I/MR

PIC18F47Q83-I/NHX

PIC18LF67K40-I/MR

PIC18F27Q10-I/STX

ECC608-TFLXWPCU-PROTO

DSPIC30F3011-30I/ML

DSPIC30F3011-20I/ML

DSPIC30F3010-30I/ML

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DSPIC30F3012-20I/ML

PIC18F46Q83-I/NHX

PIC16F18313-I/RF

ATMEGA644RFR2-ZU

AR1100-I/MQ

PIC18LF24K40-I/ML

PIC18F25K40-I/ML

PIC16LF1503-I/MV

PD39210C-011019

PD39210R-011020

LE9551CMQC

LE9551DMQC

24CS128T-E/ST66KVAO

MCP4251T-503E/STVAO

MCP6009T-E/STVAO

MCP6479T-E/STVAO

MCP45HV51T-502E/STVAO

AVR32DB28T-E/SSVAO

PIC16F18046T-E/SSVAO

PIC18F27Q10T-E/SSVAO

PIC16F15254T-E/SSVAO

DSPIC33EV256GM002T-E/SSVAO

PIC16F18023T-E/STVAO

PIC16F18124T-E/STVAO

MCP6022-E/STVAO

MCP25625-E/SSVAO

25LC256-E/ST16KVAO

25LC040A-E/ST16KVAO

PIC18F26K83-E/SSVAO

PIC18F25K83-E/SSVAO

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DSPIC33EV32GM102-E/SSVAO

PIC18LF26K40-E/SSVAO

PIC18F26Q10-E/SSVAO

PIC18LF25K40-E/SSVAO

PIC18F24Q10-E/SSVAO

PIC18F24Q10-E/SOVAO

PIC18F46K80T-I/PT

PIC18F67K90T-I/PT040

PIC18F67K90T-I/PT041

PIC18F67J11T-I/PTC06

PIC18LF45K80T-I/PT

PIC18LF46K80T-I/PT

MCP98244T-BE/MNYAA

PIC16F1779T-I/MV

PIC16LF1777T-I/MV

PIC16LF1779T-I/MV

PIC16F1454T-I/JQ

PIC16F1578T-I/GZ

DSPIC33EP32GS504T-I/PT

DSPIC33FJ64GS606T-I/PTD22

ATSAM4LC4CA-AUR

ATSAM4LS4CA-AUR

DSPIC33CK1024MP406T-I/PT

PIC18LF45K42T-I/PT

PIC18F45K42T-I/PT

DSPIC33FJ32MC204T-I/PT

DSPIC33CK1024MP706T-I/PT

DSPIC33CK512MP406T-I/PT

DSPIC33CK512MP706T-I/PT

DSPIC33CK256MP406T-I/PT

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DSPIC33CK256MP706T-I/PT

PIC18LF46K42T-I/PT

PIC18F46K42T-I/PT

DSPIC33CK1024MP410T-I/PT

DSPIC33CK1024MP710T-I/PT

PIC24FJ64GA204-I/PT

PIC24FJ64GB410-I/PT

AT89C51IC2T-RLTUM

ATSAMD21J16B-MMUT

ATSAMD21J17D-MMUT

AVR64EA48T-E/PT

AVR32EA32T-E/PT

AVR32EA48T-E/PT

AVR64DD32T-E/PT

PIC32CM1216JH01032T-E/PT

PIC32CM1216JH01048T-E/Y8X

AVR128DA32T-E/PT

AVR128DA64T-E/PT

AVR128DA48T-E/PT

ATSAME54N20A-AFT-SL1

PIC18F46K40T-E/PT

DSPIC33CK64MP206T-E/PT

DSPIC33CK64MP506T-E/PT

PIC18F47J13-I/ML

PIC18F43K20-I/ML

PIC16LF720-I/ML

PIC16LF1933-I/ML

LX3302AQPW

PIC16F883T-E/SS

MCP47FVB02A2T-E/ST

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MCP47FEB01A2T-E/ST

MCP47FEB01A3T-E/ST

MCP47FVB11A0T-E/ST

MCP47FVB01A1T-E/ST

MCP47FVB22A1T-E/ST

MCP47FVB22A2T-E/ST

MCP47FVB12A0T-E/ST

MCP47FVB12A1T-E/ST

MCP47FVB22A3T-E/ST

USB4914T-I/Y9XVAA

USB4914T-I/Y9XVBA

DSPIC33CK512MP410T-I/PT

DSPIC33CK512MP710T-I/PT

DSPIC33CK256MP410T-I/PT

PIC18F47K42T-I/PT

PIC18LF47K42T-I/PT

DSPIC33CK256MP710T-I/PT

DSPIC33CK1024MP408T-I/PT

DSPIC33CK1024MP708T-I/PT

DSPIC33CK512MP408T-I/PT

DSPIC33CK512MP708T-I/PT

ATSAM4LC2CA-AUR

ATSAM4LS2CA-AUR

DSPIC33CK256MP408T-I/PT

DSPIC33CK256MP708T-I/PT

DSPIC33CK1024MP405T-I/PT

DSPIC33CK1024MP705T-I/PT

DSPIC33CK512MP405T-I/PT

DSPIC33CK512MP705T-I/PT

DSPIC33CK256MP405T-I/PT

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DSPIC33CK256MP705T-I/PT

ATF1502AS-10AU44-T

ATF1504AS-10AU44-T

ATF1504ASL-25AU44-T

ATF1502ASV-15AU44-T

ATMEGA1608-AUR

ATMEGA808-AUR

ATSAMC20E16A-AUT

ATSAMD21E17D-AUT

ATSAMD21E17A-AUT

ATSAMD21E18A-AUT

ATSAMD21E16B-AUT

ATSAMD21E15B-AUT

ATSAMD20J16A-AUTA2

ATSAMD20E14A-AUT

ATSAMD20E15A-AUT

ATSAML21E15B-AUT

ATSAML21E16B-AUT

ATSAML21E17B-AUT

ATSAML21E18B-AUT

ATSAMD20E16A-AUT

ATSAMD20E17A-AUT

ATSAML21E18B-AUT-SLL

ATSAML10E14A-AUT

ATSAML10E15A-AUT

PIC24FJ32GA002T-E/ML

PIC16LF1938T-E/ML

PIC24FJ64GA002T-E/ML

MCP8025T-115E/MP

MCP4021T-202E/MC

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MCP4021T-502E/MC

MCP4021T-103E/MC

MCP4021T-503E/MC

MCP19114T-E/MQ

MCP8025AT-115E/MP

PIC18F46K22T-E/MV032

MCP98243T-BE/MC

MCP98243T-BE/MCAA

PIC16HV616T-E/ML

DSPIC33EP64MC206T-E/MRC04

MCP4541T-103E/MF

MCP4541T-104E/MF

PIC14000T-04/SO

PIC16C773T/SS

PIC16C56AT-04/SO

PIC18LF65K80T-I/PT

PIC18LF66K80T-I/PT

DSPIC33FJ64MC506T-I/PTC21

PIC18F65K80T-I/PT

DSPIC30F2023T-30I/PT

PIC16C62B-04/SS

PIC16C62B-20/SS

HS12-100P0S/12PS30

PIC16C73B-04/SS

PIC16C73B-20/SS

PIC16F873-20/SOV01

PIC16F690T-E/SS049

25LC128T-E/SNRVA

PIC24HJ64GP202T-E/SO

PIC24HJ64GP502T-E/SO

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PIC24HJ128GP502T-E/SO

PIC24HJ32GP302T-E/SO

DSPIC33FJ64GP202T-E/SO

PIC16F873AT-I/SO

PIC24FV32KA301T-I/SS

PIC24FV16KA301T-I/SS

PIC18F25Q24T-I/SO

PIC16F17554T-I/SS

PIC16F17555T-I/SS

PIC16F17556T-I/SS

PIC16F17554T-I/SO

PIC16F17555T-I/SO

PIC16F17556T-I/SO

PIC18F14Q41T-I/SS021

24CS128T-I/ST

PIC16LF1509T-I/SS028

PIC16LF1509T-I/SS029

PIC16C55AT-04I/SS

PIC18LF25J10T-I/SS038

PIC12F675T-I/SN026

PIC12F635T-I/SN050

ATMEGA329A-AU

ATMEGA6450-16AU

ATMEGA6490-16AU

ATMEGA3290PV-10AU

ATMEGA162V-8AU

ATMEGA2560-16AU-HCM

AT90CAN64-16AU

ATMEGA64L-8AU

PIC32MX170F512L-I/PT

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PIC18LF55K42-I/PT

DSPIC33FJ64MC710-I/PT

DSPIC33FJ256MC710A-I/PF

PIC32MX675F512H-80I/PT

PIC32MX575F256H-80I/PTC22

24AA04T-I/SN

24AA01HT-I/SN

24LC01BT-I/SN

24AA01T-I/SN

24LC16BHT-I/SN

PIC16LF1782T-I/SS

PIC16LF1825T-I/ST

MCP2035T-I/ST

PIC18LF26K22T-I/SS

PIC16F1459T-I/SS

PIC16F882T-I/SS

24AA16T-I/SNB22

PIC16F610T-I/ST041

PIC18F26K20T-I/SO

PIC18F25K22T-I/SO

PIC24F32KA302T-I/SS

PIC24F16KA302T-I/SS

RE342S16TF

PIC24FV16KA302T-I/SS

PIC24FV32KA302T-I/SS

24AA16T-I/SN

PIC16LF723T-I/SO

PIC16F876AT-I/SSC36

PIC18F2410T-I/SO

PIC18F46K20T-I/ML032

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

OS81210AMR-B2B-010200

PIC16LF15325T-I/JQ021

PIC24FJ256GB106T-I/MR033

PIC24FJ256GB106T-I/MR034

ATSHA204A-MAH8L-S

24CS128T-I/Q4B

AVR32SD32T-I/QZB

ATECC608B-MAH8N-T

AVR128DA48ST-I/6MX

AVR128DA32ST-I/QZB

ATECC608C-MAH8T-T

PIC16F17524T-I/ML

PIC16F17525T-I/ML

PIC16F17526T-I/ML

PIC16F17544T-I/ML

AGL250V5-VQG100

M1AGL250V2-VQ100

M1AGL250V2-VQG100

M1AGL250V5-VQ100

M1AGL250V5-VQG100

A3P125-1VQ100

A3P125-1VQG100

A3P125-2VQ100

A3P125-2VQG100

A3P125-VQ100

PIC18F2480-E/SO

AVR32DD28-E/SO

LAN8651B1-E/REL

PIC16F15376-E/MLVAO

PIC32CM6408MC00032-E/RTBVAO

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AVR128DA48-E/6LXL10

DSPIC33EP32GP504-I/PT

ATMEGA32A-AU

ATMEGA48A-AU

ATMEGA48PA-AU

DSPIC33EP32MC204-I/PT

PIC24EP32MC204-I/PT

PIC32CM5164JH01048-I/Y8X

PIC32CM2532JH00048-I/Y8X

PIC32CM5164JH00048-I/Y8X

PIC32CM2532JH01048-I/Y8X

DSPIC33CH64MP506-I/PT

DSPIC33CH128MP506-I/PT

DSPIC33CH64MP206-I/PT

DSPIC33CH128MP206-I/PT

DSPIC33CH64MP505-I/PT

DSPIC33CH128MP505-I/PT

DSPIC33CH64MP205-I/PT

DSPIC33CH128MP206-I/PTC01

DSPIC33CK128MP206-I/PTC01

DSPIC33CK128MP506-I/PTC02

DSPIC33CK256MP506-I/PTC03

PIC16F18345-I/GZ

ATMEGA6450V-8AU

ATMEGA32L-8AU

ATMEGA128L-8AU

ATMEGA128A-AU

ATMEGA128-16AU

ATMEGA8L-8AU

ATMEGA8-16AU

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ATMEGA3290PA-AU

ATMEGA1280-16AU

ATMEGA1280V-8AU

ATMEGA165P-16AU

PIC18F47Q84-I/PT

DSPIC30F5011-20I/PT

TC7660SEOA723

TC7660EOA723

MCP601-E/ST

MCP6022-E/ST

MCP6024-E/ST

MCP42050-E/ST

MCP42100-E/ST

MCP6S92-E/SN

MCP42010-E/ST

MCP602-E/ST

MCP6022-E/SN

TC622VOA

PIC16F767-E/SS

PIC16C773-E/SS

PIC16C63-04E/SO

PIC16F636-E/ST

PIC16F872-E/SS

MCP6542-E/SN

MCP6142-E/SN

PIC16F628-04E/SS

MCP6234-E/ST

MCP6548-E/SN

MCP6543-E/SN

MCP6244-E/ST

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MCP6547-E/SN

MCP6549-E/ST

PIC16F628-20E/SS

PIC12F683T-E/SN084

PIC12F683T-E/SN

25LC160AT-E/SN

PIC18F6620T-E/PTVAO

DSPIC33CK256MP608T-E/PTVAO

DSPIC33CK256MC505T-E/PTVAO

DSPIC33CK1024MP710T-E/PTVAO

PIC18F45K22T-E/PTVAO-GM

DSPIC33CK64MC105T-E/PTVAO

DSPIC33CK32MC105T-E/PTVAO

ATSAMC21G18A-AZT510

ATSAMC21G17A-AZTVAO

ATSAMC21G18A-AZTVAO

ATSAMC20G17A-AZTVAO

DSPIC33CK256MP305T-E/PTVAO

PIC16F18876T-E/PTVAO

ATSAMC21J17A-AZT510

ATSAMC21J18A-AZT510

ATSAMC21J18A-AZTVAO

ATSAMC21J17A-AZTVAO

ATSAMC21J16A-AZTVAO

ATSAMC20J16A-AZTVAO

ATSAMC20J18A-AZTVAO

PIC16F1516T-I/SS024

93LC86BT-I/ST

93AA86BT-I/ST

24LC64T-I/STRVE

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93LC86AT-I/ST

93AA86AT-I/ST

93LC66BT-E/ST15KVAO

25LC256T-E/ST16KVAO

MCP602T-E/STVAO

DSPIC33EV32GM102T-E/SSVAO

25LC040AT-E/ST16KVAO

PIC18F25K83T-E/SSVAO

PIC18LF26K40T-E/SSVAO

PIC24EP128GP202T-E/SSVAO

PIC18LF25K40T-E/SSVAO

PIC18F24Q10T-E/SSVAO

PIC18F24Q10T-E/SOVAO

24LC02BT-E/ST16KVAO

25LC160DT-E/ST16KVAO

24AA32AT-E/ST16KVAO

AVR64EA32-E/RXB

AVR32EA32-E/RXB

DSPIC33AK128MC102-E/M7

DSPIC33AK64MC102-E/M7

DSPIC33AK32MC102-E/M7

PIC16F1937-E/MV

AT86RF233-ZF

PIC16F15225-E/MG

AVR128DA64-E/MR

AVR128DA32-E/RXB

ATTINY817-MF

PIC16F18144-E/6N

PIC16F17145-E/6N

ATSAMD21G15B-MZT

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ATSAMD21G16B-MZT

PIC32MK0512MCF064-I/PT

DSPIC33EP128MC204-I/PTA3

PIC32MX575F512H-80I/PTC24

PIC32MZ2048EFH064-250I/PT

PIC32MZ2048EFH064-250I/PTC21

PIC32MX440F128L-80I/PT

PIC32MX564F128L-I/PT

PIC32MX534F064L-I/PT

PIC32MX564F064L-I/PT

PIC32MX664F128L-I/PT

PIC32MX775F256H-80I/PT

PIC32MX460F512L-80I/PT

PIC32MX460F256L-80I/PT

PIC32MX575F512L-80I/PTC21

PIC32MX575F512L-80I/PT

PIC32MX575F256L-80I/PT

PIC32MX274F256D-I/PT

PIC32MX254F128D-I/PT

PIC24HJ256GP210A-I/PF

DSPIC33FJ128GP710-I/PT

DSPIC33FJ256GP510-I/PT

PIC32MX530F128H-I/PT

PIC32MX170F512H-I/PT

PIC32MX130F128H-I/PT

PIC32MZ2048EFH100-I/PFM21

DSPIC33FJ64GP710-I/PT

PIC32MX120F064H-I/PT

PIC32MX250F256H-I/PT

PIC32MX230F128H-I/PT

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PIC32MX250F128D-50I/PT

PIC32MX150F256H-I/PT

PIC16F887-I/PT

PIC32MX150F128D-50I/PT

PIC32MZ1024ECG064-I/PT

PIC24HJ256GP610-I/PT

DSPIC33FJ64GP310-I/PT

DSPIC33EV32GM004-I/PT

PIC32MX250F256L-I/PT

DSPIC33EV32GM104-I/PT

DSPIC33EV256GM104-I/PT

DSPIC33EV128GM004-I/PT

DSPIC33FJ128MC510-I/PT

DSPIC33FJ128MC710-I/PT

PIC32MX440F128H-80I/PT

PIC32MX420F032H-40I/PT

PIC32MX664F064L-I/PF

PIC32MX764F128L-I/PF

PIC32MX330F064L-I/PF

PIC32MX430F064L-I/PF

PIC16F18877-I/PT

DSPIC33EP256MU810-I/PF

DSPIC33EP512MU810-I/PF

PIC32MX360F512L-80I/PT

PIC32MX360F256L-80I/PT

PIC32MX320F128L-80I/PT

PIC16LF1904T-I/PT

PIC16F1719T-I/PT

PIC16F1717T-I/PT

PIC16LF1937T-I/PT

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PIC32MX575F512LT-80I/PT024

PIC16F1934T-I/PT

ATA663211-GBQW0

PIC18F45Q43-E/MPVAO

PIC16F1786-E/MLVAO

PIC18F47Q83-E/NHXVAO

ATSAMC21E17A-MZ510

ATSAMC21E18A-MZVAO

ATSAMC21E15A-MZVAO

ATSAMC20E16A-MZVAO

ATSAMD21G18A-MZ510

PIC16F19197-E/5LXVAO

PIC16LF19196-E/5LXVAO

ATTINY3217-MZ-VAO

PIC16LF1936-E/MLVAO

UTC2000-E/MG042

PIC16F15356-E/MVVAO

PIC32MX675F256H-80I/PTD21

PIC32MX695F512H-80I/PTD22

M1A3P250-VQG100

A3P060-1VQ100

A3P060-1VQG100

HV2601TQ-G

HV2705TQ-G

HV2605TQ-G

A3P060-2VQ100

A3P060-2VQG100

A3P060-VQ100

DSPIC33EV128GM106T-I/PTVAO

DSPIC33EV64GM006T-I/PTVAO

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DSPIC33EV64GM004T-I/PTVAO

DSPIC33EV64GM104T-I/PTVAO

DSPIC33EV32GM104T-I/PTVAO

DSPIC33EV256GM106T-I/PTVAO

PIC16F887T-I/PTVAO

PIC24HJ128GP506AT-I/PTVAO

AT25010B-MAHL-E

ATMEGA1609-MUR

ATMEGA809-MUR

PIC12LF1572T-I/MFSIS

PIC18F45K42T-I/ML

PIC18LF46K42T-I/ML

AT25020B-MAHL-T

AT25020B-MAHL-E

PIC18F46K42T-I/ML

DSPIC33EP32GP502T-I/MM

ATMEGA3209-MUR

PIC16F570-I/SS

PIC16LF1454-I/ST

93LC46B-I/ST

24AA512-I/ST

DSPIC33EP512MC502-E/MM

PIC16F1512-E/MV

PIC16F1513-E/MV

DSPIC33EV32GM002-E/MM

DSPIC33EV32GM102-E/MM

DSPIC33EV64GM002-E/MM

DSPIC33EV64GM102-E/MM

DSPIC33EV128GM002-E/MM

DSPIC33EV128GM102-E/MM

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DSPIC33EP32GS504-E/ML

DSPIC33EP16GS504-E/ML

PIC24F32KA304-E/ML

PIC24FV32KA304-E/ML

PIC24F32KA302-E/ML

PIC16F1939-E/ML

DSPIC33EP64GS504-E/ML

PIC24FJ256GA106-E/MR

DSPIC33EV64GM106-E/MR

PIC16F1783-E/MV

PIC16F1789-E/MV

DSPIC33FJ128MC706A-E/MR

DSPIC33FJ128MC506A-E/MR

MCP23017-E/ML

MTD6508-ADJE/JQ

PIC16F1707-E/ML

PIC24FJ64GA106-E/MR

PIC24FJ128GA106-E/MR

PIC24HJ64GP506A-E/MR

MCP23S17-E/ML

DSPIC33FJ128GP706A-E/MR

DSPIC33FJ64GP206A-E/MR

A3PN250-1VQ100

A3PN250-1VQG100

A3PN250-2VQ100

A3PN250-2VQG100

A3PN250-VQ100

DSPIC33FJ256MC510-I/PT

PIC32MX550F256L-I/PT

DSPIC33EV256GM004-I/PT

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DSPIC33EV128GM104-I/PT

DSPIC33FJ256MC710-I/PT

PIC32MX550F256L-I/PF

PIC16F18325T-I/JQ

PIC16LF18325T-I/JQ

PIC16F18323T-I/JQ

KSZ8081MNXIA-TR

KSZ8091MNXIA-TR

24LC64T-I/MNY

24AA64T-I/MNY

24FC64T-I/MNY

PIC16LF18323T-I/JQ

24LC64FT-I/MNY

24AA64FT-I/MNY

24FC64FT-I/MNY

DSPIC33EP64MC204T-I/ML

DSPIC33EP64MC504T-I/ML

ATSAMC21E18A-MUTS2

PIC18F26Q43T-I/STX

PIC18LF45K22T-I/ML

ATSAMC20J17A-AZTVAO

PIC16F18855T-E/MV

PIC16F18875T-E/MV

PIC12F615T-E/MF086

PIC16F1574T-E/JQ

PIC16F1575T-E/JQ

PIC16F18324T-E/JQ

DSPIC33EP64MC206T-E/MR

DSPIC33EP64MC506T-E/MR

PIC24EP64MC206T-E/MR

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USB5742BT/2G

USB5742BT/2GC01

USB5744BT/2GX01

USB5744T/2G

USB5744T/2GD02

USB5744T/2GTB

USB5744T/2GX01

USX5044T/2G

USB5742T/2G

LAN9253T/R4X

USB5807CT/KD

USB5806CT/KD

USB5806CT/KDD01

PIC16LF1519-E/PT

ATSAME54N19A-AZ

ATSAME54N20A-AZ

ATSAME53N20A-AZ

ATSAME51N19A-AZ

ATSAME51N20A-AZ

ATSAMD51N19A-AZ

DSPIC33EP128GS708-E/PT

AVR64DB64T-E/PTVAO

AVR128DB64T-E/PTVAO

PIC32CX1025SG41100T-E/E5XVAO

PIC18F57Q84T-E/PTVAO

ATA5830-WNQW-MB

ATA6562-GBQW1-BW

ATA6570-GCQW1-MB

ATA6614Q-PLQW-1-BW

ATA6614Q-PLQW-1-MB

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ATA6617C-P3QW-1-GM

ATA6622C-PGQW-1-MB

ATA6624C-PGQW-1-VW

ATA663211-GBQW-BW

PIC18F67K40-E/MR

PIC24FJ512GL406-I/PT

AT32UC3L0128-AUT

AT32UC3L0256-AUT

ATUC128L4U-AUT

ATUC256L4U-AUT

ATUC64L4U-AUT

ATSAMD21E18A-AU-SLL

ATSAMD21J18A-AU-SLL

PIC32CM2532LE00100-I/PF

PIC32CM2532LS00100-I/PF

PIC32CM2532LE00064-I/PT

PIC32CM2532LS00064-I/PT

PIC32CM2532LE00048-I/Y8X

PIC32CM2532LS00048-I/Y8X

PIC32MX270F512H-I/PT

PIC32MX570F512H-I/PT

PIC32MX270F512L-I/PT

PIC32MX570F512L-I/PT

DSPIC33AK128MC105-I/PT

DSPIC33AK64MC105-I/PT

ATSAMD51N20A-AU-RB

PIC16F726T-I/SS034

PIC32MX250F128B-I/ML

PIC32MX150F128D-I/ML

PIC32MX130F064D-I/ML

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A3P060-VQG100IX277

DSPIC33CH256MP206-I/PTC01

ATSAMD21J17A-MMU

ATSAMD21J18A-MMU

ATSAMD21J18A-MMU-SLL

PIC16F1847-I/MV

DSPIC33EP64MC202-I/MM

DSPIC33EP64MC502-I/MM

PIC24EP64MC202-I/MM

PIC16F18855-I/ML

PIC16F18855-I/MV

PIC16LF18855-I/MV

A3PN250-VQG100

A3PN250-1VQ100I

PIC16F1619-E/GZ

PIC16F15324-E/JQ

PIC16F1708-E/ML034

PIC16F18326-E/JQ

PIC18F1220-E/ML

PIC16F15354-E/ML

PIC18F26K40-E/MV

MEC1418-NU-D0

MEC1404-NU

MEC1418-NU

MEC1406-NU

SCH5555V-NU

LAN9311-NU

PIC32MX470F512L-120/PF

PIC32MX470F512L-120/PT

PIC32MX470F512H-120/PT

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PIC32MX470F512L-120/PT021

HV20822TQ-G

HV238TQ-G

HV2201TQ-G

ATF1504AS-7AX100

A3P250-1VQ100

A3P250-1VQG100

A3P250-2VQ100

A3P250-2VQG100

A3P250-VQ100

A3P250-VQG100

M1A3P250-1VQ100

M1A3P250-1VQG100

M1A3P250-2VQ100

M1A3P250-2VQG100

M1A3P250-VQ100

PIC16LF1825T-E/STVAO

MCP6022T-E/STVAO-BW

MCP47FVB02A0T-E/STVAO

MCP47FVB12A0T-E/STVAO

MCP47FVB22A3T-E/STVAO

PIC16F1704T-E/STVAO

PIC16F1705T-E/STVAO

PIC16LF1705T-E/STVAO

PIC16LF1554T-E/STVAO

ATMEGA4808-XFR-VAO

PIC16F1824T-E/STVAO

24AA256T-E/ST16KVAO-GM

PIC18F26Q10T-E/SSVAO

PIC16F1825T-E/STVAO

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F1773T-E/SSVAO

PIC16F1776T-E/SSVAO

PIC16F15356T-E/SSVAO

PIC16F15324T-E/STVAO

PIC16F688T-E/STVAO

PIC16F18325T-E/STVAO

25AA256T-E/ST16KVAO

PIC16F18323T-E/STVAO

DSPIC33EV32GM102T-E/SSVAO-GM

DSPIC33CK64MP102T-E/SSVAO

PIC16F1703T-E/STVAO

24LC256T-E/ST16KVAO

24AA256T-E/ST16KVAO

24FC256T-E/ST16KVAO

PIC16F1615T-E/STVAO

PIC24FJ64GA406T-I/MR

PIC24FJ256GA406T-I/MR

PIC24FJ256GB406T-I/MR

PIC24FJ128GB406T-I/MR

PIC32MZ1024EFK100T-E/PT

PIC32MK1024GPK064T-E/PT

PIC32MK0512GPK064T-E/PT

KSZ9031RNXCC-TR

UTC2000T/MG

USB4715T/Y9X

MCP73871T-2CC/ML

KSZ8041NL-TR

KSZ8041RNL-TR

KSZ8851SNL-TR

KSZ8081RNBCA-TR

Date: Tuesday, July 22, 2025

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KSZ8091RNBCA-TR

KSZ8081MNXCA-TR

KSZ8091MNXCA-TR

LAN9250T/ML

LAN9252T/ML

LAN9353T/ML

KSZ8081RNACA-TR

KSZ8081RNDCA-TR

KSZ8091RNACA-TR

KSZ8091RNDCA-TR

SPNZ801128-TR

SPNZ801143-TR

USB2512BT/M2

USB2513BT/M2

PIC16F15325T-E/STVAO

PIC16F18324T-E/STVAO

PIC32MZ2048EFH100-E/PF

PIC32MZ2048EFM100-E/PF

PIC24EP512GU810-E/PT

PIC24HJ128GP204-E/PT

PIC24HJ128GP504-E/PT

PIC24EP512GP206-E/PT

PIC32MK1024GPD100-E/PT

PIC32MK0512GPE064-E/PT

PIC32MK0512GPD064-E/PT

PIC32MK0512MCF064-E/PT

PIC32MK1024GPE100-E/PT

DSPIC33EP512MU810-E/PT

PIC24EP256GU810-E/PT

DSPIC33EP512GP504-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33EP512MC504-E/PT

PIC16F18877-E/PT

PIC24EP512GP806-E/PT

PIC32CM1216MC00032-I/PT

PIC32CM6408MC00032-I/PT

DSPIC33EP256GP504-I/PT

DSPIC33EP256MC204-I/PT

DSPIC33EP256MC504-I/PT

PIC24EP256MC204-I/PT

PIC24FJ128GL410-I/PT

PIC24FJ256GL410-I/PT

PIC24FJ512GL410-I/PT

PIC24FJ128GU410-I/PT

PIC24FJ256GU410-I/PT

PIC24FJ512GU410-I/PT

A3P250-VQG100I

AGL060V5-VQG100I

A3P125-VQG100I

DSPIC33EP256GP506-I/PT

DSPIC33EP256MC506-I/PT

PIC24EP256MC206-I/PT

PIC16F18875-I/PT

A3P125-VQG100IX94

DSPIC33CK256MP206-I/PTC05

A3P250-VQG100IX537

A3P250-VQG100IX538

A3P250-VQG100IX60

DSPIC33CH512MP508-I/PT

DSPIC33CH512MP208-I/PT

DSPIC33CH256MP508-I/PTC01

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33CH512MP208-I/PTC02

DSPIC33CH256MP208-I/PTC03

DSPIC33CH512MP508-I/PTC04

AGL250V5-VQG100IX377

DSPIC33CH256MP508-I/PTC05

DSPIC33CH256MP508-I/PT

DSPIC33CH256MP208-I/PT

A3P030-VQG100IX94

AGL250V5-VQG100IX52

PIC24FJ512GU406-E/PT

ATSAMC21G15A-AZ

ATSAMC21G16A-AZ

ATSAMC21G17A-AZ

ATSAMC21G18A-AZ

ATSAMC20G18A-AZ

ATSAMC20G17A-AZ

ATSAMC20G16A-AZ

ATSAMC20G15A-AZ

ATSAMD20E16B-AZ

ATSAMD20E15B-AZ

ATSAMD20J16B-AZ

ATSAMD20J15B-AZ

ATSAMD20G16B-AZ

ATSAMD20G15B-AZ

ATSAMC21E15A-AZ

ATSAMC21E16A-AZ

ATSAMC21E17A-AZ

ATSAMC21E18A-AZ

ATSAMC20E18A-AZ

DSPIC33FJ32GP204T-E/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC17C42A-25/PQ

PIC17C756A-16/PT

PIC17C756A-33/PT

PIC16C77-20/PQ

PIC16C74B-20/PQ

PIC16C924-04/PT

PIC16LC924-04/PT

PIC16C74B-04/PQ

PIC16C65A-20/PQ

PIC16C924-08/PT

TC7109ACKW

MEC1310-NU

MEC1322-NU-C0

MEC1324-NU

KBC1126-NU

PIC32MX450F256L-120/PF

PIC32MX450F256L-120/PT

PIC32MX450F256H-120/PT

MEC1322-NU

TC7129CKW

ATF1504AS-7AX44

MEC1428-NU-C1

ATF1508AS-7AX100

MEC1408-NU

MEC1404-NU-D0

MEC1406-NU-D0

MEC1416-NU-D0

MEC1414-NU

PIC16F18446-I/GZ

MCP4641T-503E/ST

Date: Tuesday, July 22, 2025

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MCP4641T-502E/ST

MCP4641T-103E/ST

MCP4641T-104E/ST

25LC640AXT-E/ST

MCP4911T-E/SN

PIC18LF2420T-E/SOC03

MCP6071T-E/SN

MCP6051T-E/SN

MCP6061T-E/SN

MCP4901T-E/SN

MCP4811T-E/SN

MCP4342T-104E/ST

MCP4342T-502E/ST

MCP4342T-103E/ST

PIC16F18345T-I/SS

PIC16F1503T-I/ST053

PIC16F15225T-I/ST

PIC16F15256T-I/SS

PIC16F15255T-I/SS

PIC16F1936T-I/SSC03

AVR128DB28T-I/SS

AVR64DB28T-I/SS

DSPIC33EP128MC202T-I/SS

AVR32DB28T-I/SS

PIC16F526T-I/ST

PIC24EP128GP202T-I/SS

ATSAMD21E17D-MFT

ATSAMC20E18A-MZT

ATSAMC20E17A-MZT

ATSAMC20E16A-MZT

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ATSAMC20E15A-MZT

DSPIC33CK1024MP706T-E/MR

PIC12HV615T-I/MF028

24AA32AT-I/MNY

PIC12HV615T-I/MF

PIC12HV615T-I/MF026

PIC12HV615T-I/MF027

PIC12HV615T-I/MF030

PIC18F23K20T-I/ML

PIC18F26Q10-E/MLVAO

PIC32CM2532JH01064T-E/PT

PIC32CM5164JH01064T-E/PT

PIC32CM5164JH01048T-E/Y8X

PIC16LF877-04I/PQ

PIC18LF458-I/PT

PIC18LF448-I/PT

PIC16C67-04I/PQ

PIC16LC67-04I/PQ

PIC16F874-04I/PQ

PIC16F874-20I/PQ

PIC16LF874-04I/PQ

PIC17C44-16I/PT

PIC18LF8520-I/PT

PIC16LC64A-04I/PQ

PIC16C74A-04I/PQ

PIC16C74A-20I/PQ

PIC17LC44-08I/PQ

PIC18F8520-I/PT

PIC16C65B-04I/PQ

PIC18LF8525-I/PT

Date: Tuesday, July 22, 2025

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MCP4642T-104E/MF

MCP4642T-503E/MF

MCP4652T-502E/MF

MCP4652T-103E/MF

ATSAMD20E15B-MZ

LAN8670C2-E/LMX

LAN8672C2-E/LNX

LAN8671C2-E/U3B

ATSAMD21G16B-MZ

ATSAMD21G15B-MZ

PIC18F54Q71-E/6LX

PIC18F55Q71-E/6LX

PIC18F44Q71-E/MP

PIC18F45Q71-E/MP

PIC16F1823-E/JQ

PIC18F26Q71-E/STX

PIC18F24Q71-E/STX

PIC18F25Q71-E/STX

PIC18F25K83-E/ML

PIC18F26K83-E/ML

DSPIC33AK128MC103-E/M7

DSPIC33AK64MC103-E/M7

DSPIC33AK32MC103-E/M7

DSPIC33AK128MC105-E/M7

DSPIC33AK64MC105-E/M7

DSPIC33AK32MC105-E/M7

PIC16F18876-E/MV

PIC18F2480-E/ML

PIC18F4480-E/ML

AVR64EA48-E/6LX

Date: Tuesday, July 22, 2025

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PIC18F56Q71-E/6LX

AVR32EA48-E/6LX

AVR16EA48-E/6LX

AVR16EA28-E/STX

MTCH1030-E/MG

MCP6244T-E/STVAO

MCP6274T-E/STVAO

MCP41HV51T-103E/STVAO

MCP6294T-E/STVAO

LX3301AQPW-TR

MCP604T-E/STVAO

MCP6404T-E/STVAO

MCP6444T-E/STVAO

MCP6284T-E/STVAO

MCP6034T-E/STVAO

MCP6144T-E/STVAO

HV2818/R4X

HV2918/R4X

KSZ9031RNXCA

LAN8710A-EZC-ABC

LAN8720A-CP-ABC

LAN9253/R4X

USB5807C/KD

USB5806C/KD

USB5734/MR

USB5734/MRD01

USB5734/MRD02

USB5734/MRTB

LAX8710A/S8X

DSPIC33EP64MC204T-H/MLVAO

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F767-I/ML

MCP73833-CNI/MF

PIC12LF1822T-E/SN

MCP6H04T-E/ST

PIC24FV16KA301T-E/SS

PIC16F1933T-E/SS

24LC256T-E/ST

MCP4902T-E/ST

PIC18F25K22T-E/SS

24LC256T-E/STRVE

MCP654T-E/ST

MCP6444T-E/ST

MCP4342T-503E/ST

MCP4332T-502E/ST

MCP4332T-103E/ST

MCP4332T-104E/ST

MCP4912T-E/ST

MCP4332T-503E/ST

93C66T-E/SN

MCP4801T-E/SN

PIC16F726T-E/SS

PIC16F723T-E/SS

DSPIC33EV32GM006-I/MR

DSPIC33EV32GM106-I/MR

DSPIC33EV32GM104-I/ML

DSPIC33FJ128GP306A-I/MR

DSPIC33FJ128GP206A-I/MR

DSPIC33FJ64GP706A-I/MR

DSPIC33FJ128GP706A-I/MR

DSPIC33FJ64MC706A-I/MR

Date: Tuesday, July 22, 2025

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DSPIC33FJ64MC506A-I/MR

DSPIC33FJ64GP802-I/MMB21

PIC18F24Q24-E/SO

PIC18F25Q24-E/SO

PIC16LF1554-E/STM10

PIC16LF1559-E/SSM10

PIC16F17554-E/SS

PIC16F17555-E/SS

PIC16F17556-E/SS

PIC16F17554-E/SO

PIC16F17555-E/SO

PIC16F17556-E/SO

ATTINY1616-XF

PIC16F17544-E/SS

PIC16F17545-E/SS

AVR64DA32T-E/RXB

MIC37303YML-T5

MIC37303YML-TR

ATSAML10E14A-MFT

ATSAML10E15A-MFT

ATSAML11E14A-MFT

ATSAML11E15A-MFT

ATSAML10E16A-MFT

ATSAML11E16A-MFT

MIC69101-1.8YML-TR

MIC69103YML-TR

MIC69153YML-TR

ATSAML10E16A-MZT

ATSAML10E15A-MZT

ATSAML11E15A-MZT

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ATSAML11E16A-MZT

PIC32MK0256MCJ064-E/PT

PIC32MK0256GPG064-E/PT

PIC16LF18344-E/GZ

PIC18F65K40-E/MR

PIC16F1933-E/MV

PIC16LF1619-E/GZ

PIC24F16KA101-E/MQ

PIC24F16KA102-E/ML

PIC16LF1938-E/MV

PIC16LF18424-E/ST

PIC16LF18425-E/ST

93C46A-E/SN

PIC16F18426-E/ST

PIC16LF18426-E/ST

PIC32MX575F256LT-80I/PF

PIC32MX695F512LT-80I/PF

PIC32MX150F256LT-50I/PT

PIC32MX170F512LT-50I/PT

DSPIC33EP128GP506T-I/PT

PIC32MX675F512LT-80I/PF

ATSAMD20G14B-AUT

ATSAMD20G15B-AUT

PIC32MX250F128DT-I/PT025

PIC18LF55K42T-I/PTC01

ATSAM4LC8CA-AUR

ATSAMD20G16B-AUT

PIC24FJ64GA010T-I/PT

PIC18F4431T-I/PT029

ATSAM4LS8CA-AUR

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ATSAML22G16A-AUT

ATSAMD21G15B-AUT

ATSAMD21G16B-AUT

PIC24FJ128GB410T-I/PT

PIC24FJ64GB410T-I/PT

PIC18F4431T-I/PT030

ATSAML22G17A-AUT

ATSAML22G18A-AUT

PIC32MZ0512EFE064T-I/PT025

DSPIC33CK64MC105T-I/PT

DSPIC33EP64GS506T-I/PT020

DSPIC33EP64GS506T-I/PTC08

AT80C51RD2T-RLRUM

DSPIC33EP64GS506T-I/PT

PIC32MZ0512EFE064T-I/PTA23

PIC32MZ0512EFE064T-I/PT

PIC16F916-I/ML

PIC18LF2450-I/ML

PIC18F2450-I/ML

PIC16LF72-I/ML026

PIC18LF4420-I/ML

PIC16F873A-I/ML

PIC16LF873A-I/ML

DSPIC33EP32MC202T-H/MMVAO

PIC16F886T-H/MLVAO

DSPIC33FJ128MC804T-H/MLVAO

DSPIC33EP32MC204T-H/MLVAO

DSPIC33FJ64MC804T-H/MLVAO

DSPIC33EP256MC204T-H/MLVAO

PIC16F616T-H/MLVAO

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DSPIC33FJ32MC202T-H/MMVAO

DSPIC33EP128MC204T-H/MLVAO

DSPIC33EV64GM004T-H/MLVAO

ATA6564-GBQW0

AT27BV1024-90JU

AT27C2048-55JU

AT27C2048-90JU

MT9171AP1

MT9172AP1

MT9122AP1

PIC18F24K40T-I/MV

PIC18F25K40T-I/MV

PIC16F18175T-I/PT

DSPIC33CK256MP205T-I/PTC05

ATMEGA1609-AUR

ATMEGA809-AUR

ATMEGA3209-AUR

PIC18F54Q71T-I/PT

PIC18F55Q71T-I/PT

ATSAMC20J17A-AUTS2

AT32UC3L0128-AUR

AT32UC3L0256-AUR

ATUC128L4U-AUR

ATUC256L4U-AUR

ATUC64L4U-AUR

PIC32CM2532LE00100T-I/PF

PIC32CM2532LS00100T-I/PF

PIC32CM2532LE00064T-I/PT

PIC32CM2532LS00064T-I/PT

PIC32CM2532LE00048T-I/Y8X

Date: Tuesday, July 22, 2025

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PIC32CM2532LS00048T-I/Y8X

PIC16F18346T-I/SS

PIC16LF18346T-I/SS

PIC18F06Q41T-I/ST

DSPIC33EP64GP502T-I/SS

PIC18F06Q40T-I/ST

AVR64DD28T-I/SS

AVR64DD28T-I/SO

PIC12F1571T-I/SN

PIC12F1572T-I/SN

24LC128T-I/SNRVF

PIC16LF18345T-I/SS

24AA128T-I/SNRVF

24FC128T-I/SN

AVR64DB48T-E/PT

ATSAMD51N19A-AZT

AVR32DB48T-E/PT

DSPIC33EP128GS708T-E/PT

DSPIC33CK256MP205T-E/PTC06

DSPIC33EP128GS808T-E/PT

DSPIC33EP64GS808T-E/PT

DSPIC33EP64GS708T-E/PT

PIC32MK0128MCA048T-E/Y8X

DSPIC33CH256MP206T-E/PTC02

ATSAME54N20A-AZT

AVR128DB48T-E/PT

ATSAMC21N18A-AZT

ATSAMC21N17A-AZT

ATSAMC20N18A-AZT

ATSAMC20N17A-AZT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

AVR64DA64T-E/PT

PIC24HJ64GP504T-E/PT

DSPIC33FJ64GP204T-E/PT

AVR64DA32T-E/PT

AVR64DA48T-E/PT

DSPIC33FJ64MC804T-E/PT

ATSAML10E16A-AZT

ATSAML10E15A-AZT

ATSAML11E15A-AZT

ATSAML11E16A-AZT

ATSAML10E14A-AFT

ATSAML10E15A-AFT

ATSAML10E16A-AFT

ATSAML11E14A-AFT

ATSAML11E15A-AFT

ATSAML11E16A-AFT

ATSAMC20J18A-AZT

ATSAMC21J18A-AZT

ATSAMC21J17A-AZT

ATSAMC20J17A-AZT

ATSAMC21J16A-AZT

ATSAMC20J16A-AZT

ATSAMC20J15A-AZT

ATTINY1624-XU

25LC640-I/SN

25AA640-I/SN

25AA320-I/SN

25C320-I/SN

PIC18LF2523-I/SO

PIC18F2523-I/SO

Date: Tuesday, July 22, 2025

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PIC18LF2423-I/SO

PIC32MZ0512EFF064T-I/PT

PIC32MZ2048EFG064T-I/PT

PIC32MZ2048EFH064T-I/PT

PIC32MZ2048EFM064T-I/PTN21

PIC18LF2680-I/SO

MCP2140A-I/SO

RE46C109S16F

PIC18F2220-I/SOV02

PIC18F14K50-I/SS

DSPIC33FJ64MC804-E/PTVAO

PIC18F66K80-E/PTVAO

PIC18F45K80-E/PTVAO

PIC18F46K80-E/PTVAO

PIC32MZ1024EFH100-E/PTVAO

DSPIC33EV32GM006-H/PT

DSPIC33EV32GM106-H/PT

DSPIC33EV128GM004-H/P8

DSPIC33EV128GM104-H/P8

DSPIC33EV64GM004-H/P8

PIC16F17546-E/SS

DSPIC33EP128GP502T-E/MM

24FC02T-E/Q4B

PIC16F1779T-E/MV

PIC16LF1779T-E/MV

PIC16F1503T-E/MG039

PIC16LF1503T-E/MG

DSPIC33CK128MC105T-E/M7

24LC256T-E/MNY

24AA256T-E/MNY

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DSPIC33CK256MC506T-E/MR

DSPIC33CK128MC506T-E/MR

DSPIC33CK256MC106T-E/MR

DSPIC33CK128MC106T-E/MR

MIC5219YMT-TR

PIC16F17524-E/ST

PIC16F17525-E/ST

PIC16F17526-E/ST

MCP3912BA1-E/SS

MCP3919BA1-E/SS

MCP3913BA1-E/SS

24LC16B-M/SN

25LC640A-M/SN

MCP606-I/ST

MCP608-I/ST

MCP6024-I/ST

MCP3302-CI/ST

MCP3302-BI/ST

MCP6544-I/ST

MCP607-I/ST

MCP609-I/ST

MCP6549-I/ST

MCP42100-I/ST

MCP42010-I/ST

MCP602-I/ST

MCP601-I/ST

MCP6542-I/SN

HCS301-I/SN

HCS300-I/SN

MCP6022-I/SN

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PIC18F4680-I/ML

PIC16LF726-I/ML

PIC18LF2431-I/MM

PIC18LF2580-I/ML

PIC18LF4580-I/ML

DSPIC33CH512MP206T-I/PTC03

ATSAM4C16CB-AUTR

DSPIC33CH128MP206T-I/PTC01

DSPIC33CK128MP206T-I/PTC01

PIC12C508AT-04I/SN221

PIC12C508AT-04I/SN231

PIC12LC508AT-04I/SN167

24LC08BHT-I/SN

24AA08HT-I/SN

24AA08T-I/SN

11AA02UIDT-I/SN

PIC16F916T-I/SS029

ATSAMD21G18A-MZTVAO

ATTINY417-MZT-VAO

ATTINY817-MZT-VAO

MCP98243T-BE/MNYVAO

TC1301B-FHAVMFTR

TC1302B-FPVMFTR

TC1301B-DPAVMFTR

TC1302B-DRVMFTR

TC1302B-DSVMFTR

TC1301B-HOVMFTR

TC1301A-FFAVMFTR

TC1301A-FFEVMFTR

TC1301A-FGAVMFTR

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TC1301A-FSAVMFTR

PIC12C508AT-04I/SN077

PIC18LF25K22T-I/SS

PIC16LF1512T-I/SS

PIC16LF1513T-I/SS

PIC18LF26K22T-I/SSC03

24LC08BT-I/SN

PIC16LF1847T-I/SO

PIC18LF23K22T-I/SS

PIC18F26K22T-I/SO022

PIC16F916T-I/SS

25AA080AT-I/ST

25LC160AT-I/ST

25AA160AT-I/SN103

PIC16F610T-I/ST043

PIC16F1783T-I/SO

PIC24EP64MC202-E/MM

ATTINY3224-XU

PIC16F1825-I/ST027

PIC16F1825-I/ST036

PIC16F1825-I/ST

PIC16F18046-I/SS

AVR32DA28-I/SO

AVR64DU28-I/SS

PIC12HV615-I/SN

PIC16LF18324-I/ST026

PIC16F15256-I/SS

PIC16F15254-I/SS

PIC16F726-I/SS

PIC16F726-I/SO

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PIC16F15255-I/SS

DSPIC33CK64MC102-I/SS

DSPIC33CK32MC102-I/SS

PIC18F26Q83-I/SS

PIC18F26Q84-I/SS

PIC18F2423-I/SO

PIC18F26Q83-I/SO

PIC18F8680-I/PT

PIC16C77-04I/PT

PIC16C77-20I/PT

MCP48CVB04T-E/MLVAO

PIC32CM2532JH01048T-E/U5B-SL3VAO

PIC32CM2532JH01064T-E/5LX-SL3VAO

ATSAMC21G17A-MZT510

PIC18F27Q84T-E/5NVAO

DSPIC33CK128MC505T-E/M7VAO

PIC32CM5164JH01048T-E/U5B-SL3VAO

MCP4431-103E/ML

PIC16F1827-E/ML

PIC16F884-E/ML

PIC16LF726-E/ML

MCP3422A4-E/MC

MCP3422A6-E/MC

PIC16F677-E/ML

MCP3901A0-E/ML

MCP4431-104E/ML

PIC18F2331-E/MM

PIC16F916-E/ML

MCP4431-503E/ML

PIC16F1516T-I/SO

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93AA46CT-I/ST

93LC46CT-I/ST

93LC56BT-I/ST

93LC56CT-I/ST

93C46BT-I/ST

PIC16F872T-I/SS034

PIC24FJ32GB002T-I/SO

PIC16C56AT-04I/SO030

PIC16C56AT-04I/SO034

PIC16F726T-I/SS030

24AA64FT-I/ST

24FC512T-I/ST

PIC18F14K50T-I/MQ052

PIC18F14K50T-I/MQ053

ATSAML11E16A-MUTKPH

PIC24EP512GU810T-I/PT

PIC32MZ2048EFH064T-250I/PTC21

PIC32MZ2048EFH064T-250I/PT

PIC32MX695F512LT-80I/PT

PIC32MX675F512LT-80I/PT

PIC32MX675F256LT-80I/PT

PIC32MX550F256LT-I/PF

PIC32MX530F128LT-I/PF

PIC32MX795F512LT-80I/PTE22

DSPIC30F5011T-30I/PT

DSPIC30F5013T-30I/PT

PIC32MX795F512LT-80I/PTE21

PIC16F876A-E/SO

PIC18F27Q10-E/SS

PIC18F27Q10-E/SO

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PIC16F1513-E/SS

PIC16F873A-E/SS

AT32UC3C1256C-AUT

AT32UC3C1512C-AUT

AT32UC3C164C-AUT

PIC24EP256GP206-I/PT

PIC18F47Q10-I/PT

PIC18F45Q10-I/PTC02

PIC18F45Q10-I/PT

PIC18F46Q10-I/PT

PIC24FJ128GL306-I/PT

PIC24FJ64GL306-I/PT

DSPIC33CH64MP508-I/PT

DSPIC33CH128MP508-I/PT

DSPIC33CH64MP208-I/PT

25AA320AT-I/SN

25AA160DT-I/SN

25AA080CT-I/SN

25LC320AT-I/SN

25LC160DT-I/SN

PIC16LF1508T-I/SS

PIC16LF1509T-I/SS

PIC16F874AT-E/PT

PIC16F18444T-I/SS

AVR64EA32-I/PT

AVR64EA48-I/PT

DSPIC33CK256MC506-I/PT

DSPIC33CK128MC506-I/PT

PIC18F56Q71-I/PT

DSPIC33CK256MC106-I/PT

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PIC16F18445T-I/SS

24AA256UIDT-I/ST

PIC16LF18446T-I/SS

PIC16F1936T-I/SO022

PIC16F1936T-I/SO040

PIC16F1936T-I/SO043

PIC12LF1501T-I/SN023

PIC12LF1501T-I/SN024

24LC256T-I/SNRVF

24AA256UIDT-I/SN

DSPIC33CK64MP102T-I/SS

DSPIC33CK32MP102T-I/SS

PIC16F1823T-I/ST

PIC12F615T-I/SN020

PIC12F615T-I/SN043

PIC12F615T-I/SN051

PIC12F615T-I/SN057

KSZ8081RNBIA-TR

KSZ8091RNBIA-TR

PIC32CM1216MC00032T-I/RTB

PIC32CM6408MC00032T-I/RTB

PIC18LF43K22T-I/ML

PIC18LF46K22T-I/ML

24FC64T-I/MC

PIC16F1503T-I/MG

AT24C04C-MAHM-E

DSPIC33EP64MC202T-I/MM

DSPIC33EP64MC502T-I/MM

PIC24EP64MC202T-I/MM

PIC24EP64MC204T-I/ML

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ATSAMD21J17A-MMUT

ATSAM4LS8AA-MUR

PIC16F1847T-I/MV

LAN9353TI/ML

PIC16LF1936T-I/ML020

PIC16LF1936T-I/ML

PIC16LF1936T-I/MV

PIC16F1939T-I/MV

DSPIC30F2020T-30I/MM

PIC16F17174T-I/MP

PIC16F18174T-I/MP

PIC16F17175T-I/MP

PIC16F18175T-I/MP

PIC16F17154T-I/STX

PIC16F18154T-I/STX

PIC16F17155T-I/STX

PIC16F18155T-I/STX

PIC18F66K90-I/PT

PIC18F67K22-I/PT027

PIC18F65K90-I/PT

PIC18F67J11-I/PTC03

PIC24FJ128GA006-I/PTC2

25LC080CT-E/ST16KVAO

25LC320AT-E/ST16KVAO

PIC16F18326T-E/STVAO

25LC640AT-E/ST16KVAO

MCP6489T-E/STVAO

AVR32DA28T-E/SSVAO

DSPIC33CK32MP502T-E/SSVAO

24LC64T-E/ST16KVAO

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24AA64T-E/STVAO

PIC16F15323T-E/STVAO

PIC32MM0128GPM064-E/MRVAO

AVR32DA32-E/RXBVAO

PIC18F24Q10-E/MLVAO

DSPIC33EP64MC504-E/MLVAO

PIC18F25Q10-E/MLVAO

PIC16F1828-E/GZVAO

25LC160D-E/MNY16KVAO

25AA080C-E/MNY16KVAO

ATTINY417-MZ-VAO

PIC32MM0064GPL020-E/MLVAO

PIC18F2480-E/MLVAO

ATSAME51N20A-AZT

DSPIC33EP64MC504-I/PTVAO

PIC16F1575-I/ST

PIC18LF2515-I/SO

PIC18F2515-I/SO

PIC16LF1575-I/ST

PIC16LF722A-I/SS

PIC18LF2620-I/SO

PIC18F2620-I/SO

PIC18F2610-I/SO

PIC16LF1578-I/SS

PIC16LF1579-I/SS

MIC2568-0YSM

MIC2568-1YSM

PIC16LF1554-I/ST

PIC18LF2525-I/SO

PIC18F2525-I/SO

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PIC16LF1574-I/ST

MCP602-I/SN

MCP602-I/SNREL

PIC16F1713-I/SS

PIC24FJ64GA204-I/ML

ENC424J600-I/ML

PIC18LF46J50-I/ML

34VL02T/MNY

34VL02T/MNYC21

24VL024T/MNY

24VL014HT/MNY

24VL025T/MNY

PIC32MZ2048EFH100T-I/PT

PIC32MZ2048EFG100T-I/PTL22

PIC32MZ2048EFG100T-I/PTL23

PIC18F27Q43-E/STX

PIC18F26Q43-E/STX

PIC18F67K22T-I/PT027

PIC24FJ64GA310T-I/PT

PIC24FJ128GA310T-I/PT

PIC24FJ64GA308T-I/PT

PIC24FJ128GA308T-I/PT

PIC18F65K90T-I/PT

PIC18F65K90T-I/PTRSL

PIC16LF1718T-I/SS

PIC18LF27K40T-I/SS

PIC12F1572T-I/SN020

PIC12F1571T-I/SN030

PIC12F1571T-I/SN038

PIC16LF1559T-I/SSM10

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PIC12F1571T-I/SN063

PIC12F1572T-I/SN064

PIC12F1571T-I/SN066

ATSAMC21J15A-MMUT

ATSAMC21J16A-MMUT

ATSAMC21J17A-MMUT

ATSAMC20E15A-MUT

ATSAMC20E16A-MUT

ATSAMC20E18A-MUT

ATSAMC21E15A-MUT

AT24C16C-MAHDHP-T

PIC18F1320T-I/ML

PIC18F1220T-I/ML

AT34C02D-MAHMHL-T

AT34C02D-MAHM-T

AT34C02D-MAHM-E

AT24C32E-MAHM-T

AT24C16C-MAHM-T

AT25256B-MAHL-T

AT25256B-MAHL-E

AT24C64D-MAHM-T

AT25040B-MAHL-E

AT25040B-MAHL-T

PIC12F629T-I/MD

DSPIC33EP64GS504T-I/MLRB3

PIC18F45K80T-I/ML

PIC18F46K80T-I/ML

PIC16LF1779T-I/ML

PIC16F1779T-I/ML

MCP4341T-502E/ML

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PIC24HJ64GP202T-E/MM

PIC24HJ64GP502T-E/MM

MCP3901A0T-E/ML

MCP3918A1T-E/ML

PIC24HJ32GP302T-E/MM

DSPIC33FJ64GP202T-E/MM

DSPIC33FJ64GP802T-E/MM

DSPIC33FJ128GP202T-E/MM

MCP3910A1T-E/ML

DSPIC33EP128GS702T-E/MM

DSPIC33FJ32MC302T-E/MM

PIC32MK0512GPE064T-E/MR

PIC32MK0512GPD064T-E/MR

PIC32MK0512MCF064T-E/MR

DSPIC33EP256MC504T-E/ML

PIC24EP256GP204T-E/ML

PIC24EP256MC204T-E/ML

DSPIC33EP64GS804T-E/ML

DSPIC33FJ128MC202T-E/MM

DSPIC33FJ128MC802T-E/MM

DSPIC33EP128GS704T-E/ML

DSPIC33EP128GS804T-E/ML

PIC24HJ128GP202T-E/MM

PIC24HJ128GP502T-E/MM

MCP4241T-502E/ML

MCP47FEB18T-E/MQ

MCP47FEB28T-E/MQ

MCP4241T-103E/ML

AGL060V5-VQG100

AGL125V5-VQG100

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A3P030-VQG100X376

A3P030-VQG100X52

A3P060-VQG100X376

A3P060-VQG100X537

KSZ8721BT

HV20220TQ-G

HV2701TQ-G

HV2301TQ-G

LAN91C111-NU

LAN91C113-NU

KSZ8041TL

DSPIC33EP128MC504T-H/PTVAO

DSPIC33EP128MC506T-H/PTVAO

PIC18F26Q10-I/SSVAO

PIC18F25Q10-I/SSVAO

PIC32MK1024MCM100T-E/PT

ATSAME54N19A-AZT

ATSAME53N20A-AZT

ATSAME51N19A-AZT

PIC16F18875T-I/PTVAO

PIC18F45Q10T-I/PTVAO

DSPIC33FJ64GS606T-50I/PTVAO

PIC18F46Q10T-I/PTVAO

OS81050AHR-E1A-011007-V01

ATMXT641T-ATR

ATMXT449T-ATR

PIC18F45K20T-I/PTVAO

OS8104AAHR-D1B-V01

OS81050ATR-E1A-011007-V01

DSPIC33CH512MP506T-I/PTVAO

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33CH256MP505T-I/PTVAO

ATMXT336S-ATR

ATMXT224S-ATR

DSPIC33EP32MC204T-I/PTVAO

PIC16F1939T-I/PTVAO

ATMXT449TD-ATR

ATMXT641TD-ATRVA2

ATMXT449TD-ATRVA2

ATMXT225TD-ATRVA2

24AA32A-I/ST

93AA46B-I/ST

PIC18F23K20-I/SS

PIC16F1709-I/SS

DSPIC33FJ64GP802-I/SO043

24LC04B-I/ST

24AA04-I/ST

PIC16LF1765-I/ST

PIC16LF1764-I/ST

PIC16LF1705-I/ST

PIC16LF1709-I/SS

PIC16LF1619-I/SS

PIC16LF1614-I/ST

PIC16LF1618-I/SS

RE340S16F

PIC16F1613-I/ST

PIC16LF1769-I/SS

PIC16LF1768-I/SS

PIC16F1615-I/ST

PIC32MX250F128D-I/ML

PIC32MX230F064D-I/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MX210F016B-I/ML

ATSAMD21E15L-AFT

ATSAMD21E18A-AFT

ATSAMD21E18A-AZT

ATSAMD21E17A-AZT

DSPIC33CK128MC105T-E/PT

PIC16F610T-I/ST

PIC16F610T-I/ST028

25LC640AXT-I/ST

PIC18F2321T-I/SO

24C02CT-I/ST

PIC16LF722T-I/SS

24AA64XT-I/ST

PIC16LF72T-I/SS

PIC12F510T-I/MC

DSPIC33EP256GP504T-I/ML

PIC24EP256MC204T-I/ML

ATSAMD20G18A-MUT

ATMEGA1608-MUR

PIC16F1938T-I/MV

PIC18LF45K42T-I/ML

AT25010B-MAHL-T

DSPIC33EV64GM104-H/P8

DSPIC33EV32GM004-H/P8

DSPIC33EV32GM104-H/P8

DSPIC33EP64MC204-H/PT

DSPIC33EP64MC504-H/PT

PIC18F66K80T-I/MR

PIC32MM0256GPM028T-I/ML026

PIC16F1783T-I/MV024

Date: Tuesday, July 22, 2025

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LE9672WQCT

LE79272PQCT

LE9622RQCT

DSPIC33FJ32GP302T-I/MM

DSPIC33FJ64MC202T-I/MM

DSPIC33EV128GM002T-I/MM

DSPIC33FJ64MC802T-I/MM

PIC24FJ64GB406T-I/MR

PIC32MX270F256BT-I/ML

DSPIC33FJ128MC202T-I/MM

DSPIC33FJ128MC802T-I/MM

PIC32MX170F256BT-I/ML

DSPIC30F4013T-30I/MLB31

DSPIC33FJ32MC302T-I/MM

PIC32MK1024GPD064T-I/MR

DSPIC33EP32GS504T-I/MLC10

DSPIC33EP64GS504T-I/MLC11

PIC24HJ128GP502T-I/MM

PIC24HJ32GP302T-I/MM

PD69210R-034400-TR

MCP3208T-CI/SL

HA0120T-I/SS

MCP3204T-CI/ST

MCP23016T-I/SS

PIC16F873AT-I/SS

PIC18F13K50T-I/SS

25AA640AXT-I/ST

PIC18F2680T-I/SO

PIC16C621AT-04I/SS083

25LC128XT-I/ST

Date: Tuesday, July 22, 2025

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24FC512T-I/ST14

PIC16C620AT-04I/SS071

OS8104AAT-D1B-V01

DSPIC33CK32MC105-I/PTVAO

DSPIC33CK64MC105-I/PTVAO

PIC16F917-I/PTVAO

PIC32MX530F128HT-50I/MR

PIC32MX170F256DT-50I/ML

PIC16F1788T-I/ML

PIC32MX775F256HT-80I/MR

PIC32MX550F256HT-I/MR

PIC32MZ2048EFG100T-I/PTL24

ATMEGA88PA-AUR

DSPIC33FJ32GS606T-I/PTC01

DSPIC33CK128MP206T-I/PT

DSPIC33CK256MP506T-I/PT

DSPIC33FJ32GS606T-I/PTC04

PIC18F87J90T-I/PT

AT89LP51RB2-20JU

AT89LS52-16JU

AT89S52-24JU

AT89S51-24JU

AT89LP51RC2-20JU

AT89LP52-20JU

AT89LP51ED2-20JU

AT89S8253-24JU

MT8952BP1

ATF2500C-15JU

ATF1500AL-20JU

ATF1502AS-10JU44

Date: Tuesday, July 22, 2025

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ATF1502ASV-15JU44

DSPIC33EP512GP806T-E/PT

DSPIC33EP512MC806T-E/PT

PIC24EP512GP806T-E/PT

PIC24HJ256GP206AT-E/PT

PIC32MZ1024EFM100T-E/PF

PIC32MZ2048EFG100T-E/PF

DSPIC30F5011T-20E/PT

DSPIC30F5013T-20E/PT

PIC32MZ1024EFG100T-E/PF

PIC32MZ1024EFH100T-E/PF

ATSAMC20J17A-MMZT

ATSAMC21J16A-MMZT

ATSAMC20J16A-MMZT

ATSAMC20J15A-MMZT

PIC16F18445T-E/GZ

PIC16LF18446T-E/GZ

UCS4002T-E/6N

AVR16EB32T-E/RXB

AVR16EB28T-E/STX

AVR16EA32T-E/RXB

DSPIC33EDV64MC205T-E/M7

UCS4003T-E/8N

24LC64T-E/MNYAXX

24CS512T-E/Q4B

PIC16F15344T-E/GZ

25CS640T-E/Q4B

DSPIC33EP256MC204T-E/MLC02

MCP6V72T-E/MNY

DSPIC33EP32GP504T-E/ML

Date: Tuesday, July 22, 2025

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DSPIC33EP32MC204T-E/ML

MCP4431T-502E/ML

MCP4431T-103E/ML

MCP4431T-104E/ML

DSPIC33CH256MP208T-I/PTC03

DSPIC33CH512MP508T-I/PTC04

PIC18F47Q84T-I/NHX

PIC12LF1840T48AT-I/ST

25LC020AT-I/ST

25AA020AT-I/ST

PIC16F15355T-E/ML

PIC16LF15354T-E/ML

PIC16LF15355T-E/ML

PIC16F15355T-E/MV

PIC16F72T-I/SS

PIC16F684T-I/ST069

PIC16LF1826T-I/SO

MCP3004T-I/ST

MCP3008T-I/SL

PIC18F24K20T-I/SSH2

25AA320AT-I/SNB22

MCP3202T-BI/SN

MCP3202T-CI/SN

25LC040AT-I/ST

25AA040AT-I/ST

PIC12F509T-I/SN058

PIC12F509T-I/SN

25LC010AT-I/ST

25AA010AT-I/ST

PIC16F726T-I/SS041

Date: Tuesday, July 22, 2025

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PIC16F726T-I/SS042

PIC16F726T-I/SS043

PIC16F726T-I/SS044

PIC16F726T-I/SS045

PIC16F726T-I/SS046

PIC16F1516T-I/SS028

25A512T-I/ST

PIC16F870T-I/SO

PIC16F73T-I/SO088

PIC16F726T-I/SS025

ATMEGA1608-XUR

ATMEGA808-XUR

AA540F-01-1416-G-LF

PIC16F684T-I/ST096

PIC16F627AT-I/SO034

PIC16F72T-I/SO

PIC16F73T-I/SO

24FC64-I/MC

PIC24EP64MC206-I/MR

DSPIC33EP64MC204-I/ML

PIC32CM1216MC00032-I/RTB

PIC18F26Q43-I/STX

PIC18LF45K22-I/ML

PIC18LF43K22-I/ML

PIC32CM6408MC00032-I/RTB

PIC18LF46K22-I/ML

PIC32MX570F512HT-I/MR

PIC32MX174F256BT-I/MM

DSPIC33FJ16GS502T-50I/MM

PIC32MX230F064DT-I/ML

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PIC32MX695F512HT-80I/MRD21

PIC32MX695F512HT-80I/MR

PIC32MX675F256HT-80I/MR

PIC32MX150F256HT-I/MR

PIC32MX170F512HT-I/MR

PIC18F6627T-I/PT036

PIC24FJ128GA006T-I/PT033

PIC24FJ128GA006T-I/PTV04

PIC24FJ96GA006T-I/PT

PIC24FJ64GA006T-I/PTC03

24CW1280T-I/ST

PIC16F882T-I/SS030

MCP2221AT-I/ST

MCP2221T-I/ST

PIC32MX795F512HT-80I/MR

AT24C16D-MAHM-T

AT24C16D-MAHM-E

PIC24HJ256GP206AT-I/MR

DSPIC33FJ256GP506AT-I/MR

ATF1504ASV-15AU44

PIC32MX270F512H-50I/MR022

DSPIC33CK256MP306-I/MR

DSPIC33EP16GS202-I/MM

DSPIC33EP32GS202-I/MM

MTCH105-I/ML

PIC18F24Q10-I/STX

PIC24FJ32GA104T-I/ML

PIC16F1829T-I/GZ

PIC16LF1829T-I/GZ

PIC16LF1508T-I/GZ

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DSPIC33FJ64GP802T-I/MMB21

PIC18F26K22T-I/ML

PIC18LF46K22T-I/MV

HA7621T-I/MV

PIC24FJ32GB004T-I/ML

PIC24FJ64GA102T-I/ML

AT28HC256F-90JU

AT28C256-15JU

AT28C256E-15JU

AT28BV256-20JU

AT28C256EF-15JU

AT27C010-45JU

PIC18LF2520-I/SO

MCP604-I/ST

MCP3304-CI/SL

PIC16C62B-20I/SS

PIC16C62B-04I/SS

24LC64X-I/ST

PIC16F73-I/SS

PIC24EP128MC206-I/MR

DSPIC33EP128GP504-I/ML

DSPIC33EP128MC204-I/ML

PIC18F4680T-E/PT

PIC18F46K22T-E/PT

PIC18F66K22T-E/PT

PIC18F46K20T-E/PTC03

DSPIC33FJ128GP306AT-E/PT

PIC24HJ128GP206AT-E/PT

PIC24HJ128GP306AT-E/PT

PIC18F44K22T-E/PT

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MCP9844T-BE/MNY

MCP9844T-BE/MNYAB

MCP23S17T-E/ML

MCP4011T-202E/MC

MCP4011T-502E/MC

MCP4011T-103E/MC

MCP4011T-503E/MC

MCP4652T-104E/MF

MCP4652T-503E/MF

MCP4662T-502E/MF

MCP4662T-103E/MF

MCP4662T-104E/MF

MCP4662T-503E/MF

PIC18F45K80T-E/PT

AVR32SD32-I/QZB

AVR128DA48S-I/6MX

AVR128DA32S-I/QZB

LE87402MQC

WP300TX01-I/ML02C02

PIC16F17524-I/ML

PIC16F17525-I/ML

PIC16F17526-I/ML

PIC16F17544-I/ML

PIC16F17545-I/ML

PIC16F17546-I/ML

PIC32CM6408JH00032-I/RTB

PIC32CM6408JH00064-I/5LX

LAX9252I/ML

PIC32CM3204GV00048-I/U5B

PIC32CM3204GV00032-I/RTB

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AVR16EA48T-E/PT

DSPIC33AK128MC105T-E/PT

DSPIC33AK64MC105T-E/PT

DSPIC33AK32MC105T-E/PT

PIC18F65K22T-E/PT

AVR64EA32T-E/PT

AT28BV64B-20JU

PIC18F25Q10-I/STX

MTCH108-I/GZ

ATSAMD21G16B-MU

DSPIC33EV64GM006T-I/MR

PIC16F19195-I/MR

PIC16F1787-I/ML

PIC16LF18325-I/JQ

SY58023UMG

SY89228UMG

PIC16F15356-I/ML

DSPIC33EP32GS504-I/MLC09

PIC16LF1554-I/ML

PIC16LF15313-I/RF

PIC16F19155-I/MV

PIC16LF1705-I/ML

PIC32MZ1024EFK100T-E/PF

PIC32MZ1024EFF100T-E/PF

PIC16F18876T-E/PT

PIC32MZ2048EFH100T-E/PF

PIC32MZ2048EFM100T-E/PF

PIC32MZ0512EFE100T-E/PF

PIC16F17544T-I/SS

TC1044SCOA713

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PIC16LC62BT-04/SO

TC7660COA713

TC7662BCOA713

PIC16C57CT-04/SO

PIC32MX340F512HT-80V/MR

PIC32MX340F128HT-80V/MR

PIC32MX440F256HT-80V/MR

PIC32MX340F256HT-80V/MR

PIC32MX320F128HT-80V/MR

PIC32MX320F064HT-40V/MR

PIC32MX150F256HT-V/MR

PIC32MX230F128HT-V/MR

PIC32MX170F512HT-V/MR

PIC32MX130F128HT-V/MR

PIC32MX250F256HT-V/MR

PIC32MX270F512HT-V/MR

PIC32MX550F256HT-V/MR

PIC32MX530F128HT-V/MR

DSPIC30F2010T-30V/MMA31

PIC16F1503-I/MG

DSPIC33EP64MC504-I/ML

PIC24EP64MC204-I/ML

PIC32MX420F032HT-40V/PT

PIC32MX360F512LT-80V/PT

ATSAMD20G14A-ANT

ATSAMD20G15A-ANT

ATSAMD20G17A-ANT

PIC32MX330F064HT-V/PT

PIC32MX440F256HT-80V/PT

PIC32MX340F256HT-80V/PT

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PIC32MX320F128HT-80V/PT

PIC32CM2532JH00100T-E/PF

PIC32CM5164JH00100T-E/PF

PIC32CM2532JH01100T-E/PF

PIC32CM5164JH01100T-E/PF

PIC32CM2532JH00064T-E/PT

PIC32CM5164JH00064T-E/PT

PIC16F15325T-I/ST

23K640T-I/ST

23K256T-I/ST

PIC16F73T-I/SO169

PIC16F1823T-I/ST041

23A256T-I/ST

23A640T-I/ST

25AA080D-I/ST

25LC160C-I/ST

25LC080C-I/ST

25AA080C-I/ST

PIC18F14Q41-E/SS

PIC18F15Q41-E/SS

PIC16F18025-E/ST

PIC16F18026-E/ST

PIC16F1786-E/SS

PIC18F24Q71-E/SS

PIC18F25Q71-E/SS

PIC18F24Q71-E/SO

PIC18F25Q71-E/SO

PIC16F15256-E/SO

PIC16F15254-E/SO

PIC16F15255-E/SO

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PIC16F722-I/ML

PIC18LF4585-I/ML

PIC16F723A-I/MV

PIC18F23K20-I/MV

PIC24FJ192GA106T-I/PT

ATF1508ASVL-20AU100-T

ATF1508ASV-15AU100-T

PIC18F66J11T-I/PT

PIC16F77T-I/PT102

PIC16LF1939T-I/PT024

PIC16LF1939T-I/PT

PIC18F6622T-I/PT

PIC18F6527T-I/PT

PIC16LF77T-I/PTC10

PIC18F45K80T-I/PT

PIC18F87K90-E/PT

DSPIC33FJ128GP804-E/PT

DSPIC33CK256MP205-E/PT

DSPIC33CK32MP205-E/PT

DSPIC33CK32MP505-E/PT

DSPIC33EP64GS506-E/PTRB3

PIC18F87K22-E/PT

AVR32DA32-E/PT

DSPIC33CK1024MP710-E/PT

DSPIC33CK1024MP708-E/PT

DSPIC33CH128MP206-E/PT

DSPIC33EV128GM106-E/PTC02

DSPIC33CH64MP505-E/PT

DSPIC33CH128MP505-E/PT

DSPIC33CH64MP205-E/PT

Date: Tuesday, July 22, 2025

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DSPIC33CH128MP205-E/PT

ATSAMD21J16B-AF

ATSAMD21J15B-AF

DSPIC33CH64MP506-E/PT

DSPIC33CH128MP506-E/PT

PIC16LF18856T-E/MV

MCP6V87T-E/MNY

PIC16F15323T-E/JQ

EMC1403-2-AIA-TR

PIC16F18856T-E/MV

24LC014HT-E/MNY

24LC024HT-E/MNY

34LC02T-E/MNY

PIC18F2580T-E/ML

24FC04HT-E/Q4B

24FC16T-E/Q4B

24FC08T-E/Q4B

34AA02T-E/MNY

ATSAMD20J17A-MMUT

OS81216AFR-B2B-010300-VAO

PIC18F26K20T-I/MLVAO

PIC18F25K20T-I/MLVAO

DSPIC33FJ64MC204T-I/PTC21

DSPIC33EV256GM004T-I/PT

DSPIC33EV256GM104T-I/PT

PIC32MX150F256HT-I/PT

PIC32MX170F512HT-I/PT

PIC32MX530F128HT-50I/PT

PIC32MX130F128HT-I/PT

PIC32MX120F064HT-I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MX250F256HT-I/PT

PIC32MX230F128HT-I/PT

DSPIC33EP512GM310T-I/PF

DSPIC30F6010AT-30I/PT

PIC32MX250F256LT-50I/PT

PIC24FJ128GA702-I/ML

PIC18LF26K42-I/ML

PIC32MK0256GPG064-I/R4X

PIC16F690-I/ML

ATMEGA1608-MU

PIC32MX695F512H-80I/MR

PIC32CM3204GV00032-E/RTB

PIC32CM3204GV00064-E/5LX

PIC32CM3204JH00048-E/U5B

DSPIC33CK128MC105-I/PT

AVR128DB32-I/PT

AVR64DB32-I/PT

AVR32DB32-I/PT

ATUC64D4-AUT

ATUC128D4-AUT

ATSAMD21J18A-AZTVAO

DSPIC33CK512MP608T-E/PTVAO

PIC32MZ2048EFM100T-E/PTVAO

DSPIC33CK256MP606T-E/PTVAO

PIC18F46Q10T-E/PTVAO

DSPIC33CH128MP508T-E/PTVAO

PIC32MX220F032BT-V/SS

PIC32MX210F016BT-V/SS

PIC32MX775F256HT-80I/PT

DSPIC33CK128MC506T-I/MR

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

24FC512T-I/Q4B

ATECC108A-MAHUC-T

PIC18F2423T-I/ML

PIC16F15256T-I/STX021

DSPIC33CK256MC106T-I/MR

DSPIC33CK128MC106T-I/MR

ATECC508A-MAHQA-T

ATECC508A-MAH1C-T

ATECC508A-MAHUZ-T

ATSHA204A-MAH1D-T

PIC32MX270F512HT-50I/MR024

ATECC508A-MAH2E-T

ATECC508A-MAH2F-S

DSPIC33CH64MP508-E/PT

DSPIC33CH128MP508-E/PT

PIC24EP256GP206-E/PT

PIC24FJ128GL306-E/PT

PIC24FJ64GL306-E/PT

DSPIC33CH64MP208-E/PT

DSPIC33CH128MP208-E/PT

DSPIC33CK512MPT608-E/PT

AT89C51CC02CA-SISUM

MCP47FVB01A3T-E/ST

93LC46BT-E/ST

MCP47FVB02A0T-E/ST

MCP47FVB02A1T-E/ST

MCP47FVB02A3T-E/ST

MCP47FVB11A1T-E/ST

MCP47FVB11A2T-E/ST

MCP47FEB12A1T-E/ST

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

MCP47FEB12A2T-E/ST

11LC010T-E/SN

11LC080T-E/SN

11LC020T-E/SN

11LC160T-E/SN

11LC040T-E/SN

24AA025UIDT-I/SN

11LC010T-I/SN

PIC18LF25J10T-I/SS047

11LC020T-I/SN

PIC24FJ64GL302T-I/SO

DSPIC33CK256MP506T-I/PTC03

DSPIC33CK64MP506T-I/PTC04

DSPIC33CK256MP508T-I/PTC03

ATSAM4C32CA-AUTR

PIC32MM0256GPM064T-I/PT034

PIC32MM0064GPM064T-I/PT

DSPIC33CK128MP208T-I/PTC04

PIC32MM0128GPM064T-I/PT

PIC32MM0256GPM064T-I/PTC21

PIC32MM0256GPM064T-I/PT

DSPIC33CK128MP205T-I/PTC06

PIC24EP128GP204T-I/PT037

PIC18F56Q84T-I/PT

AVR32DA48T-I/PT

DSPIC33CH512MP506T-I/PT

DSPIC33CK32MP505T-I/PT

DSPIC33CH512MP206T-I/PT

PIC18F57Q83T-I/PT

PIC18F57Q84T-I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33CK128MP205T-I/PT

DSPIC33CK128MP505T-I/PT

DSPIC33CK64MP205T-I/PT

DSPIC33CK256MP205T-I/PT

DSPIC33CK256MP505T-I/PT

DSPIC33CK64MP205T-I/PTC04

DSPIC33CK64MP505T-I/PT

DSPIC33CK32MP205T-I/PT

DSPIC33CH256MP506T-I/PT

DSPIC33CH256MP206T-I/PT

PIC24EP128GP204T-I/PT030

PIC24EP128GP204T-I/PT032

PIC24EP128GP204T-I/PT035

ATSAMD21G18A-AUTA1

PIC32MX120F032BT-V/SS

DSPIC30F2020T-30E/SOB34

RE46C195S16T

93AA46/SN

93AA56/SN

93AA66/SN

RE46C190S16TF

RE46C101S8TF

RE46C317S8TF

RE46C318S8TF

RE46C194S16T

LX34070T-H/ST

LX34050QPW-TR

LX3302AQPW-TR-EASY

LX3302AQPW-TR-C01

RE46C600S16T

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MX530F128L-V/PF

PIC32MX570F512L-V/PF

PIC32MX550F256L-V/PF

PIC32MX470F512L-V/PT

PIC32MX370F512L-V/PF

PIC32MX174F256D-V/PT

PIC32MX470F512L-V/PF

PIC32MX320F064H-80V/PT

PIC32MX320F032H-40V/PT

PIC32MX340F512H-80V/PT

PIC32MX150F128D-V/PT

PIC32MX250F128D-V/PT

PIC32MX230F064D-V/PT

PIC32MX340F128H-80V/PT

PIC32MX130F064D-V/PT

PIC32MX440F256H-80V/PT

PIC32MX420F032H-40V/PT

25AA160A-I/ST

25LC080B-I/ST

25AA080B-I/ST

PIC16F913-I/SS

PIC24FJ128GB202-I/SS

PIC24FJ64GB202-I/SS

24AA02E64-I/SN

24AA02UID-I/SN

PIC18F26K22-I/SS

PIC18LF26J50-I/SS

PIC16F1782-I/SS

HA1018-I/SS

93C86C-I/ST

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC18LF26K22-I/SO

HA4582-I/SO

HA4581-I/SO

PIC16LF1902-I/SS

PIC16LF1903-I/SS

93LC76C-I/ST

93AA76C-I/ST

93AA86C-I/ST

PIC12F529T39A-I/ST

PIC18LF27J13-I/SO

PIC18LF26J13-I/SO

24LC32AF-I/ST

PIC16F1936-I/SS

HA1839-I/SS

PIC24FJ128GB610T-I/PT

PIC24FJ256GB610T-I/PT

DSPIC33EP32MC204T-I/PT

PIC32MZ1024ECM064T-I/PT

PIC32MZ2048ECM064T-I/PT

PIC32MX460F512LT-80I/PT

ATSAMHA1G17A-MZT-BVAO

ATA5785-GHqw-VAO

ATA5785-GHqw

ATA5781N-WNqw

ATA5833-WNqw-VAO

ATTINY1617-MBT-VAO

ATTINY417-MBT-VAO

PIC32MZ0512EFK064T-I/PT

PIC24EP512GP806T-I/MR

PIC32MX440F256HT-80I/MR

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MX440F512HT-80I/MR

PIC32MX440F128HT-80I/MR

PIC32MX420F032HT-40I/MR

PIC24F16KL402T-I/ML

LE9530CPQCT

LE9530DPQCT

ATSHA204A-TCSMU

DSPIC33EP512GM706T-I/MRC01

ATSAMD21G18A-AUTN01

ATMEGA8A-AUR

ATSAMD20E16B-AUT

ATSAMD20E14B-AUT

PIC24FV32KA302-E/SS

24LC025-E/ST

93C46A-E/ST

PIC16F1823-E/STC07

PIC18F2221-E/SS

PIC18F2221-E/SO

PIC18F25K22-E/SO

24LC64F-E/SN

MCP6044-E/ST

PIC18F2321-E/SS

DSPIC33EP128GM604-E/ML

DSPIC33EP256GM604-E/ML

MEC1416-NU

24LC128T-I/MNY

PIC16LF1459-I/SS

PIC16F570-I/SO

PIC24FV08KM202-I/SS

PIC24FV16KM102-I/SS

Date: Tuesday, July 22, 2025

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DSPIC33EV64GM004-H/PTVAO

DSPIC33EV64GM104-H/PTVAO

DSPIC33EV256GM104-H/PTVAO

PIC18F4680-H/PTVAO

DSPIC33CK256MP505-H/PTVAO

DSPIC33EP512MC506-H/PTVAO

DSPIC33CK512MP605-H/PTVAO

DSPIC33CK128MP505-H/PTVAO

DSPIC33EP64MC504-H/PTVAO

PIC18F25Q71T-I/STX

ATECC508A-MAHJ4-S

ATECC508A-MAHZA-S

ATECC508A-MAHZA-T

ATECC508A-MAHZK-S

AVR64DA48T-I/6LX

AVR64DA64T-I/MR

AVR64DA32T-I/RXB

ATECC508A-MAHZK-T

ATECC608B-MAH1E-T

ATECC608B-MAHWT-T

PIC16F17176T-I/MP

PIC16F18176T-I/MP

ATSAML21G16B-MUT

ATSAML21G17B-MUT

ATSAML21G18B-MUT

ATSAML21G18B-MUT-SLL

PIC18F46Q43T-I/MP

PIC18F26K20T-I/ML058

PIC16F18075-E/MP

PIC16F18054-E/STX

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F18055-E/STX

ATSAML10E16A-MZ

ATSAML10E15A-MZ

ATSAML11E15A-MZ

PIC18F2480T-I/ML

MCP73831T-2ACI/MC

PIC18F47J53T-I/ML

MCP73832T-2DCI/MC

MCP73832T-3ACI/MC

MCP73832T-4ADI/MC

MCP73832T-2ACI/MC

MCP73832T-2ATI/MC

PIC18F4520T-I/ML

MCP73833T-6SI/MF

MCP73833T-AMI/MF

MCP73833T-B6I/MF

MCP73833T-BZI/MF

PIC16LF76T-I/ML057

PIC16F616T-I/ML

24LC16BT-I/MC

24AA16T-I/MC

PIC18LF2520T-I/ML

PIC18F2520T-I/ML

PIC16F76T-I/ML

MCP73834T-CNI/MF

PIC16F883T-I/ML

PIC18LF452T-I/ML

PIC16LF73T-I/ML

PIC16F73T-I/ML

MCP73832T-5ACI/MC

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F737T-I/ML

PIC18LF45K80T-I/ML

PIC18LF4520T-I/ML

PIC16F917T-I/ML

PIC16LF726T-I/ML

MCP73833T-FCI/MF

MCP73833T-G8I/MF

MCP73833T-GPI/MF

MCP73833T-NVI/MF

PIC16LF1516-I/MVVAO

PIC16LF1518-I/MVVAO

PIC16F15344-I/MLVAO

PIC16LF15344-I/MLVAO

ATTINY1627-MUVAO

PIC16F18456-I/STXVAO

PIC18F47Q84-I/NHXVAO

PIC16F886-H/MLVAO

DSPIC33FJ128MC804-H/MLVAO

PIC18F25K80-H/MMVAO

KSZ8051MNLV-VAO

ATTINY1617-MB-VAO

ATTINY417-MB-VAO

AVR64DA48-E/6LXL10

PIC18F26Q83-E/5NVAO

PIC32CM1602GV00032T-I/T5X

PIC32CM3204GV00064T-I/V2X

DSPIC33EP512GM706T-I/MRC02

DSPIC33EP128GM706T-I/MR

LE89156PQCT

ECC608-MAHNT-T

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ECC608-MAHNT-S

LE88266TQCT

LE88286TQCT

PIC24FV16KM202T-I/ML

PIC24F16KM202T-I/ML

AVR64DU32T-I/RXB

AVR64DU28T-I/STX

LE87270NQCT

BCM6304KMLGT

PIC32CM6408MC00048T-I/U5BS2

PIC16LF18877T-I/MVC04

LE87285NQCT

LE87557NQCT

PIC32CM2532JH00064T-I/5LX

PIC32CM5164JH00064T-I/5LX

PIC32CM2532JH01064T-I/5LX

PIC32CX1025SG41100-E/E5X-N02

ATSAME54N20A-AF-SL1

ATSAME54N20A-AF-SL2

ATSAME54N20A-AF-SL3

PIC16F15375-E/PT

PIC16F15376-E/PT

PIC16F15385-E/PT

PIC16F15386-E/PT

PIC16LF15385-E/PT

PIC16LF15386-E/PT

AVR32DB48-E/PT

DSPIC33CK256MP206-E/PTC06

DSPIC33CK256MP205-E/PTC06

DSPIC33CH256MP206-E/PTC02

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16LF1517-E/PT

PIC18F44Q71-I/PT

ATSAM4LC4AA-AU

PIC32MX170F256D-I/PT

PIC32MX270F256D-I/PT

PIC18F45Q71-I/PT

ATSAM4LS4AA-AU

ATSAM4LC2AA-AU

ATSAM4LS2AA-AU

DSPIC33AK512MPS510-I/PT

DSPIC33AK256MPS510-I/PT

DSPIC33AK512MPS210-I/PT

DSPIC33AK256MPS210-I/PT

DSPIC33AK512MC510-I/PT

DSPIC33AK256MC510-I/PT

DSPIC33AK512MC210-I/PT

DSPIC33AK256MC210-I/PT

ATSAMD51N20A-AUN02

DSPIC33AK512MPS506-I/PT

DSPIC33AK256MPS506-I/PT

MCP8021T-3315H/9PXVAO

PIC32MX360F512LT-80I/PT

PIC32MX470F512LT-I/PT021

PIC32MX370F512LT-I/PT

PIC32MX470F512LT-I/PT

DSPIC33EV128GM004T-I/PT

PIC32MX430F064HT-I/PT

PIC32MX360F256LT-80I/PT

DSPIC33FJ64MC506AT-I/PT029

DSPIC33FJ64MC506AT-I/PT034

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATMEGA644A-AUR

ATMEGA644PA-AUR

PIC24HJ128GP204T-I/PT

PIC24HJ64GP204T-I/PT

PIC24FJ256GA106T-I/PT037

DSPIC33EP128GM710T-I/PF

PIC16F1934-E/ML

ATSAMD21J16B-MMF

ATSAMD21J15B-MMF

ATSAMD21J17D-MMF

PIC16F17114-E/MD

PIC16F18056-I/STX

PIC16F1618-I/ML

DSPIC33EP128MC504-I/ML

PIC24EP128GP204-I/ML

PIC24EP128MC204-I/ML

USB4715-I/Y9X

PIC16F1503-I/MG031

PIC32MX170F256D-I/ML

PIC32MX270F256D-I/ML

MEC1515H-D0-I/3CW

24AA014-I/ST

34LC02-I/ST

34AA02-I/ST

MCP6004-I/ST

24AA32AX-I/ST

PIC16LF1513-I/SO

93C56C-I/ST

AT28HC64B-70JU

PIC32MX340F128HT-80V/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MX775F256LT-80V/PT

PIC32MX675F256LT-80V/PT

PIC32MX795F512LT-80V/PT

PIC32MX775F512LT-80V/PT

PIC32MX695F512LT-80V/PT

PIC32MX530F128LT-V/PF

PIC32MX570F512LT-V/PF

PIC32MX675F512LT-80V/PT

PIC32MX450F128HT-V/PT

PIC32MX450F256LT-V/PT

PIC24FJ128GA010-I/PF

PIC18F65J90-I/PT

PIC18F64J90-I/PT

PIC18F63J90-I/PT

PIC24FJ96GA010-I/PT

PIC24FJ64GA010-I/PT

PIC24FJ128GA110-I/PT

PIC16F724-I/PT

PIC18F63J11-I/PT

PIC18F64J11-I/PT

PIC18F65J94-I/PT

PIC24FJ96GA010-I/PF

PIC18F65J11-I/PT

PIC18F43K22-I/PT

PIC18F86J94-I/PT

PIC18F87J94-I/PT

PIC16LF1934-I/PT

PIC32CM6408JH00048T-I/Y8X

PIC32CM6408JH00032T-I/T5X

PIC32CM3204GV00048T-I/Y8X

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32CM3204GV00032T-I/T5X

PIC32CM1602GV00064T-I/V2X

PIC32CM1602GV00048T-I/Y8X

DSPIC33FJ256GP710AT-E/PT

DSPIC33FJ16GS404T-E/PT

AT24C32D-MAHM-T

AT24C32D-MAHM-E

AT24C01D-MAHM-T

AT25128B-MAHL-E

AT25128B-MAHL-T

AT24C16C-MAHM-E

PIC24FJ64GA004-E/PT

PIC18F46Q43-E/PT

DSPIC33CK256MP605-H/M7

DSPIC33CK512MP305-H/M7

DSPIC33CK512MP605-H/M7

DSPIC33CK256MP306-H/MR

DSPIC33CK256MP606-H/MR

DSPIC33CK512MP306-H/MR

DSPIC33CK512MP606-H/MR

DSPIC33CK1024MP706-H/MR

DSPIC33CK512MP406-H/MR

DSPIC33CK512MP706-H/MR

ATSAMC21G17A-MZT-SL2

ATSAMC21G17A-MZT-SL3

ATMEGA4808-MFR

AVR64DB48T-E/6LX

AVR32DB48T-E/6LX

ATTINY1607-MFR

ATTINY807-MFR

Date: Tuesday, July 22, 2025

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AVR128DB48T-E/6LX

MIC68200-1.0YML-TR

MIC68200-1.2YML-TR

MIC68200-1.5YML-TR

MIC68200-1.8YML-TR

PIC32MZ2048EFM064T-I/MR

DSPIC30F3010T-30I/ML

ATSAMD20E17A-MUTA2

ATTINY427-MUR

PIC16LF1826-I/MV

DSPIC33FJ64MC202T-I/SO

DSPIC33FJ64MC802T-I/SO

DSPIC33FJ32MC302T-I/SO

DSPIC33FJ128MC802T-I/SO

PIC32MX130F064BT-I/SS

PIC32MX230F064BT-I/SS

PIC18LF14K50T-I/SSC03

PIC32MX230F256BT-50I/SS

PIC32MX230F256BT-I/SS

PIC32MX130F256BT-50I/SS

PIC32MX130F256BT-I/SS

PIC18F25Q10T-I/SS

PIC16F18114-E/MD

PIC16LF1704-E/ML

PIC16F753-E/ML

PIC16HV753-E/ML

DSPIC33CK1024MP705-E/M7

DSPIC33CK1024MP706-E/MR

PIC16F17115-E/MD

PIC16F18115-E/MD

Date: Tuesday, July 22, 2025

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DSPIC33CK1024MP405-E/M7

DSPIC33CK512MP405-E/M7

DSPIC33CK512MP705-E/M7

DSPIC33CK256MP405-E/M7

PIC16F676-E/ML

DSPIC33CK256MP705-E/M7

KSZ8041RNL

KSZ8851SNL

MCP622-E/MF

MCP9843-BE/MC

MCP4341-104E/ML

MCP4341-502E/ML

MCP4341-103E/ML

MCP2515-E/ML

MCP4921-E/MC

PIC18F25K20-I/SO

PIC18LF2321-I/SO

PIC18F2321-I/SO

RE46C105S14F

PIC24FV32KA301-I/SS

PIC24FV16KA301-I/SS

PIC16F722-I/SS

PIC32AK1216GC41048T-I/PT

PIC32AK6416GC41048T-I/PT

PIC32AK3208GC41048T-I/PT

PIC16LF1559T-I/SSC01

PIC12F508T-I/SN025

PIC16F1827T-I/SOC06

PIC16F1826T-I/SSC03

PIC12F615T-I/SN058

Date: Tuesday, July 22, 2025

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PIC18F26K22T-I/SS025

PIC16F1826T-I/SS030

PIC16F1826T-I/SS031

MCP7940NT-I/SN

MCP7940MT-I/SN

PIC16LF1509T-I/SSC01

24AA128T-I/MNY

24FC128T-I/MNY

USB2514BT-I/M2

AVR64EA32T-I/RXB

ATSAMD21E16B-MUTN10

AVR64EA48T-I/6LX

DSPIC33AK128MC102T-I/M7

DSPIC33AK64MC102T-I/M7

PIC24F08KL302-I/MQ

PIC18LF4550-I/ML

PIC18F4550-I/ML

MCP73833-HAI/MF

PIC12LF1501-I/MF

PIC24F16KM204-I/ML

PIC16LF1459-I/ML

PIC18F65K90-I/MR

PIC18F45K22-I/MV

PIC18LF45K50-I/MV

ATSAMD21J18A-AUTN01

ATSAMD21G17A-AUT

ATSAMD21G18A-AUT

ATSAMD21G17A-AUTA1

PIC18F86J15T-I/PT

PIC18F85J10T-I/PT

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PIC18F87J10T-I/PT

DSPIC33AK64MC106T-I/PT

DSPIC33AK32MC106T-I/PT

PIC16F884T-I/PT

AT32UC3A1128-AUR

AT32UC3A1256-AUR

ATTINY48-AUR

PIC24FJ128GA410T-I/PT

PIC24FJ64GA410T-I/PT

PIC24FJ256GB410T-I/PT

PIC32MK1024MCF100T-I/PT

DSPIC33AK128MC106T-I/PT

PIC32MK1024GPE100T-I/PT

PIC32MK1024GPD100T-I/PT

PIC32MK0512GPE100T-I/PT

MCP4262T-502E/MF

MCP4262T-103E/MF

MCP3426A4T-E/MC

MCP3426A6T-E/MC

MCP3422A5T-E/MC

MCP4532T-103E/MF

MCP4532T-104E/MF

MCP4532T-503E/MF

PIC18F4520T-E/ML

MCP4532T-502E/MF

MCP6N11T-001E/MNY

MCP6N11T-005E/MNY

MCP4542T-502E/MF

MCP4542T-103E/MF

MCP4542T-104E/MF

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MCP4542T-503E/MF

MCP6N11T-002E/MNY

MCP6N11T-010E/MNY

MCP3427T-E/MF

MCP4232T-103E/MF

MCP4232T-104E/MF

MCP4921T-E/MC

MCP6N11T-100E/MNY

AVR32DD28-I/SO

PIC16F1703T-I/ST

QT160-AG2019T-20I/SS

24CW160T-I/ST

24CW320T-I/ST

24CW640T-I/ST

PIC16LF726T-I/SS021

DSPIC33CK64MC105T-E/PT

DSPIC33CK32MC105T-E/PT

PIC32MZ0512EFE064T-E/PT

PIC32MZ0512EFF064T-E/PT

PIC32AK3208GC41064T-E/PT

AVR64DA32ST-E/PT

AVR64DA48ST-E/PT

AVR64DA64ST-E/PT

AVR32DA32ST-E/PT

MCP4361T-502E/ML

DSPIC33EP512MC504T-E/ML

DSPIC33EP512MC204T-E/ML

DSPIC33EP256MC206T-E/MRRA3

ATSAMD20G18A-MNT

ATSAMD20G15A-MNT

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ATA6580-GTQW1-VAO

ATA6581-GTQW1-VAO

PIC16F1716-I/SO

PIC16F18325-I/ST

ATSAMC21J18A-MMZT

ATSAMC21J15A-MMZT

ATSAMC21J17A-MMZT

PIC18F26K80T-I/SS

PIC16F1782T-I/SS

HCD2-00ESI/D2C60TR

11LC161T-I/SN

11AA161T-I/SN

PIC32MX340F128H-80I/PT

PIC32MX440F256H-80I/PT

PIC32MX440F512H-80I/PT

SY54017ARMG

SY54017RMG

SY54020ARMG

SY54020RMG

PIC16LF18856-E/MV

PIC18F45K80-E/ML

PIC18F46K80-E/ML

PIC18F26K42-E/ML

MCP19119-E/MQ

PIC16LF1777-E/ML

PIC24EP512GP206-E/MR

PIC24EP512MC206-E/MR

DSPIC33EP512MC506-E/MR

DSPIC33EP256GP506-E/MR

DSPIC33EP256MC206-E/MR

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PIC16F15225T-E/STVAO

MCP6054T-E/STVAO

MCP6064T-E/STVAO

MCP6074T-E/STVAO

MCP6024T-E/STVAO

MCP6004T-E/STVAO

PIC16LF18446T-E/SSVAO

24CW160T-E/ST66KVAO

24CW320T-E/ST66KVAO

24CW640T-E/ST66KVAO

DSPIC33CK128MC502T-E/SSVAO

PIC16LF18326T-E/STVAO

24AA128T-E/ST16KVAO

24LC128T-E/ST16KVAO

24CS256T-E/ST66KVAO

DSPIC33EP64GP502-E/MM

PIC24EP64GP202-E/MM

DSPIC33EP32MC502-E/MM

MCP3208T-CI/SLVAO

MCP3008T-I/SLVAO

24FC512T-I/ST16KVAO

24LC512T-I/ST16KVAO

25AA256T-I/ST16KVAO

25AA040XT-I/STVAO

PIC24FJ64GU205T-I/PT

PIC24FJ32GU205T-I/PT

PIC24FJ64GP205T-I/PT

DSPIC33CK256MP308T-I/PT

AT89C51CC01UAT-RLRUM

DSPIC33FJ32GS406T-50I/PT

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DSPIC33FJ64GS606T-50I/PTC01

DSPIC33FJ64GS406T-50I/PT

DSPIC33FJ64GS606T-50I/PT

DSPIC33EP256GM710T-I/PT

PIC32MX270F512HT-50I/PT023

PIC18LF56K42T-I/PTC02

PIC32MM0256GPM048T-I/PT030

PIC16F1503T-E/STVAO

DSPIC33CK32MC102T-E/SSVAO

LX34211QPW-TR-VAO

ATSAMHA0G15A-MZT-BVAO

ATSAMHA0G14A-MZT-BVAO

EQCO510C0T-V/6NXVAO

MEC1416-I/NU

PIC16F19176-I/PT

PIC16LF1939-I/PT

ATSAMD21E16B-AU

PIC18LF47K40-I/ML

ATMEGA1609-MU

PIC18LF25K40-I/ML

ATSAMD21G15B-MU

WP300TX01-I/ML01C00

WP300RX01-I/ML01C00

DSPIC33CK256MP606-I/MR

DSPIC33CK512MP306-I/MR

PIC24HJ128GP506A-E/PTVAO

DSPIC33EP256GP506-E/PTVAO

PIC16F18877-E/PTVAO

DSPIC33EV256GM104-E/PTVAO

PIC16F887-E/PTVAO

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DSPIC33EP256MC206-E/PTVAO

PIC32CM6408JH00064T-E/5LX

PIC32CM6408JH00048T-E/U5B

PIC32CM6408JH00032T-E/RTB

ATSAMC21G18A-MZT-SL3

PIC32CM3204GV00064T-E/5LX

PIC32CM3204GV00048T-E/U5B

PIC32CM3204GV00032T-E/RTB

PIC32CM1602GV00064T-E/5LX

PIC32CM1602GV00048T-E/U5B

PIC32CM1602GV00032T-E/RTB

ATSAMD21E16B-MF

ATSAMD21E15B-MF

DSPIC33CK256MP306-E/MR

DSPIC33CK256MP606-E/MR

MCP48CMB04-E/ML

MCP48CMB14-E/ML

MCP48CMB24-E/ML

MCP48CVB04-E/ML

MCP47CMB08-E/ML

PIC32CM1216MC00048-E/U5B

PIC32CM6408MC00048-E/U5B

PIC32CM1216MC00032-E/RTB

PIC32CM6408MC00032-E/RTB

ATTINY1617-MF

MCP2542FD-E/MF

DSPIC33EP16GS202-E/MM

DSPIC33EP32GS202-E/MM

DSPIC33CK512MP306-E/MR

DSPIC33CK512MP606-E/MR

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MCP47CMB04-E/ML

MCP47CVB08-E/ML

MCP48CMB08-E/ML

MCP48CMB18-E/ML

MCP47CVB18-E/ML

MCP47CVB28-E/ML

MCP48CVB14-E/ML

MCP48CVB18-E/ML

MCP251863T-E/SS

ATSAME51N20A-AFT

ATSAME53N19A-AFT

ATSAME53N20A-AFT

ATSAME54N19A-AFT

ATSAME54N20A-AFT

PIC16F1937T-E/PT

ATMEGA3209-AFR

ATSAMC21E15A-AZT

ATSAMC21E16A-AZT

ATSAMC21E17A-AZT

ATSAMC21E18A-AZT

ATSAMC20E18A-AZT

ATSAMC20E17A-AZT

ATSAMC20E16A-AZT

ATSAMC20E15A-AZT

ATSAMC21G15A-AZT

AVR64DA64-E/PTVAO

AVR64DA32-E/PTVAO

24AA256-E/SN

24FC256-E/SN

DSPIC33CK32MP102-E/SS

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PIC16F1823-E/ST

PIC16F1825-E/ST

PIC16LF1708-E/SS

PIC16LF1773-E/SS

25AA128-E/SN

PIC16F1773-E/SS

PIC16LF1776-E/SS

PIC16F1776-E/SS

PIC12F1612-E/SN

PIC16F1614T-I/ST

24FC02T-I/ST

24LC02BHT-I/ST

PIC12F629T-I/SN245

PIC16F616T-I/ST

24FC01T-I/ST

24LC01BHT-I/ST

PIC12F629T-I/SN

24FC04T-I/ST

24FC04HT-I/ST

93LC46T-I/SN

24AA01HT-I/ST

93LC46BT-I/SN

93AA46T-I/SN

93C46BT-I/SNRVA

93LC66T-I/SN

93AA56T-I/SN

93AA66T-I/SN

93LC56T-I/SN

PIC12F510T-I/SN058

PIC12F629T-I/SN039

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PIC12F629T-I/SN247

DSPIC33EP16GS202T-I/SS

PIC12F629T-I/SN069

DSPIC33EP32GS202T-I/SS

PIC16F1824T-I/ST

PIC32MX250F128BT-I/SS

MCP42010T-I/STBAX

PIC16F1823T-I/ST042

PIC16F913T-I/SO

PIC16F883T-I/SS063

PIC16F883T-I/SS071

PIC16F15323T-I/ST

PIC24FJ128GB202T-I/SS

PIC32CM3204JH00032-E/RTB

PIC32CM3204JH00064-E/5LX

PIC32CM1602GV00064-E/5LX

PIC32CM1602GV00048-E/U5B

PIC32CM1602GV00032-E/RTB

ATSAMC21J18A-OMMZ

PIC32MX230F064BT-V/SS

PIC32MX110F016BT-V/SS

ATA6563-GBQW0

DSPIC33EV64GM104T-H/MLVAO

DSPIC33EV128GM102T-H/MMVAO

DSPIC33EP64MC202T-H/MMVAO

MCP6C02T-020H/Q8BVAO

MCP6C02T-100H/Q8BVAO

MCP6C02T-050H/Q8BVAO

ATTINY461-15MD

PIC18F26K80T-H/MMVAO

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ATA6562-GBQW0

ATA6566-GBQW0

DSPIC33FJ64MC204T-H/MLVAO

ATA6565-GCQW0

ATTINY861-15MD

PIC16F1619T-H/MLVAO

PIC18F25K80T-H/MMVAO

ATA6580-GTQW0-VAO

ATA6581-GTQW0-VAO

MCP6004-I/STAAA

PIC16F723A-I/SS

PIC16F1516-I/SS024

24LC64X-I/STRVE

PIC16LF1613-I/ST

24LC64-I/STRVE

24LC02BH-I/SN100

24LC32AX-I/ST

PIC16F1512-I/SO

PIC16F1513-I/SO

PIC16LF1516-I/SS

PIC16LF1518-I/SS

24C01C-I/ST

24LC014H-I/ST

24AA014H-I/ST

PIC16LF1936-I/SS

PIC16F1516-I/SS

PIC16F1454-I/ST

PIC16F1455-I/ST

24LC014-I/ST

PIC16F1936-I/SO

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PIC16F1936-I/SOC04

PIC16F1707-I/SS

PIC16LF1703-I/ST

PIC16LF1707-I/SS

24LC16B-I/ST116

ATECC608A-TFLXTLSU

PIC32MK1024MCM064T-I/MR

PIC24FJ512GL406T-I/MR

PIC24FJ128GU406T-I/MR

PIC24FJ256GU406T-I/MR

PIC24FJ512GU406T-I/MR

PIC32MK0512MCM064T-I/MR

24LCS22AT-I/SN

24LCS21AT-I/SN

24LC21AT-I/SN

ATSAMC21J15A-AZT

ATMEGA168PA-MUR

24AA52T-I/MNY

PIC16F18425T-I/JQC01

24LCS52T-I/MC

24AA52T-I/MC

PIC16F1719T-I/MV

ATMEGA3208-MUR

PIC18F45K40T-I/ML

PIC18F46K40T-I/ML

PIC18LF45K40T-I/ML

PIC18LF46K40T-I/ML

PIC24FJ16GA002T-I/ML023

24FC01T-I/Q4B

24FC02T-I/Q4B

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PIC16F1717T-I/MV

A010201T-I/MQ050

AR1100T-I/MQ

PIC32MX120F064HT-I/MRH21

25LC010AT-I/MNY

DSPIC33CK128MC106T-E/PTVAO

DSPIC33CK128MC505T-E/PTVAO

PIC18F46Q43T-E/PTVAO

ATSAMC20E17A-AZT510

AVR128DA48ST-E/PTVAO

PIC24EP256GP204T-E/PTVAO-VW

PIC32CM2532JH01032T-E/PTVAO

PIC16LF1503T-I/ARC

PIC16F15325T-I/JQ

AVR128DB32T-I/RXB

AVR16EA32T-I/RXB

PIC18F25K20T-I/ML044

AVR32DB32T-I/RXB

AVR64DB32T-I/RXB

AVR16EA28T-I/STX

ATTINY1617-MZ-VAO

PIC16F18875-E/MVVAO

PIC16F1939-E/MVVAO

MCP6002-E/MCVAO

MCP1725-1802E/MCVAO

PIC16LF18345-E/GZVAO

PIC16LF18323-E/JQVAO

AVR32DA48-E/6LXVAO

PIC18F25Q10-E/STXVAO

PIC16F15324-E/JQVAO

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PIC16F15324-E/7NVAO

ATSAMD21J18A-MMZVAO

PIC18F46Q10-E/MPVAO

ATSAMD21G18A-MZVAO

PIC16F18425-E/JQVAO

ATTINY817-MZ-VAO

MCP9804-E/MCVAO

MCP1725-1202E/MCVAO

PIC16F1829-E/MLVAO

PIC18F57Q84-E/6MXVAO

ATMEGA4809-MF-VAO

PIC16F15354-E/5NVAO

PIC18F26Q10-E/STXVAO

ATMEGA16L-8AUR

ATMEGA8515-16AUR

ATMEGA8515L-8AUR

ATMEGA644PV-10AUR

ATMEGA1281V-8AUR

PIC16LF1614-I/ML

PIC32CM6408MC00048-I/U5B

SY88982LMG

OS81214AF-B2B-010300-VAO

OS81216AF-B2B-010300-VAO

PIC18F26K20-I/MLVAO

PIC18F25K20-I/MLVAO

PIC16F1827-I/MLVAO

PIC16F15324-I/7NVAO

KSZ8051RNLUB-VAO

OS81212AF-B2B-010300-VAO

24AA16-I/MC16KVAO

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PIC16LF1829-I/MLVAO

PIC16F1829-I/MLVAO

PIC16F18455-I/STXVAO

PIC16F15224-I/7NVAO

PIC16LF1454-I/MLVAO

DSPIC33EV64GM006-I/MRVAO

MCP2221A-I/MLVAO

PIC16F1786-I/MLVAO

PIC16F19197-I/5LXVAO

MCP2200-I/MQVAO

PIC16LF18856-I/MLVAO

PIC16F15224-I/MGVAO

KSZ9031RNXUB-VAO

PIC16LF18425-I/JQVAO

USB4925-I/Y9XVAA

USB4715-I/Y9XVAA

USB4914-I/Y9XVAA

USB4914-I/Y9XVBA

PIC12LF1822-I/MFVAO

PIC12LF1840-I/MFVAO

PIC12F1572-I/MFVAO

AVR32DA32-I/RXBVAO

PIC18F25Q10-I/MLVAO

DSPIC33CK128MP505-E/PTC01

DSPIC33CK64MP505-E/PTC02

PIC16F18125-E/7NVAO

PIC32CM3204GV00032-E/RTBVAO

PIC18F47Q84-E/NHXVAO

AVR64DD32-E/RXBVAO

PIC32MM0256GPM064-E/MRVAO

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PIC16F18146-E/6NVAO

PIC16F15255-E/STXVAO

PIC16F15256-E/STXVAO

PIC32MX340F128L-80I/PT

MCP6484-E/ST

MCP6474-E/ST

MCP6494-E/ST

PIC16HV616-E/ST

93C86C-E/ST

25LC160B-E/ST

93C76C-E/ST

PIC18F24K22-E/SO

PIC18F23K22-E/SO

TCN75AVOA

PIC18LF25K22-E/SO

PIC32MX250F128BT-I/ML

PIC32MX120F032BT-50I/ML

PIC24FJ512GB606T-I/MR

PIC24FJ128GB202T-I/MM

PIC32MX220F032BT-50I/ML

PD69210R-035200-TR

PIC24FJ64GB202T-I/MM

PIC32MX230F256DT-I/ML

PIC32MX130F256DT-50I/ML

PIC32MX130F256DT-I/ML

SY89833LMG-TX

ATSAMD21E16B-MUT-SLL

PIC24FJ128GB204T-I/ML

PIC24FJ128GA202T-I/MM

PIC32MX120F032DT-50I/ML

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ATA5291N-GJQW

MCP4232T-502E/MF

MCP4232T-503E/MF

MCP4242T-502E/MF

MCP4252T-503E/MF

MCP3422A3T-E/MC

MCP4242T-103E/MF

MCP4242T-104E/MF

MCP4552T-502E/MF

TC1301A-AHAVMFTR

KSZ8041FTL

LAN8710A-EZC-TR-ABC

LAN8720A-CP-TR-ABC

USB5742BT/2GX01

PIC16F886T-E/SS

PIC12F509T-E/SN055

25LC128T-E/SN

PIC12F1501T-E/SN022

ATSAM3S2AA-MU

ATSAM3S4AA-MU

PIC16LF1619-I/GZ

PIC24F16KA101-I/MQ

ATSAMD20E15B-MU

PIC16F1933-I/MV

PIC16LF1938-I/MV

PIC16F1619-I/GZ

PIC16F1938-I/MLRA2

PIC16LF1938-I/MLC01

SY75572LMG

SY58011UMG

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SY58012UMG

SY84113BUMG

ATECC608B-MAHWB-T

PIC18F56Q71T-I/6LX

PIC18F26Q71T-I/STX

PIC18F24Q71T-I/STX

PIC32MX110F016D-V/ML

PIC32MX350F256H-V/MR

PIC32MX450F256H-V/MR

PIC32MX340F256H-80V/MR

PIC32MX320F128H-80V/MR

PIC32MX440F128H-80V/MR

PIC32MX440F512H-80V/MR

PIC32MX320F064H-40V/MR

PIC32MX320F064H-80V/MR

AVR64DA32-E/RXBVAO

PIC32MK0512GPD064-I/MR

PIC16LF18877-I/MV

DSPIC33EP512MC806-E/MR

PIC24EP512GP806-E/MR

DSPIC33EP512GP806-E/MR

PIC24EP512MC204-E/ML

DSPIC33EP64MC206T-I/PT

DSPIC33EP64MC506T-I/PT

PIC24EP64MC206T-I/PT

PIC24FJ128GL406T-I/PT

PIC24FJ256GL406T-I/PT

PIC24FJ512GL406T-I/PT

PIC24FJ128GU406T-I/PT

PIC24FJ256GU406T-I/PT

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PIC24FJ512GU406T-I/PT

PIC16F17174T-I/PT

PIC16F18174T-I/PT

PIC16F17175T-I/PT

PIC18F57Q84-E/PTVAO

PIC32CM5164JH01064-E/PTVAO

MCP6004T-I/ST

PIC24FJ256GL410-E/PT

PIC24FJ512GL410-E/PT

PIC24FJ128GU410-E/PT

PIC24FJ256GU410-E/PT

PIC24FJ512GU410-E/PT

PIC16F877A-E/PT

PIC18F47Q10-E/PT

PIC16F874A-E/PT

DSPIC33EP256MC506-E/PT

ATSAMD21E16B-AZ

ATSAMD21E15B-AZ

ATSAMD21J16B-AZ

ATSAMD21J15B-AZ

ATSAMD21G16B-AZ

DSPIC33EV64GM106T-I/MR

PIC24FJ128GA606T-I/MR

PIC24FJ256GA606T-I/MR

PIC32MX150F128BT-I/ML

PIC12F1571T-I/MF059

PIC32MX250F128DT-I/ML026

PIC32MX150F128DT-I/ML

DSPIC33FJ16GP102T-I/ML

PIC24FJ512GA606T-I/MR

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PIC16F886T-E/ML

MCP3426A0T-E/MC

MCP3426A3T-E/MC

MCP662T-E/MF

MCP4262T-104E/MF

MCP4242T-503E/MF

DSPIC33FJ128GP202T-I/SO

DSPIC33FJ128GP802T-I/SO

DSPIC33FJ64GP202T-I/SO

PIC16F690T-I/SS041

PIC16F690T-I/SS

PIC32MX150F128BT-50I/SS

PIC16F687T-I/SS043

PIC16F687T-I/SS

DSPIC33EV32GM106T-E/PTVAO

DSPIC33EV128GM106T-E/PTVAO

DSPIC33EV64GM106T-E/PTVAO

DSPIC33EP256MC506T-E/PTVAO

DSPIC33EV32GM004T-E/PTVAO

DSPIC33EV128GM104T-E/PTVAO

DSPIC33EV64GM004T-E/PTVAO

DSPIC33EV64GM104T-E/PTVAO

PIC18F66K40T-E/PTVAO

DSPIC33CH64MP206-H/PT

PIC18F26J53-I/SO

PIC18F4420T-I/PT

PIC18F452T-I/PT

PIC18LF8585-I/PT

PIC18F8585-I/PT

PIC16LF74-I/PT

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PIC16C64A-20I/PT

PIC18LF442-I/PT

PIC18F442-I/PT

PIC18LF452-I/PT

ATMEGA164P-20AQ

ATMEGA164PV-10AQ

ATXMEGA64C3-AN

ATXMEGA64D3-AN

A3P060-VQG100IX430

PIC18F13K22-I/ML

PIC18F23K22-I/MV

DSPIC33CH128MP206-H/PT

DSPIC33CH64MP505-H/PT

PIC32MZ2048ECG100-I/PT

PIC32MX320F064H-80I/PT

PIC32MZ2048ECH100-I/PT

PIC32MZ1024ECM100-I/PT

PIC16F18876-I/PT

PIC32MX370F512L-I/PT

PIC32MX470F512L-I/PT

DSPIC33EP512MC806-I/PT

PIC24EP512GP806-I/PT

DSPIC33FJ16GS404-50I/PT

DSPIC33EP256MU810-I/PT

DSPIC33EP512MU810-I/PT

PIC32MX340F256H-80I/PT

DSPIC33FJ256GP506A-I/PT

PIC24EP256GU810-I/PT

DSPIC33EP256MU806-I/PT

DSPIC33EP512GP806-I/PT

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PIC32MX170F256D-50I/PT

PIC24EP512GU810-I/PT

PIC24FJ128GL305-I/PT

PIC24FJ64GL305-I/PT

DSPIC33FJ64MC506-I/PTC21

DSPIC33FJ128GP706-I/PT

DSPIC33FJ256GP506-I/PT

DSPIC33FJ64GS610-50I/PF

DSPIC33FJ32GS610-50I/PF

PIC24HJ64GP206-I/PT

MCP617T-I/SN

PIC16F1718T-I/SSC01

MCP2200T-I/SSRVB

MCP2210T-I/SS

25LC128T-I/SN

25AA128T-I/SN

PIC12F1501T-I/SN027

PIC12F1501T-I/SNH1A

PIC12F1501T-I/SNH2A

PIC12F1501T-I/SNH3A

PIC12F1501T-I/SNL1A

PIC12F1501T-I/SNL2A

PIC12F1501T-I/SNL3A

PIC12F1501T-I/SNL4A

PIC12F675T-I/SN191

PIC12F675T-I/SN194

PIC32CM5164JH01100-I/PF-SL3

PIC32CZ2051CA70100-I/E5X

DSPIC33CK256MP505-I/PTC07

AVR128DA48S-I/PT

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AVR128DA64S-I/PT

AVR128DA32S-I/PT

ATSAM4LC2CA-AUN01

AVR16EB32-I/RXB

AVR16EB28-I/STX

KSZ8051RNLV

PIC24HJ128GP506A-H/MR

DSPIC33FJ128MC706A-H/MR

MCP8025A-115H/MP

PIC18F4585-H/ML

MCP8025-115H/MP

PIC24EP512MC206-H/MR

DSPIC33EP512MC206-H/MR

DSPIC33EP512MC506-H/MR

PIC24EP512GP206-H/MR

DSPIC33EP512GP506-H/MR

DSPIC33FJ32MC202-H/MM

PIC24HJ128GP502-H/MM

DSPIC33FJ64MC802-H/MM

DSPIC33FJ128MC802-H/MM

DSPIC33FJ64MC804-H/ML

DSPIC33FJ128MC804-H/ML

PIC24HJ128GP504-H/ML

DSPIC33FJ64GP802-H/MM

DSPIC33CH512MP506-H/MR

PIC18LF24K40-I/MV

PIC18LF25K40-I/MV

PIC18F25K40-I/MV

AT90CAN64-16MU-HDC

DSPIC33EP32GS502-I/MM

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DSPIC33EP16GS502-I/MM

PIC16F1719-I/MV

PIC16F1717-I/MV

ATMEGA808-MU

RE46C109S16TF

PIC18F24J10T-I/SS

PIC16F870T-I/SS

PIC16LF870T-I/SS

PIC16LF819T-I/SSTSL049

PIC18F25J10T-I/SS

PIC16C622AT-04I/SO091

ATA6585-GTQW1-VAO

ATA6586-GTQW1-VAO

PIC16LF1503T-E/MVVAO

ATSAMC21E18A-MZT-SL3VAO

ATSAMD21E18A-MZTVAO

ATSAMD21E16B-MZTVAO

DSPIC33CK32MC102-E/SSVAO

MCP4922-E/STVAO

MCP45HV31-103E/STVAO

MCP6234-E/STVAO

MCP41HV51-103E/STVAO

MCP41HV51-502E/STVAO

MCP6294-E/STVAO

LX3301AQPW

MCP604-E/STVAO

MCP6034-E/STVAO

MCP6564-E/STVAO

MCP6569-E/STVAO

MCP6544-E/STVAO

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PIC16F15225-E/STVAO

MCP6054-E/STVAO

MCP6064-E/STVAO

MCP6074-E/STVAO

PIC16LF1824-E/STVAO

PIC16F1503-E/STVAO-MB

PIC16LF18446-E/SSVAO

DSPIC33CK128MC502-E/SSVAO

PIC16LF18326-E/STVAO

24LC128-E/ST16KVAO

PIC16F18326-E/STVAO-VW

PIC16F1503-E/STVAO-VW

24AA128-E/ST16KVAO

DSPIC33EV64GM102-E/SSVAO

DSPIC33FJ64GP804-I/ML

PIC32MZ2048EFM064-I/MR

PIC32MZ2048EFH064-I/MR

DSPIC33FJ64GS406-I/MR

PIC32MX350F256H-I/MR

DSPIC33FJ32GP104-I/ML

PIC24FJ32MC104-I/ML

DSPIC33EP32GP504-I/ML

DSPIC33EP32MC204-I/ML

DSPIC33EP256MC206-I/MR

DSPIC33EP256MC506-I/MR

PIC24HJ128GP504-I/ML

24LC32AT-I/MC

24AA32AT-I/MC

SST39VF010-70-4C-NHE

SST39VF040-70-4C-NHE-PP013

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SST39VF040-70-4C-NHE-RVL

SST49LF008A-33-4C-NHE

SST49LF080A-33-4C-NHE

DSPIC33EP256MC506T-H/PTVAO

DSPIC33EP64MC506T-H/PTVAO

PIC18F45K80T-H/PTVAO

DSPIC33FJ256GP506AT-H/PTVAO

DSPIC33EV128GM104T-H/PTVAO

DSPIC33EV64GM004T-H/PTVAO

DSPIC33EV64GM104T-H/PTVAO

DSPIC33EV256GM004T-H/PTVAO

DSPIC33FJ128MC506AT-H/PTVAO

DSPIC33EP64MC204T-H/PTVAO

DSPIC33CK256MP505T-H/PTVAO

DSPIC33EP512MC506T-H/PTVAO

DSPIC33CK512MP605T-H/PTVAO

DSPIC33CK128MP505T-H/PTVAO

AT89C55WD-24JUR

AT89S8253-24JUR

MT8952BPR1

AT27C2048-55JU-T

AT27BV1024-90JU-T

AT27C2048-90JU-T

AT28C010E-15JU-T

MT9171APR1

PIC32MZ1024EFE064-E/MR

PIC32MZ1024EFF064-E/MR

PIC24FJ256GB406-I/MR

PIC24FJ128GB406-I/MR

PIC24FJ192GB106-I/MR

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC24FJ256GB106-I/MR

PIC12F1612-I/MF

PIC16LF1613-I/ML

PIC16F1933-I/ML

PIC16F1783-I/MV

93LC46AT-I/SNRVA

PIC18F27J53T-I/SS

PIC18F2525T-I/SOC02

PIC12F629T-I/SN241

24LC04BT-I/SNA29

MTCH108T-I/SS

PIC12F629T-I/SN232

PIC12F510T-I/SNC02

PIC18F27J13T-I/SS

PIC16LF1459T-I/SS020

24LC01BT-I/SNA23

PIC24EP64MC202T-E/MM

DSPIC33EP64MC204T-E/ML

DSPIC33EP64MC504T-E/ML

PIC24EP64MC204T-E/ML

DSPIC30F3014-20I/PT

DSPIC30F3014-30I/PT

DSPIC30F4013-20I/PT

DSPIC30F4013-30I/PT

DSPIC33FJ64MC202-E/SO

PIC24FJ32MC101-E/SS

DSPIC33FJ09GS302-E/SO

PIC24HJ64GP502-E/SO

PIC24HJ128GP202-E/SO

PIC24HJ64GP202-E/SO

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DSPIC33FJ64GP802-E/SO

DSPIC33FJ32MC102-E/SO

PIC24HJ128GP502-E/SO

PIC24HJ32GP302-E/SO

DSPIC33FJ64GP202-E/SO

PIC18LF14K22-E/SS

DSPIC33FJ128GP202-E/SO

DSPIC33FJ128GP802-E/SO

DSPIC33FJ32GP302-E/SO

ATMEGA4808-XF

PIC24FJ128GL302-E/SO

PIC24FJ64GL302-E/SO

PIC18LF23K22-E/SS022

24AA025E48-E/SN

11AA080-I/SN

11LC160-I/SN

PIC16LF18324-I/ST

DSPIC33EV128GM002-I/SS

DSPIC33EV128GM102-I/SS

11AA160-I/SN

11LC161-I/SN

11AA161-I/SN

11AA040-I/SN

11LC040-I/SN

11LC020-I/SN

11AA020-I/SN

24AA025E64-I/SN

24AA025UID-I/SN

DSPIC33EV32GM102-I/SS

PIC18F24K20-E/SO

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MCP4631-103E/ST

MCP4021-502E/SN

MCP4021-503E/SN

MCP4021-103E/SN

MCP4021-202E/SN

MCP3426A5-E/SN

MCP6051-E/SN

MCP6H94-E/ST

MCP4341T-503E/ML

MCP4351T-502E/ML

MCP4351T-103E/ML

PIC24HJ128GP504T-E/ML

PIC24HJ32GP304T-E/ML

TC1301A-EFAVMFTR

TC1301A-EGAVMFTR

TC1301A-FDAVMFTR

TC1302A-HPVMFTR

TC1302A-IAVMFTR

TC1301B-FFAVMFTR

TC1301B-FGAVMFTR

A3PN060-VQG100X376

A3PN060-ZVQG100X300

A3PN125-VQG100X376

AGLN060V2-VQG100IX11

AGLN060V5-VQ100IX28

AGLN125V5-VQG100IX6

AGLN125V5-VQG100IX94

AGLN250V2-VQ100IX3

PIC32MX270F512H-V/PT

PIC32MX570F512H-V/PT

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PIC32MX270F512L-V/PT

PIC32MX570F512L-V/PT

PIC32MX170F256D-V/PT

PIC32CX2051MTG128-I/X9B

PIC32CX1025MTG128-I/X9B

DSPIC33EP64GS504-I/PT

DSPIC33EP32GS504-I/PT

DSPIC33EP16GS504-I/PT

DSPIC33FJ64GS606-I/PTD22

ATSAMD21G18A-AU-SLL

ATSAM4LC4CA-AU

ATSAM4LS4CA-AU

AT89C51IC2-SLRUM

PIC32CM6408MC00032T-I/PT

DSPIC33CH128MP208T-I/PT

PIC32CM1216MC00048T-I/Y8X

PIC32CM6408MC00048T-I/Y8X

PIC32MX170F512L-50I/PF

PIC32MX250F256L-50I/PF

DSPIC33CH512MP206-H/MR

DSPIC33CH256MP506-H/MR

DSPIC33CH256MP206-H/MR

PIC16F1829-H/ML

DSPIC33EP128GM706-H/MR

PIC24HJ64GP502-H/MM

DSPIC33FJ16GS502-H/MM

PIC18F26K80-H/MM

PIC18F25K80-H/MM

PIC18F45K80-H/ML

PIC18F46K80-H/ML

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PIC12F1840-H/MF

DSPIC33CK256MP305-H/M7

AGL060V2-VQG100

PIC32MZ1024ECG100T-I/PT

PIC24HJ256GP206AT-I/PT

DSPIC33EP256MU810T-I/PT

DSPIC33FJ256GP506AT-I/PT

DSPIC33EP512MU810T-I/PT

PIC24EP256GU810T-I/PT

PIC18LF26K40T-I/SS

PIC18F24K40T-I/SS

PIC18F25K40T-I/SS

PIC16F18044T-I/SS

PIC18LF24K40T-I/SS

PIC18LF25K40T-I/SS

PIC16F15354T-I/SSC01

PIC16F15354T-I/SS

PIC16LF1907-I/MV

PIC16F1787-I/MV

PIC16F1459-I/ML

PIC16F1784-I/MV

PIC18F4455-I/ML

PIC12F1501-I/MC

PIC24F16KL402-I/MQ

PIC18LF4458-I/ML

PIC32MX370F512H-V/PT

PIC32MX470F512H-V/PT

TC7107IKW

PIC18F1320-E/ML

PIC16F1708-E/ML035

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PIC16F19195-E/MR

ATSAMD21E17L-MF

PIC18F24K42-E/ML

PIC16F684-I/ST

PIC16LF1503-I/STC03

PIC16F1503-I/ST

PIC16F18326-I/ST

PIC16LF1709-I/ML

PIC16LF1619-I/ML

PIC16F1618-I/GZ

PIC16F1613-I/ML

PIC16F15376-E/MVVAO

PIC16F15385-E/6MXVAO

PIC18F25Q10-E/5NVAO

PIC18F24Q10-E/MVVAO

PIC16F18445-E/GZVAO

PIC16LF18446-E/GZVAO

PIC16LF15356-E/MVVAO

DSPIC33EDV64MC205-E/M7VAO

PIC16F15375-E/MVVAO

PIC16F15213-E/MFVAO

PIC16LF15355-E/5NVAO

DSPIC33CK128MC106-E/MRVAO

PIC16LF15344-E/MLVAO

UCS4002-E/6NVAO

PIC16C621A-04I/SO

PIC16LF76-I/SO

PIC16F76-I/SO

PIC16C73B-04I/SO

PIC16C73B-20I/SO

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PIC16LC73B-04I/SO

PIC16C66-10I/SO

PIC16C66-20I/SO

PIC16LC66-04I/SO

MCP6547-I/SN

MCP6S21-I/SN

PIC16LF767-I/SO

MCP6S28-I/SL

PIC16C57C-20I/SO

PIC16F872-I/SO

PIC16C57C-20I/SS

PIC16C620A-04I/SO

PIC16C620A-20I/SO

PIC16LC620A-04I/SO

PIC16C76-04I/SO

PIC16LF88-I/ML

PIC16F88-I/ML

PIC16LF87-I/ML

PIC16F87-I/ML

PIC18F4682-I/ML

PIC12F635-I/MD

PIC18LF4685-I/ML

PIC10F220-I/MC

PIC18F4685-I/ML

PIC18F4331-I/ML

PIC18LF4431-I/ML

PIC10F222-I/MC

PIC18LF1230-I/ML

PIC18F1230-I/ML

PIC18F4431-I/ML

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MCP1602-120I/MF

MCP1602-150I/MF

MCP1602-180I/MF

PIC16LF876A-I/ML

ATSAMD51N19A-AFT

ATMEGA168-15MZ

TA010-MAYDAT-VAO

SY88053CLMG

SY88063CLMG

SY88073LMG

ATSAMD21E17D-MU

ATSAM3N1AB-MU

PIC18F24K42-I/ML

PIC24FJ128GB606-I/MR

PIC24FJ256GB606-I/MR

PIC24FJ512GB606-I/MR

DSPIC33EP64GS504-I/MLRB3

PIC24FJ1024GA606-I/MR

PIC24FJ128GA606-I/MR

PIC24FJ256GA606-I/MR

PIC24FJ512GA606-I/MR

24AA04T-I/ST

93LC56AT-I/ST

PIC16F1512T-I/SO

PIC16F1513T-I/SO

PIC16LF1516T-I/SS

PIC16LF1518T-I/SS

24LC014HT-I/ST

24AA014HT-I/ST

24C01CT-I/ST

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34LC02T-I/ST

34AA02T-I/ST

24LC02BT-I/SN104

PIC16F1516T-I/SS

93LC46BT-I/ST

PIC16LF1936T-I/SS

ATXMEGA128A1U-AUR

ATXMEGA64A1U-AUR

ATXMEGA256D3-AURA3

ATXMEGA256C3-AURA0

ATXMEGA192C3-AUR

ATMEGA16L-8AURA0

ATMEGA32L-8AUR

ATMEGA32L-8AURA4

PIC16F15375T-I/PT

PIC16F15376T-I/PT

PIC16F15385T-I/PT

PIC16F15386T-I/PT

ATMEGA3290-16AUR

ATMEGA3290V-8AUR

ATMEGA3290PV-10AUR

PIC16LC72A-04/SO

PIC16C620A-04/SO

PIC16C620A-20/SO

PIC16C76-20/SO

PIC16F873-04/SO

PIC32CM2532LS00048T-E/Y8X

ATMEGA162-16AUR

ATMEGA644-20AUR

ATMEGA329PV-10AUR

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ATMEGA329PV-10AURA0

AT90CAN64-16AUR

ATXMEGA16A4U-AUR

ATXMEGA32A4U-AUR

ATXMEGA128C3-AUR

ATXMEGA128D3-AURA1

ATMEGA324PB-AUR

ATMEGA64L-8AUR

ATMEGA16A-AUR

ATMEGA16-16AUR

PIC18F46K80-I/PTVAO

OS8104AAH-D1B-V01

DSPIC33EV64GM006-I/PTVAO

PIC16F946-I/PTVAO

DSPIC33EV32GM104-I/PTVAO

DSPIC33EV64GM004-I/PTVAO

DSPIC33EV64GM104-I/PTVAO

PIC16F887-I/PTVAO

SPYNIC25-E1A-010129-V02

OS81050AH-E1A-011007-V01

DSPIC33EV256GM106-I/PTVAO

ATMXT641TD-ATVA2

ATMXT449TD-ATVA2

ATMXT225TD-ATVA2

PIC16F18875-I/PTVAO

AT27C4096-90JU-T

PIC24HJ128GP204T-I/ML

PIC24HJ128GP504T-I/ML

PIC24HJ32GP304T-I/ML

DSPIC33FJ64GP204T-I/ML

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PIC32MX230F256DT-50I/ML

DSPIC33EP256MC204T-I/ML

DSPIC33EP256MC504T-I/ML

PIC24EP256GP204T-I/ML

DSPIC33EV128GM102T-I/MM

DSPIC33EV64GM002T-I/MM

DSPIC33EV64GM102T-I/MM

DSPIC33EV32GM002T-I/MM

PIC32MX564F128HT-I/MRC21

PIC32MX564F128HT-I/MR

DSPIC33CK256MP406-H/MR

DSPIC33CK256MP706-H/MR

DSPIC33CK1024MP405-H/M7

DSPIC33CK1024MP705-H/M7

DSPIC33CK512MP405-H/M7

DSPIC33CK512MP705-H/M7

DSPIC33CK256MP405-H/M7

DSPIC33CK256MP705-H/M7

DSPIC33CK1024MP406-H/MR

PIC24FJ64GB002-I/ML

PIC24FJ32GB002-I/ML

PIC16F1789-I/MV

PIC24FJ128GA106-I/MR

PIC24FJ192GA106-I/MR

PIC24FJ256GA106-I/MR

PIC24F16KA304-I/ML

PIC24F32KA304-I/ML

PIC24FJ64GA106-I/MR

PIC24F08KL201-I/MQ

PIC24F16KL401-I/MQ

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PIC24F08KL401-I/MQ

PIC24F08KL301-I/MQ

USB2512B-I/M2

USB2513B-I/M2

USB2514B-I/M2

PIC24FJ64GB106-I/MR

PIC24FJ128GB106-I/MR

PIC16F527-I/ML

DSPIC33FJ128MC706A-I/MR

DSPIC33FJ128MC506A-I/MR

PIC24F04KL101-I/MQ

PIC16F1703-I/ML

PIC16F1707-I/ML

DSPIC33CK64MP506-I/PTC04

DSPIC33CK128MP508-I/PTC01

DSPIC33CK64MP508-I/PTC02

DSPIC33CK256MP508-I/PTC03

DSPIC33CK128MP208-I/PTC04

ATSAM4C8CB-AUT

DSPIC33CK32MP205-I/PTC01

DSPIC33CK64MP205-I/PTC04

DSPIC33CK128MP205-I/PTC06

AGL250V2-VQ100I

ATSAM4C16CB-AUT

AGL250V2-VQG100I

ATSAMD21E17L-MFT

24FC01T-E/Q4B

PIC16LF18875T-E/ML

ATMEGA3208-MFR

24LC08BT-E/MC

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24LC16BT-E/MNY

PIC18LF46K40T-E/MV

PIC18F45K40T-E/MV

PIC18F46K40T-E/ML

DSPIC33FJ64GP802T-E/MM041

MCP6V97T-E/MNY

24LC08BHT-E/MNY

24AA16T-E/MNY

24LC16BHT-E/MNY

24LC08BT-E/MNY

DSPIC33EP64GS502T-E/MM

DSPIC33EP32GS502T-E/MM

DSPIC33EP64GS402T-E/MMC02

PIC16F18875T-E/ML

PIC16LF1503T-E/MV

PIC24EP32MC202T-E/MM021

ATSAMD21E16B-MFT

ATSAMD21E15B-MFT

ATSAMD21E16L-MFT

ATSAMD21E15L-MFT

ATSAMD21E15B-MFTA7

ATMEGA808-MFR

DSPIC33EP32GS202T-E/MM

DSPIC33CK512MP606T-E/MR

DSPIC33CK256MP306T-E/MR

PIC32CM1216MC00032T-E/RTB

PIC32CM6408MC00032T-E/RTB

DSPIC33CK256MP606T-E/MR

DSPIC33CK512MP306T-E/MR

24LC16BT-E/MNYRVF

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PIC32CM1216MC00048T-E/U5B

PIC32CM6408MC00048T-E/U5B

DSPIC33EP16GS202T-E/MM

MCP2542FDT-E/MF

PIC16F18325T-E/JQ

DSPIC33EP32MC202T-E/MM

24C01CT-E/MNY

24C01CT-E/MC

24LC024T-E/MNY

24LC025T-E/MNY

24LC024T-E/MC

24LC025T-E/MC

DSPIC33CK256MP305T-E/M7

DSPIC33CK256MP605T-E/M7

DSPIC33EV128GM004T-H/PTVAO

DSPIC33CK128MC106T-H/PTVAO

DSPIC33EV256GM104T-H/PTVAO

PIC32MZ1024EFM064-E/PT

PIC32MZ2048EFG064-E/PT

PIC32MZ2048EFH064-E/PT

PIC32MZ2048EFM064-E/PTN23

PIC32MZ0512EFK064-E/PT

PIC32MZ1024EFE064-E/PT

PIC32MZ1024EFF064-E/PT

PIC32MZ1024EFG064-E/PT

PIC32MZ1024EFH064-E/PT

ATSAMD21G16B-AF

ATSAMD21G15B-AF

PIC24FJ128GA204-E/PT

DSPIC33CK64MP206-E/PT

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DSPIC33CK32MP206-E/PT

DSPIC33CK32MP506-E/PT

DSPIC33CK256MP208-E/PT

DSPIC33CK256MP508-E/PT

DSPIC33CK128MP208-E/PT

DSPIC33CK128MP508-E/PT

DSPIC33CK64MP208-E/PT

DSPIC33CK64MP508-E/PT

DSPIC33CK64MP506-E/PT

DSPIC33CK128MP206-E/PT

DSPIC33CK128MP506-E/PT

PIC18F47Q43-E/PT

DSPIC30F6015-20E/PT

DSPIC30F6010A-20E/PT

DSPIC30F6010A-20E/PTC03

PIC16LF15356T-I/SS

25LC320AXT-I/ST

25AA320AXT-I/ST

PIC18F14Q41T-I/SS020

25CS320T-I/ST

AVR32DU28T-I/SS

AVR16DU28T-I/SS

AVR32DU20T-I/SS

AVR16DU20T-I/SS

PIC16F17156T-I/SO

PIC16F18156T-I/SO

PIC16F19156T-I/SS022

PIC16F19156T-I/SS

PIC16LF19155T-I/SS

PIC16LF19156T-I/SS

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33CK128MP205-E/PTVAO

DSPIC33CK128MP505-E/PTVAO

PIC24EP128GP204T-I/PT039

AVR128DB64T-I/PT

AVR64DB64T-I/PT

PIC18F67K22T-I/PT036

AVR16DU32T-I/PT

AVR32DU32T-I/PT

ATSAMC21N18A-AUTGR

PIC32CM2532JH00032T-I/PT

PIC32CM2532JH01032T-I/PT

KSZ8041FTLI-TR

ATMEGA324A-AURA3

AVR16EB32T-I/PT

PIC16F19175T-I/PT

PIC16F19176T-I/PT

PIC18F45Q43T-I/PT

PIC18F55Q43T-I/PT

PIC16LF19175T-I/PT

PIC16LF19176T-I/PT

PIC16LF19186T-I/PTC01

PIC16F19185T-I/PT

PIC16F19186T-I/PT

PIC16LF19185T-I/PT

PIC16LF19186T-I/PT

PIC32CM5164LE00048T-I/Y8X

AVR32EA32T-I/PT

AVR32EA48T-I/PT

PIC32CM5164LE00064T-I/PT

PIC32CM5164LE00100T-I/PF

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32CM5164LS00048T-I/Y8X

PIC32MX370F512HT-I/PT

PIC32CM5164LS00064T-I/PT

PIC32MX470F512HT-I/PT

PIC32CM5164LS00100T-I/PF

AVR64EA32T-I/PT

AVR64EA48T-I/PT

ATSAMC21G18A-AUT

ATSAMC21G17A-AUT

ATSAMC21G18A-AUTN01

PIC24HJ256GP206T-I/PT035

PIC18F46Q83T-I/PT

PIC18F46Q84T-I/PT

PIC18F56Q83T-I/PT

PIC18F67J11T-I/PT

DSPIC33CK256MC506T-I/PT

DSPIC33CK128MC506T-I/PT

DSPIC33CK256MC106T-I/PT

DSPIC33CK128MC106T-I/PT

PIC18F57K42T-I/PT

PIC18LF57K42T-I/PT

PIC18F67J50T-I/PT024

PIC18F45Q24T-I/PT

PIC18F46Q24T-I/PT

PIC18F55Q24T-I/PT

PIC18F56Q24T-I/PT

PIC24HJ64GP204-E/ML

24VL014T/MNY

LAN7800T/Y9X

LE88262TQCT

Date: Tuesday, July 22, 2025

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MCP2150T-I/SS

MCP2155T-I/SS

MCP2140T-I/SS

PIC16LF628AT-I/SO

PIC16C620AT-04I/SS

MCP2140T-I/SORVB

PIC16LF819T-I/SS

MCP2150T-I/SSRVB

MCP2155T-I/SSRVB

PIC16F819T-I/SS

PIC16LF818T-I/SS

PIC16F818T-I/SS

PIC18F47Q84T-E/PT

ATSAMD51N20A-AFT

ATSAME51N19A-AFT

LX34311T-H/ST

PIC16C67-04I/L

PIC16C926-I/L

PIC16C77-10I/L

PIC16C77-20I/L

PIC16LC77-04I/L

PIC16C74A-04I/L

PIC16C74A-20I/L

PIC18LF6680-I/L

PIC18F6680-I/L

PIC16LC926-I/L

PIC18C601-I/L

PIC17C756A-33I/L

PIC17LC756A-08I/L

PIC16LF877A-I/L

Date: Tuesday, July 22, 2025

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PIC16F877A-I/L

PIC16LF871-I/L

PIC18LF6585-I/L

PIC18F6585-I/L

PIC16F871-I/L

PIC16F874-04I/L

PIC16F874-20I/L

PIC16LF874-04I/L

DSPIC33AK512MPS505-I/PT

DSPIC33AK256MPS505-I/PT

DSPIC33AK512MPS206-I/PT

PIC18F66K40-I/MR

PD69210R-022420

PD69210C-022419

PIC16LF15323-I/JQ

ATSHA204A-MAHJX-T

PIC16F18045T-I/SS

PIC16F15356T-I/SS

PIC18F25K83T-I/SS

PIC18F26K83T-I/SS

PIC18LF25K83T-I/SS

PIC18LF26K83T-I/SS

PIC18F26K42T-I/SS

PIC18LF26K42T-I/SS

PIC24HJ64GP502T-I/SOA21

PIC18F27K42T-I/SS

PIC18LF27K42T-I/SS

PIC18F24Q10T-I/SS

PIC16F18855T-I/SSC01

PIC16F18856T-I/SS

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PIC16LF18856T-I/SS

PIC16F18854T-I/SS

PIC16LF18854T-I/SS

PIC18LF25J10T-I/SS044

PIC16F1788T-I/SS023

PIC16F1788T-I/SSC01

25LC640T-I/SN

PIC32AK1216GC41064T-I/PT

PIC32AK6416GC41064T-I/PT

PIC32AK3208GC41064T-I/PT

AVR64DA64ST-I/PT

AVR32DA32ST-I/PT

AVR64DA32ST-I/PT

AVR32DA48ST-I/PT

23A640-I/ST

MIC2179YSM

MIC2179-5.0YSM

PIC16F18444-I/SS

PIC16F18445-I/SS

HT12-100PAS/12PT49

11LC080-I/SN

PIC24EP32GP202-E/MM

PIC24EP32MC202-E/MM

DSPIC33EP64GP506-E/MR

PIC24EP64GP206-E/MR

DSPIC33FJ16GS402-E/MM

PIC24HJ32GP204-E/ML

PIC16F18324T-E/ST

PIC12C509AT-04E/SN

PIC16F15323T-E/ST027

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AVR32DA28T-E/SO

DSPIC33EP64MC202T-E/SSC05

PIC12F1822T-E/SN

PIC12F1822T-E/SNC07

PIC12HV615T-E/SN035

AVR64DA48ST-I/PT

ATSAMC20J16A-AUTS2

DSPIC33CH512MP206T-I/PTC04

DSPIC33CH256MP506T-I/PTC05

DSPIC33CH256MP206T-I/PTC06

DSPIC33CH256MP508T-I/PTC05

DSPIC33CH512MP208T-I/PTC06

PIC32MK1024MCM100T-I/PTN01

ATSAMC21G18A-AUTS2

PIC18F4520T-E/PT

25LC256T-I/ST

DSPIC33FJ32MC204T-E/ML

MCP4631T-503E/ML

MCP4641T-502E/ML

MCP669T-E/ML

MCP660T-E/ML

MCP4651T-502E/ML

MCP4651T-103E/ML

MCP4651T-104E/ML

MCP2544WFDT-E/MF

MCP98208T-E/MNY-GLW08

MCP4651T-503E/ML

DSPIC33CK128MC505-H/M7

DSPIC33CK256MC105-H/M7

DSPIC33CK128MC105-H/M7

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MCP2561-H/MF

MCP2561FD-H/MF

MCP2562-H/MF

MCP2562FD-H/MF

MCP8026-115H/MP

DSPIC33CK256MC505-H/M7

DSPIC33EV256GM002-H/MM

DSPIC33EV256GM102-H/MM

DSPIC33EV256GM106-H/MR

DSPIC33EV256GM004-H/ML

DSPIC33EV256GM104-H/ML

DSPIC33EP256GP506-H/MR

DSPIC33EV128GM002-H/MM

DSPIC33EV128GM102-H/MM

DSPIC33EV64GM002-H/MM

DSPIC33EV64GM102-H/MM

DSPIC33EP64MC206-H/PT

DSPIC33EP128MC204-H/PT

DSPIC33EP128MC504-H/PT

PIC24EP128GP204-H/PT

PIC24EP128MC204-H/PT

DSPIC33EP128MC206-H/PT

DSPIC33EP128MC506-H/PT

PIC24EP128GP206-H/PT

PIC24EP128MC206-H/PT

DSPIC33EP512GM306-H/PT

DSPIC33EP512GM706-H/PT

DSPIC33EP512GM710-H/PT

DSPIC33EP256MC206-H/PT

DSPIC33EP256MC506-H/PT

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DSPIC33CK256MC505-H/PT

ATA6585-GTQW0-VAO

ATA6586-GTQW0-VAO

PIC16F1614-H/MLVAO

DSPIC33EP128MC206T-H/MRVAO

DSPIC33EP128MC506T-H/MRVAO

PIC16F1503T-H/MGVAO

PIC16F1829T-H/MLVAO

PIC16F1824T-H/MLVAO

ATA6570-GCQW0

ATA6571-GCQW0-VAO

AGLN125V2-VQ100

AGLN125V2-VQG100

AGLN250V2-VQ100

AGLN250V2-VQG100

AGLN250V5-ZVQG100

AGLN060V5-VQG100

AGLN060V5-VQ100

AGLN125V5-VQ100

DSPIC33CK128MC505-H/PT

DSPIC33CK256MC105-H/PT

DSPIC33CK128MC105-H/PT

DSPIC33EP32MC204-H/PT

DSPIC33FJ64MC804-H/PT

DSPIC33EP128GP504-H/PT

DSPIC33EP128GP506-H/PT

DSPIC33AK32MC106-H/PT

DSPIC33AK128MC106-H/PT

DSPIC33AK64MC106-H/PT

DSPIC33AK32MC105-H/PT

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DSPIC33AK128MC105-H/PT

DSPIC33AK64MC105-H/PT

DSPIC33CK256MC506-H/PT

DSPIC33CK128MC506-H/PT

DSPIC33CK256MC106-H/PT

24LC02B/ST

24AA02/ST

93LC66A/ST

24VL024H/ST

24VL024/ST

24VL025/ST

DSPIC33EP64MC202T-E/MM

DSPIC33EP64MC502T-E/MM

93LC56B-E/ST

93LC56C-E/ST

PIC16F18455-E/SS

PIC16F18456-E/SS

24LC024-E/SN

24LC025-E/SN

24LC014-E/SN

PIC16LF18857-E/SS

PIC24F16KA101-E/SS

PIC16F1764T-E/ST

ATMEGA4808-XFR

AVR128DB28T-E/SO

AVR64DB28T-E/SO

AVR32DB28T-E/SO

AVR64DA28T-E/SS

AVR64DA28T-E/SO

PIC16LF15356T-E/SS

Date: Tuesday, July 22, 2025

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PIC18F27Q83T-E/SS

25LC320AXT-E/ST

AT27C4096-55JU-T

SST39SF040-55-4I-NHE-T

SST39SF020A-55-4I-NHE-T

SST39SF010A-55-4I-NHE-T

SST39SF020A-70-4I-NHE-T

SST39SF010A-70-4I-NHE-T

SST39VF010-70-4I-NHE-T

PIC18F66K40-I/PT

ATSAM4LC8CA-AU

ATSAM4LS8CA-AU

PIC24FJ64GU205-I/PT

DSPIC33CH512MP205-I/PT

DSPIC33CH256MP505-I/PT

PIC32MK1024MCM064-I/PT

PIC32MK0512MCM064-I/PT

PIC32MK1024GPK064-I/PT

PIC32MK0512GPK064-I/PT

PIC24FJ256GA410-I/PT

DSPIC33EP128GS704T-I/ML

DSPIC33EP128GS804T-I/ML

24FC01T-I/MUY

24FC02T-I/MUY

24FC04T-I/MUY

PIC32MK1024GPE064T-I/MR

PIC16F1503T-E/MG087

MCP8026T-115E/MP

MCP8026T-115E/MPB3

ATTINY3227-MFR

Date: Tuesday, July 22, 2025

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PIC16F18026T-E/ML

PIC16F18046T-E/ML

MIC5219-5.0YMT-TR

LAN8670C2T-E/LMX

LAN8672C2T-E/LNX

LAN8671C2T-E/U3B

11LC080T-I/SN

11AA080T-I/SN

PIC16LF18324T-I/ST

11LC160T-I/SN

11AA160T-I/SN

11AA020T-I/SN

11LC040T-I/SN

11AA040T-I/SN

11AA010T-I/SN

24AA025E48T-I/SN

24AA025E64T-I/SN

PIC18F26K22T-I/SSC04

PIC16F726T-I/SS031

DSPIC33AK512MC210T-I/PT

DSPIC33AK256MC210T-I/PT

PIC24HJ128GP306AT-I/PT060

ATMEGA64-16AUR

PIC32MX460F512LT-80I/PT024

PIC16LF1519T-I/PT

DSPIC33FJ64MC508AT-I/PT

PIC18LF46J53-I/PT

PIC24FV16KM204-I/PT

PIC24FV08KM204-I/PT

PIC18F4410-I/PT

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PIC24FJ64GC006-I/PT

PIC24FJ64GA306-I/PT

PIC24FJ128GA306-I/PTREL

MCP48CVB24-E/ML

MCP48CVB28-E/ML

PIC18LF27K40-E/ML

PIC18LF24K40-E/MV

PIC18LF25K40-E/MV

DSPIC33EV256GM002-E/MMC01

DSPIC33EP32MC202-E/MM

DSPIC33EP512GP504-E/ML

MCP48FEB18-E/MQ

MCP48FEB28-E/MQ

PIC24EP512GP202-E/MM

PIC24FJ256GL406-E/MR

PIC24FJ512GL406-E/MR

PIC24FJ128GU406-E/MR

PIC24FJ256GU406-E/MR

PIC24FJ512GU406-E/MR

DSPIC33EP512GP506-E/MR

DSPIC33EP512MC206-E/MR

MCP41HV31-103E/MQ

MCP41HV31-503E/MQ

MCP41HV31-104E/MQ

PIC18F66K22-E/MR

PIC18F45K22-E/MV

24AA512-I/SN

24FC512-I/SN

24LC08BH-I/SN

PIC18LF2550-I/SO

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PIC16LF1455-I/ST

PIC24F16KM202-I/SS

PIC24FV16KM202-I/SO

PIC24FV08KM202-I/SO

HCS201-I/SN

11AA02UID-I/SN

PIC16F1783-I/SS

PIC18LF24K22-I/SS

24LC02BH-I/SN

24AA02E48-I/SN

93LC86C-I/ST

24AA02H-I/SN

93C76C-I/ST

MCP6031-E/MC

PIC18F4520-E/ML

MCP4431-502E/ML

MCP3426A0-E/MC

MCP4361-104E/ML

MCP4361-503E/ML

MCP3426A4-E/MC

MCP3426A3-E/MC

PIC24HJ256GP206A-E/MR

DSPIC33FJ256GP506A-E/MR

DSPIC33FJ16GP102-E/ML

USB5734T/MRD02

LAX8710AT/S8X

MCP73853T-I/ML

PIC16F648AT-I/ML

PIC32MZ2048ECG100-I/PF

PIC32MX250F256H-50I/PT

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PIC32MX130F128H-50I/PT

PIC32MX120F064H-50I/PT

PIC32MZ1024ECG100-I/PF

PIC32MX230F128H-50I/PT

PIC32MX230F128L-50I/PT

PIC32MX270F512L-50I/PT

PIC32MX550F256L-50I/PT

PIC24HJ128GP210-I/PT

PIC24HJ128GP310-I/PT

DSPIC33FJ32GS610-50I/PT

DSPIC33FJ64GS608-50I/PT

PIC32MX570F512L-50I/PT

DSPIC33FJ128MC510-I/PF

DSPIC33FJ128MC710-I/PF

DSPIC33FJ256MC510-I/PF

QT6E22-ASG

ATMEGA324P-20AU

ATXMEGA384C3-AU

ATXMEGA384D3-AU

AT89S52-24AU

AT89LS52-16AU

AT89S52-24AUA1

ATMEGA325PV-10AU

ATMEGA1281-16AU

ATMEGA644V-10AU

ATMEGA644PV-10AU

ATMEGA644P-20AU

AT90CAN32-16AU

AT89LP52-20AU

ATXMEGA256A3-AU

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ATXMEGA192A3-AU

DSPIC33CK1024MP406-E/MR

DSPIC33CK512MP406-E/MR

DSPIC33CK512MP706-E/MR

DSPIC33CK256MP406-E/MR

PIC16F684-E/ML

PIC16LF18855-E/ML

PIC16LF18856-E/ML

ATSAMD21E17D-MZ

ATSAMD21E17D-MF

DSPIC33CK256MP706-E/MR

PIC16F1615-E/ML

PIC16LF1516-E/MV

PIC16LF1518-E/MV

PIC16LF18854-E/ML

PIC16LF1517-E/MV

AVR64DD32-E/RXB

PIC16F17176-E/MP

PIC16F18176-E/MP

DSPIC33FJ32MC204-I/PTVAO

PIC16F1947-I/PTVAO

PIC24FJ32GA004-I/PTVAO

PIC16F1946-I/PTVAO

DSPIC33FJ64MC804-I/PTVAO

PIC16F1517-I/PTVAO

PIC16LF1934-I/PTVAO

PIC16F1937-I/PTVAO

PIC16F1934-I/PTVAO

PIC16LF1937-I/PTVAO

PIC18F65K22-I/PTVAO

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F1527-I/PTVAO

PIC18F45K22-I/PTVAO

MCP23017-E/MLVAO

PIC16F1718-E/MVVAO

PIC18F45Q10-E/MPVAO

MCP1725-3302E/MCVAO

MCP2050-500E/MQVAO

PIC16F15224-E/MGVAO

PIC16F15225-E/MGVAO

LAN8671C2-E/U3BVAO

DSPIC33CK1024MP705-E/M7VAO

LAN8670C2-E/LMXVAO

LAN8672C2-E/LNXVAO

ATSAMD21G15B-MZVAO

ATSAMC20G17A-MZVAO

ATSAMC21G17A-MZ510

ATSAMC21G18A-MZ510

ATSAMC21G17A-MZVAO

MCP4141-104E/MFVAO

PIC16LF18426-E/JQVAO

MCP662-E/MFVAO

MCP4161-502E/MFVAO

PIC16F18346-E/GZVAO

PIC16C76-10I/SO

PIC16C76-20I/SO

PIC16C55A-04I/SO

PIC16C55A-20I/SO

PIC16LC72A-04I/SO

AT27C020-90JU

COM20020I3V-DZD

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

AT28C64B-15JU

AT27BV010-90JU

PIC18F25K80T-I/MM

PIC18F26K80T-I/MM

DSPIC33EP64GS804T-I/ML

PIC16LF723A-I/SS

PIC16LF87-I/SS052

ATMXT1296M1T-ATVA1

MCP4661T-502E/ML

DSPIC33EP128MC504T-I/ML

ATECC608B-MAH7I-T

PIC16F1786T-I/ML

PIC24EP128MC204T-I/ML

USB4715T-I/Y9X

PIC24FJ256GB206T-I/MR

PIC18F27Q10T-I/ML

PIC18F24Q10T-I/ML

PIC18F25Q10T-I/ML

PIC18F26Q10T-I/ML

TC1302B-DTVMFTR

MCP4801T-E/MC

MCP4542T-103PE/MF

MCP4562T-103PE/MF

PIC24FJ32MC102-E/ML

ATSHA204A-MAHLS-T

ATSHA204A-MAHPG-S

ATSHA204A-MAHPG-T

ATSAMD21G17A-MUTA0

ATSAMD21G18A-MUT

HV5622PJ-G

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC24HJ32GP304-I/ML

PIC32MX775F512H-80I/MR

PIC32MX775F256H-80I/MR

PIC24EP256GP206-I/MR

AT28LV010-20JU-051

AT89C51ED2-SMSUM

AT28C010-12JU-076

AT28LV010-20JU-319

AT28C010E-12JU-341

AT89LP51ID2-20JU

AT89LP6440-20JU

TC7106ILW

TC7106AILW

TC7107ILW

TC7107AILW

TC850ILW

ATSAMD20J14A-AUTA2

AVR64DU32T-I/PT

PIC16LF18877T-I/PTRA3

MTR7519T-I/PTC04

PIC16LF1946T-I/PTC01

PIC18F66K90T-I/PTC07

PIC18F65K40T-I/PT

PIC16F1719T-I/ML

PIC16F1782T-I/MV

PIC16F1717T-I/ML

PIC16LF1719T-I/ML

PIC16LF1717T-I/ML

PIC16F1782T-I/ML

PIC16LF1718T-I/ML

Date: Tuesday, July 22, 2025

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PIC16LF1719T-I/MV

PIC16LF1717T-I/MV

PIC18LF4620T-I/ML

PIC18F4620T-I/ML

PIC16F1718T-I/MV

PIC16F1783T-I/ML

PIC18LF4525T-I/ML

PIC16LF1904T-I/MV022

PIC12F1840T-I/MF

PIC16F1516T-I/MV

PIC16F1518T-I/MV

PIC16F1704T-I/ML

DSPIC33EV256GM104T-I/ML

PIC16LF723AT-I/ML

PIC16F1937T-I/ML

PIC12LF1501T-I/MC020

PIC18LF46K22T-I/MV022

PIC24FJ64GA306T-I/MR

PIC24FJ128GA306T-I/MR

PIC24FJ32GA002T-I/MLC11

PIC24FJ64GA002T-I/ML

PIC24FJ16GA002T-I/ML

MTCH810T-I/MF

PIC16F1705T-I/ML

PIC12LF1572T-I/MF

PIC16LF1938T-I/ML

PIC16F648A-E/ML

TC1301A-UHAVMF

TC1301B-UPBVMF

PIC18F4682-E/ML

Date: Tuesday, July 22, 2025

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MCP1727-3002E/MF

MCP1727-3302E/MF

MCP1727-5002E/MF

MCP1727-ADJE/MF

TC1301B-FSAVMF

MCP1726-2502E/MF

MCP1726-3002E/MF

MCP1726-3302E/MF

MCP1726-5002E/MF

MCP1726-ADJE/MF

PIC18F4685-E/ML

MCP1726-1202E/MF

MCP1726-1802E/MF

PIC12F509-E/MC

MCP1727-2502E/MF

MCP1726-0802E/MF

MCP1727-0802E/MF

MCP1727-1202E/MF

MCP1727-1802E/MF

PIC10F220-E/MC

TC1302B-IAVMF

TC1301A-ADAVMF

MCP4251-502E/ML

MCP4251-103E/ML

PIC12F508-E/MC

PIC32MZ0512EFE064-E/MR

SST39VF040-70-4I-NHE-T

SST39SF040-70-4I-NHE-T

AT28C010E-12JU-T

AT28HC64B-90JUT-441

Date: Tuesday, July 22, 2025

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AT28HC64B-70JUT-441

AT28HC256-12JU-070

AT28HC256E-12JU-070

SST39SF040-55-4C-NHE-T

SST39SF020A-55-4C-NHE-T

SST39SF010A-55-4C-NHE-T

SST39SF040-70-4C-NHE-T

SST39SF020A-70-4C-NHE-T

SST39SF010A-70-4C-NHE-T

SST39LF020-55-4C-NHE-T

SST39LF010-55-4C-NHE-T

SST39LF040-55-4C-NHE-T

SST39LF040-55-4C-NHE-RVL-T

SST39VF040-70-4C-NHE-T

SST39VF020-70-4C-NHE-T

SST39VF010-70-4C-NHE-T

SST49LF008A-33-4C-NHE-T

SST49LF080A-33-4C-NHE-T

ATF1502AS-7JX44-T

PIC16C67T-04I/L

PIC16C74AT-04I/L

PIC18F6585T-I/L

PIC18F452T-I/L

PIC16F871T-I/L

PIC16F877AT-I/L

PIC16F74T-I/L

AY0438T-I/L

PIC16F877T-20I/L

PIC16F77T-I/L

PIC16F874AT-I/L

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PIC16LF874T-04I/L

PIC17C756AT-16I/L034

HV518PJ-G-M903

HV5308PJ-B-G-M903

MM5450YV-TR

MM5451YV-TR

MIC58P01YV-TR

MIC59P50YV-TR

MIC5801YV-TR

AT89S51-24JUR

AT89S52-24JUR

AT89LP52QS840-20JUR840

PIC16F1454T-I/ST

PIC16F1936T-I/SOC04

PIC16F1936T-I/SO

24LC16BT-I/ST114

24LC16BT-I/ST116

PIC18F23K20T-I/SS

PIC16F1709T-I/SS

24LC02BT-I/ST

PIC16LF1614T-I/ST

PIC16LF1618T-I/SS

RE340S16TF

AGLN125V5-VQG100

AGLN250V5-VQ100

AGLN250V5-VQG100

AGLN250V2-VQG100PZ03

AGLN060V2-VQG100I

AGLN060V2-VQ100I

AGLN125V2-VQ100I

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AGLN125V2-VQG100I

AGLN250V2-VQ100I

AGLN250V2-VQG100I

AGLN250V5-ZVQG100I

A3PN125-VQG100IQ162

AGLN060V5-VQG100I

AGLN060V5-VQ100I

AGLN125V5-VQ100I

AGLN125V5-VQG100I

AGLN250V5-VQ100I

AGLN250V5-VQG100I

AGLN250V2-VQG100IPZ03

AGLN060V2-ZVQG100

AGLN060V5-ZVQG100

AGLN060V2-ZVQG100I

ATSAMD20E16B-AN

ATSAMD20E14B-AN

ATSAMD20E15B-AN

AGLN060V5-ZVQ100I

AGLN060V5-ZVQG100I

A3PN060-ZVQG100

PIC18F46K22-E/MV

PIC18F27Q84-I/SO

AVR32DA28-I/SS

PIC18LF26J11-I/SO

PIC18F26J11-I/SO

PIC18LF25J11-I/SO

DSPIC33AK128MC102-I/SS

DSPIC33AK64MC102-I/SS

PIC32MM0064GPM048T-I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MM0128GPM048T-I/PT

PIC32MM0256GPM048T-I/PT

PIC32MX350F256HT-I/PT020

PIC18F85J11T-I/PT

PIC32MK1024MCM064T-I/PT

PIC32MK0512MCM064T-I/PT

PIC32MK1024GPK064T-I/PT

PIC18F85J90T-I/PT

PIC32MK0512GPK064T-I/PT

PIC32MZ0512EFK100T-I/PT

PIC16F18446-E/GZ

PIC24HJ32GP304-E/ML

PIC32MX274F256BT-I/MM

PIC32MX120F032BT-I/ML

PIC32MX174F256DT-I/ML

25AA160DT-I/MNY-PR

PIC16F1789T-I/ML

DSPIC33EP64GP506T-I/MR

PIC24EP64GP206T-I/MR

DSPIC33EP64GP504T-I/ML

PIC24EP64GP202T-I/MM

PIC24EP256MC202-I/SS

PIC18F2320-I/SOV02

PIC12HV609-I/SN

PIC16LF18444-I/SS

PIC16LF18445-I/SS

PIC16F18446-I/SS

PIC16F688-I/ST

PIC32MM0016GPL028-I/SS

PIC32MM0032GPL028-I/SS

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PIC32MM0064GPL028-I/SS

PIC18F44J50T-I/PT

PIC18F47J13T-I/PT

PIC18LF4321T-I/PT

PIC18F4321T-I/PT

PIC18F46J11T-I/PT

PIC18F4685T-I/PT

PIC18F45J50T-I/PT

PIC18F4320T-I/PT

PIC16LF1946T-I/PT

PIC18F46J50T-I/PT

PIC18F8490T-I/PT

DSPIC30F3014T-30I/PT

DSPIC30F4013T-30I/PT

PIC24FJ128GA108T-I/PT

PIC18F45J10T-I/PT

PIC18F4221T-I/PT

PIC24FJ256GA108T-I/PT

PIC18F66J50T-I/PT

PIC16F1946T-I/PT

PIC18F8622T-I/PT

PIC18F8527T-I/PT

PIC16F877T-20I/PT

PIC18F44J10T-I/PT

PIC18LF4580T-I/PT

PIC24FJ128GA008T-I/PT

PIC18F4680T-I/PT

PIC24FJ256DA210T-I/PT

PIC18F65J10T-I/PT

PIC24F32KA304T-I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33CK256MP606-E/PT

ATMEGA2560-16AUR

ATMEGA32L-8AURA0

ATMEGA32L-8AURA2

ATMEGA6450P-AUR

ATMEGA6490-16AUR

ATMEGA6490V-8AUR

ATMEGA8L-8AURA3

ATMEGA325V-8AUR

ATMEGA640V-8AUR

ATMEGA640-16AUR

ATXMEGA16A4-AUR

PIC16F871-I/PT

PIC16LF871-I/PT

PIC16F877-04I/PT

PIC16F877-20I/PT

PIC16LF877-04I/PT

PIC16LF874A-I/PT

ATSAMD21E15B-AU

PIC24FJ1024GA606-I/PT

PIC24FJ128GA606-I/PT

PIC16LF15344-I/SS

PIC16F13123-I/ST

PIC16F13124-I/ST

PIC16F13125-I/ST

PIC16F13143-I/SS

PIC16F13144-I/SS

PIC16F13145-I/SS

MCP602-I/STAAA

PIC18F14Q41-I/SS020

Date: Tuesday, July 22, 2025

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PIC16F15355-I/SS

PIC16LF15354-I/SS

PIC16F18023-I/ST

PIC16F18024-I/ST

PIC16LF15355-I/SS

ATTINY3226-XU

PIC16LF1778-I/SS

PIC16F1778-I/SS

PIC16F1778-I/SSC02

ATTINY426-XU

ATTINY826-XU

DSPIC33FJ64GP204-E/ML

DSPIC33FJ64GP804-E/ML

DSPIC33FJ128GP204-E/ML

DSPIC33FJ128MC804-I/PT

PIC32MX270F512H-50I/PT020

DSPIC33CK512MP306-I/PT

DSPIC33CK512MP606-I/PT

DSPIC33CK256MP308-I/PT

PIC24FJ256GB406-I/PT

DSPIC33CK256MP608-I/PT

DSPIC33CK512MP308-I/PT

PIC32MK0128MCA048T-I/6MX

PIC32MK0128MCA032T-I/RTB

DSPIC33EP64MC204-E/ML

DSPIC33EP64MC504-E/ML

PIC24EP64MC204-E/ML

MCP8026-115E/MP

MCP8026-115E/MPB3

ATSAMD20G16B-MZ

Date: Tuesday, July 22, 2025

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ATSAMD20G15B-MZ

DSPIC30F1010-20E/MM

DSPIC30F2020-20E/MM

PIC24FJ256GA702-E/ML

PIC24FJ128GA702-E/ML

PIC24FJ64GA702-E/ML

MCP98244T-BE/MNY

MCP9844T-BE/MNYAA

PIC16F1783T-E/MV

11LC160T-E/MNY

MCP16501TC-E/RMB

PIC24EP256GP206T-E/PT

DSPIC33EP256MC506T-E/PT

ATSAMD21J16B-AZT

DSPIC33EP256MU806-I/MR

DSPIC33EP512GP806-I/MR

DSPIC33EP512MC806-I/MR

PIC16F18877-I/MV

PIC32MX320F064H-80I/MR

PIC24FJ64GL302-I/ML

DSPIC33FJ16GS502-50I/MM

PIC32MX120F032B-50I/ML

PIC32MX220F032B-50I/ML

PIC32MX440F256H-80I/MR

PIC32MX440F512H-80I/MR

PIC24EP512GP806-I/MR

PIC32MX440F128H-80I/MR

DSPIC33FJ06GS202-I/MM

DSPIC33FJ16GS404-50I/ML

ATMEGA644P-20AQ

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ATXMEGA16A4U-AN

ATXMEGA32A4U-AN

ATMEGA88PB-AN

ATMEGA48PB-AN

ATMEGA165PV-8AN

ATMEGA16L-8AQ

ATMEGA128-16AN

ATMEGA8A-AN

PIC16LF15324-E/JQ

PIC16F18013-E/MF

PIC16F18014-E/MF

IS1871SF-202-TRAY

IS1870SF-202-TRAY

PIC16LF15345-E/GZ

PIC12LF1822-E/RF

PIC16LF15325-E/JQ

PIC12F1822T-E/SN055

MTCH1060T-E/SS

PIC18F25K40T-E/SS

PIC12F1822T-E/SN046

PIC16F1938T-E/SS

PIC16F753T-E/ST

PIC16HV753T-E/ST027

PIC32MX534F064L-I/PF

PIC24FJ512GL408-I/PT

PIC24FJ128GU408-I/PT

ATSAMD21G16B-AU

PIC32MX230F064B-I/ML

PIC32MX120F032D-50I/ML

PIC32MX220F032D-50I/ML

Date: Tuesday, July 22, 2025

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PD69210R-035200

PIC32MX130F256D-I/ML

PIC32MX130F256D-50I/ML

PIC32MX775F512H-80I/MRE21

PIC32MX230F256D-50I/ML

PIC32MX230F256D-I/ML

PD69210C-022319

DSPIC33EP512MC204-I/ML

PD69210R-022320

USB2422-I/MJ

PIC32MX150F128B-I/ML

PIC32MX120F032D-I/ML

PIC24EP512GP204-I/ML

DSPIC33EP512GP506-I/MR

DSPIC33EP512MC504-I/ML

PIC18F24Q10-I/ML

PIC32MX110F016D-I/ML

PIC32MX220F032D-I/ML

PIC32MX120F032B-I/ML

PIC32MX110F016B-I/ML

ZL88602LDG1

LE9622RQC

ZL88702LDG1

ZL88103LDG1

PIC24EP512GP202-I/MM

PIC18LF26K80-I/MM

DSPIC33EP512MC202-I/MM

DSPIC33EP512MC502-I/MM

PIC24EP512MC204-I/ML

PIC18LF26K80-I/MMC01

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC24FJ128GL406-I/MR

PIC24FJ256GL406-I/MR

PIC18F25K80-I/MM

PIC18F26K80-I/MM

PIC18F25K80-I/MMC04

PIC24FJ512GL406-I/MR

DSPIC33EP128GS806T-E/PTVAO

PIC18LF46K22-I/PTVAO

ATMXT1067TD-ATI2CCPVAO

ATMXT1067TD-ATSPIVAO

ATMXT1067TD-ATI2CVAO

PIC18F6627-I/PTVAO

ATMXT1296M1T-ATVAO

PIC16F916-I/SO

PIC16F913-I/SO

PIC16F1716-I/SS

PIC16F722A-I/SS

24AA044-I/ST

34AA04-I/ST

HSA0-040SIA/A0SS10

HSA2-040SIA/A2S20A

HSA2-040SCA/A2324

HSA2-0C0SDA/A2S21

HSA2-040SCA/A2320A

HSA2-0C0SIA/A2S23

HA1631-I/SO

25LC640A-I/SN

25AA640A-I/SN

25LC640A-I/ST

25AA640A-I/ST

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PIC16F1786-I/SS

HSA2-0C0SIA/A2S20A

HSA0100SI/A0SS0B

PIC16F1828-I/SS027

PIC16F18855-E/MV

PIC16LF18855-E/MV

PIC16F18875-E/MV

ATSAMD21J18A-MMF

PIC16F1847-E/MV

DSPIC33CK512MP606-I/MR

ATSAMD20G18A-MUA2

ATSAMD20G14A-MUA2

ATSAMD20G15A-MUA2

DSPIC33AK32MC106-I/PT

PIC32MK0512GPD100-I/PT

PIC32MK0512MCF100-I/PT

ATF1502ASL-25AU44

ATF1502AS-10AU44

PIC18LF65K40-I/PT

PIC18LF66K40-I/PT

PIC18F87K90-I/PTC09

ATMEGA4808-AU

ATMEGA4809-AU

PIC18F6720-I/PTC01

PIC16LF1934-I/PT025

PIC18LF6720-I/PT

PIC18F6720-I/PT

PIC18LF6620-I/PT

DSPIC33FJ128MC706A-I/PT

PIC18F6620-I/PT

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PIC18LF8720-I/PT

PIC18F8720-I/PT

PIC18F66K40T-I/PT

PIC18LF65K40T-I/PT

PIC18LF66K40T-I/PT

PIC32CM2532JH00100T-I/PF

PIC32CM5164JH00100T-I/PF

PIC32CM2532JH01100T-I/PF

PIC32CM5164JH01100T-I/PF

PIC16F19195T-I/PT

PIC16F19196T-I/PT

PIC16F19197T-I/PT

PIC16LF19195T-I/PT

PIC16LF19196T-I/PT

PIC16LF19197T-I/PT

PIC18F67K40T-I/PT

PIC18LF67K40T-I/PT

PIC32CM2532JH00064T-I/PT

PIC32CM5164JH00064T-I/PT

PIC32CM2532JH01064T-I/PT

PIC32CM5164JH01064T-I/PT

PIC32CM5164JH01048T-I/Y8X

PIC32CM2532JH00048T-I/Y8X

PIC32CM5164JH00048T-I/Y8X

PIC16C622A-04I/SO

MCP6543-I/SN

PIC16LF72-I/SO

PIC16F72-I/SO

MCP2140-I/SO

PIC16LF872-I/SO

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PIC16C73A-10I/SO

PIC16C73A-20I/SO

PIC16LC73A-04I/SO

PIC16C63A-04I/SO

PIC16C63A-20I/SO

PIC16F873-04I/SO

PIC16F873-20I/SO

PIC16LF873-04I/SO

PIC16LC773-I/SS

MCP6142-I/SN

PIC16LC57C-04I/SS

PIC16LC56A-04I/SO

PIC16C773-I/SS

PIC16C72-10I/SS

PIC16LC63A-04I/SO

PIC16C73A-04I/SO

MCP6548-I/SN

PIC16C72A-04I/SO

PIC16C72A-20I/SO

MCP6042-I/SNREL

PIC16F876-04I/SO

PIC16F876-20I/SO

PIC16LF876-04I/SO

PIC18LF252-I/SO

PIC18F252-I/SO

PIC16C66-04I/SO

PIC16LF876A-I/SO

PIC16F873A-I/SO

PIC16F876A-I/SO

MCP2155-I/SSRVB

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PIC14000-04I/SO

PIC16C55A-20I/SS

PIC16LF873A-I/SO

PIC18LF242-I/SO

PIC18F242-I/SO

PIC16C57C-04I/SS

PIC16C622A-20I/SO

PIC16C56A-04I/SO

PIC16C56A-20I/SO

PIC16C62B-04I/SO

PIC16C62B-20I/SO

PIC16LC62B-04I/SO

PIC16LF870-I/SO

PIC16C57C-04I/SO

PIC16C621A-20I/SO

PIC16LC621A-04I/SO

PIC16LF73-I/SO

PIC16F73-I/SO

24AA01-I/ST

24LC02B-I/ST

24AA02-I/ST

93AA66B-I/ST

93AA66C-I/ST

93LC66A-I/ST

DSPIC33FJ64GP206A-I/MR

PIC32MX575F256HT-80V/PT

PIC32MX575F256HT-80V/PTC23

PIC32MX575F512HT-80V/PT

LAN9250/ML

LAN9252/ML

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LAN9353/ML

PIC18F13K22T-E/SS

MCP634T-E/ST

PIC16F1826T-E/SO

25LC160DT-E/SN16KA21

MCP6H74T-E/ST

24LC08BT-E/ST

93LC86BT-E/ST

93LC76AT-E/ST

93LC76BT-E/ST

93C86BT-E/ST

93C76AT-E/ST

93C76BT-E/ST

PIC12HV609-E/MF

PIC18F452-E/ML

PIC18F1330-E/ML

MCP4231-502E/ML

MCP4141-502E/MF

MCP4241-502E/ML

MCP4241-103E/ML

MCP4241-104E/ML

MCP3423-E/MF

MCP4152-103E/MF

PIC10F200-E/MC

PIC18F2420-E/ML

MCP4232-104E/MF

MCP4331-502E/ML

MCP4331-103E/ML

MCP4242-104E/MF

MCP4232-103E/MF

Date: Tuesday, July 22, 2025

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MCP4242-503E/MF

MCP4262-103E/MF

MCP4262-104E/MF

MCP4252-103E/MF

MCP4252-104E/MF

MCP4261-103E/ML

MCP6033-E/MC

MCP4232-503E/MF

MCP4242-502E/MF

MCP4242-103E/MF

MCP4232-502E/MF

MCP4331-104E/ML

MCP4262-502E/MF

MCP4252-503E/MF

PIC18F2520-E/ML

PIC18F24K20-E/ML

PIC18LF46K22T-I/PT024

ATSAMD21J17A-AUT

ATSAMD21J18A-AUT

PIC32CM2532JH01048T-I/Y8X

ATSAM4C8CB-AUTR

DSPIC33CH256MP206T-I/PTC01

DSPIC33CH256MP506T-I/PTC02

PIC24HJ128GP204-I/PT

PIC24HJ128GP504-I/PT

DSPIC33FJ64GP804-I/PT

DSPIC33FJ128GP204-I/PT

PIC32MX250F256L-I/PF

PIC32MX270F512L-I/PF

PIC32MZ2048EFM100-I/PF

Date: Tuesday, July 22, 2025

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PIC32MK0512MCJ064-I/PT

PIC32MK0512GPG064-I/PT

ATXMEGA64D3-AUA6

DSPIC33FJ128MC204-I/PT

DSPIC33FJ32MC304-I/PT

PIC32MX675F512L-80I/PF

PIC32MX675F256L-80I/PF

PIC32MX795F512L-80I/PF

PIC32MX575F512L-80I/PF

PIC32MX775F512L-80I/PF

PIC18F56K42-I/PT

PIC32MZ1024EFE100T-I/PT

PIC32MZ1024EFF100T-I/PT

PIC24FJ64GA406T-I/PT

PIC24FJ256GB406T-I/PT

PIC24FJ128GB406T-I/PT

PIC24FJ64GB406T-I/PT

PIC16LF1823T-I/MLC04

SY88022ALMG-TR

24LC32AFT-I/MNY

24AA32AFT-I/MNY

AT25160B-MAHL-T

AT25160B-MAHL-E

AT25080B-MAHL-T

AT25080B-MAHL-E

AT25320B-MAHL-T

AT25320B-MAHL-E

AT24C02C-MAHM-T

AT24C02D-MAHM-T

AT24C04D-MAHM-E

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AT24C08D-MAHM-T

AT24C128C-MAHM-T

AT24C04C-MAHM-T

AT24C02C-MAHM-E

AT24C128C-MAHM-E

PIC16F1614-I/ST

DSPIC33EP16GS202-I/SS

DSPIC33EP32GS202-I/SS

PIC16F616-I/ST

93LC46B-I/SN

93AA46-I/SN

93LC56-I/SN

PIC18LF27J53-I/SS

PIC12F629-I/SN207

PIC16F1824-I/ST

PIC12F629-I/SN208

93LC46-I/SN

93AA66-I/SN

PIC12F629-I/SN

93LC66-I/SN

93AA56-I/SN

PIC18F27J53-I/SS

PIC18LF26J53-I/SS

PIC18F27J13-I/SS

PIC18LF26J13-I/SS

PIC18F26J53-I/SS

PIC18LF27J13-I/SS

PIC18F26Q10-I/SSC01

PIC18F26J13-I/SS

MTCH105-I/ST

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PIC16F1828-I/SS

MTCH108-I/SS

24LC16B-I/ST

PIC18F25K80-I/SS

PIC12F635-I/SN057

24FC256-I/ST

MCP6H94T-E/ST

MCP3426A2T-E/SN

MCP3426A5T-E/SN

MCP4821T-E/SN

MCP4362T-103E/ST

MCP4362T-104E/ST

MCP4362T-502E/ST

MCP4021T-502E/SN

PIC16F1618T-I/SS

PIC16F1613T-I/ST

PIC16LF1707T-I/SS

PIC16F1823T-I/ST036

PIC16F1718T-I/SS

PIC16LF1933T-I/SS

PIC16F1938T-I/SS

PIC16F726T-I/SS029

PIC16F1615T-I/ST

PIC16LF1615T-I/ST

PIC16LF1765T-I/ST

PIC16LF1764T-I/ST

PIC16LF1705T-I/ST

PIC16LF1709T-I/SS

PIC16LF726T-I/SS023

PIC16F1705T-I/ST

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PIC16F1704T-I/ST

PIC16F1708T-I/SS

PIC16F1788T-I/SS

PIC16LF1708T-I/SS

24LC32AT-I/ST

PIC16F616T-I/ST090

MCP2030AT-I/ST

PIC18LF26K22T-I/SS022

PIC18LF2515T-I/SO

PIC16F1574T-I/ST

PIC16F1575T-I/ST

PIC16LF722AT-I/SS

PIC18LF2620T-I/SO

PIC18F2620T-I/SO

PIC18LF2525T-I/SO

PIC18F2525T-I/SO

PIC18LF26K22T-I/SS021

PIC16LF1827T-I/SOC02

PIC16LF73T-I/SOC12

34AA04T-I/ST

PIC16LF1574T-I/ST

PIC16LF1575T-I/ST

PIC16F722AT-I/SS022

PIC16F722AT-I/SS024

25CS320T-E/ST

MCP2022T-500E/ST

MCP4642T-502E/MF

PIC16F1782T-E/ML

PIC12F1840T-E/MF

PIC16F1704T-E/ML

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PIC18F26K22T-I/SO

DSPIC33EP32GS504T-E/PT

DSPIC33FJ32MC204T-E/PT

ATMEGA1608-AFR

ATMEGA808-AFR

ATSAMD21E17L-AFT

ATSAMD21E17D-AFT

ATSAMD21E17A-AFT

DSPIC33CK256MC505T-E/PT

DSPIC33CK128MC505T-E/PT

PIC16F1713T-E/SS

PIC16LF1827T-E/SS

PIC16LF1847T-E/SS

24LC01BT-E/SN

PIC16F1828T-E/SS

24LC04BHT-E/SN

PIC12F509T-E/SN062

PIC16F15325T-E/ST

24AA256T-E/ST

24AA16T-E/ST

PIC12F510T-E/SN070

PIC16F1503T-E/ST

24LC16BHT-E/ST

PIC16F684T-E/ST

24LC08BHT-E/ST

ATTINY424-XFR

ATTINY824-XFR

PIC16F18326T-E/ST

MCP41HV51T-502E/ST

MCP41HV51T-103E/ST

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MCP41HV51T-503E/ST

MCP41HV51T-104E/ST

PIC16F627AT-E/SO

MCP6489T-E/ST

PIC16F18856T-E/SS

PIC16F18854T-E/SS

PIC16F1518T-E/SS

PIC16F1788T-E/SS

ATTINY1624-XFR

PIC24F16KA102T-E/SSC01

25C040T-E/SN

24LC256-I/SNRVF

PIC16F17524-I/ST

PIC16LF1507-I/GZ

PIC32MX320F128H-80I/MR

PIC32MX320F064H-40I/MR

PIC32MX340F128H-80I/MR

PIC32MX370F512H-I/MR

PIC32MX470F512H-I/MR

PIC18F1220-E/SS

25LC320A-E/ST

25LC080D-E/ST

PIC18F45K20-I/ML

PIC12F1822T-I/SNC08

PIC16F1933T-I/SS024

25LC128T-I/ST

MTCH6102T-I/SS

25AA128T-I/ST

PIC18F1320T-I/SS

PIC12F508T-I/SN056

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PIC12F508T-I/SN066

PIC12F508T-I/SN

PIC18LF1220T-I/SS

PIC18F1220T-I/SS

25LC080DT-I/ST

25AA080DT-I/ST

25AA080CT-I/ST

25LC080CT-I/ST

25LC160CT-I/ST

25AA160CT-I/ST

25LC320AT-I/ST

25LC160DT-I/ST

25AA160DT-I/ST

25AA320AT-I/ST

25AA320AT-I/STB22

MCP6042T-I/SN

PIC12LF1840T39AT-I/ST

PIC18F25Q10T-E/MLVAO-MB

PIC18F25Q10T-I/STXVAO-VW

PIC18F26K40-E/MLVAO-VW

PIC18F26K40T-E/MLVAO-VW

PIC18F46K40T-E/MVVAO-VW

PIC24EP128GP202T-I/MMVAO-GM

PD69210R-022720-TR

PD69210C-022719-TR

PD69210R-022720

PD69210C-022719

ATA5700F1000M-WDQW-MB

ATSAME54N20A-AFT-SL2

ATSAME54N20A-AFT-SL3

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ATMEGA4808-AFR

DSPIC33FJ32GP202-I/MM

PIC32MX274F256B-I/MM

PIC32MX154F128B-I/MM

PIC32MX154F128D-I/ML

PIC16F685-I/ML

PIC16F687-I/ML

PIC32MX130F128H-I/MR

PIC32MX130F128H-50I/MR

PIC32MX270F512HT-I/PT

PIC32MX270F512LT-50I/PT

PIC32MX570F512LT-50I/PT

PIC32MX550F256LT-50I/PT

PIC32MX250F256LT-I/PT

PIC32MX150F256LT-I/PT

PIC32MX170F512LT-I/PT

DSPIC33FJ64GS610T-I/PF

PIC16F1936-E/SS

TC7116ACKW

TC7117CKW

TC7117ACKW

PIC17C43-16/PQ

PIC17C44-16/PQ

PIC17C44-25/PQ

PIC16C64A-20/PQ

AVR64DB32T-I/PT

AVR32DB32T-I/PT

DSPIC33CK256MC505T-I/PT

DSPIC33EV256GM102-H/SS

PIC24EP512MC202-H/SO

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33EV32GM102-H/SO

DSPIC33EV128GM002-H/SO

DSPIC33EV128GM102-H/SO

DSPIC33EV64GM002-H/SO

DSPIC33EV64GM102-H/SO

DSPIC33EV32GM002-H/SO

PIC24HJ128GP502-H/SO

DSPIC33FJ64MC802-H/SO

DSPIC33FJ64GP206AT-I/PT032

PIC24FJ32GA004T-I/PT

PIC24HJ128GP310AT-I/PT

PIC24HJ128GP510AT-I/PT

PIC24FJ48GA004T-I/PT

DSPIC33EV256GM102-I/MM

PIC24FJ64GA006T-I/PT039

DSPIC33EP64MC204T-I/PTC01

PIC16F1789T-I/PT

DSPIC33EP32GS506T-I/PT

PIC18F66K90T-I/PTC01

PIC18F87K22T-I/PTC02

PIC24FJ128GC010T-I/PT

PIC18F45K20T-I/PTC07

PIC18LF46K22T-I/PTC01

MPL360BT-I/Y8X

PIC24FJ256DA206T-I/PT

PIC24FJ128DA106T-I/PT

PIC18F4431T-I/PT027

PIC18F4431T-I/PT028

PIC24FJ64GA106T-I/PT

PIC18F85J10-I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

AT32UC3A1128-AUT

PIC32MK1024GPE100-I/PTA22

PIC32MK1024GPE100-I/PT

PIC32MK1024GPD100-I/PT

PIC24FJ128GA106T-I/PTA5

A3PN250-1VQG100I

A3PN250-2VQG100I

A3PN250-2VQG100I

A3PN250-VQ100I

ATMEGA32U4-AUR

ATMEGA32U4RC-AUR

ATMEGA325PA-AUR

ATMEGA329A-AUR

ATMEGA329PA-AUR

ATMEGA325A-AUR

ATMEGA644P-20AUR

AT90CAN128-16AUR

ATMEGA328PB-AUR

ATMEGA32A-AURA5

ATMEGA3250V-8AUR

ATMEGA3250-16AUR

ATMEGA649-16AUR

ATMEGA645-16AUR

ATMEGA8535-16AUR

ATMEGA8535L-8AUR

ATMEGA32-16AUR

ATMEGA168A-AUR

ATMEGA48PA-AURB0

PIC16F1777-E/ML

PIC16LF1779-E/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F1779-E/ML

PIC18F65K80-E/MR

PIC18F66K80-E/MR

PIC16LF1777-E/MV

PIC16F1777-E/MV

PIC16LF1779-E/MV

PIC16F1779-E/MV

WP200TX01-E/ML001

PIC32MZ0512EFE064-E/MRAR0

PIC18F27K40-E/ML

PIC18F24K40-E/MV

PIC16LF1527-E/MR

PIC16LF1526-E/MR

PIC16F1527-E/MR

PIC16F1526-E/MR

PIC24F08KA101-E/MQ

MCP6044T-E/STVAO

PIC32MX564F128H-V/PT

PIC32MX534F064H-V/PT

DSPIC30F3012-30I/ML

PIC16F18044-I/ML

PIC16F18045-I/ML

DSPIC30F3013-20I/ML

DSPIC30F3013-30I/ML

PIC16F18076-I/MP

DSPIC30F2011-20I/ML

DSPIC30F2011-30I/ML

PIC18F27Q10-I/ML

PIC18F47Q10-I/MP

PIC18F47Q43-I/MP

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DSPIC30F2012-20I/ML

PIC18LF46K22T-E/PTVAO

PIC16F887T-E/PTVAO

PIC16F18875T-E/PTVAO

DSPIC33CK256MP508T-E/PTVAO

PIC16F74T-E/PTVAO

DSPIC33EP256GP506T-E/PTVAO

PIC16F18877T-E/PTVAO

DSPIC33EV256GM104T-E/PTVAO

PIC16F1519T-E/PTVAO

DSPIC33CH512MP206T-E/PTVAO

DSPIC33CH256MP506T-E/PTVAO

DSPIC33EP64MC204T-E/PTVAO

DSPIC33CH256MP206T-E/PTVAO

DSPIC33EP32GP504T-E/PTVAO

DSPIC33EP32MC204T-E/PTVAO

DSPIC33CH256MP505T-E/PTVAO

DSPIC33CK128MP206T-E/PTVAO

DSPIC33CK256MP505T-E/PTVAO

ATMEGA329P-20AUR

ATMEGA162V-8AUR

ATXMEGA128D3-AUR

ATMEGA128A-AUR

ATMEGA128L-8AUR

AT42QT2640-AUR

AT42QT1481-AUR

ATMEGA88PA-AURA3

ATMEGA16U4-AUR

ATMEGA3290PA-AUR

ATMEGA168-20AUR

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ATMEGA168V-10AUR

AT90USB646-AUR

AT90USB647-AUR

ATXMEGA256A3-AUR

ATXMEGA64A3-AUR

ATXMEGA128A3-AUR

ATMEGA88PB-AUR

ATMEGA48PB-AUR

PIC16LF15385T-I/PT

PIC16LF15386T-I/PT

ATMEGA128L-8AURA6

ATMEGA128-16AURA0

ATMEGA128-16AUR

ATMEGA88A-AUR

PIC32MX430F064H-I/PT

PIC32MX330F064L-I/PT

PIC32MX430F064L-I/PT

PIC16F1713T-E/MVVAO

PIC32MZ2048ECH064-I/MR

DSPIC33EP64GP504-I/ML

PIC24EP64GP204-I/ML

DSPIC33FJ16GP304-I/ML

DSPIC33FJ32GP204-I/ML

DSPIC33FJ16MC304-I/ML

DSPIC33FJ32MC204-I/ML

PIC24HJ16GP304-I/ML

DSPIC33EP64GP506-I/MR

PIC24EP64GP206-I/MR

PIC24HJ32GP204-I/ML

PIC24HJ256GP206A-I/MR

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CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33FJ16GS404-I/ML

DSPIC33FJ256GP506A-I/MR

PIC32MX170F512H-V/PT

PIC32MX575F256H-80V/PTC23

PIC32MX250F256H-V/PT

PIC32MX550F256H-V/PT

ATSAMD20G14B-AN

ATSAMD20G15B-AN

PIC32MX764F128H-V/PT

ATSAMD20E18A-AN

ATSAMD20E16A-AN

ATSAMD20E17A-AN

ATSAMD20E15A-AN

ATSAMD20E14A-AN

ATSAMD20J14B-AN

ATSAMD20J15B-AN

A3PN250-ZVQG100

A3PN250-ZVQG100I

A3PN060-1VQ100

AGLN125V2-ZVQG100

AGLN125V5-ZVQG100I

AGLN125V5-ZVQG100

A3PN060-VQG100Q129

A3PN060-1VQ100I

A3PN060-1VQG100I

A3PN125-1VQ100I

A3PN125-1VQG100I

A3PN125-2VQ100I

AGLN125V2-ZVQG100I

A3PN060-1VQG100

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A3PN060-2VQ100

A3PN060-2VQG100

93C56CT-E/SN

93C66CT-E/SN

PIC16LF15345T-E/SS

DSPIC33CK64MP102T-E/SSC02

24CSM01T-E/ST

AVR32SD28T-E/SS

AVR32SD20T-E/SS

24CS32T-E/ST

24CS64T-E/ST

PIC16LF1559T-E/SSM10

PIC16LF1554T-E/STM10

PIC16F15354T-E/SS

DSPIC30F2012-30I/ML

PIC18F26Q10-I/STX

USB5742-I/2G

DSPIC30F3010-20I/ML

PIC16LF1825-I/ML

PIC32MX270F512H-50I/MR

PIC32MX550F256H-50I/MR

PIC32MX570F512H-50I/MR

MCP1722-3310H/Q8B

MCP1722-3312H/Q8B

MCP1722-5010H/Q8B

MCP1722-5012H/Q8B

PIC16F15356-I/STX

PIC18F44J10-I/ML

AVR32DA48-I/6LX

PIC18LF24J10-I/ML

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PIC18F24J10-I/ML

PIC32MX150F256H-50I/MR

PIC32MX170F512H-50I/MR

PIC18F67K90-I/MR

PIC32MX250F256H-50I/MRJ21

PIC32MX250F256H-50I/MR

PIC16F1717-I/MP

PIC18F67K22-I/MR

PIC18F67K90-I/MRRSL

PIC18F67K22-I/MRRSL

PIC18F25J10-I/ML

PIC18LF45J10-I/ML

PIC18F45J10-I/ML

LAN7800-I/Y9X

PIC18F43K22-I/MP

PIC24F08KL302-I/ML

PIC24F16KL402-I/ML

AT89LP51ED2-20MU

AT89LP51ID2-20MU

PIC16F15375-I/ML

PIC16F15376-I/ML

PIC16LF15375-I/ML

PIC16LF15376-I/ML

ATMEGA32A-MU

AT89LP51RD2-20MU

PIC16LF15386-I/6LX

PIC16LF15356-I/ML

LAN8720AI-CP-ABC

ATMEGA32-16MU

ATMEGA164PV-10MU

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ATMEGA164P-20MU

PIC16F17144-I/6N

AT89LP51RB2-20MU

ATXMEGA128A4U-MH

AVR64DU28T-I/SS

PIC16LF18324T-I/ST026

PIC12HV615T-I/SN022

PIC12HV615T-I/SN

PIC16F726T-I/SS

DSPIC33CK64MC102T-I/SS

DSPIC33EV32GM002-H/SS

DSPIC33EV32GM102-H/SS

25CS320-H/ST

24LC16BT-M/SN

25LC640AT-M/SN

PIC18F55Q43-I/6LX

PIC18F45Q43-I/MP

PIC18F25Q43-I/STX

ATECC608C-TFLXTLSU-PROTO

PIC18F24K22T-I/ML

DSPIC33FJ128MC706AT-I/MR

24AA32AT-I/MCB27

93C46CT-I/MNY

93C46CT-I/MC

93C56CT-I/MNY

93C66BT-I/MC

93C56BT-I/MC

ATTINY1626-XU

PIC16LF15325-I/ST

ACE15345

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F15345-I/SS

PIC16LF15345-I/SS

PIC16LF1786-I/SS

PIC18F24Q24-I/SS

PIC18F25Q24-I/SS

PIC18F26Q24-I/SS

PIC18F24Q24-I/SO

PIC18F25Q24-I/SO

PIC18F26Q24-I/SO

PIC18F04Q20-I/ST

PIC18F05Q20-I/ST

PIC18F14Q20-I/SS

PIC18F15Q20-I/SS

AVR32EB28-I/SS

AVR32SD20-I/SS

AVR32SD28-I/SS

AT24C64B-10TU-1.8

AT24C64B-10TU-2.7

PIC16F17554-I/SS

PIC16F17555-I/SS

PIC16F17556-I/SS

PIC16F17554-I/SO

PIC16F17555-I/SO

PIC16F17556-I/SO

PIC18F14Q41-I/SS021

PIC16F1717T-E/MVVAO

PIC10F206-I/MC

PIC18LF4682-I/ML

PIC16F628A-I/ML

PIC16LF628A-I/ML

Date: Tuesday, July 22, 2025

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PIC24EP256MC206-I/MR

DSPIC33FJ64GP204-I/ML

PIC32MK1024GPE064-I/MR

PIC32MK1024GPD064-I/MR

PIC32MK1024MCF064-I/MR

PIC24EP256GP204-I/ML

PIC24EP256MC204-I/ML

PIC32MK0512GPE064-I/MR

PIC18LF452T-I/PT

PIC18LF4510T-I/PT

ATTINY817-MBT-VAO

ATSAMDA1E16B-MBTVAO

SYA75603ATWL-TRVAO

SYA75604ATWL-TRVAO

SYA75603BTWL-TRVAO

PIC32MX350F128HT-I/PT

PIC32MX450F256HT-I/PT

PIC32MX450F128HT-I/PT

PIC32MX350F256LT-I/PT

PIC32MX350F128LT-I/PT

ATMEGA164PA-AUR

DSPIC33EP512GM306T-I/PTC01

DSPIC33EV32GM104T-I/PT

DSPIC33EV32GM106T-I/PT

PIC32MX450F256LT-I/PT

PIC32MX450F128LT-I/PT

MCP6002T-I/SN

24LC64FT-I/ST

24FC64FT-I/ST

PIC24FJ16GA004T-I/PT

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DSPIC33FJ64GP206AT-I/PT

PIC24HJ128GP306AT-I/PT

24C02CT-E/ST

MCP3422A6T-E/SN

MCP6L94T-E/ST

MCP4251T-503E/ST

MCP79410-I/ST

MCP79411-I/ST

MCP79412-I/ST

PIC16F15254-I/SO

PIC16F15255-I/SO

MCP79400-I/ST

MCP79401-I/ST

93LC46A-I/SN

93AA46A-I/SN

93AA46B-I/SN

93C46B-I/SN

DSPIC33FJ64MC506AT-I/PTVAO

DSPIC33EP256MU806T-I/PTVAO

PIC18F65K80T-I/PTVAO

PIC18F66K80T-I/PTVAO

PIC18F45K80T-I/PTVAO

PIC18F46K80T-I/PTVAO

DSPIC33FJ256GP506AT-I/PTVAO

PIC18F4431-I/PT

PIC18LF4331-I/PT

AVR32DB32-I/RXB

AVR64DB32-I/RXB

AVR16EA28-I/STX

PIC32MK0128MCA048-I/6MX

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PIC32MK0128MCA032-I/RTB

AVR64DA64-I/MR

AVR64DA32-I/RXB

PIC16F785-I/ML

PIC16HV785-I/ML

PIC16F17176-I/MP

PIC16F18176-I/MP

PIC32CM1216JH01048-I/U5B

DSPIC33EP128GM304-I/ML

DSPIC33EP128GM604-I/ML

DSPIC33EP256GM304-I/ML

DSPIC33EP256GM604-I/ML

DSPIC33EP512GM304-I/ML

DSPIC33EP512GM604-I/ML

93LC66CT-I/MC

93AA66CT-I/MC

93LC66AT-I/MC

93AA66AT-I/MC

24LC64T-I/MC

24AA64T-I/MC

PIC24FJ128GB106T-I/MR

PIC24FJ256GB106T-I/MR

PIC16LF1613T-I/ML

93AA46BT-I/MNY

93LC46CT-I/MNY

93AA46CT-I/MNY

93LC66CT-I/MNY

93AA66BT-I/MNY

DSPIC33EV64GM006-E/PT

DSPIC33EV64GM106-E/PT

Date: Tuesday, July 22, 2025

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PIC16LF18877-I/PT

MTR1202-I/PT

PIC24FJ256GA704-I/PT

DSPIC33EP64MC204-I/PTC02

PIC16F1789-I/PT

DSPIC33EP32GS506-I/PT

DSPIC33EP16GS506-I/PT

DSPIC33EP512GM306-I/PTC01

PIC16F59-I/PT021

PIC18F67K40-I/PT

PIC16LF1946-I/PTC01

PIC24FJ1024GB610-I/PTREL

PIC24FJ128GA704-I/PTC01

PIC18F66K90-I/PTC01

PIC18F87K22-I/PTC02

MCP6489T-E/ST12M

24CS128T-E/ST

PIC18F25Q43T-E/SS

ATTINY1616-XFR

PIC16F15256T-E/SS

MCP3912BA1T-E/SS

MCP3919BA1T-E/SS

MCP3913BA1T-E/SS

PIC12C508AT-04E/SN

PIC16F18045T-E/SS

PIC18F24Q24T-E/SS

PIC18F24Q24T-E/SO

93LC46BT-I/MNY

93AA76CT-I/MC

PIC16LF1904T-I/MV

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PIC16F1947-I/PTC02

PIC16LF1947-I/PTC02

PIC16LF1947-I/PTC03

MTR7519-I/PTC04

MTR7519-I/PT

MTR5117-I/PT

PIC18LF67K40-I/PT

PIC18F47Q43-I/PT

A3P250-1VQ100I

A3P250-1VQG100I

A3P250-2VQ100I

A3P250-2VQG100I

A3P250-VQ100I

M1A3P250-1VQ100I

PIC18F47Q10-I/PTC01

M1A3P250-1VQG100I

M1A3P250-2VQ100I

M1A3P250-2VQG100I

DSPIC33CK512MPT608T-I/PT

DSPIC33CK256MPT608T-I/PT

PIC18LF46K40T-E/PT

DSPIC33CK1024MP406T-E/PT

DSPIC33CK1024MP706T-E/PT

DSPIC33CK512MP406T-E/PT

DSPIC33CK512MP706T-E/PT

DSPIC33CK256MP406T-E/PT

DSPIC33CK256MP706T-E/PT

DSPIC33CK1024MP410T-E/PT

DSPIC33CK1024MP710T-E/PT

DSPIC33CK512MP410T-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F15325-E/JQVAO

PIC18F46Q43-E/MPVAO

ATSAML10E16A-MZVAO

PIC16F18426-E/JQVAO

PIC16F1579-E/GZVAO

PIC16F1782-E/MVVAO

PIC18F27Q43-E/STXVAO

PIC18F25Q43-E/STXVAO

PIC18F26Q43-E/STXVAO

PIC16LF15345-E/6NVAO

PIC18F24K40-E/MLVAO

PIC16F15345-E/GZVAO

PIC16F18345-E/6NVAO

LAN8650B1-E/LMXVAO

LAN8651B1-E/LMXVAO

PIC16F18046-E/MLVAO

PIC16F18026-E/MLVAO

PIC32MX130F256DT-V/ML

PIC32MX230F256DT-V/ML

PIC32MX130F064DT-V/ML

PIC32MX250F128DT-V/ML

PIC32MX230F064DT-V/ML

PIC18F57Q84-E/PT

DSPIC30F3014-20E/PT

DSPIC30F4013-20E/PT

DSPIC33CK512MP305-I/PT

ATSAMD20G18A-AUA2

ATSAMD20G16A-AUA2

DSPIC33CK512MP605-I/PT

DSPIC33CK256MP306-I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33CK256MP606-I/PT

PIC24FJ32GU205-I/PT

PIC24FJ64GP205-I/PT

AT89C51CC01CAT-RLTUM

AT89C51CC01UAT-RLTUM

DSPIC33CK256MP206-I/PT

DSPIC33CK256MP506-I/PT

DSPIC33FJ32GS606-50I/PT

ATSAMD20E15A-AUA2

ATSAMD20E16A-AUA2

ATSAMD20E17A-AUA2

PIC18F87J90-I/PT

ATSAMD20E14A-AUA2

ATSAMD20E18A-AUA2

DSPIC33FJ32GS606-I/PTD23

DSPIC33FJ64GS406-I/PT

DSPIC33FJ64GS606-I/PT

DSPIC33FJ32GS406-I/PT

DSPIC33FJ32GS606-I/PT

DSPIC33FJ128GP804-I/PT

ATSAMD20G17A-AUA2

PIC32MX270F512H-50I/PT023

ATSAMD20G15A-AUA2

ATSAMD20G14A-AUA2

PIC18LF56K42-I/PTC02

PIC24FJ256GA406-I/PT

PIC24FJ128GA406-I/PT

PIC24FJ64GA406-I/PT

AT89C51AC2T-RLTUM

PIC18F57Q43-I/PT

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PIC24HJ32GP304-I/PT

ATSAM4C32CA-AUT

AT89C51RC2T-RLTUL

AT89C51IC2T-RLTUL

PIC16LF19197-I/PTC03

PIC16F19196-I/PT

PIC16F19197-I/PT

PIC16LF19195-I/PT

PIC16LF19196-I/PT

ATSAMD20E15B-AUT

PIC24FJ128GA306T-I/PT

ATF1504AS-10AU100-T

ATMEGA3208-AUR

ATSAMC20E17A-MZVAO

ATSAMD21E17D-MZVAO

PIC18F56Q43-E/6LXVAO

ATSAMC21J17A-MMZVAO

DSPIC33EV128GM002-E/MMVAO

DSPIC33EP64MC202-E/MMVAO

DSPIC33EV64GM006-E/MRVAO

DSPIC33EV256GM006-E/MRVAO

ATXMEGA32A4-AUR

ATXMEGA64D3-AURA4

ATXMEGA64D3-AUR

ATXMEGA64C3-AUR

ATMEGA2560V-8AUR

ATMEGA325P-20AUR

ATMEGA325P-20AURA0

ATMEGA6450V-8AUR

ATMEGA1281-16AUR

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ATMEGA649A-AUR

ATMEGA645A-AUR

ATMEGA645P-AUR

ATMEGA48V-10AUR

ATMEGA48-20AUR

ATMEGA644V-10AUR

PIC16F17176T-I/PT

PIC16F18176T-I/PT

ATMEGA324PV-10AUR

AT90CAN32-16AUR

ATXMEGA384C3-AUR

ATXMEGA32C3-AUR

MCP2140T-I/SO

PIC18F242T-I/SO

PIC16C56AT-04I/SO

PIC16F872T-I/SO

MCP6142T-I/SN

PIC16LF876AT-I/SO

PIC16LF872T-I/SO

PIC16C620AT-04I/SO

PIC16LF72T-I/SO

PIC16C773T-I/SS

PIC16C55AT-20I/SS

PIC16F873T-20I/SO

PIC16LF873T-04I/SO

PIC18LF252T-I/SO

PIC18F252T-I/SO

PIC16C72AT-04I/SO

PIC16F876T-20I/SO

PIC16LF76T-I/SO

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PIC16F76T-I/SO

PIC16LF870T-I/SO

MCP6548T-I/SN

MCP6547T-I/SN

MCP6S21T-I/SN

MCP6S28T-I/SL

PIC16C63AT-04I/SO

PIC16LF873AT-I/SO

PIC16C621AT-04I/SO

PIC16C621AT-20I/SO

PIC16C57CT-04I/SO

PIC16LC622AT-04I/SO

PIC16C622AT-04I/SO

PIC14000T-04I/SO

PIC16LC621AT-04I/SO

PIC16C72AT-04I/SO077

PIC16C621AT-04I/SO050

PIC16C621AT-20I/SO051

PIC18LF1320T-I/SS

PIC16C621AT-20I/SO060

PIC16F76T-I/SO073

MCP2150T-I/SSRVC

MCP2155T-I/SSRVC

PIC16F627T-20I/SS

PIC16C57CT-04I/SS042

PIC16C622AT-04I/SS

PIC16C622AT-20I/SS

MCP2140T-I/SSRVB

PIC32MX534F064LT-V/PT

PIC32MX130F064DT-V/PT

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PIC32MX230F064DT-V/PT

PIC32MX675F256LT-80V/PF

PIC32MX795F512LT-80V/PF

PIC18F24K22-I/MV

PIC18F26K22-I/MLC03

MCP73871-2CCI/ML

PIC18F24K42-I/MV

PIC16F18425-I/JQ

PIC16LF18424-I/JQ

MTCH6301-I/ML

PIC16F18424-I/JQ

PIC16F15354-I/MV

PIC16F18025T-I/ML

ATSAMC20E16A-MUTS2

DSPIC33FJ16GS502T-I/MM

ATMEGA4809-MUR

PIC32MX230F128HT-I/MRJ21

ATSAMD21E18A-MUT

ATSAMD21E18A-MUTA1

ATSAMD21E17A-MUTA1

ATSAMD21E17A-MUT

ATSAMD21G17A-MUT

ATSAMD21G17A-MUTA1

PIC18F26K20T-I/ML

ATSAMD21G18A-MUTA1

ATSAMD21G18A-MUTN01

PIC24FJ128GL406T-I/MR

PIC24FJ256GL406T-I/MR

PIC18F26Q83T-I/5N

PIC18F27Q84T-I/5N

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PIC10F322T-I/MC033

PIC18F27Q83T-I/5N

ATMEGA8L-8AURA5

ATMEGA8-16AUR

ATMEGA8L-8AUR

ATMEGA3250PA-AUR

ATMEGA3290A-AUR

ATMEGA3250A-AUR

DSPIC33CK128MC106-I/MR

AVR64DD28-I/STX

PIC16F15213-I/MF

PIC16F15214-I/MF

PIC18F57Q43-I/6LX

PIC18F56Q43-I/6LX

KSZ8081MNXIA

PIC16F1826-I/ML

PIC16F1826-I/MV

AVR64EA48-I/6LX

PIC18LF2423-I/ML

PIC18F2423-I/ML

DSPIC33CK256MC505-I/M7

DSPIC33CK128MC505-I/M7

DSPIC33CK256MC105-I/M7

PIC16F19176-E/MV

PIC16LF19175-E/MV

PIC24EP128GP202T-I/MM038

PIC32MX320F032HT-40I/MR

DSPIC33EP512MC206T-I/MR

PIC32MX320F128HT-80I/MR

PIC18F26K22T-I/SO029

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PIC12LF1571T-I/SN035

PIC32MX270F512HT-50I/MR

PIC18F24J10T-I/ML

25LC160C-E/ST

25LC080C-E/ST

25AA160D-E/ST

25LC160D-E/ST

PIC18F1320-E/SS

PIC12F617-E/SN034

DSPIC33CH512MP205T-E/PT

DSPIC33CH256MP505T-E/PT

DSPIC33CH256MP205T-E/PT

PIC32MZ1024EFE100T-E/PT

PIC32MZ1024EFF100T-E/PT

PIC32MZ1024EFG100T-E/PT

PIC32MZ1024EFH100T-E/PT

DSPIC33EP512GM706-I/MRC02

DSPIC33EP128GM306-I/MR

DSPIC33EP128GM706-I/MR

DSPIC33EP256GM306-I/MR

DSPIC33EP256GM706-I/MR

DSPIC33EP512GM306-I/MR

DSPIC33EP512GM706-I/MR

LE89156PQC

PIC16F18026-I/ML

PIC16F18046-I/ML

LE88266TQC

LE88286TQC

PIC24FV16KM202-I/ML

PIC24FV08KM202-I/ML

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PIC24FV16KM102-I/ML

KSZ9031RNXIC

AVR64DU32-I/RXB

AVR64DU28-I/STX

PIC32CM5164JH01048-I/U5B

PIC32CM2532JH00048-I/U5B

PIC24F16KM202-I/ML

PIC24F08KM202-I/ML

LE87270NQC

PIC32CM5164JH00048-I/U5B

PIC32CM2532JH01048-I/U5B

BCM6304KMLG

PIC16LF18877-I/MVC04

LE87285NQC

LE87557NQC

LE87100NQC

ATSHA204A-MAHMD-B

LE87282MQC

BCM65060IMLG

RE46C730IV28

BCM6305KMLG

BCM65050IMLG

DSPIC33EP128MC204T-I/PT

PIC24EP128GP204T-I/PT

DSPIC33EP128MC206T-I/PT

DSPIC33EP128MC506T-I/PT

PIC16LF1847-I/STX

AT86RF233-ZU

ATSAMD20E14B-MU

ATSAMD20E16B-MU

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PIC16LF18425-I/JQ

PIC18F67K40-I/MR

PIC16LF18344-I/GZ

PIC24F16KA102-I/ML

PIC18F65K40-I/MR

DSPIC33FJ64MC202-E/MM

DSPIC33FJ64MC802-E/MM

DSPIC33FJ06GS102A-E/MM

DSPIC33FJ09GS302-E/MM

PIC32MZ2048EFG064-E/MR

PIC24EP256GP204-E/ML

PIC24EP256MC204-E/ML

PIC24HJ32GP302-E/MM

PIC18F25K40T-E/MLVAO

PIC18F45K40T-E/MVVAO

ATTINY461-15MZ

PIC18F26Q10T-E/MLVAO

PIC16F18326T-E/7NVAO

AVR32DA32T-E/RXBVAO

MCP16502TAA-E/S8BVAO

MCP16502TAB-E/S8BVAO

MCP16502TAC-E/S8BVAO

MCP16502TAD-E/S8BVAO

MCP16502TAE-E/S8BVAO

ATA6624C-PGQW-1

ATA6630-GLQW

PIC18F25Q10T-E/MLVAO

PIC18F24Q10T-E/MLVAO

ATA6562-GBQW1

ATA6563-GBQW1

Date: Tuesday, July 22, 2025

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ATA6560-GBQW

PIC16F1828T-E/GZVAO

25LC160DT-E/MNY16KVAO

25AA080CT-E/MNY16KVAO

ATA6614Q-PLQW-1

MCP1703AT-2502E/MCVAO

MCP1703AT-5002E/MCVAO

MCP1725T-1202E/MCVAO

AVR32DA48T-E/6LXVAO

ATA6565-GCQW1

ATTINY1617-MZT-VAO

PIC16F15324T-E/7NVAO

PIC16F18875T-E/MVVAO

PIC16LF18345T-E/GZVAO

MCP6002T-E/MCVAO

ATTINY261-15MZ

DSPIC33FJ128GP804T-E/PTVAO

PIC16F1784T-E/PTVAO

PIC16F1787T-E/PTVAO

PIC16F1719T-E/PTVAO

PIC18F46K22T-E/PTVAO

PIC18F66K90T-E/PTVAO

PIC16LF1519T-E/PTVAO

PIC16F1526T-E/PTVAO

PIC16F727T-E/PTVAO

PIC18F45K22T-E/PTVAO

PIC16F1937T-E/PTVAO

DSPIC33FJ128GP706AT-E/PTVAO

DSPIC33EP64GS506T-E/PTVAO

DSPIC33EP32GS506T-E/PTVAO

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PIC18F45K80T-E/PTVAO

PIC18F46K80T-E/PTVAO

PIC32MZ1024EFH100T-E/PTVAO

PIC16LF1939T-I/MV

PIC16LF1939T-I/ML

PIC16F1938T-I/ML

PIC24FJ32GA002T-I/ML

PIC24FJ16GA002T-I/MLC06

PIC24FJ48GA002T-I/ML

PIC16F1718T-I/ML

MCP2150-I/SSRVC

PIC18F26K20-I/SO

PIC16F723-I/SS

PIC16F723-I/SO

PIC18LF2585-I/SO

PIC18LF2553-I/SO

PIC18F2553-I/SO

MCP607-I/SN

MCP6022-I/ST

24LC01BH-I/SN

24AA01H-I/SN

PIC16LF1516-I/SO

24AA04H-I/SN

93LC76A-I/ST

93AA76A-I/ST

93LC76B-I/ST

A010201-I/SS

PIC12C508A-04I/SN

PIC18F24K50-I/SO

PIC18F25K50-I/SO

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PIC16F1512-I/SS

PIC16HV616-I/ST

PIC18LF26J53-I/SO

PIC24FJ128GA202-I/SS

24LC512-I/SN

PIC16F1619-I/SS

PIC16F1618-I/SS

PIC16LF1713-I/SO

PIC16LF1716-I/SO

PIC16LF1933-I/SS

PIC16LF726-I/SS

PIC24EP128GP206T-I/PT

PIC16F1527T-I/PT

PIC16F1526T-I/PT

PIC18LF45K22T-I/PT

ATSAMC21J18A-AUT

ATSAMC20E16A-AUTS2

ATSAMC21E18A-AUT64

PIC16F15274T-I/PT

PIC16F15275T-I/PT

PIC16F15276T-I/PT

PIC32MZ2048EFG100T-I/PF21

PIC24FJ256GL410T-I/PT

PIC24FJ512GL410T-I/PT

PIC24FJ128GU410T-I/PT

PIC24FJ256GU410T-I/PT

MCP79411T-I/SN

MCP79412T-I/SN

AVR128DB28T-I/SO

AVR64DB28T-I/SO

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PIC18F26Q43T-I/SS

PIC18F26Q43T-I/SO

AVR32DB28T-I/SO

MCP79401T-I/SN

MCP79402T-I/SN

PIC24FJ256GA702T-I/SS

PIC24FJ128GA702T-I/SS

PIC24FJ64GA702T-I/SS

PIC16F18046T-I/SS

PIC16LF720T-I/SS

PIC24FJ256GA610T-I/PT

PIC24FJ512GA610T-I/PT

DSPIC33FJ16GS404T-50I/PT

DSPIC33FJ16GS504T-50I/PT

PIC32MX130F064DT-I/PTF22

PIC32MX570F512LT-I/PF

PIC24HJ64GP206T-I/PT

DSPIC33FJ64GP204T-E/ML

DSPIC33FJ64GP804T-E/ML

MCP6042-E/SN

PIC16LF18856-E/SS

PIC12F617-E/SN031

PIC16F1703-E/ST

25AA128-E/ST

MCP7940N-E/SN

25LC040A-E/ST

PIC12F509-E/SN

25LC010A-E/ST

PIC24HJ128GP506AT-E/PT

DSPIC33FJ128MC706AT-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33EP64GS506T-E/PTC01

DSPIC33EP64GS506T-E/PT

ATSAMD20E16A-ANT

ATSAMD20E17A-ANT

ATSAML21E15B-ANT

ATSAML21E16B-ANT

ATSAML21E17B-ANT

ATSAMD20E15A-ANT

ATSAMD20E14A-ANT

ATSAMD20E18A-ANT

ATSAML21E18B-ANT

ATSAMDA1E16B-ABT

ATSAMDA1E15B-ABT

ATSAMDA1E14B-ABT

ATSAMC20J18A-ANT

ATSAMC20G15A-ANT

ATSAMDA1G16B-ABT

ATSAMDA1G15B-ABT

ATSAMDA1G14B-ABT

ATSAMC20G16A-ANT

ATSAMC20G17A-ANT

ATSAMC20G18A-ANT

RE341-V/PTAAA

PIC18F4585-H/PT

PIC18F4680-H/PT

DSPIC33FJ128GP706A-H/PT

PIC24HJ256GP206A-H/PT

PIC24HJ16GP304-H/PT

DSPIC33FJ16GS504-H/PT

PIC24HJ128GP504-H/PT

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PIC16C64A-20I/L

PIC17C756A-16I/L

PIC18LF4520T-I/PT

PIC18F4431T-I/PT

PIC18F6520T-I/PT

PIC18F97J60T-I/PT

PIC18F87J60T-I/PT

PIC18LF4523T-I/PT

PIC18LF6622T-I/PT

PIC18LF6527T-I/PT

PIC18F6723T-I/PT

PIC18F86J60T-I/PT

PIC18LF8722T-I/PT

PIC18F8722T-I/PT

PIC18LF6520T-I/PT

PIC18F6490T-I/PT

PIC16LF877AT-I/PT

PIC16F877AT-I/PT

PIC18F4520T-I/PT

PIC18F4523T-I/PT

PIC18F66J90T-I/PT

PIC18F8627T-I/PT

PIC18F87J11T-I/PT

PIC18F8628T-I/PT

PIC18F6621T-I/PT

PIC18F458T-I/PT

PIC16F1938-I/SS

PIC16LF1615-I/ST

PIC16F1718-I/SS

PIC16F1705-I/ST

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PIC16F1704-I/ST

PIC16F1708-I/SS

PIC16F1788-I/SS

ATTINY827-MUR

PIC18F57Q83T-I/6MX

PIC18F57Q84T-I/6MX

ATSAMD20E18A-MUT

ATSAMD20E18A-MUTA2

ATSAMD20E18A-MUTA8

ATSAMD20E18A-MUTA9

ATSAMD20E18A-MUTB0

ATSAMD20E18A-MUTB1

ATSAMD20E18A-MUTB2

ATSAMD20E18A-MUTB3

ATSAMD20E18A-MUTN01

ATSAMD20E18A-MUTN02

PIC16F18856T-I/MLC01

PIC16F18146-E/SS

AVR32DB28-E/SO

PIC24FJ256GA702-E/SS

PIC24FJ128GA702-E/SS

PIC24FJ64GA702-E/SS

AVR64DA28-E/SS

AVR64DA28-E/SO

PIC16F18054-E/SS

PIC16F18055-E/SS

PIC16F18054-E/SO

PIC16F18055-E/SO

MCP6009-E/ST

MCP6479-E/ST

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AVR64DD28-E/SO

24AA16-E/ST

PIC16F18056-E/SS

PIC16F18056-E/SO

PIC18F25K50-E/SS

PIC18F24K50-E/SO

PIC18F25K50-E/SO

PIC18LF25K50-E/SS

PIC16F18046-E/SS

PIC16LF15356-E/SS

25LC320AX-E/ST

PIC16F15345-E/SS

25CS320-E/ST

DSPIC33CK512MP710T-E/PT

DSPIC33CK256MP410T-E/PT

24LC04B/ST

24LC024/SN

24LC025/SN

24C02C/SN

24C01C/SN

93LC66A/SN

93LC66B/SN

93LC56A/SN

93LC56B/SN

34VL02/SN

24VL014H/SN

24VL024H/SN

24VL024/SN

24VL025/SN

24VL014/SN

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24C00/SN

24LC00/SN

24AA00/SN

24LCS52/SN

24LC01B/ST

24LC16B/ST

93LC66/SN

93LC56/SN

93LC46/SN

93LC46B/SN

25LC320/SN

25C320/SN

25LC040/SN

25C040/SN

24LCS21A/SN

24LC21A/SN

24LC21/SN

HCS300/SN042

93LC46A/SN

ATMEGA88-15MT2

ATMEGA168-15MD

ATTINY261-15MD

ATTINY167-A15MD

ATTINY87-A15MD-VAO

PIC16F1615T-H/MLVAO

DSPIC33CK128MC105T-H/M7VAO

DSPIC33CK512MP606T-H/MRVAO

DSPIC33CK256MP606T-H/MRVAO

MCP2557FDT-H/MFVAO

DSPIC33AK64MC102T-H/M7VAO

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ATA5780N-WNQW

ATA5830N-WNQW

ATMEGA168-15MT1

ATA5835-GHQW-VAO

MCP1725-3302E/MC

MCP1725-5002E/MC

MCP1725-ADJE/MC

MCP1725-2502E/MC

MCP1725-3002E/MC

TC1302B-EIVMF

DSPIC33CK32MC102T-H/SSVAO

DSPIC33EV32GM002T-H/SSVAO

MCP251863T-H/SSVAO

25CS320T-H/ST36KVAO

LX34070T-H/STVAO

LX3302AQPW-TR

LX34050QPW-TR-VAO

LX3302AQPW-TR-GM

LX34311T-H/STVAO

LX34070AT-H/STVAO

LE87100NQCT

LE87282MQCT

BCM65060IMLGT

PIC32CM5164JH01064T-I/5LX

RE46C730IV28T

PIC32CM5164JH01048T-I/U5B

PIC32CM2532JH00048T-I/U5B

PIC32CM5164JH00048T-I/U5B

PIC32CM2532JH01048T-I/U5B

BCM6305KMLGT

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BCM65050IMLGT

PIC16LF1938T-I/MVPAX

PIC16F18856T-I/MV

PIC16LF18856T-I/MV

PIC16F18854T-I/MV

PIC18F24K42T-I/MV

PIC18F25K42T-I/MV

PIC16F15354T-I/MV

PIC18LF24K42T-I/MV

PIC18LF25K42T-I/MV

PIC18F26K40T-I/MV

PIC18LF26K40T-I/MV

PIC16F1516-E/ML

PIC16F1518-E/ML

PIC16LF18856-E/STX

PIC18F26K40-E/ML

PIC16F18856-E/MV

ATMEGA2564RFR2-ZF

ATSAML11E16A-MFKPH

ATSAML11E15A-MFKPH

ATMEGA1284RFR2-ZF

ATMEGA644RFR2-ZF

25LC080D-E/MNY

25LC080C-E/MNY

PIC16F1769-E/ML

25LC160C-E/MNY

PIC16F1768-E/ML

25LC160D-E/MNY

PIC16F18856-E/STX

PIC16LF18876-E/MV

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PIC16F18854-E/ML

PIC24FJ1024GA606-E/MR

PIC24FJ128GA606-E/MR

MCP47FVB28-E/MQ

MCP47FVB04-E/MQ

MCP47FVB14-E/MQ

MCP47FVB24-E/MQ

PIC24FJ512GB606-E/MR

PIC24FJ128GB606-E/MR

PIC24FJ256GB606-E/MR

PIC18F56Q43-E/PT

DSPIC33EP128GS704-E/PT

DSPIC33EP128GS804-E/PT

DSPIC33EP64GS804-E/PT

DSPIC33CK256MC505-E/PT

DSPIC33CK256MPT608-E/PT

AT89C51IC2T-RLRUM

PIC32MZ1024EFE064T-I/PT

PIC32MZ1024EFF064T-I/PTF21

PIC32MZ1024EFF064T-I/PT

PIC32MZ1024EFG064T-I/PT

PIC32MZ1024EFG064T-I/PTN22

AT89C51IC2T-RLRUL

PIC32MZ2048EFM064T-I/PT

PIC16LF19197T-I/PTC04

PIC16LF19197T-I/PTC05

PIC24FJ256GA410T-I/PT

PIC24FJ64GA204T-I/PT

PIC16LF1947T-I/PTC01

MCP4541T-503E/MF

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MCP4551T-502E/MF

MCP4531T-104E/MF

MCP4531T-503E/MF

MCP4541T-502E/MF

MCP4561T-104E/MF

MCP4561T-503E/MF

MCP4531T-502E/MF

MCP4531T-103E/MF

MCP4561T-502E/MF

MCP4561T-103E/MF

MCP4551T-103E/MF

PIC16F1787T-E/ML021

LX34050QPW-VAO

PIC16F616-H/STVAO

DSPIC33EV256GM102-H/SSVAO

DSPIC33CK256MP505-E/PTC03

DSPIC33CK32MP205-E/PTC04

PIC18F56Q83-E/PT

PIC18F56Q84-E/PT

AVR32DA48-E/PT

ATA5787-GHqw-VAO

ATA5830-WNqw

93C46B/SN

HCS301/SN032

DSPIC33EP64MC202T-H/SSVAO

25LC640AT-H/ST16KVAO

PIC16F1825T-H/STVAO

PIC16F1503T-H/STVAO

PIC16F1615T-H/STVAO

PIC16F616T-H/STVAO

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PIC16F1619T-H/SSVAO

PIC16F1614T-H/STVAO

DSPIC33EV128GM102T-H/SSVAO

DSPIC33CH512MP505-I/PT

DSPIC33EP128GS706-I/PT

DSPIC33EP128GS806-I/PT

DSPIC33EP128GS706-I/PTC01

DSPIC33EP64GS806-I/PT

DSPIC33CH256MP205-I/PT

PIC32MK0256GPG064-I/PT

PIC18F46J50-I/PTREL

PIC18F8628-I/PT

PIC18F458-I/PT

PIC16F505-E/MG

PIC10F206-E/MC

MCP4262-503E/MF

MCP4252-502E/MF

PIC18F66K80T-I/PT

PIC24FJ128GA106T-I/PT041

PIC18LF6722T-I/PT

PIC18F6722T-I/PT

PIC18LF6627T-I/PT

PIC18F6627T-I/PT

DSPIC33EP256MU806T-I/PT025

PIC24FJ512GB606T-I/PTC03

PIC18F6585T-I/PT

DSPIC33EV64GM106T-I/PT

HV2701TQ-G-M931

HV2705TQ-G-M931

PIC32MZ1024ECG064T-I/MR

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PIC32MX340F128HT-80I/MR

PIC32MZ0512EFE064T-I/MR

DSPIC33EP512GP806T-I/MR

PIC32MZ0512EFF064T-I/MR

PIC24HJ16GP304T-I/ML

ATSAMD20G17A-MUT

ATSAMD20G16A-MUT

ATSAMD20G15A-MUT

ATSAMD20G14A-MUT

PIC32MX775F512HT-80I/MR

PIC32MZ2048ECH064T-I/MR

PIC32MZ2048ECM064T-I/MR

PIC24HJ32GP204T-I/ML

DSPIC33FJ16GP304T-I/ML

DSPIC33FJ32GP204T-I/ML

DSPIC33FJ16MC304T-I/ML

PIC32MZ1024EFK064T-I/MR

PIC32MZ1024EFM064T-I/MR

PIC18F67J10-I/PTC03

PIC18F8723-I/PT

PIC18LF8723-I/PT

PIC18F67J10-I/PT

PIC18F66J15-I/PT

PIC10LF320-I/MC

MCP4231T-502E/ST

MCP4251T-103E/ST

24LC014HT-E/SN

24LC014HT-E/ST

MCP4651T-103E/ST

MCP4651T-104E/ST

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MCP4251T-104E/ST

MCP4651T-503E/ST

PIC16F870T-E/SS

MCP4651T-502E/ST

MCP4631T-502E/ST

MCP4631T-103E/ST

MCP4631T-104E/ST

MCP4631T-503E/ST

PIC32MZ2048EFG064T-I/MRL21

DSPIC33EP512GP502T-I/MM

PIC32MX340F256HT-80I/MR

ATTINY817-MB-VAO

SYA75603ATWLVAO

SYA75604ATWLVAO

DSPIC33CK64MP505-E/PTVAO

DSPIC33EV32GM104-E/PTVAO

PIC18LF45K22-E/PTVAO

DSPIC33CK1024MP708-E/PTVAO

PIC16F1527-E/PTVAO-BW

DSPIC33CH512MP508-E/PTVAO

DSPIC33CH512MP208-E/PTVAO

DSPIC33CH256MP508-E/PTVAO

DSPIC33CH256MP208-E/PTVAO

ATMEGA4809-AF-VAO

DSPIC33EP128GS804-E/PTVAO

DSPIC33EP64GS804-E/PTVAO

ATSAMD21E16B-AZVAO

ATSAMD21G16B-AZVAO

DSPIC33CK512MP605-E/PTVAO

ATSAMD21E18A-AZ510

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ATSAMD21E18A-AZVAO

ATSAMD21J18A-AZ510

ATSAMD21G18A-AZ510

DSPIC33CK256MP206-E/PTVAO

DSPIC33CK256MP506-E/PTVAO

DSPIC33CK128MP506-E/PTVAO

DSPIC33CK64MP206-E/PTVAO

DSPIC33CK64MP506-E/PTVAO

DSPIC33EP64GS504-E/PTVAO

93C86C-I/SN

93LC86A-I/SN

93AA86A-I/SN

93LC86B-I/SN

24LC08BT-I/MNY

PIC18F66K22T-I/MR

MCP73833T-HAI/MF

PIC18LF24J11T-I/ML

ENC424J600T-I/ML

PIC16LF1503T-I/MG

PIC12LF1501T-I/MC

PIC16F1513T-I/MV

PIC24FJ32GA004T-I/ML

PIC18F67K90T-I/PT

PIC18F67K22T-I/PT

PIC18F67K22T-I/PTRSL

ATSAMD21E15B-AZT

PIC24EP256GP206T-E/PTA3

TC7107AIKW713

TC7106IKW713

TC7106AIKW713

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TC7107IKW713

TC7107IPT713

TC7106IPT713

TC7106AIP713

PIC18F67J60T-I/PT

DSPIC33CK32MC105T-I/PT

DSPIC33FJ128MC506AT-I/PT

PIC32MZ1024EFH064T-I/PTH21

PIC24HJ128GP506AT-I/PT

AT89C51ED2T-RLRUMA0

PIC32MZ1024EFH064T-I/PT

AT89C51RC2T-RLRUL

AT89C51ED2T-RLRUM

AT89C51RD2T-RLRUM

AT89C51ID2T-RLRUM

PIC32MZ0512EFE064T-I/PTA21

PIC32MZ0512EFE064T-I/PTA22

PIC32MZ1024EFK064T-I/PT

PIC32MZ1024EFM064T-I/PT

PIC32MX350F256HT-I/PT021

PIC32MZ2048EFM100T-I/PTN21

PIC32MZ2048EFM100T-I/PT

PIC24FJ128GA106T-I/PT

PIC24FJ128GA106T-I/PTC13

PIC24FJ256GA106T-I/PT

ATMEGA168PA-AUR

PIC32MZ1024EFH100T-I/PT

PIC32MZ1024EFK100T-I/PT

ATMEGA324PB-AN

ATMEGA128A-AN

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AT42QT1481-AN

ATMEGA88PA-AN

ATMEGA164PA-AN

ATMEGA325A-AN

ATMEGA165P-16AN

ATMEGA328PB-AN

ATMEGA32A-AN

ATMEGA168PA-AN

ATMEGA48PA-AN

ATMEGA324PA-AN

ATMEGA169PA-AN

ATXMEGA192A3U-AN

ATXMEGA256A3U-AN

ATXMEGA32D4-AN

ATXMEGA32C3-AN

ATXMEGA32D3-AN

ATMEGA64A-AN

AVR128DA64S-E/PT

ATSAMD20J16B-OAZ

ATSAMD20G16B-OAZ

ATSAMD20E16B-OAZ

ATSAMD21E17D-OAZ

PIC32CM6408JH00048-E/Y8X

PIC32CM2532LE00064-E/PT

PIC32CM2532LS00064-E/PT

DSPIC33FJ128MC804-E/PT

DSPIC30F4011-20E/PT

DSPIC30F2023-20E/PT

PIC32CM2532LE00048-E/Y8X

PIC18F57Q83-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

USB5734T/MR

USB5734T/MRD01

AVR16EB28-E/STX

PIC18F25Q43-E/STX

UCS4002-E/6N

AVR16EA32-E/RXB

DSPIC33EDV64MC205-E/M7

PIC18F55Q43-E/6LX

PIC18F45Q43-E/MP

24LC256-I/SNREL

PIC18F2480-I/SO

PIC16LF76-I/SS

PIC16F76-I/SS

PIC16LF873A-I/SS

PIC16LF722-I/SO

PIC16LC62B-04I/SS

PIC16C63A-20I/SS

PIC16LC63A-04I/SS

ENC28J60-I/SOC02

PIC18F2680-I/SO

PIC18LF2320-I/SO

PIC18F2320-I/SO

PIC18LF2220-I/SO

PIC18F2220-I/SO

PIC32MX254F128DT-V/PT

ATSAMC21G16A-AZT

ATSAMC21G17A-AZT

ATSAMC21G18A-AZT

ATSAMC20G18A-AZT

ATSAMC20G17A-AZT

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ATSAMC20G16A-AZT

ATSAMC20G15A-AZT

AVR32DD32T-E/PT

AVR16DD32T-E/PT

AVR16EA32T-E/PT

PIC12F1822-E/SNC07

DSPIC33CK64MC102-E/SS

PIC16F15256-E/SS

DSPIC33CK32MC102-E/SS

PIC18F26K20-E/SS

PIC18F26K20-E/SSC05

PIC18F25K20-E/SS

PIC18F25K20-E/SSC13

PIC18F25K20-E/SSC14

PIC18F24K20-E/SS

PIC18F26Q84-E/SO

DSPIC30F4012-20E/SO

DSPIC33FJ09GS302-I/SO

DSPIC33FJ32GP102-I/SS

DSPIC33FJ32MC102-I/SS

PIC24HJ64GP202-I/SO

PIC16F15214T-E/MFVAO

TA010-MAYCZT-VAO

ATMEGA4808-MFR-VAO

24LC128T-E/MNY16KVAO

MCP2562T-E/MFVAO

MCP2562FDT-E/MFVAO

MCP1726T-ADJE/MFVAO

24AA128T-E/MNY16KVAO

PIC16F914-I/PT

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PIC16F1939-I/PT

DSPIC33CK64MC105T-H/PTVAO

DSPIC33CK256MC505T-H/PTVAO

DSPIC33CK512MP606T-H/PTVAO

DSPIC33CK256MP606T-H/PTVAO

DSPIC33CK512MP608T-H/PTVAO

DSPIC33AK64MC105T-H/PTVAO

DSPIC33AK128MC105T-H/PTVAO

ATMXT225T-ABR

ATMXT641T-ABR

ATMXT641T-ABR074

ATMXT449T-ABR

ATMXT641TD-ABR

ATMXT449T-ABR074

ATMXT449TD-ABR

ATMXT641TD-ABRVA2

PIC32CM6408JH00032-E/T5X

PIC32CM6408JH00064-E/V2X

24AA08HT-I/MNY

24LC02BHT-I/MNY

AVR64DB64-I/PT

PIC18F67K22-I/PT036

AVR16DU32-I/PT

AVR32DU32-I/PT

ATSAMC21N18A-AUGR

KSZ8041FTLI

AVR16EB32-I/PT

PIC18F45Q43-I/PT

PIC18F55Q43-I/PT

AVR32EA32-I/PT

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AVR32EA48-I/PT

PIC32CM5164LE00048-I/Y8X

PIC32CM5164LE00064-I/PT

PIC32CM5164LE00100-I/PF

PIC32MX370F512H-I/PT

PIC32MX470F512H-I/PT

PIC32CM5164LS00048-I/Y8X

PIC32CM5164LS00064-I/PT

PIC32CM5164LS00100-I/PF

PIC32CM2532JH00032-I/PT

PIC32CM2532JH01032-I/PT

PIC16F627AT-I/ML

PIC16F884T-I/ML

PIC16F873AT-I/ML

PIC16F688T-I/ML

PIC16F882T-I/ML

MCP23016T-I/ML

PIC16F72T-I/ML

PIC18LF2420T-I/ML

ATSAMC21G16A-ANT

PIC32CZ2051CA70100T-V/E5X

MCP73838T-NVI/MF

MCP73838T-FCI/MF

PIC16LF819T-I/ML

PIC16LF818T-I/ML

PIC12F683T-I/MD

PIC16LF876AT-I/ML

MCP73831T-2ATI/MC

MCP73831T-2DCI/MC

MCP73831T-3ACI/MC

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MCP73831T-4ADI/MC

MCP73831T-5ACI/MC

PIC18LF13K50T-I/MQ

PIC16F505T-I/MG

PIC18F2580T-I/ML

24LC32A-I/SN

24AA32A-I/SN

PIC18LF26K22-I/SS

PIC16F1459-I/SS

PIC18LF2455-I/SO

PIC16F882-I/SS

PIC18F2458-I/SO

DSPIC33EP512GM706-E/MR

PIC18F8627T-I/PT027

PIC18LF4480T-I/PT

PIC18F67J10T-I/PT

PIC18F66J15T-I/PT

PIC18F8723T-I/PT

PIC18F448T-I/PT

PIC18F67J90T-I/PT

PIC18F65J15T-I/PT

PIC18F87J50T-I/PT

PIC18LF4680T-I/PT

PIC18F4580T-I/PT

PIC18F67J50T-I/PT

PIC18LF4320T-I/PT

PIC18F66J10T-I/PT

PIC16C774T-I/PT

PIC18F4480T-I/PT

PIC18F45J11T-I/PT

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PIC18F47J53T-I/PT

PIC18F46J53T-I/PT

DSPIC33CK512MP408-H/PT

DSPIC33CK512MP708-H/PT

DSPIC33CK256MP408-H/PT

MCP6C02T-050H/Q8B

MCP6C02T-100H/Q8B

DSPIC33FJ32MC202T-H/MM

MCP2542WFDT-H/MF

MCP2544WFDT-H/MF

PIC32MZ0512EFF064T-E/MR

PIC32MZ0512EFK064T-E/MR

MCP23008T-E/ML

PIC32MZ1024EFE064T-E/MR

PIC32MZ1024EFF064T-E/MR

PIC16LF1613T-E/ML

PIC32MK1024MCF100-I/PT

PIC32MK0512GPE100-I/PT

AT32UC3A1256-AUT

PIC32MX534F064H-I/PT

ATTINY48-AU

DSPIC33CH128MP206T-I/PT

ATSAMD20J18A-AUT

ATSAMD20J15A-AUT

ATSAMD20J16B-AUT

ATSAMD20J14B-AUT

ATSAMD20J15B-AUT

ATSAMD20J16A-AUT

ATSAMD20J17A-AUT

ATSAMD20J14A-AUT

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ATSAMD20J18A-AUTA2

ATSAMD20J17A-AUTA2

DSPIC33CH64MP505T-I/PT

DSPIC33CH128MP505T-I/PT

DSPIC33CH64MP205T-I/PT

DSPIC33CH128MP205T-I/PT

ATSAMD20J15A-AUTA2

AT89C51RC-24JU

AT89C55WD-24JU

SY100E310LJY

AT89LP51RD2-20JU

PIC12HV615T-E/SN043

PIC12HV615T-E/SN044

PIC12HV615T-E/SN

DSPIC33CK64MC102T-E/SS

DSPIC33CK32MC102T-E/SS

PIC18F25K20T-E/SSC13

PIC18F24K20T-E/SS

PIC18F26Q84T-E/SS

DSPIC33AK128MC102T-E/SS

AVR32DA28T-E/SS

DSPIC33AK64MC102T-E/SS

DSPIC33AK32MC102T-E/SS

PIC12F1840T-E/SN

MCP3426A7T-E/MC

MCP4821T-E/MC

MCP73871T-2AAI/ML

MCP73871T-2CAI/ML

MCP73871T-2CCI/ML

AVR64DA48-E/PTVAO

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PIC18F46K40-E/PTVAO

ATSAMC21N18A-AZ510

ATSAMC20N17A-AZVAO

ATSAMC21N18A-AZVAO

ATSAMC21N17A-AZVAO

PIC16F15386-E/PTVAO

PIC16F15385-E/PTVAO

PIC16LF15386-E/PTVAO

PIC16F884-E/PTVAO

PIC16F19176-E/PTVAO

DSPIC33CK128MC505-E/PTVAO

DSPIC30F5011-20E/PTVAO

DSPIC33CK1024MP706-E/PTVAO

DSPIC33EP256MU810-E/PTVAO

PIC18F47Q84-E/PTVAO

DSPIC33CK128MC105-E/PTVAO

PIC24FJ256GA704-E/PTVAO

DSPIC33CK256MC506-E/PTVAO

PIC18F46Q84-E/PTVAO

PIC32MK0256MCJ048-E/Y8XVAO

ATSAMC21G15A-AZVAO

DSPIC33CK256MP506-E/PTVAO-VW

PIC18F46Q43-E/PTVAO

AVR128DA48S-E/PTVAO

PIC32CM2532JH01032-E/PTVAO

PIC18F27Q43T-I/SO

25AA640T-I/SN

25AA320T-I/SN

25C320T-I/SN

PIC16F18324T-I/ST

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PIC24F16KA102T-I/SSC01

PIC16F690T-I/SS054

25LC040T-I/SN

25AA040T-I/SN

25C040T-I/SN

PIC18F27Q43T-I/SS

25LC320T-I/SN

PIC18F2523T-I/SO

HSA2-040SIA/A2S20ATR

HSA2-040SCA/A2324TR

ATTINY1624-XUR

PIC24FV16KM202-E/ML

PIC24F16KM202-E/ML

ATMEGA1609-MF

DSPIC33EP128GM706-E/MR

DSPIC33EP256GM706-E/MR

MCP47CMD22-E/MG

MCP48CMD12-E/MG

PIC18F26Q10-E/STX

MCP48CMD21-E/MG

AVR32DA32-E/RXB

ATXMEGA32D3-AUR

ATXMEGA64D3-AURA6

AT89S52-24AUR

AT89LS52-16AUR

ATMEGA168PB-AUR

ATMEGA169PV-8AUR

ATMEGA169P-16AUR

ATMEGA169PV-8AURA3

ATMEGA128L-8AURA3

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ATMEGA128-16AURA3

ATMEGA16L-8AURA5

ATMEGA16-16AURA5

ATMEGA165PV-8AUR

ATMEGA3250PV-10AUR

ATMEGA325PV-10AUR

ATMEGA3290PV-10AUA0

ATTINY88-AUR

AT42QT1110-AUR

PIC16F18425T-E/JQVAO

ATSAMD21G17D-MZTVAO

ATA6670-FFQW-1

MCP9804T-E/MCVAO

ATTINY88-15MZ

MCP4921T-E/MCVAO

DSPIC33EV256GM002-I/MM

PIC16F631-I/ML

PIC24FJ32GA004-I/ML

PIC24FJ64GA004-I/ML

PIC18LF46K22-I/MV

PIC18F26K22-I/ML

PIC18LF44K22-I/MV

PIC24FJ64GA102-I/ML

PIC18LF43K22-I/MV

PIC24FJ32GA104-I/ML

DSPIC33EV64GM006-I/MR

PIC16F1512-I/MV

PIC24FJ64GA004T-I/ML

PIC24FJ32GA004T-I/MLC12

PIC24FJ64GA104T-I/ML

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PIC24EP512MC206-I/MR

PIC32MX664F064H-I/MR

PIC32MX764F128H-I/MR

PIC32MX534F064H-I/MR

PIC32MX564F064H-I/MR

PIC32MX664F128H-I/MR

DSPIC33FJ64GS606-I/MR

DSPIC33FJ32GS406-I/MR

DSPIC33FJ32GS606-I/MR

PIC24HJ64GP204-I/ML

PIC24HJ64GP504-I/ML

PIC24HJ128GP204-I/ML

PIC32MX550F256H-I/MR

PIC32MX170F512H-I/MR

PIC32MX250F256H-I/MR

PIC32MZ2048EFG064-I/MR

ATA8520D-GHPW

ATA8520D-GHQW

ATA8520-GHPW

ATSAMD20G15A-MUTA2

ATSAMD20G16A-MUTA2

PIC24FJ32GU202T-I/ML

PIC24FJ64GP202T-I/ML

PIC24FJ32GP202T-I/ML

PIC18F14K50T-I/MQ054

PIC32MX270F512HT-50I/MR022

ATSAMD20G17A-MUTA2

ATSAMD20G18A-MUTA2

MTCH105T-I/ML

PIC16LF18325-E/ST

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PIC16LF18855-E/SS

PIC24HJ12GP202-E/SS

DSPIC33FJ12GP202-E/SS

DSPIC33FJ12MC202-E/SS

PIC16F676-E/ST

PIC16LF19197-I/PT

PIC32MZ0512EFE064-I/PT

PIC32MZ0512EFF064-I/PT

PIC32MX564F064H-I/PT

PIC32MX664F128H-I/PT

PIC16LF18857-E/ML

PIC32MK1024GPK064-E/MR

PIC32MK0512GPK064-E/MR

PIC32MK1024MCM064-E/MR

PIC32MK0512MCM064-E/MR

PIC32MK0512GPG064-E/R4X

PIC32MK0256MCJ064-E/R4X

PIC32MK0256GPG064-E/R4X

PIC32MK0512MCJ064-E/R4X

PIC16LF15323-E/JQ

PIC18F66K40-E/MR

PIC16F15323-E/JQ

PIC18F47Q84-E/NHX

PIC16F1613-E/ML

PIC18LF45K42-E/ML

PIC24FJ128GL302-E/ML

PIC24FJ64GL302-E/ML

PIC18LF46K42-E/MV

PIC18F2580-E/ML

DSPIC33EP32GS504-E/MLC11

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ATSAMD21G17L-MF

PIC24FJ64GA110-I/PF

PIC18F6310-I/PT

PIC18LF8722-I/PT

PIC18F8722-I/PT

PIC18F6723-I/PREL

PIC18F8723-I/PREL

PIC18LF6520-I/PT

PIC18C601-I/PT

PIC18F6490-I/PT

PIC16LF777-I/PT

PIC18LF4320-I/PT

PIC16C774-I/PT

PIC16LC774-I/PT

PIC16C774-I/PQ

PIC16LC926-I/PTC03

PIC18F86J11-I/PT

PIC16LF18346T-E/MLVAO

PIC16LF18346T-E/GZVAO

PIC16LF18326T-E/JQVAO

MCP662T-E/MFVAO

MCP4151T-103E/MFVAO

MCP4151T-104E/MFVAO

PIC18F26Q10T-E/STXVAO

DSPIC33EP256GP502T-E/MMVAO

ATSAMD20E16B-MZTVAO

PIC12F1822T-E/MFVAO

PIC12F1840T-E/MFVAO

PIC12LF1571T-E/MFVAO

PIC16LF1946-I/PT

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PIC24FJ64GA104-I/PTREL

PIC16LF727-I/PT

PIC24FJ96GA008-I/PT

PIC18F4321-I/PT

DSPIC33EP32MC202T-E/SS

24LC02BHT-E/SN

MCP6V89T-E/ST

ATECC608C-MAHA3-S

ATECC608C-MAHA4-S

ATECC608B-MAHWG-T

PIC32MZ1024EFH100T-I/PTH21

PIC32MZ2048EFG100T-I/PT

PIC32MX130F256DT-I/PT

PIC24FJ1024GB610T-I/PT

PIC16F526-I/MG

PIC18LF452-I/ML

PIC18F452-I/ML

PIC18LF14K50-I/MQ

MCP2036-I/MG

PIC16LF1828-I/ML

PIC18F4420-I/ML

PIC18LF4520-I/ML

PIC18LF4510-I/ML

PIC18F2410-I/ML

PIC16F819-I/ML

PIC16F610-I/ML

24LC16B-I/MC

PIC16F917-I/ML

PIC16F914-I/ML

PIC18LF45K80-I/ML

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PIC18LF4321-I/ML

PIC18F4321-I/ML

PIC32CM3204GV00048-E/Y8X

PIC32CM3204GV00032-E/T5X

PIC32CM3204GV00064-E/V2X

PIC32CM3204JH00048-E/Y8X

PIC32CM3204JH00032-E/T5X

PIC32CM3204JH00064-E/V2X

ATSAMC21J18A-OAZ

PIC32CM1602GV00064-E/V2X

PIC32CM1602GV00048-E/Y8X

PIC32CM1602GV00032-E/T5X

ATSAMC21G18A-OAZ

PIC24FJ512GA606-I/PT

PIC24FJ1024GB606-I/PT

PIC24FJ128GB606-I/PT

PIC24FJ256GB606-I/PT

PIC24FJ512GB606-I/PT

PIC18F6622-I/PT

PIC18F6527-I/PT

ATSAMD21J16B-AU

ATSAMD21J15B-AU

PIC18F45K80-I/PT

ATSAMC20G16A-MZ

ATSAMC20G15A-MZ

AT90PWM81-16MF

PIC16F17126-E/7N

PIC16F1507-E/ML

AVR64DB48-E/6LX

AVR32DB48-E/6LX

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

AVR128DB48-E/6LX

AVR128DA48-E/6LX

PIC16F15325-E/JQ

AVR32DB32-E/RXB

AVR64DB32-E/RXB

AVR128DB32-E/RXB

PIC32MK0128MCA048-E/6MX

PIC32MK0128MCA032-E/RTB

PIC16F785-E/ML

PIC16HV785-E/ML

PIC32CM1216JH01048-E/U5B

PIC16F685-E/ML

PIC16F687-E/ML

PIC16F689-E/ML

DSPIC33EP128GM304-E/ML

PIC16F690-E/ML

ATSAMD21J15B-MMZ

ATSAMD21J16B-MMZ

PIC16F15323-I/ST

PIC32MX130F256B-I/SS

PIC32MX230F064B-I/SS

PIC32MX150F128B-I/SSF21

PIC18F25Q10-I/SS

PIC32MX110F016B-I/SS

PIC32MX220F032B-I/SS

PIC32MX210F016B-I/SS

ATXMEGA128D4-MH

ATXMEGA64D4-MH

PIC16F1507-I/ML

AVR32EA48-I/6LX

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PIC16F17146-I/6N

PIC16F18146-I/6N

PIC16F18144-I/6N

PIC16F17145-I/6N

PIC16F18145-I/6N

PIC16F17124-I/7N

PIC16F18124-I/7N

AT89LP51RC2-20MU

AT89LP51IC2-20MU

PIC16F15376-I/MP

PIC16LF15356-I/MV

PIC16F15375-I/MV

PIC16F15376-I/MV

PIC16LF15375-I/MV

PIC16LF15376-I/MV

AVR64DB48-I/6LX

ATMEGA324PA-MU

ATMEGA324A-MU

PIC16F17126-I/7N

PIC16F18126-I/7N

PIC16F17125-I/7N

ATMEGA2561-16AUR

ATMEGA2561V-8AUR

ATXMEGA128A4U-AUR

ATXMEGA128D4-AUR

SY88083LMG

SY88953ALMG

24CS256T-E/Q4B

ATSAMD21G17D-MZT

ATSAMD21G18A-MZT

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ATSAMD21G17A-MZT

PIC24EP256GP202T-E/MM

MCP48CVB24T-E/ML

MTD6508T-ADJE/JQREL

MCP19115T-E/MQ

ATSAMD21E15B-MZT

ATSAMD21E16B-MZT

MCP19117T-E/STX

PIC16F1708T-E/ML027

PIC16F1708T-E/ML030

PIC16F1708T-E/ML034

PIC16F1708T-E/ML035

PIC16F1708T-E/ML037

PIC16F1708T-E/ML038

PIC16F1708T-E/ML

PIC16F1508T-E/ML

PIC16F1509T-E/ML

MCP48FEB08T-E/MQ

MCP48FEB14T-E/MQ

MCP48FEB18T-E/MQ

DSPIC33EP512GM604T-I/ML

ZL30291LDF1

ZL30292LDF1

PIC18F55Q71T-I/6LX

PIC18F44Q71T-I/MP

PIC18F45Q71T-I/MP

PIC16F18046T-I/ML

ATSAML10E14A-MUT

ATSAML10E15A-MUT

ATSAML10E16A-MUT

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ATSAML11E14A-MUT

ATSAML11E15A-MUT

ATSAML11E16A-MUT

USB5742T-I/2G

USB5742BT-I/2G

USB5744BT-I/2GX01

USB5744T-I/2G

USB5744T-I/2GTB

HV5524K7-G-M933

HV5624K7-G-M933

AVR128DB64-I/MRC01

PIC32MX664F064H-I/PT

PIC12LF1822T-E/RF

PIC18LF26K22T-E/ML

PIC16F1764T-E/ML

24CSM01T-E/Q4B

PIC32CM5164JH01048T-E/U5B-SL3

PIC16F1705T-E/ML

24CS32T-E/Q4B

24CS64T-E/Q4B

PIC18LF25K40-I/SS

PIC18F25K40-I/SS

PIC24HJ256GP610A-I/PT

MCP4241T-104E/ML

MCP4241T-503E/ML

MCP47FEB04T-E/MQ

EMC1442-A-AC3-TR

MCP4231T-502E/ML

MCP4261T-502E/ML

DSPIC33FJ64GP706A-E/PT

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PIC24HJ128GP206A-E/PT

DSPIC33FJ128GP206A-E/PT

PIC24HJ128GP306A-E/PT

DSPIC33FJ128GP310A-E/PT

PIC16LF1567-E/PT

PIC16LF722A-I/MV

DSPIC33EV64GM006-E/MR

MCP47CVD01-E/MG

MCP4251-104E/ST

MCP4251-503E/ST

MCP3422A3-E/SN

MCP3422A6-E/SN

MCP4231-104E/ST

MCP4231-503E/ST

MCP3422A1-E/SN

24LC024H-E/SN

24LC024H-E/ST

24C02C-E/ST

MCP3422A2-E/SN

PIC16F916-E/SO

PIC18F2680-E/SO

MCP4661-503E/ST

MCP4241-104E/ST

MCP4241-503E/ST

MCP3422A7-E/SN

24LC014H-E/SN

MCP3424-E/ST

PIC16F916-E/SS

24LC128-E/ST

PIC18F2420-E/SO020

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PIC16F882-E/SO

PIC16F882-E/SS

PIC16F913-E/SO

MCP4651-104E/ST

MCP4651-503E/ST

24LC014H-E/ST

MCP4631-104E/ST

MCP4631-503E/ST

MCP6569-E/ST

MCP4661-502E/ST

PIC16F73-E/SS

PIC16F785-E/SS

MCP3422A0-E/SN

MCP4651-103E/ST

24LC512-E/ST14

PIC18F2520-E/SO032

PIC16F913-E/SS

PIC16F76-E/SS

MCP4651-502E/ST

PIC18F2220-E/SO

MCP4922-E/ST

MCP6064-E/ST

MCP6062-E/SN

MCP6054-E/ST

MCP4352-104E/ST

MCP4352-503E/ST

MCP4661-104E/ST

MCP6052-E/SN

24C02C-E/SN

24C01C-E/SN

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MCP3426A0-E/SN

PIC24FJ32GA002-E/SO

PIC24FJ64GA002-E/SO

ATSAML11E16A-MZ

PIC16F1824-E/JQ

PIC16LF1824-E/ML

PIC16LF1824-E/JQ

WP200RX01-E/ML001

ATSAML10E14A-MF

ATSAML10E15A-MF

ATSAML11E16A-MF

AVR32DD32-E/RXB

AVR16DD32-E/RXB

ATSAML10E16A-MF

ATSAML11E14A-MF

ATSAML11E15A-MF

PIC16F18076-E/MP

PIC18F46Q71-E/MP

PIC18F46K80-I/PT

PIC18F67K90-I/PT040

PIC18F67K90-I/PT041

PIC16F1779-I/PT

PIC16F1777-I/PT

DSPIC33EP32GS506-I/PTC09

PIC18F67J11-I/PT

MTR6618-I/PT

PIC18F66J16-I/PT

PIC18F67J11-I/PTC04

AT24C32E-XHM-T

PIC18F14Q41T-I/SS022

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PIC18F26K20T-I/SO024

PIC16F17144T-I/SS020

PIC16LF1554T-I/ST044

MCP42010T-E/ST

MCP6S92T-E/SN

MCP6022T-E/ST

MCP6024T-E/ST

MCP601T-E/ST

MCP42050T-E/ST

MCP42100T-E/ST

TC622VOA713

MCP6242T-E/SN

MCP6542T-E/SN

MCP602T-E/ST

MCP6142T-E/SN

MCP6234T-E/ST

MCP6548T-E/SN

MCP6543T-E/SN

MCP6547T-E/SN

MCP6244T-E/ST

DSPIC33EP256GM604-E/PTVAO

PIC16LF18323T-I/ST029

PIC16F1825T-I/ST026

PIC16F1825T-I/ST027

PIC16F1825T-I/ST036

PIC16F1825T-I/ST

AVR32DA28T-I/SO

PIC18F26K20T-I/SSLPR

PIC16F1782-E/SS

MCP2022-330E/ST

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MCP2022P-500E/ST

MCP2022P-330E/ST

PIC16LF1713-E/SS

PIC16LF1716-E/SS

AVR16EB14-E/ST

AVR16EB20-E/SS

AVR16EB28-E/SS

PIC18F25Q43-E/SS

PIC18F25Q43-E/SO

MCP2022-500E/ST

PIC24FJ64GA006T-I/PT040

AVR128DA48ST-I/PT

AVR128DA64ST-I/PT

AVR128DA32ST-I/PT

PIC32CM5164JH01100T-I/PF511

PIC32CM5164JH01100T-I/PF510

PIC32CM3204JH00064T-I/V2X

PIC32CM3204JH00048T-I/Y8X

PIC32CM3204JH00032T-I/T5X

PIC32CM6408JH00064T-I/V2X

PIC32MK0512MCF064T-E/PT

PIC32MK1024GPE100T-E/PT

DSPIC33EP256MU806T-E/PTC01

DSPIC33EP128GS806T-E/PT

DSPIC33EP64GS806T-E/PT

DSPIC33EP128GS706T-E/PT

DSPIC33FJ16MC304T-E/PT

DSPIC33EP64MC204T-E/PT

PIC18F66K40T-E/PT

DSPIC33FJ64GP202-E/MM

Date: Tuesday, July 22, 2025

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DSPIC33FJ64GP802-E/MM

DSPIC33FJ128GP202-E/MM

DSPIC33FJ128MC202-E/MM

DSPIC33FJ128MC802-E/MM

DSPIC33FJ32MC302-E/MM

PIC24HJ64GP202-E/MM

PIC24HJ64GP502-E/MM

PIC24HJ128GP202-E/MM

PIC24HJ128GP502-E/MM

DSPIC33EP32GP504-E/ML

DSPIC33EP32MC204-E/ML

DSPIC33EP32MC504-E/ML

PIC24EP32GP204-E/ML

PIC24EP32MC204-E/ML

ATMEGA3209-MF

PIC32MZ0512EFK064-E/MR

PIC24FV32KA304-I/ML

DSPIC33EV128GM002-I/MM

PIC24FV16KA304-I/ML

DSPIC33EV128GM102-I/MM

DSPIC33EV64GM102-I/MM

PIC24FV16KA302-I/ML

DSPIC33EV64GM106-I/MR

DSPIC33EV128GM004-I/ML

RE46C400V28T

ATSAMD20E16B-MNT

ATSAMD20E14B-MNT

ATSAMD20E15B-MNT

PIC32MX350F128HT-V/MR

RE46C401V28T

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ATSAMD21E16L-MNT

ATMEGA16-16MUR

ATMEGA8535L-8MUR

ATMEGA8535-16MUR

ATMEGA164A-MUR

ATMEGA164PA-MUR

PIC16F17114T-I/MD

PIC16F17115T-I/MD

LAN8720AI-CP-TR-ABC

LAN8710AI-EZK-TR-ABC

PIC16F1507T-I/ML

AVR32EA48T-I/6LX

ATSAMD21E16B-MUTN02

ATMEGA328PB-MUR

LAX8710A-I/S8X

PD77020-020300

PD77010-0101-0000

PD77010-0102-0000

PIC32MK0128MCA032-I/RTBN01

DSPIC33FJ32MC204-V/MLC21

ATSAMD20E16B-MN

ATSAMD20E14B-MN

ATSAMD20E15B-MN

ATSAMD21E17L-MN

LE87612MQC

RE354Q16

RE355Q16

PIC32MX130F128H-V/MR

PIC32MX150F256H-V/MR

PIC32MX170F512H-V/MR

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PIC32MX120F064H-V/MR

PIC32MX250F256H-V/MR

PIC32MX230F128H-V/MR

PIC32MX274F256D-V/ML

PIC32MX370F512H-V/MR

PIC32MX470F512H-V/MR

PIC32MX154F128D-V/ML

PIC32MX254F128D-V/ML

PIC32MX530F128H-V/MR

PIC32MX150F128D-V/ML

PIC32MX130F064D-V/ML

PIC32MX250F128D-V/ML

PIC32MX230F064D-V/ML

PIC32MX174F256D-V/ML

PIC32MX575F512H-80V/MR

PIC32MX575F256H-80V/MR

PIC32MX150F128B-V/ML

PIC16F15356T-I/STX

PIC16F18855T-I/MLC02

ATECC108A-MAHCZ-T

ATECC508A-MAHDA-T

ATECC508A-MAHCZ-T

ATECC608A-MAHDA-T

ATECC608A-MAHCZ-S

ATECC608A-MAHCZ-T

PIC32MX150F256HT-50I/MR

PIC32MX170F512HT-50I/MR

ATECC508A-MAHDA-S

ATECC508A-MAHCZ-S

MCP1722T-5010H/Q8B

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MCP1722T-5012H/Q8B

PIC18F26K22T-I/ML032

AVR32DA48T-I/6LX

AT24C512C-MAHM-T

AT24C512C-MAHM-E

PIC18F25J10T-I/ML

PIC18F45J10T-I/ML

ATECC508A-MAHAW-S

ATECC608B-TNGACTU-C

ATECC608B-TNGLORAU-C

PIC18F67K22T-I/MR

MCP1722T-3310H/Q8B

MCP1722T-3312H/Q8B

PIC18F26K22T-I/ML026

ATECC608B-TNGTLSU-C

ATECC608A-TNGTLSU-C

ECC608-TFLXWPCU

PIC16F1717T-I/MP

DSPIC33CK256MP208-E/PTVAO

PIC32MK0128MCA048-E/Y8XVAO

DSPIC33CK512MP710-E/PTVAO

AVR128DA64-E/PTVAO

DSPIC33CK512MPT608-E/PTVAO

ATSAME51N19A-AZ510

ATSAME51N20A-AZVAO

ATSAMD51N19A-AZVAO

PIC32CM2532JH01048-E/Y8XVAO

PIC32CM5164JH00048-E/Y8XVAO

PIC32CM2532JH01064-E/PTVAO

DSPIC33CK256MP406-E/PTVAO

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PIC32CM5164JH01100-E/PF510

PIC32CX1025SG41100-E/E5XVAO

PIC18F67J11T-I/PTC03

PIC16F18076T-I/PT

PIC16LF15375T-I/PT

11LC161T-I/MNY

11LC160T-I/MNY

DSPIC30F4013T-30I/ML

PIC24F16KL401T-I/MQ

PIC24F08KL201T-I/MQ

93C56BT-I/MNY

93C56CT-I/MC

93C56AT-I/MC

PIC24FJ32GA104T-I/ML025

PIC16F1613T-I/ML

PIC16LF1615T-I/ML

ATSAML21G18B-ANT

ATSAML21G16B-ANT

ATSAML21G17B-ANT

ATSAMD20J14A-ANT

ATSAMD20J15A-ANT

ATSAMD20J16B-ANT

ATSAMD20J16A-ANT

ATSAMD20J17A-ANT

ATSAMD20J18A-ANT

ATSAMD20J14B-ANT

ATSAMD21G18A-MU

PIC12F675T-E/MD

MCP9804T-E/MC

PIC12F519T-E/MC046

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PIC18F26K22T-E/ML

MCP45HV31-104E/MQ

PIC12LF1501-E/MC

MCP6N16-010E/MF

MCP6N16-001E/MF

MCP6N16-100E/MF

PIC16F1828-E/GZ

PIC16LF1508-E/GZ

MCP45HV51-502E/MQ

MCP45HV51-103E/MQ

MCP45HV51-503E/MQ

MCP45HV51-104E/MQ

PIC16LF1825-E/JQ

PIC16F1507-E/GZ

PIC16F1829-E/GZ

DSPIC33EV256GM102-E/MM

PIC16LF1829-E/ML

PIC24FJ64GB204-E/ML

PIC24FJ128GA202-E/MM

PIC24FJ128GB204-E/ML

PIC24FJ64GB202-E/MM

DSPIC33EV256GM002-E/MM

PIC18LF46K22-E/MV

PIC16F1933-E/ML

PIC18LF45K50-E/MV

DSPIC33EV256GM006-E/MR

DSPIC33EV256GM106-E/MR

PIC24FJ64GA202-E/MM

PIC24FJ16GA004-E/ML

PIC24FJ32GA004-E/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC24FJ64GA004-E/ML

PIC18F45K50-E/MV

MCP6002-E/MC

PIC18LF44K22-E/MV

PIC24FJ64GA104-E/ML

MCP4021T-503E/SN

MCP4362T-503E/ST

MCP4011T-103E/SN

MCP4011T-202E/SN

93LC76CT-E/ST

MCP45HV51T-502E/ST

MCP45HV31T-103E/ST

MCP45HV31T-503E/ST

MCP6V14T-E/ST

MCP23S17T-E/SS

MCP45HV31T-502E/ST

MCP45HV51T-103E/ST

MCP45HV51T-503E/ST

DSPIC33FJ32MC202T-E/SOC22

11LC161T-E/SN

PIC16F1823-I/JQ

PIC32MX270F512H-I/MR

LE79271AMQC

LE79271MQC

PIC32MX570F512H-I/MR

PIC18F26Q71-I/STX

PIC18F24Q71-I/STX

PIC18F25Q71-I/STX

PIC18F25K83-I/ML

PIC18F26K83-I/ML

Date: Tuesday, July 22, 2025

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DSPIC33AK32MC103-I/M7

DSPIC33AK128MC103-I/M7

DSPIC33AK64MC103-I/M7

ATSAMD20G16B-MU

ATSAMD20G15B-MU

ATSAMD20G14B-MU

DSPIC33AK128MC105-I/M7

PIC24EP128GP204-E/PT

PIC16F17176-E/PT

PIC16F18176-E/PT

PIC16F17174-E/PT

PIC16F18174-E/PT

PIC16F17175-E/PT

PIC16F18175-E/PT

AVR128DB32-E/PT

DSPIC33CK128MC505-E/PT

ATSAMC20E17A-AZ

ATSAMC20E16A-AZ

ATSAMC20E15A-AZ

PIC18F44Q71-E/PT

PIC18F45Q71-E/PT

PIC18F54Q71-E/PT

PIC18F55Q71-E/PT

DSPIC33AK128MC105-E/PT

DSPIC33AK64MC105-E/PT

DSPIC33AK32MC105-E/PT

PIC18F4480-E/PT

PIC16LF18876-E/PT

PIC18F56Q71-E/PT

AVR64EA32-E/PT

Date: Tuesday, July 22, 2025

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AVR64EA48-E/PT

PIC18F65K22-E/PT

AVR32EA32-E/PT

AVR32EA48-E/PT

AVR16EA32-E/PT

AVR16EA48-E/PT

SAMD21J17DRT-V2X-HP_ASSY

PIC18F46Q71-E/PT

AVR128DA32-E/PT

AVR128DA64-E/PT

AVR128DA48-E/PT

PIC18F24Q10-I/SSVAO

PIC18F26K83-I/SSVAO

24LC04B-I/ST16KVAO

AVR32DA28-I/SSVAO

DSPIC33EP512GP502-I/SOVAO

PIC16LF1825-I/STVAO

PIC16F1705-I/STVAO

PIC16F19155-I/SSVAO

PIC16F15244-I/SSVAO

PIC16F676-I/STVAO

PIC16F18325-I/STVAO

PIC16F18323-I/STVAO

PIC16F616-I/STVAO

PIC16LF18324-I/STVAO

MCP3004-I/STVAO

PIC16F15245-I/SSVAO

MCP3208-BI/SLVAO

24LC128-I/ST16KVAO

PIC24FJ32GA104-E/ML

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DSPIC33EV32GM006-E/MR

DSPIC33EP512GP502-E/MM

DSPIC33EP512MC202-E/MM

PIC16LC622A-04I/SO

PIC16C63-20I/SO

PIC16C621-04I/SS

MCP2140-I/SORVB

PIC16C620A-20I/SS

HA3089-I/SO

PIC16F818-I/SS

DSPIC33CK1024MP705T-E/M7VAO

LAN8672C2T-E/LNXVAO

LAN8671C2T-E/U3BVAO

ATSAMD21G15B-MZTVAO

PIC18LF66K40T-I/MR

PIC16LF19195T-I/MR

PIC16LF19196T-I/MR

PIC18F25K20T-I/MLC02

PIC16F887T-I/PT

DSPIC33FJ16GS504T-I/PTC02

PIC32MX150F128DT-50I/PT

PIC24EP64GP204T-I/PT

PIC32MX170F512LT-I/PF

PIC32MX795F512LT-80I/PF

PIC32MX775F512LT-80I/PF

PIC32MX775F256LT-80I/PF

PIC24HJ32GP204T-I/PT

DSPIC33FJ16MC304T-I/PT

PIC32MX675F256LT-80I/PF

PIC32MX570F512HT-50I/PT

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ATSAMC21G18A-AZT-SL3

DSPIC33CK256MP206T-E/PTC06

DSPIC33CK256MC506T-E/PT

DSPIC33CK128MC506T-E/PT

DSPIC33CK256MC106T-E/PT

PIC16LF1554-I/MLM10

PIC16LF1559-I/MLM10

PIC16F1937-I/MP

PIC16F1937-I/MV

PIC16F15225-I/MG

ATMEGA324P-20MU

ATSAMD21J16B-MMFT

ATSAMD21J15B-MMFT

PIC16LF18345T-E/GZ

ATSAMD21E18A-MZT

ATSAMD21E17A-MZT

PIC18F46K22T-E/ML

ATSAMD21J17D-MMFT

DSPIC33CK1024MP405T-E/M7

DSPIC33CK1024MP705T-E/M7

PIC16F1615T-E/ML

ATSAMC21E18A-MZT

AVR64DA28T-E/SSVAO

MTCH1060T-E/SSVAO

PIC16F1823T-E/STVAO

PIC16F1574T-E/STVAO

MCP3004T-E/STVAO

PIC16F1778T-E/SSVAO

PIC16LF15325T-E/STVAO

PIC18F27Q84T-E/SSVAO

Date: Tuesday, July 22, 2025

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MCP41HV51T-502E/STVAO

MCP3008T-E/SLVAO

PIC18F25Q10T-E/SSVAO

25LC128T-E/ST16KVAO

PIC18F27Q83T-E/SSVAO

24CSM01T-E/ST66KVAO

PIC18F26K83T-E/SSVAO

25CS640T-E/ST36KVAO

MCP6004T-E/STVAO-VW

PIC18F25Q43T-E/SSVAO

DSPIC33EV64GM002T-E/SSVAO

PIC16F18446T-E/SSVAO

25CS320T-E/ST36KVAO

24LC64FT-I/SN

24AA64FT-I/SN

24AA32AT-I/SN

24LC64T-I/SN

24AA64T-I/SN

PIC24FJ16GA002T-I/SO

11AA02E48T-I/SN

DSPIC33FJ16GS502T-I/SOC01

24LC024T-I/ST

24AA024T-I/ST

A010201T-I/SS

AVR64DB48T-I/6LX

AVR16DD28-I/SO

PIC18F06Q41-I/ST

DSPIC33EP64GP502-I/SS

PIC18F06Q40-I/ST

PIC12C509A-04I/SNC09

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PIC16LF18326-I/ST

PIC16F18346-I/SSC03

PIC16F18346-I/SS

PIC16LF18346-I/SS

PIC12F1571-I/SN030

PIC12F1571-I/SN032

PIC24HJ64GP504-E/ML

PIC24HJ128GP204-E/ML

PIC24HJ128GP504-E/ML

ATMXT449TD-ABRVA2

ATMXT225TD-ABRVA2

ATSAMDA1G16A-ABT

ATMXT225TD-ABR

ATSAMDA1G16B-ABTVAO

ATSAMDA1G15B-ABTVAO

ATMXT1296M1T-ABRVA1

ATMXT1067TD-ABRI2CCPVAO

ATMXT1067TD-ABRSPIVAO

ATMXT1067TD-ABRI2CVAO

ATMXT1296M1T-ABRVAO

ATSAMDA1G16B-ABTVAO-SG

ATSAMDA1G16B-ABTVAO-GM

ATSAMDA1J16B-ABTVAO

ATSAMDA1J16B-ABTVAO-GM

ATMEGA328PB-ABTVAO

PIC24FJ32GA004-I/PT

DSPIC33FJ64MC508A-I/PT

DSPIC33FJ128GP708A-I/PT

DSPIC33FJ64GP708A-I/PT

PIC18LF6722-I/PT032

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DSPIC33EV256GM106-I/PTREL

DSPIC33FJ128MC708A-I/PT

PIC16F1823T-I/STC06

PIC16F1825T-I/STC02

PIC12LF1822T-I/SN

PIC12F675T-I/SN112

PIC16F684T-I/ST041

PIC32MK0512GPD064T-E/PT

PIC16LF1827-I/SS

25LC128-I/SN

25AA128-I/SN

PIC12F1822-I/SN052

PIC16LF1784-E/PT

PIC24FV16KM204-E/PT

DSPIC30F6014A-20E/PTREL

PIC18F4221-E/PT

PIC18F4321-E/PT

PIC16F1787-E/PT

PIC18LF46K22-E/PT

PIC16F1527-E/PT

PIC16F1526-E/PT

DSPIC30F6015-20E/PTC01

PIC16F727-E/PT

PIC18F65J11T-I/PT

PIC24FJ256GA110T-I/PT

PIC18LF4585T-I/PT

PIC18F4585T-I/PT

PIC18F6390T-I/PT

PIC24FJ128GA010T-I/PT

PIC18F64J90T-I/PT

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PIC18F65J90T-I/PT

DSPIC30F6012A-30I/PT

DSPIC30F6011A-30I/PF

DSPIC30F6012A-30I/PF

PIC18F56Q83-I/PT

PIC18F56Q84-I/PT

DSPIC30F6013A-30I/PT

DSPIC30F6014A-30I/PT

AVR32DA48-I/PT

DSPIC33CH256MP206-I/PT

DSPIC30F4011-20I/PT

DSPIC30F4011-30I/PT

DSPIC30F2023-30I/PT

PIC18F57Q83-I/PT

PIC18F57Q84-I/PT

MCP2562FDT-H/MF

MCP8026T-115H/MP

DSPIC33EP64MC202T-H/MM

DSPIC33EP128MC206T-H/MR

DSPIC33EP128MC504T-H/ML

DSPIC33EP256GP504T-H/ML

DSPIC33EP256MC204T-H/ML

DSPIC33EP256MC504T-H/ML

PIC24EP256GP204T-H/ML

PIC24EP256MC204T-H/ML

DSPIC33EP32GP504T-H/ML

DSPIC33EP32MC204T-H/ML

DSPIC33EP32MC504T-H/ML

PIC24EP32GP204T-H/ML

PIC24EP32MC204T-H/ML

Date: Tuesday, July 22, 2025

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DSPIC33AK128MC105T-H/M7

DSPIC33AK64MC105T-H/M7

DSPIC33AK32MC105T-H/M7

DSPIC33EP256MC504-E/ML

DSPIC33EP256GP504-E/ML

PIC32CM5164JH01064-I/5LX

ATMEGA4809-MU

ATSAMD21G17A-MU

ATSAMD21G17A-MUA1

ATSAMD21G18A-MUA1

IS1871SF-102-TRAY

DSPIC33FJ64MC204T-E/ML

PIC18F4221-I/PT

PIC18LF8622-I/PT

PIC18F47J13-I/PT

PIC32MX470F512LT-V/PT

PIC32MX460F256LT-80V/PT

PIC32MX440F128LT-80V/PT

PIC32MX370F512LT-V/PF

PIC32MX470F512LT-V/PF

PIC32MX370F512LT-V/PT

PIC16F17154-E/STX

PIC16F18154-E/STX

PIC16F17155-E/STX

93LC66A-E/SN

PIC12F615-E/SN

93LC66B-E/SN

93LC86A-E/SN

PIC12F510-E/SN

PIC24F08KL200-E/ST

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PIC24F04KL100-E/ST

PIC24F08KL201-E/SS

PIC24F16KL401-E/SS

PIC16F886-E/SS

PIC24F04KL101-E/SS

PIC24F16KL402-E/SS

24LC32AF-E/SN

PIC16F886-E/SO

PIC18LF25K83-E/SS

PIC18LF26K83-E/SS

TA010-TFLXU-VU

PIC32MX370F512L-I/PF

PIC32MX470F512L-I/PF

PIC32MZ2048ECG100-I/PTD21

PIC32MX320F032H-40I/PT

PIC18LF4525-I/PT

PIC18LF45K50-I/PT

PIC18LF46J50-I/PT

PIC18LF45J50-I/PT

PIC18F4620-I/PT

PIC18F4525-I/PT

DSPIC33EP128MC206-I/PTA3

PIC18F46K20-I/PTC06

PIC18F46K20-I/PT

PIC16F946-I/PT

PIC16F1937-I/PT

PIC16F1937-I/PTC02

MTR2727-I/PT

PIC18LF47J13-I/PT

PIC18LF46J13-I/PT

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PIC18F45K22-I/PT

PIC16F882T-I/SO

PIC12F1822T-I/SN053

DSPIC33CH512MP206-E/PTVAO

DSPIC33CH256MP506-E/PTVAO

DSPIC33CH256MP206-E/PTVAO

DSPIC33CH256MP505-E/PTVAO

PIC32MM0064GPM064-E/PTVAO

DSPIC33EP64MC204-E/PTVAO

A3P125-1VQ100I

PIC16F18075-I/PT

A3P125-1VQG100I

AGL250V5-VQ100I

PIC16F1516-I/ML

PIC16LF18856-I/STX

PIC16F1518-I/ML

LE9540CUQC

LE9540DUQC

PIC18F26K40-I/ML

AT86RF215M-ZU

PIC16F18856-I/MV

ATMEGA1284RFR2-ZU

PIC32CM5164JH01064-E/PT

PIC32CM5164JH01048-E/Y8X

PIC32CM2532JH00048-E/Y8X

PIC32CM5164JH00048-E/Y8X

DSPIC33CH128MP215-E/PTC01

DSPIC33CK64MP105-E/PTC01

DSPIC33AK128MC106-E/PT

DSPIC33AK64MC106-E/PT

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DSPIC33AK32MC106-E/PT

PIC16F917-E/PT

PIC18LF65K40-E/PT

PIC18LF66K40-E/PT

PIC18F45Q10-E/PT

PIC18F46Q10-E/PT

PIC16F914-E/PT

PIC16F887-E/PT

ATMEGA4808-AF

ATMEGA4809-AF

ATSAMD21J17A-AZ

ATSAMD21J18A-AZ

DSPIC33AK128MC105T-I/PT

MCP2050T-330E/MQVAO

MCP2515T-E/MLVAO

DSPIC33FJ09GS302T-E/MMVAO

DSPIC30F2010T-20E/MMVAO

DSPIC33EV128GM004T-E/MLVAO

PIC16F1779T-E/MLVAO

MCP41010-I/SN

PIC12LF1552-I/SN

PIC12F617-I/SN030

PIC12F519-I/SN

PIC16LF18323-I/ST

MCP41100-I/SN

93C66C-I/SN

93C66A-I/SN

93C66B-I/SN

93LC46C-I/SN

93AA46C-I/SN

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25LC160A-I/SN

PIC16LF18856T-I/MLVAO

PIC16F15224T-I/MGVAO

PIC16LF18326T-I/7NVAO

ATMEGA168-15MT

PIC16F18346T-I/GZVAO

KSZ9031RNXUB-TRVAO

USB4925T-I/Y9XVAA

USB4715T-I/Y9XVAA

HV2201TQ-G-M931

HV20822TQ-G-M931

HV20220TQ-G-M931

DSPIC33CK512MP305T-E/M7

24LC014T-E/MNY

DSPIC33CK512MP605T-E/M7

24LC014T-E/MC

24C02CT-E/MNY

24C02CT-E/MC

MCP98243T-BE/MCAB

25LC010AT-E/MNY

25LC010AT-E/MC

25LC040AT-E/MNY

25LC040AT-E/MC

PIC18F47K40T-E/ML

25LC020AT-E/MNY

25LC020AT-E/MC

EMC1414-A-AIA-TR

EMC1403-1-AIA-TR

MCP41HV51T-502E/MQ

MCP41HV51T-103E/MQ

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MCP41HV51T-503E/MQ

MCP41HV51T-104E/MQ

MCP19061T-E/RTB

PIC16LF1825T-E/ML

MCP16502TAC-E/S8B-M

MCP16501TA-E/RMB-M

MCP19125T-E/MQ

MCP16502TAA-E/S8B

MCP16502TAB-E/S8B

MCP16502TAC-E/S8B

MCP16502TAD-E/S8B

MCP16502TAE-E/S8B

DSPIC33CK128MP505T-E/PTVAO

AVR32DA48T-E/PTVAO

DSPIC33CK128MP205T-E/PTVAO

DSPIC33CK64MP505T-E/PTVAO

PIC18LF45K22T-E/PTVAO

PIC18LF47K40T-E/PTVAO

DSPIC33CK1024MP708T-E/PTVAO

DSPIC33CH512MP508T-E/PTVAO

DSPIC33CH512MP208T-E/PTVAO

DSPIC33CH256MP508T-E/PTVAO

DSPIC33CH256MP208T-E/PTVAO

ATMEGA4808-AFR-VAO

ATMEGA4809-AFR-VAO

TC1301A-NICVMF

TC1302B-PHVMF

PIC16F72-E/ML

TC1301B-GPDVMF

MCP3422A0T-E/SN

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC17C752-33/PT

PIC17C42A-16/PQ

PIC16F1619T-E/GZ

PIC16LF1619T-E/GZ

PIC16LF1938T-E/MV

ATA6560-GBQW-N

24LC32AFT-E/MNY

PIC18F45K80T-E/ML

PIC18F46K80T-E/ML

MCP2200-I/SS

PIC18F26K22-I/SSC04

25LC256-I/SN

25AA256-I/SN

PIC16F648A-I/SS

PIC16F648A-I/SSC06

PIC12F615-I/SN083

PIC12F615-I/SN

93AA76A-I/SN

93LC76B-I/SN

93AA76B-I/SN

93LC66C-I/SN

DSPIC33CK128MP505T-E/PT

DSPIC33CK64MP205T-E/PT

ATSAMD20J15B-ANT

ATSAMD20E16B-ANT

ATSAMD20E14B-ANT

ATSAMD20E15B-ANT

PIC32MX534F064HT-V/PT

PIC32MX564F064HT-V/PT

PIC32MX664F128HT-V/PT

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PIC32MX664F064HT-V/PT

PIC32MX564F128HT-V/PT

PIC16F15225-E/ST

DSPIC30F1010-20E/SO

DSPIC30F2020-20E/SO

93C46AT-I/ST

93AA76AT-I/ST

PIC16C620A-04I/SS

PIC16F627-04I/SS

PIC16F627-20I/SS

PIC18F8525-I/PT

PIC16C65B-20I/PQ

PIC18LF8621-I/PT

PIC18F8621-I/PT

PIC18LF8680-I/PT

PIC16F1824T-E/STVAO-GM

25LC256T-E/ST16KVAO-MB

PIC16F1823T-E/JQ

PIC18F25K83T-E/ML

AVR16EA28T-E/STX

DSPIC33AK128MC103T-E/M7

DSPIC33AK64MC103T-E/M7

DSPIC33AK32MC103T-E/M7

MIC2129T-E/U3B

AVR32DD32T-E/RXB

AVR16DD32T-E/RXB

AVR32DD28T-E/STX

AVR16DD28T-E/STX

DSPIC33AK128MC105T-E/M7

DSPIC33AK64MC105T-E/M7

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DSPIC33AK32MC105T-E/M7

PIC18F2480T-E/ML

PIC24EP32MC202T-E/MM023

DSPIC33FJ256GP510A-I/PT

DSPIC33FJ256GP710A-I/PT

PIC32MZ1024ECH064-I/PT

PIC32MZ2048ECH064-I/PT

PIC32MZ1024ECM064-I/PT

PIC32MX270F512H-50I/PT

PIC32MX550F256H-50I/PT

PIC32MX530F128H-50I/PT

DSPIC33FJ256MC510A-I/PT

DSPIC33FJ64GS610-50I/PT

PIC24HJ128GP510-I/PT

PIC24HJ256GP210-I/PT

PIC24HJ256GP610-I/PF

PIC32MZ0512EFE100-I/PTA21

ATSAMD20E17A-AU

PIC24FJ128GA106-I/PTC13

PIC32MZ1024EFM100-I/PT

ATSAMD20E14A-AU

PIC32MZ1024EFK100-I/PTK21

PIC32MZ2048EFG100-I/PTL22

PIC32MZ2048EFG100-I/PT

PIC32MZ2048EFH100-I/PTM21

ATSAMD20E16A-AU

ATSAMD20E15A-AU

PIC24HJ128GP506A-I/PT

ATMEGA88PA-AU

ATMEGA168PA-AU

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PIC32MZ0512EFE100-I/PT

DSPIC33CK64MP506-I/PT

DSPIC33CK32MP206-I/PT

DSPIC33CK128MP208-I/PT

DSPIC33CK128MP508-I/PT

DSPIC33CK64MP208-I/PT

DSPIC33CK64MP508-I/PT

MTR6067-I/PT

PIC18F86J90-I/PTC04

PIC18F86J90-I/PT

DSPIC33CK32MP506-I/PT

DSPIC33CK256MP208-I/PT

DSPIC33CK256MP508-I/PT

DSPIC33FJ64GS406-50I/PT

DSPIC33FJ64GS606-50I/PT

DSPIC33FJ32GS406-50I/PT

DSPIC33CK128MP206-I/PT

DSPIC33CK128MP506-I/PT

PIC16LF1947-I/PT

PIC16LF1947-I/PTC01

DSPIC33CK64MP206-I/PT

PIC32MZ1024EFF100-I/PTF23

PIC32MM0064GPM048-I/PT

PIC32MM0128GPM048-I/PT

PIC32MM0256GPM048-I/PT

PIC32MZ2048EFH100-I/PT

PIC32MZ2048EFM100-I/PTN21

PIC32MX440F512H-80V/PT

PIC32MX440F128H-80V/PT

PIC32MX360F512L-80V/PT

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PIC32MX360F256L-80V/PT

PIC32MX530F128H-V/PT

PIC32MX130F128H-V/PT

PIC32MX120F064H-V/PT

PIC32MX230F128H-V/PT

PIC32MX370F512L-V/PT

PIC32MX460F256L-80V/PT

PIC32MX320F128L-80V/PT

PIC32MX340F128L-80V/PT

PIC32MX460F512L-80V/PT

PIC32MX440F128L-80V/PT

PIC32MX795F512H-80V/PT

PIC32MX775F512H-80V/PT

PIC16F1777T-E/MLVAO

MCP19119T-E/MQVAO

DSPIC33EV64GM104T-E/MLVAO

MCP19125T-E/MQVAO

PIC18F26K40T-E/MLVAO

PIC16F1768T-E/6NVAO

PIC16F1769T-E/6NVAO

DSPIC33EP128MC504T-E/MLVAO

IS1870SF-102-TRAY

SY58020UMG

PIC32MX320F064HT-40I/MR

PIC32MX340F512HT-80I/MR

DSPIC33FJ128GP802T-I/MM039

SYCUSTDIP2-TR

PIC32MX675F512HT-80I/MR

DSPIC33EP512MC506T-I/MR

PIC32MX320F064HT-80I/MR

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DSPIC30F3013T-20I/ML

DSPIC30F3013T-30I/ML

PIC32MZ1024EFG064T-I/MR

PIC32MZ1024EFH064T-I/MR

LE9621AQCT

AT27LV010A-70JU

AT27LV512A-90JU

DSPIC33FJ12MC202T-E/ML

ATMEGA1609-MFR

ATMEGA809-MFR

PIC24EP64GP206T-E/MR

PIC18LF26J50-I/ML

PIC16LF1789-I/MV

PIC32MX330F064H-I/PT

ATSAMD20G14A-AU

PIC24EP512MC204-I/PT

PIC24EP256GP204-I/PT

MCP2542WFDT-E/MF

PIC32MZ1024EFH064T-E/MR

PIC32MZ1024EFK064T-E/MR

PIC16F1788T-E/ML

DSPIC33FJ16GP102T-E/ML

PIC32MZ1024EFM064T-E/MR

PIC32MZ2048EFG064T-E/MR

PIC32MZ2048EFH064T-E/MR

DSPIC33FJ06GS202T-E/MM

DSPIC33FJ06GS102T-E/MM

DSPIC33FJ16GS402T-E/MM

MCP4631T-502E/ML

PIC16F1824-H/STVAO

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PIC16F1503-H/STVAO

PIC16F1619-H/SSVAO

MCP45HV31-502E/MQ

MCP45HV31-103E/MQ

24LC01B-E/MC

MCP1632-AAE/MC

MCP1632-BAE/MC

MCP45HV31-503E/MQ

PIC16F15323T-E/ST029

PIC16F1829T-E/SS

DSPIC33CK256MC502T-E/SS

DSPIC33CK128MC502T-E/SS

DSPIC33CK256MC102T-E/SS

PIC16F15324T-E/ST

DSPIC33CK128MC102T-E/SS

PIC16F1708T-E/SS

PIC16F1709T-E/SS

PIC16F1619T-E/SS

24CS256T-E/ST

PIC16LF1508T-E/SS

24FC256T-E/ST

PIC16LF1509T-E/SS

MCP3913A1T-E/SS

DSPIC33EV32GM002T-E/SS

PIC16F18345T-E/SS

AVR128DB28T-E/SS

AVR64DB28T-E/SS

AVR32DB28T-E/SS

24FC256T-E/SN

DSPIC33CK64MP102T-E/SS

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DSPIC33CK32MP102T-E/SS

PIC16F1823T-E/ST

PIC16F1825T-E/ST

PIC16F18344T-E/SS

PIC16LF18344T-E/SS

PIC16LF1773T-E/SS

PIC16F1773T-E/SS

DSPIC33EP32GP502T-E/SS

25AA128T-E/SN

MCP6499T-E/ST

PIC16F1513T-E/SS

PIC16F18855T-E/SS

24AA256T-E/SN

24LC256T-E/STNOK

LX34211QPW-TR

PIC16F688T-E/ST

PIC18F16Q40T-E/SS

PIC16F1579T-E/SS

DSPIC33EP64MC202T-E/SS

DSPIC33EP64MC502T-E/SS

PIC24EP64MC202T-E/SS

PIC16F1508T-E/SS

PIC16F1509T-E/SS

ATTINY3224-XFR

PIC24HJ12GP202T-E/SS

DSPIC33FJ12GP202T-E/SS

PIC16F676T-E/ST

DSPIC33FJ12MC202T-E/SS

MCP6232T-E/SN

PIC12F629T-E/SN244

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MTCH1030T-E/ST

PIC16F677T-E/SS

PIC16F1936T-E/SO

PIC18F14Q40T-E/SS

AVR16EA28T-E/SS

AVR32DD28T-E/SS

AVR16DD28T-E/SS

AVR32DD28T-E/SO

AVR16DD28T-E/SO

AVR64EA28T-E/SS

PIC16F18346T-E/SS

PIC16LF18346T-E/SS

AVR32EA28T-E/SS

AVR64DD28T-E/SS

AVR64DD28T-E/SO

PIC12F1571T-E/SN

PIC12F1572T-E/SN

MCP42U83T-502E/ST

MCP42U83T-103E/ST

MCP42U83T-203E/ST

DSPIC33EP128GM604-E/PTVAO

ATSAMC21G16A-AZVAO

DSPIC33EP128GS808-E/PTVAO

PIC18F47Q10-E/PTVAO

AVR128DA32-E/PTVAO

AVR128DA48-E/PTVAO

DSPIC33FJ16GS504-50I/ML

PIC18LF26K22-E/ML

PIC16F1765-E/ML

PIC16F1764-E/ML

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PIC18F55Q24-E/6LX

PIC18F56Q24-E/6LX

PIC18F24Q10-I/SO

PIC18F25Q10-I/SO

DSPIC33EP512GP502-I/SO

DSPIC33EP512MC202-I/SO

DSPIC33EP512MC502-I/SO

PIC18F25K80-I/SO

PIC32MX110F016DT-I/PTF21

PIC32MX120F032DT-I/PT

PIC32MX110F016DT-I/PT

DSPIC33FJ64GS608T-I/PT

DSPIC33FJ64MC506AT-I/PTC27

PIC32MX150F256HT-50I/PT

PIC32MX170F512HT-50I/PT

PIC32MX130F128HT-50I/PT

PIC12F509T-I/MCVAO

PIC18F2480T-I/MLVAO

93AA76B-I/ST

24LC16BH-I/SN

24AA16H-I/SN

MCP42050-I/ST

PIC18F26K22-I/SO

PIC18F25K22-I/SO

MCP617-I/SN

PIC16LF1906-I/SO

PIC16LF1906-I/SS

PIC16LF1825-I/ST

24LC64-I/SN

24AA64-I/SN

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PIC16F1847-I/SS

PIC18F25J50-I/SS028

PIC18F46Q24-E/MP

PIC18F26Q24-E/STX

PIC32CM5164JH01048-E/U5B-SL3

PIC18F24Q24-E/STX

PIC18F25Q24-E/STX

PIC16LF1554-E/MLM10

PIC18F2520-I/ML

PIC16LF877A-I/ML

PIC18F4423-I/ML

PIC16F877A-I/ML

PIC16LF737-I/ML

PIC16F737-I/ML

PIC18LF13K50-I/MQ

PIC16F505-I/MG

PIC18F45K22-I/ML

PIC18F44K22-I/ML

PIC18F56Q83-I/6MX

PIC18F56Q84-I/6MX

MTCH112-I/MF

PIC12LF1840-I/MF

PIC18F43K22-I/ML

PIC18F46K22-I/ML

PIC18F25J10-I/ML020

ATSAMD21J16B-MMU

ATSAMD21J15B-MMU

ATSAMD21J17D-MMU

PIC16F1934-I/MV

PIC12LF1822-I/MF

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PIC12F609T-I/MD

PIC16F1934T-I/MV

PIC16F1934T-I/ML

PIC18F25J10T-I/ML020

PIC16LF1704T-I/ML

DSPIC33CK1024MP405T-I/M7

DSPIC33CK1024MP705T-I/M7

DSPIC33CK512MP405T-I/M7

DSPIC33CK512MP705T-I/M7

DSPIC33CK256MP405T-I/M7

DSPIC33CK256MP705T-I/M7

DSPIC33EP256MC204-E/ML

PIC18F25K80-E/MM

PIC18F26K80-E/MM

ATMEGA324PV-10MU

ATMEGA168PB-MU

ATMEGA644PA-MU

ATMEGA644A-MU

ATMEGA644V-10MU

ATMEGA644-20MU

ATMEGA644PV-10MU

ATMEGA32L-8MU

ATMEGA8515L-8MU

ATMEGA8515-16MU

ATMEGA644P-20MU

AT89LP52-20MU

AT89LP51-20MU

ATMEGA88PB-MU

ATMEGA48PB-MU

ATMEGA16L-8MU

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ATMEGA16-16MU

ATMEGA16A-MU

PIC16F722AT-I/SS

PIC16LF87T-I/SS052

PIC16F916T-I/SO

24AA044T-I/ST

PIC16F1713T-I/SS

PIC16C925-I/PT

PIC18LF6621-I/PT

PIC17C756A-33I/PT

PIC18F448-I/PT

PIC18LF4423-I/PT

PIC18LF6622-I/PT

PIC18LF6527-I/PT

PIC18F452-I/PTC17

PIC18F4480-I/PT

PIC18F87J60-I/PTREL

PIC24HJ128GP510A-I/PT042

PIC16LF1517-I/PT

PIC16LF1519-I/PT

PIC18F26Q24T-I/SO

PIC12F1572T-I/SN071

AVR32SD28T-I/SS

AVR32SD20T-I/SS

AT24C64B-10TU-2.7-T

AT24C64B-10TU-1.8-T

24CS32T-I/ST

24CS64T-I/ST

PIC18F24Q24T-I/SS

PIC18F24Q24T-I/SO

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DSPIC33EV32GM104-E/PT

PIC24FJ256GL408-E/PT

PIC24FJ512GL408-E/PT

PIC24FJ128GU408-E/PT

PIC24FJ256GU408-E/PT

DSPIC33EP64MC206-E/PTA8

DSPIC33EP32GP504-E/PT

DSPIC33EP32MC204-E/PT

DSPIC33FJ32MC304-E/PT

DSPIC33EP256MC206-E/PT

DSPIC33FJ64MC204-E/PT

DSPIC33FJ128MC204-E/PT

PIC24FJ128GL405-E/PT

PIC24FJ256GL405-E/PT

PIC24FJ512GL405-E/PT

PIC24FJ128GU405-E/PT

PIC24FJ256GU405-E/PT

DSPIC33FJ64GP804-E/PT

PIC24EP256GP204-E/PT

DSPIC33FJ128GP204-E/PT

PIC24FJ128GL408-E/PT

DSPIC33FJ32GP304-E/PT

PIC24FJ512GU408-E/PT

PIC24FJ128GL305-E/PT

PIC24FJ64GL305-E/PT

DSPIC33EV256GM006-E/PTC01

DSPIC33CK256MC105-E/PT

AVR64DB32-E/PT

DSPIC33CK128MC105-E/PT

AVR32DB32-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC18LF45K22-E/PT

AVR32DD32-E/PT

AVR16DD32-E/PT

DSPIC33EP128MC204-E/PT

DSPIC33EP128MC504-E/PT

DSPIC33EP128MC506-E/PT

DSPIC33EP128GP506-E/PT

PIC18LF44K22-E/PT

PIC18F4680-E/PTC04

DSPIC33EP256MU806-E/PTC01

DSPIC33EP512GM306-E/PTC02

MCP6H74T-E/STVAO

MCP6H94T-E/STVAO

MCP6H04T-E/STVAO

MCP6564T-E/STVAO

MCP6569T-E/STVAO

MCP624T-E/STVAO

MCP654T-E/STVAO

MCP634T-E/STVAO

MCP664T-E/STVAO

MCP6499T-E/STVAO

MCP6544T-E/STVAO

MCP6549T-E/STVAO

DSPIC33AK128MC102T-H/M7

DSPIC33AK64MC102T-H/M7

DSPIC33AK32MC102T-H/M7

PIC18F27Q83-E/SS

PIC18F27Q84-E/SS

PIC18F27Q83-E/SO

PIC18F27Q84-E/SO

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33AK128MC102-E/SS

DSPIC33AK64MC102-E/SS

PIC18F26Q83-E/SS

PIC18F26Q84-E/SS

PIC18F26Q83-E/SO

DSPIC33AK32MC102-E/SS

DSPIC30F2010-20E/SO

AVR32DA28-E/SS

PIC24FJ256GA610-E/PT

PIC24FJ512GA610-E/PT

PIC24FJ256GB610-E/PT

PIC24FJ512GB610-E/PT

PIC24FJ1024GA606-E/PT

PIC24FJ512GB606-E/PT

PIC24FJ1024GA610-E/PT

PIC24FJ128GA606-E/PT

DSPIC33FJ16GP304-E/PT

PIC24HJ256GP210A-E/PT

PIC24HJ256GP610A-E/PT

PIC24EP512GU810-E/PF

PIC24EP256GU810-E/PF

PIC16LF18455T-I/STX

PIC16LF18456T-I/STX

PIC16F785T-I/ML045

PIC16F785T-I/ML047

PIC16F685T-I/ML

PIC16F687T-I/ML

PIC16LF1614T-I/ML

PIC32MX170F256DT-I/ML

PIC32MX270F256DT-I/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33EP128GP506T-I/MR

DSPIC33EP128MC206T-I/MR

DSPIC33EP128MC506T-I/MR

PIC24EP128MC206T-I/MR

ATECC608A-MAH3P-T

ATECC608A-MAH3Q-S

ATECC608A-MAH4W-T

ATECC608A-MAH5P-T

ATECC608A-MAHA2-S

ATECC608A-MAHAA-S

ATECC608A-MAHAC-S

ATECC608A-MAHAP-S

PIC32CM1216MC00048T-I/U5B

PIC32CM1216MC00048T-I/U5BESU

PIC32CM6408MC00048T-I/U5B

PIC16F1823T-I/ML029

ATECC608A-MAHAV-S

ATECC608A-MAHD3-S

ATECC608A-MAHGA-T

ATECC608A-MAHGX-T

SY88982LMG-TR

SY89231UMG-TR

PIC16F1527-I/PT

PIC16F1526-I/PT

PIC18LF45K22-I/PT

AVR32DD32-I/PT

PIC18LF44K22-I/PT

AVR16DD32-I/PT

PIC18LF43K22-I/PT

DSPIC33EP256MC506-I/PTA3

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATSAMD21E17D-AU

DSPIC33EP128GP504-I/PT

DSPIC33EP128MC204-I/PT

DSPIC33EP128MC504-I/PT

PIC24EP128GP204-I/PT

PIC24EP128MC204-I/PT

TC1301B-GWDVMF

TC1302B-HPVMF

TC1301B-HPEVMF

TC1302B-ICVMF

TC1301B-FDAVMF

TC1302B-DPVMF

TC1301B-FGAVMF

TC1301B-FHAVMF

TC1301A-NSBVMF

TC1301B-DPAVMF

24AA04T-I/MNY

PIC16F684-I/ST041

MCP6022-I/STAAA

PIC16LF73-I/SS

PIC16C73B-20I/SS

PIC16LC72A-04I/SS

PIC18LF14K50-I/SS

PIC16F872-I/SS

MCP3304-BI/SL

PIC16LF872-I/SS

PIC16C72A-04I/SS

PIC16C72A-20I/SS

PIC32MX270F256D-V/PT

ATMEGA644PA-AN

Date: Tuesday, July 22, 2025

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ATMEGA324P-20AQ

ATMEGA168PB-AN

ATMEGA128L-8AN

ATMEGA328P-AN

ATMEGA644PV-10AQ

ATXMEGA128A1U-AN

KSZ9031RNXIA

ATMEGA8535L-8MU

24AA02E64T-I/SN

MCP2562FDT-E/MF

PIC16F1503T-E/MG033

PIC16F1503T-E/MG

ATSAMHA1G17A-MZT-B510

ATMEGA328PB-MBTVAO

KSZ8051RNLV-TR-VAO

DSPIC33CK256MP505-H/PT

DSPIC33CK256MP308-H/PT

DSPIC33CK256MP608-H/PT

DSPIC33CK512MP308-H/PT

DSPIC33CK512MP608-H/PT

DSPIC33CK256MP305-H/PT

DSPIC33CK256MP605-H/PT

DSPIC33CK512MP305-H/PT

DSPIC33CK512MP605-H/PT

PIC18F45K80-H/PT

PIC32MX170F256B-V/ML

PIC32MX270F256B-V/ML

PIC32MX230F256D-V/ML

PIC32MX130F256D-V/ML

PIC32MX120F032B-V/ML

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PIC32MX110F016B-V/ML

PIC32MX564F064H-V/MR

PIC32MX664F128H-V/MR

PIC32MX664F064H-V/MR

PIC32MX470F512LT-120/PT022

KSZ8041FTL-TR

ATF1502AS-7AX44-T

A3P060-VQG100X7

KSZ8041TL-TR

PIC18LF8520T-I/PT

PIC18F8520T-I/PT

PIC18F8680T-I/PT

PIC18F8525T-I/PT

PIC18F442T-I/PT

PIC16F77T-I/PT058

PIC16F874AT-I/PT

PIC16F77T-I/PT

PIC16F747T-I/PT

PIC16F74T-I/PT

PIC18LF4420T-I/PT

PIC16F18055-I/SS

24FC256-I/SN

PIC16F18056-I/SS

DSPIC33CK64MP102-I/SS

DSPIC33CK32MP102-I/SS

24AA256UID-I/SN

PIC16F1823-I/ST

DSPIC33CK128MC106-I/PT

DSPIC33CK512MPT608-I/PT-TCSM

DSPIC33CK256MPT608-I/PT-TCSM

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PIC18F57K42-I/PT

DSPIC33EP128GP506-I/PT

DSPIC33EP128MC206-I/PT

DSPIC33EP128MC506-I/PT

MCP2003T-E/SN

25LC128T-E/ST

24AA64T-E/ST

PIC12F508T-E/SN

PIC32MX795F512HT-80V/MR

PIC32MX154F128DT-V/ML

PIC32MX174F256BT-V/MM

PIC32MX274F256BT-V/MM

PIC32MX254F128BT-V/MM

PIC32MX764F128HT-V/MR

PIC32MX170F256BT-V/ML

PIC32MX270F256BT-V/ML

QT6C16-ASG

ATMEGA32A-MUR

ATMEGA32-16MUR

ATXMEGA128D4-MHR

PIC24FJ128GB406-I/PT

PIC24FJ64GB406-I/PT

DSPIC33CK512MP608-I/PT

ATSAMC21J18A-AZT-SL3VAO

PIC16F15386T-E/PTVAO

ATSAME51N20A-AZTVAO

DSPIC33CK256MP506T-E/PTVAO-VW

ATSAMC21G15A-AZTVAO

PIC32MX110F016BT-V/ML

PIC32MX220F032BT-V/ML

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PIC32MX210F016BT-V/ML

PIC32MX440F512HT-80V/MR

PIC32MX440F128HT-80V/MR

PIC32MX420F032HT-40V/MR

PIC32MX320F064HT-80V/MR

PIC32MX320F032HT-40V/MR

TC1301B-FSAVMFTR

TC1302A-FFVMFTR

PIC16F917-E/ML

MCP632-E/MF

PIC12F617-E/MF

PIC12F609-E/MF

PIC16LF1828-E/ML

MCP3422A5-E/MC

PIC18F4420-E/ML

MCP3427-E/MF

PIC16F819-E/ML

PIC16F883-E/ML

MCP660-E/ML

MCP3426A6-E/MC

24LCS52-I/ST

24AA52-I/ST

PIC18LF25K22-I/SO

PIC16LF1512-I/SS

PIC32MX775F256H-80V/PT

PIC32MX575F512L-80V/PF

PIC32MX575F256L-80V/PF

PIC18F2520T-I/SOC01

PIC16CR620AT-04I/SO020

PIC16LF88T-I/SS

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MCP2022T-330E/ST

MCP2022PT-500E/ST

AVR16EB14T-E/ST

AVR16EB20T-E/SS

AVR16EB28T-E/SS

MCP2022PT-330E/ST

DSPIC33CK64MP102T-E/SSC01

MCP3008T-E/SL

24CS512T-E/ST

PIC16F15344T-E/SS

PIC16F15355T-E/SS

93LC46CT-E/SN

ATTINY3226-XFR

PIC16F1778T-E/SS

ATTINY426-XFR

ATTINY826-XFR

93LC56AT-E/SN

ATTINY1626-XFR

93LC66AT-E/SN

93LC66BT-E/SN

PIC18F27K42-I/ML

PIC18LF27K42-I/ML

PIC16F15256-I/STX

PIC16F15254-I/STX

PIC16F18346-I/ML

PIC32CM1216JH01032-I/RTB

PIC16F15255-I/STX

PIC16LF15375-I/PT

PIC16LF15376-I/PT

PIC32CM6408JH00064-I/V2X

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AVR128DB64-I/PT

PIC16F1716T-E/MVVAO

PIC16F15345T-E/MLVAO

PIC16F15345T-E/GZVAO

PIC16LF15345T-E/GZVAO

PIC16LF15325T-E/JQVAO

PIC16F1782T-E/MVVAO

PIC18F27Q43T-E/STXVAO

PIC18F25Q43T-E/STXVAO

PIC18F26Q43T-E/STXVAO

PIC16F15345T-E/6NVAO

PIC16LF15345T-E/6NVAO

PIC16LF18344T-E/6NVAO

PIC16F18345T-E/6NVAO

DSPIC33FJ32GP304T-I/ML

DSPIC33EP128GS702T-I/MM

DSPIC30F2010T-20I/MM

DSPIC33FJ64GP804T-I/ML

DSPIC33FJ128GP204T-I/ML

PIC32MX664F128HT-I/MR

PIC32MX664F064HT-I/MR

PIC32MX764F128HT-I/MR

DSPIC33FJ64MC204T-I/ML

DSPIC33FJ64MC804T-I/ML

DSPIC33FJ128MC204T-I/ML

DSPIC33FJ128MC804T-I/ML

PIC18F25K50T-E/ML020

PIC18F25K50T-E/ML022

MCP16501TA-E/RMB

MCP16501TB-E/RMB

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24LC02B-I/SN

PIC24F04KL100-I/ST

RE342S16F

PIC24F16KA302-I/SS

PIC24FV32KA302-I/SO

PIC24FJ16GA002-I/SO

PIC24F08KL200-I/ST

PIC24FV32KA302-I/SS

PIC24FV16KA302-I/SS

PIC24F16KA302-I/SO

PIC24F32KA302-I/SO

PIC24F32KA302-I/SS

24LC16B-I/SN

24AA16-I/SN

PIC16LF72-I/SO083

AVR32DD32T-I/PT

AVR16DD32T-I/PT

AVR64DD32T-I/PT

DSPIC33AK512MPS506T-I/PT

DSPIC33AK512MPS505T-I/PT

DSPIC33AK256MPS506T-I/PT

DSPIC33EP128MC206T-E/PT

DSPIC33EP32MC204T-E/PT

DSPIC33EP32GP504T-E/PT

DSPIC33FJ64GP804T-E/PT

DSPIC33FJ128GP204T-E/PT

DSPIC30F6015T-20E/PT

DSPIC30F6010AT-20E/PT

DSPIC33FJ64GS610T-E/PF

PIC32MK1024GPD100T-E/PT

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PIC32MK1024MCF100T-E/PT

PIC32MK0512GPE100T-E/PT

PIC32MK0512MCF100T-E/PT

PIC32MK0512GPD100T-E/PT

PIC32MK1024GPE064T-E/PT

PIC32MK1024GPD064T-E/PT

DSPIC33EP256MC206T-E/PT

DSPIC33FJ32GP304T-E/PT

DSPIC33FJ64MC204T-E/PT

MCP79400-I/STVAO

PIC16F636-I/STVAO

DSPIC33EV64GM102-I/SSVAO

DSPIC33EV32GM002-I/SSVAO

PIC16F18426-I/STVAO

PIC18F47K40-I/MV

PIC18F47K40-I/ML

MCP3426A2-E/MC

PIC16F1517-E/MV

MCP662-E/MF

MCP3426A5-E/MC

PIC12F752-E/MF

PIC18F4320-E/ML

MCP669-E/ML

PIC16F1519-E/MV

PIC18F2431-E/MM

MCP3426A7-E/MC

PIC16F1936-E/ML

PIC16LF1826-E/ML

PIC18F4680-E/ML

MCP4461-503E/ML

Date: Tuesday, July 22, 2025

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MCP4441-104E/ML

MCP4441-503E/ML

MCP4451-502E/ML

MCP4451-103E/ML

MCP4451-104E/ML

DSPIC33EP128MC504-H/ML

MCP8025T-115H/MP

MCP8025AT-115H/MP

MCP6C02T-020H/Q8B

DSPIC33EP32MC204T-I/ML

ZL88103LDF1

LE9641PQCT

DSPIC33EP512MC204T-I/ML

DSPIC33EP512GP504T-I/ML

PIC32MX150F256H-I/MR

DSPIC33EP32MC502-I/MM

PIC24EP32MC202-I/MM

PIC32MX150F128B-50I/ML

PIC32MX250F128B-50I/ML

PIC16F887-I/ML

PIC32MZ0512EFK064-I/MR

PIC32MZ1024EFE064-I/MR

PIC32MZ0512EFF064-I/MR

PIC32MZ1024EFF064-I/MR

PIC32MZ2048EFH064-250I/MR

PIC32MZ2048EFG064-I/MRL21

PIC32MZ0512EFE064-I/MR

PIC32MX150F128D-50I/ML

PIC12C508A-04E/SN

PIC12C509A-04E/SN

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ATTINY1624-XF

ATTINY3224-XF

AVR32DA28-E/SO

PIC12HV615-E/SN

PIC12F1822-E/SN

DSPIC33FJ06GS202-I/SO

DSPIC33FJ06GS102-I/SO

DSPIC33FJ16GS402-I/SO

DSPIC33FJ16GS502-I/SO

DSPIC33FJ16MC102-I/SS

DSPIC33FJ16GP102-I/SO

DSPIC33FJ16MC102-I/SO

PIC24FJ16MC102-I/SO

DSPIC33FJ64MC202-I/SO

DSPIC33FJ64MC802-I/SO

DSPIC33FJ128MC202-I/SO

PIC18LF14K50-I/SSC03

DSPIC33FJ128MC802-I/SO

PIC24FJ16MC102-I/SS

DSPIC30F2010-20I/SO

DSPIC30F2010-30I/SO

PIC16C717-I/SS

PIC16LC717-I/SS

ATSHA204A-MAHNK-T

ATSHA204A-MAHZH-T

DSPIC33EP128GP504T-I/ML

PIC24EP128GP204T-I/ML

PIC16F15213T-I/MF

PIC16F15214T-I/MF

ATSHA204A-MAH3C-T

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ATSHA204A-MAH3E-S

PIC18F57Q43T-I/6LX

ATSHA204A-MAHJV-T

ATSHA204A-MAHJW-T

AT28HC64B-90JU

AT27C256R-70JU

AT27LV020A-12JU

AT27C256R-45JU

AT27C512R-70JU

AT27C256R-70JU-306

AT27C512R-45JU

AT27C020-55JU

PIC32MX775F512H-80I/PT

PIC32MZ1024EFG100-250I/PT

PIC32MX575F512H-80I/PT

PIC32MX110F016D-I/PT

DSPIC33FJ32GP104-I/PT

PIC32MX350F128L-I/PF

DSPIC33AK128MC103T-H/M7

DSPIC33AK64MC103T-H/M7

DSPIC33AK32MC103T-H/M7

DSPIC33AK128MC106T-H/M7

DSPIC33AK64MC106T-H/M7

DSPIC33AK32MC106T-H/M7

DSPIC33EDV64MC205T-H/M7

PIC18F26K80T-H/MM

DSPIC33CK128MC105T-H/M7

DSPIC33FJ32MC204T-V/MLC21

PIC32MX170F256BT-V/ML020

PIC16LF1847-E/SS

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

MCP3426A7-E/SN

PIC16LF1826-E/SS

MCP3426A2-E/SN

MCP3428-E/ST

MCP3426A1-E/SN

PIC16LF1518-E/SO

PIC18F252-E/SO

MCP9843-BE/ST

MCP4821-E/SN

PIC16F1516-E/SS

DSPIC33CK64MP105T-E/PTC01

PIC16F887T-E/PT

DSPIC33AK128MC106T-E/PT

DSPIC33AK64MC106T-E/PT

DSPIC33AK32MC106T-E/PT

PIC16F917T-E/PT

ATSAMD21J17A-AZT

ATSAMD21J18A-AZT

DSPIC33EP128GS704T-E/PT

DSPIC33EP128GS804T-E/PT

DSPIC33EP64GS804T-E/PT

PIC32CM3204JH00048-I/U5B

ATTINY167-MU

ATTINY87-MU

ATMEGA164A-MU

ATMEGA164PA-MU

ATMEGA162-16MU

ATMEGA162V-8MU

AT89LP6440-20MU

AT89LP3240-20MU

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ATMEGA324PB-MU

ATMEGA32L-8MUA3

A3PN060-ZVQG100I

A3PN125-ZVQG100

A3PN125-ZVQG100I

PIC16LF1769-I/ML

PIC32CM1602GV00064-I/5LX

PIC32CM1602GV00048-I/U5B

PIC32CM1602GV00032-I/RTB

PIC32CM5164JH01064-I/5LX-SL3

PIC32AK3208GC41064-I/M7

PIC32AK3208GC41036-I/M7

PIC32AK1216GC41064-I/M7

PIC32AK6416GC41064-I/M7

PIC32AK3208GC41048-I/M7

PIC32AK1216GC41036-I/M7

PIC32AK6416GC41036-I/M7

PIC32AK1216GC41048-I/M7

PIC32AK6416GC41048-I/M7

AVR64DA48S-I/6MX

ZL30291BLDG1

AVR32DA32S-I/QZB

AVR64DA64S-I/5LX

AVR64DA32S-I/QZB

AVR32DA48S-I/6MX

PIC12F615-I/MD029

AVR32SD32-E/PT

PIC16F17574-E/PT

PIC16F17575-E/PT

PIC16F17576-E/PT

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AVR128DA32S-E/PT

AVR128DA48S-E/PT

AT32UC3C1256C-AUR

AT32UC3C1512C-AUR

PIC18F47Q10T-I/PT

AT32UC3C164C-AUR

AT32UC3C1256C-AURA0

PIC16LF722-I/ML

PIC18F45K20-I/MV

PIC18F25J11-I/ML

PIC18F24J11-I/ML

PIC18F24J50-I/ML

PIC18F26J11-I/ML

SY56011RMG-TR

LE9540DUQCT

LE9541CUQCT

SY54017RMG-TR

LE9541DUQCT

LE9540CUQCT

SY75572LMG-TR

SY58023UMG-TR

SY54011RMG-TR

SY89874AUMG-TR

SY84782UMG-TR

SY88932LMG-TR

SY58611UMG-TR

AT24C01D-MAHM-E

AT24C02D-MAHM-E

AT24C04D-MAHM-T

AT24C08D-MAHM-E

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25LC080DT-I/MNY

25LC160DT-I/MNY

25AA080DT-I/MNY

25AA160CT-I/MNY

PIC16LF1513-I/SS

24LC08B-I/SN

24AA08-I/SN

PIC18LF26K22-I/SSC03

93LC46A-I/ST

93AA46A-I/ST

PIC18LF25K22-I/SS

24AA08H-I/SN

PIC16LF1847-I/SO

24LC024-I/ST185

PIC18LF23K22-I/SS

PIC16F916-I/SS

PIC16F785-I/SS048

25AA160A-I/SN103

PIC16LF819-I/SSTSL

PIC18LF26J11-I/SS

PIC18LF25J11-I/SS

PIC18LF24J11-I/SS

PIC24FJ64GA202-I/SS

PIC16F1783-I/SO

25LC080A-I/ST

25AA080A-I/ST

25AA160B-I/ST

25LC160B-I/ST

25LC160A-I/ST

TC1302B-IAVMFTR

Date: Tuesday, July 22, 2025

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TC1301B-UPBVMFTR

TC1302A-ISVMFTR

PIC16F648AT-E/ML

TC1301A-UHAVMFTR

MCP1726T-1802E/MF

MCP1726T-5002E/MF

MCP1726T-ADJE/MF

PIC18LF57K42-I/PT

PIC18F45Q24-I/PT

PIC18F46Q24-I/PT

PIC18F55Q24-I/PT

PIC18F56Q24-I/PT

SY89295UTG

ATSAMC21J18A-AU-SL1

ATSAMC21J18A-AU-SL2

ATSAMC21J18A-AU-SL3

AVR32EB32-I/PT

AVR32SD32-I/PT

PIC16F17574-I/PT

PIC16F17575-I/PT

PIC16F17576-I/PT

PIC32MX230F128LT-I/PF

PIC32MX270F512LT-I/PF

PIC32MX534F064LT-I/PT

PIC24FJ256GA704T-I/PT

PIC24FJ128GA704T-I/PT

PIC24FJ128GA704T-I/PTC01

PIC24FJ256GA705T-I/PT

PIC32MX564F064LT-I/PT

PIC32MX664F128LT-I/PT

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PIC32MX664F064LT-I/PT

PIC32MX764F128LT-I/PT

PIC32MX564F128LT-I/PT

DSPIC33EP128MC204T-I/PTA3

PIC24FJ64GA704T-I/PT

PIC32MX764F128LT-I/PF

PIC32MM0256GPM064T-I/PT025

DSPIC33EP256MC206T-I/PT

PIC24FJ128GA705T-I/PT

ATSAMC20J15A-MMZ

ATSAMC21J15A-MMZ

PIC16F18444-E/GZ

PIC16F18445-E/GZ

PIC16LF18444-E/GZ

PIC16LF18445-E/GZ

PIC16LF18446-E/GZ

AVR16EB32-E/RXB

DSPIC30F6011AT-30I/PT

PIC24FJ128GA610T-I/PT

PIC32MX130F256DT-50I/PT

PIC32MX120F032DT-50I/PT

PIC32MX220F032DT-50I/PT

HA3200DT-I/PT

MTR6158-I/PT

ATMEGA8535-16MU

ATMEGA328PB-MU

ATSAMD21G16B-MZTVAO

ATSAMC21G18A-MZTVAO

ATSAMC20G17A-MZTVAO

MCP4161T-502E/MFVAO

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MCP632T-E/MFVAO

MCP4141T-104E/MFVAO

PIC18F57Q43T-E/6LXVAO

AVR128DA32T-E/RXBL10

PIC16LF18426T-E/JQVAO

ATA5291-GJQW

MCP3422A0T-E/MC

25AA160A-I/SN

25LC080B-I/SN

25AA080B-I/SN

93C46C-I/SN

93C56C-I/SN

93C56A-I/SN

93C56B-I/SN

PIC12LF1571-I/SN

PIC12LF1572-I/SN

PIC18LF25K83-I/SS

PIC18LF26K83-I/SS

PIC16LF648A-I/SS

PIC16F627A-I/SS

PIC32MX450F256L-I/PF

PIC32MX220F032D-I/PT

PIC32MX210F016D-I/PT

DSPIC33FJ64GS610-I/PF

DSPIC33FJ32GS610-I/PF

PIC32MX130F256D-I/PT

PIC32MX450F128L-I/PF

PIC32MK1024MCF064T-E/PT

PIC32MK0512GPE064T-E/PT

MCP6031T-E/MC

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PIC16F883T-E/ML

MCP632T-E/MF

11AA010-I/SN

PIC32MX170F256B-50I/SS

ATMEGA3208-XU

DSPIC33FJ16GS402-50I/SO

PIC16LF18446-I/SS

DSPIC33FJ16GP101-I/SS

DSPIC33FJ16MC101-I/SS

PIC24FJ16MC101-I/SS

DSPIC33FJ16MC102T-I/SS

PIC24FJ16MC102T-I/SS

DSPIC33FJ16GP102T-I/SO

PIC16F767T-I/SS

PIC32MX170F256BT-50I/SS

PIC32MX270F256BT-50I/SS

24AA044T-I/SN

PIC24HJ32GP202T-I/SO

DSPIC33FJ32MC202T-I/SO

DSPIC33FJ16MC102T-I/SO

DSPIC30F2010T-30I/SO

ATECC608A-TNGTLSU-G

PIC24HJ16GP304T-I/PT

PIC32MX250F128DT-I/PT

DSPIC30F6012AT-30I/PT

DSPIC30F6014AT-30I/PT

PIC32MX130F128LT-50I/PT

DSPIC33EP256GM306T-I/PT

DSPIC33EP256GM706T-I/PT

PIC18F87J50T-I/PT025

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PIC18F66K90T-I/PT

PIC18LF6490T-I/PT

PIC18LF6390T-I/PT

PIC16F59T-I/PT

MTCH6303T-I/PT

MTCH6301T-I/PT

PIC18F66K22T-I/PT

PIC18F65K22T-I/PT

PIC18F66K22T-I/PTRSL

PIC16LF15355-E/MV

PIC16F15344-E/ML

PIC24FJ1024GB606T-I/MR

PIC24FJ128GB606T-I/MR

PIC24FJ256GB606T-I/MR

ATSAMD21G15B-AU

ATMEGA164A-AU

PIC16F884-I/PTC02

DSPIC33EP512MC206-I/PT

DSPIC33EP512GP506-I/PT

PIC24FJ512GU408-I/PT

PIC24FJ128GL405-I/PT

PIC24FJ256GL405-I/PT

PIC24FJ512GL405-I/PT

PIC24FJ128GU405-I/PT

PIC24EP512MC206-I/PT

PIC24EP512GP206-I/PT

DSPIC33FJ16GS502T-I/SO

PIC16F687T-I/SS041

PIC16F687T-I/SS042

PIC16F18855-I/SS

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DSPIC33EP256GP502-I/SS

DSPIC33EP256MC202-I/SS

DSPIC33EP256MC502-I/SS

PIC24EP256GP202-I/SS

PIC18F67K90-E/PT

PIC18F67K22-E/PT

PIC24FJ128GL410-E/PT

DSPIC33CH128MP505T-E/PTVAO

24VL014H/ST

24VL014/ST

PIC16LF15344-E/ML

PIC16F15344-E/GZ

PIC16LF15344-E/GZ

PIC18F2455-I/SO

PIC18F2455-I/SOHXX

PIC16LF723-I/SO

24AA64F-I/SN

PIC32MX575F256L-80I/PF

PIC18F6627T-E/PT

PIC18F65K80T-E/PT

PIC24HJ128GP506A-H/PT

DSPIC33FJ128MC706A-H/PT

DSPIC33CK64MP206-H/PT

DSPIC33CK64MP506-H/PT

DSPIC33CK32MP206-H/PT

ATA5700F1000M-WDQW-VAO

SHA104-TFLXAUTHU-CZ

ECC204-MAV7W-T

ATSAML21G16B-MNT

ATSAML21G17B-MNT

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ATSAML21G18B-MNT

25AA160DT-I/MNY

25LC160CT-I/MNY

25LC080CT-I/MNY

25AA080CT-I/MNY

ATSAMG55J19A-MUT

ATSAMG55J19A-MUTN01

ATSAMG55J19B-MUT

ATSAMG55J19A-MUT-836

SY56216RMG-TR

SY88422LMG-TR

SY58609UMG-TR

SY58610UMG-TR

PIC16LF1554T-I/ML025

ATMEGA16U2-MUR

PIC16LF1509T-I/GZ

PIC18F45K20T-I/MV

PIC12F675T-E/SN091

PIC12F675T-E/SN

93LC56CT-E/SN

24LC02BT-E/SN

24LC16BT-E/SNA26

24LC256T-E/SN

24LC256T-E/SNRVE

PIC18F25K20T-E/SOC12

34LC02T-E/SN

34AA02T-E/SN

MCP2022AT-500E/ST

MCP2022AT-330E/ST

24LC128T-E/SN

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24LC04BT-E/SN

93LC56BT-E/SN

93LC56AT-E/ST

24LC08BT-E/SN

24LC014T-E/SN

24LC16BT-E/SN

93LC56CT-E/ST

93LC56BT-E/ST

24LC024T-E/SN

24LC025T-E/SN

24AA64T-E/SN

PIC12F609T-E/SN

PIC16HV785T-E/SS

PIC18LF2410T-I/ML

PIC16LF1823T-I/ML

93C76CT-I/MNY

93C46BT-I/MC

93LC86CT-I/MNY

93AA86CT-I/MNY

93LC46AT-I/MNY

PIC24HJ64GP204T-E/ML

PIC24HJ64GP504T-E/ML

PIC24HJ128GP204T-E/ML

MCP4341T-103E/ML

MCP4341T-104E/ML

MCP607T-I/SN

PIC16F610T-I/ST042

24LC01BHT-I/SN

24AA16HT-I/SN

MCP42050T-I/ST

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MCP3208T-BI/SL

93C76BT-I/ST

PIC16LF1906T-I/SS

PIC16F1847T-I/SS

93C76AT-I/ST

93LC76AT-I/ST

PIC18F13K50T-I/SS021

24FC64FT-I/SN

MCP6022T-I/ST

24LC04BT-I/SN

PIC16LF1554T-I/STM10

MCP2200T-I/SS040

PIC16LF627AT-I/SS031

PIC16LF627AT-I/SS032

PIC16F17124T-I/ST

PIC16F17125T-I/ST

PIC16F17144T-I/SS

PIC16F17126T-I/ST

PIC16F17145T-I/SS

PIC16F18145T-I/SS

PIC16F17146T-I/SS

PIC18F04Q40T-I/ST

PIC18F05Q40T-I/ST

MCP48CVB08-E/ML

ATSAMD21E16L-MF

ATSAMD21E15L-MF

PIC16F1719-E/MV

PIC16F1717-E/MV

ATMEGA808-MF

PIC24FJ32GU202-E/ML

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PIC24FJ64GP202-E/ML

PIC24FJ32GP202-E/ML

MCP47CMB18-E/ML

MCP47CMB28-E/ML

PIC24FJ64GU202-E/ML

PIC12LF1612-E/SN

ECC204-MAV8V-T

ATSAMD20E16A-MNTA2

PIC32MX450F256HT-120/MR

PIC16LF1559T-E/MLM10

DSPIC33EV32GM102T-E/MM

PIC16F15225T-E/MG

24CS128T-E/Q4B

PIC32CM2532JH01048T-E/U5B-SL3

PIC32CM2532JH01064T-E/5LX-SL3

AVR32SD32T-E/QZB

AVR128DA32ST-E/QZB

AVR128DA48ST-E/6MX

PIC16F15213T-E/MF

PIC18F46K22T-E/MVC01

ATA6561-GBQW-NFM1

DSPIC33FJ32MC202T-E/MMC01

PIC16LF1508T-E/ML

DSPIC33EP32GP502-E/SS

MCP6499-E/ST

PIC16F876A-E/SS

PIC32MX154F128BT-I/MM

DSPIC33FJ12MC202T-I/ML

PIC32MX254F128BT-I/MM

DSPIC33FJ12GP202T-I/ML

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PIC32MM0064GPL020T-I/ML

PIC32MM0016GPL028T-I/ML

PIC32MM0032GPL028T-I/ML

PIC32MM0064GPL028T-I/ML

PIC32MM0016GPL020T-I/ML

PIC32MM0032GPL020T-I/ML

PIC32MX254F128DT-I/ML

HA7619T-I/MM028

PIC32MX110F016BT-I/ML

PIC32MX220F032BT-I/ML

PIC32MX210F016BT-I/ML

ATMEGA328P-MUR

HV5523K7-G-M933

PIC32MX120F032DT-I/ML

PIC32MK1024MCF064T-I/MR

DSPIC30F2023T-30I/ML

PIC32MX110F016DT-I/ML

PIC32MX220F032DT-I/ML

PIC32MX210F016DT-I/ML

PIC24HJ64GP202T-I/MM

MCP3901A0T-I/ML

PIC32MK0512GPE064T-I/MR

PIC32MK0512GPD064T-I/MR

DSPIC33FJ32MC304-E/ML

PIC32MK0512GPD064-E/MR

PIC24FJ16MC102-E/ML

PIC32MK0512MCF064-E/MR

PIC32MZ1024EFG064-E/MR

PIC32MZ1024EFH064-E/MR

PIC32MZ1024EFK064-E/MR

Date: Tuesday, July 22, 2025

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PIC32MZ1024EFM064-E/MR

SY89295UTG-TR

AVR32SD32T-I/PT

PIC16F17574T-I/PT

PIC16F17575T-I/PT

DSPIC33EV64GM106-I/PT

DSPIC33EV32GM006-I/PT

DSPIC33EV32GM106-I/PT

ATF1504ASV-15AU100

ATSAMD20J15B-AU

ATSAMD20J14B-AU

ATSAMD20J16B-AU

DSPIC33EV256GM006-I/PT

DSPIC33EV256GM106-I/PT

ATSAML11E16A-AUKPH

DEC1515H-D0-I/Z2

PIC16F1779-I/PTC01

PIC32MZ1024EFE100-I/PF

PIC32MZ1024EFF100-I/PF

PIC32MZ1024EFG100-I/PF

ATF1504ASL-25AU100

ATF1504AS-10AU100

PIC32MX130F128L-I/PF

PIC32MZ2048EFH100-250I/PF

PIC32MZ0512EFK100-I/PF

PIC32MZ2048EFG100-I/PF

PIC32MZ0512EFE100-I/PF

PIC32MZ0512EFF100-I/PF

PIC32MX150F256L-I/PF

PIC32MX170F512L-I/PF

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PIC32MZ1024EFM100-I/PF

PIC16F13123-E/ST

PIC16F13124-E/ST

PIC16F13125-E/ST

PIC16F13143-E/SS

PIC16F13144-E/SS

PIC16F13145-E/SS

PIC16F19156-E/SS

PIC16LF19155-E/SS

PIC16LF19156-E/SS

PIC16F15355-E/SS

PIC16LF15354-E/SS

PIC16LF15355-E/SS

PIC16LF15324-E/ST

PIC16F15344-E/SS

PIC16LF15344-E/SS

PIC16F18024-E/ST

DSPIC33EV32GM002-H/MM

DSPIC33EV32GM102-H/MM

DSPIC33EV64GM106-H/MR

DSPIC33EV128GM004-H/ML

DSPIC33EV64GM004-H/ML

DSPIC33EV64GM104-H/ML

DSPIC33EP64GP502-H/MM

DSPIC33EP64MC202-H/MM

DSPIC33EP64MC502-H/MM

DSPIC33EP128MC206-H/MR

DSPIC33EP128MC506-H/MR

PIC24EP128GP206-H/MR

DSPIC33CK1024MP406T-I/MR

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DSPIC33CK1024MP706T-I/MR

DSPIC33CK512MP406T-I/MR

DSPIC33CK512MP706T-I/MR

DSPIC33CK256MP406T-I/MR

DSPIC33CK256MP706T-I/MR

KSZ9031RNXIC-TR

PIC16F18055T-I/STX

UTC2000T-I/MG

PIC16F676T-I/ML

PIC16F684T-I/ML065

PIC16F684T-I/ML

MTCH108T-I/GZ

PIC16LF1559T-I/GZ

PIC16F1615T-I/ML

MCP2221T-I/ML

MCP2221AT-I/ML

PIC16F1454T-I/ML

PIC16F1455T-I/ML

PIC16F1619T-I/GZ

PIC16LF1619T-I/GZ

PIC16F1618T-I/GZ

PIC16LF1618T-I/GZ

PIC32MK1024MCM100-I/PTN01

ATSAMD20G16B-AN

ATSAMD20J18A-AN

ATSAMD20J17A-AN

ATSAMD20J16A-AN

ATSAMD20J15A-AN

ATSAMD20J14A-AN

ATSAMD20J16B-AN

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24AA256-I/ST

MCW1001A-I/SS

PIC24FJ32GA102-I/SO

24LC08B-I/STRVE

24AA08-I/ST

PIC32MX130F064B-V/ML

PIC32MX150F128BT-V/ML

PIC32MX130F064BT-V/ML

PIC32MX250F128BT-V/ML

PIC32MX664F064HT-V/MR

PIC32MX230F064BT-V/ML

PIC32MX150F128DT-V/ML

PIC32MX564F128HT-V/MR

PIC32MX534F064HT-V/MR

PIC32MX564F064HT-V/MR

PIC32MX664F128HT-V/MR

PIC32MX350F256HT-V/MR

PIC32MX450F256HT-V/MR

PIC32MX120F032DT-V/ML

PIC32MX110F016DT-V/ML

PIC32MX120F032BT-V/ML

PIC18F45J50-I/PT

PIC18F8310-I/PT

ATMEGA168PA-15MZ

PIC18F25K80T-E/MMVAO

DSPIC33EV32GM002T-E/MMVAO

ATMEGA88PA-15MZ

ATTINY167-A15MZ

ATA6617C-P3QW-1

ATA6616C-P3QW-1

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ATA6564-GBQW1

ATA6566-GBQW1

PIC18F26K80T-E/MMVAO

PIC16F1788T-E/MLVAO

PIC16F18325T-E/7NVAO

DSPIC33CK128MC106-H/PT

TC7107CKW

PIC16F877-20/PQ

PIC16LF877-04/PQ

DSPIC33CK256MC506-I/MR

DSPIC33CK128MC506-I/MR

DSPIC33CK256MC106-I/MR

LE87286NQC

PIC16F1786-I/ML

PIC24FJ256DA206-I/MR

PIC24FJ128DA206-I/MR

PIC24FJ128DA106-I/MR

USB5744B-I/2GX01

PIC24FJ256GB206-I/MR

PIC24FJ128GB206-I/MR

PIC16F1527-I/MR

USB5742B-I/2G

PIC16F1526-I/MR

USB5742B-I/2GX01

PIC16LC65B-04/PQ

PIC16F877-04/PQ

TC7107ACKW

TC7116CKW

PIC32MX250F128DT-50I/PT

PIC32MX460F512LT-80I/PT025

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ATSAMD20G18A-AUT

ATSAMD20G17A-AUT

PIC32MZ1024ECH100T-I/PF

PIC32MZ2048ECH100T-I/PF

PIC32MZ1024ECH100T-I/PT

PIC24FJ256GA108T-I/PT042

PIC32MZ2048ECM100T-I/PF

PIC32MZ2048ECH100T-I/PT

DSPIC33AK64MC105T-I/PT

DSPIC33AK32MC105T-I/PT

AVR16EA48T-I/PT

ATSAMD51N19A-AUT

PIC16LF627A-I/SS

25AA128-I/ST

PIC16LF1828-I/SS

PIC16LF1828-I/SSC01

25LC128-I/ST

PIC16F628A-I/SS

PIC16LF628A-I/SS

25AA080A-I/SN

25LC160B-I/SN

25AA160B-I/SN

25LC080A-I/SN

PIC18LF2580-I/SOC01

PIC16F18145-E/6N

PIC16F17124-E/7N

PIC16F18124-E/7N

PIC16F17125-E/7N

PIC16F18125-E/7N

PIC16LF15376-E/MV

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MCP1602-330I/MF

MCP1602-ADJI/MF

MCP1602-FIXI/MF

MCP73834-B6I/MF

MCP73834-CNI/MF

MCP73834-FCI/MF

MCP73831-2ACI/MC

PIC12F609-I/MD

PIC16F913-I/ML

PIC18F46K20-E/PT

PIC32MK0512GPG064T-E/R4X

PIC32MK0256MCJ064T-E/R4X

PIC32MK0256GPG064T-E/R4X

ATTINY1617-MFR

AT8UA068CF1-PNRZ

PIC32CM2532LE00048T-E/U5B

PIC32CM2532LS00048T-E/U5B

MCP1726T-0802E/MF

MCP1726T-2502E/MF

MCP1726T-3002E/MF

MCP1726T-3302E/MF

MCP2561-E/MF

MCP2561FD-E/MF

MCP2562-E/MF

MCP2562FD-E/MF

PIC16F1618-E/ML

PIC16F1503-E/MG087

PIC16F1503-E/MG

PIC16F18855-E/ML

ATSAMD21J17A-MMF

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ATXMEGA128A4U-MHR

ATECC608B-MAH7Z-T

AVR32DB48T-I/6LX

ATXMEGA64D4-MHR

AVR128DB48T-I/6LX

AT42QT5480-MUR

AT42QT18C15-MUR

PIC32CM3204GV00048-E/U5B

WP300TX01-I/ML02C01

LAX9253-I/R4X

LE9530CPQC

LE9530DPQC

ATMEGA88PA-MU

AVR32DA32-I/RXB

PD69210R-035500

PIC16F18075-I/MP

PIC16F1455-I/JQ

ATSAML21J18B-MMU

PIC16LF1518-I/MV

PIC16LF1517-I/MV

PIC16LF1519-I/MV

AVR64DD32-I/RXB

SYA75604BTWL-TRVAO

ATSAMHA0E15A-MZT-BVAO

ATSAMHA0E14A-MZT-BVAO

ATSAMHA0E16A-MZT-BVAO

ATSAMHA1E16A-MBT-BVAO

ATTINY3217-MBT-VAO

ATSAMDA1E14B-MBTVAO

ATSAMDA1G16B-MBTVAO

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SYA75608TWL-TRVAO

SYA75612TWL-TRVAO

ATMEGA88-15MT1

ATSAMHA0G16A-MZT-BVAO

PIC18F26J50-I/ML

PIC18LF2221-I/ML

PIC18F2221-I/ML

PIC18LF1320-I/ML

DSPIC33CH512MP208-E/PT

DSPIC33CH256MP218-E/PTC02

DSPIC33CH256MP208-E/PTC04

DSPIC33CH512MP208-E/PTC05

DSPIC33CH256MP508-E/PT

DSPIC33CH256MP208-E/PT

DSPIC33EP64MC204-E/PT

DSPIC33EP64MC504-E/PT

PIC24EP64MC204-E/PT

DSPIC33EP64MC206-E/PT

DSPIC33EP64MC506-E/PT

PIC16F18875-E/PT

PIC24EP64MC206-E/PT

ATSAMD51N19A-AF

UCS4002T-E/6NVAO

DSPIC33FJ16MC304-E/PT

DSPIC33EP64GP504-E/PT

DSPIC33FJ32GS610-E/PT

DSPIC33FJ64GS610-E/PT

PIC32MK1024MCF100-E/PT

ATSAML21G18B-MNT-SLL

ATSAML21G17B-MNT-SLL

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PD69101ILQ-13155TR

LAN9253T-V/R4X

LAX9253T-V/R4X

ATSAMC21E16A-MNTS2

ATSAMC21G18A-MNT

ATSAMC21G16A-MNTS2

ATECC608C-MAVDA-S

ATECC608C-MAVDA-T

RE46C305Q16T

ATECC608C-MAV8K-T

KSZ8051RNLV-TR

ATECC608C-MAV8O-T

PIC32MX130F064D-I/PTF21

PIC32MX130F064D-I/PTF22

PIC24HJ16GP304-I/PT

PIC24HJ32GP204-I/PT

DSPIC33FJ16GP304-I/PT

DSPIC33FJ256MC710A-I/PT

MCP23016T-I/SO

PIC32MX564F128L-V/PF

PIC32MX534F064L-V/PF

PIC32MX330F064L-V/PT

PIC32MX430F064L-V/PT

PIC32MX450F128L-V/PF

PIC32MX764F128L-V/PF

PIC32MX430F064L-V/PF

PIC32MX564F064L-V/PF

PIC32MX664F128L-V/PF

PIC32MX664F064L-V/PF

PIC32MX330F064L-V/PF

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PIC32MX450F256L-V/PT

ATSAMD20G14A-AN

ATSAMD20G15A-AN

ATSAMD20G16A-AN

ATSAMD20G17A-AN

ATSAMD20G18A-AN

PIC32MX664F064L-V/PT

PIC32MX764F128L-V/PT

PIC32MX340F256H-80V/PT

PIC32MX320F128H-80V/PT

PIC32MX320F064H-40V/PT

PIC32MX530F128L-V/PT

PIC32MX250F256L-V/PT

PIC32MX230F128L-V/PT

PIC32MX550F256L-V/PT

PIC32MX150F256L-V/PF

PIC32MX150F256L-V/PT

PIC32MX170F512L-V/PT

PIC32MX130F128L-V/PT

PIC32MX170F512L-V/PF

PIC32MX270F512L-V/PF

ATMEGA324PA-MUR

ATMEGA324A-MUR

ATMEGA164PV-10MUR

ATMEGA164P-20MUR

ATSAMD21E17A-MUT-MB

PIC16LF15386T-I/6LX

PIC16LF15356T-I/ML

AVR128DA48T-I/6LX

AVR128DA64T-I/MR

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AVR128DA32T-I/RXB

ATSAMD21G17D-MUT

ATMEGA1284P-MUR

ATMEGA1284-MUR

25AA320A-I/ST

25LC080D-I/ST

PIC16LF1782-I/SS

24FC64-I/SN

24LC02B-I/SNA32

PIC18F25J50-I/SS030

93C46A-I/ST

24LC32AF-I/SN

PIC16LF627-04I/SS

PIC16C771-I/SS

MCP2150-I/SSRVB

LE9651PQCT

LE9652PQCT

LE9643AQCT

LE9653AQCT

SY58051AUMG-TR

SY58052AUMG-TR

SY88053CLMG-TR

SY88349NDLMG-TR

SY89874UMG-TR

SY88149NDLMG-TR

SY89833ALMG-TR

SY89230UMG-TR

DSPIC33EP64GS504T-E/PTB3

DSPIC33EP64GS504T-E/PTC13

DSPIC33EP64GS504T-E/PT

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PIC18F14Q40-E/SS

PIC18F15Q40-E/SS

PIC16F17524-E/ML

PIC16F17525-E/ML

PIC16F17526-E/ML

PIC32CM6408JH00048-E/U5B

PIC32CM6408JH00032-E/RTB

PIC32CM6408JH00064-E/5LX

DSPIC33FJ64MC506A-I/PTVAO

PIC18F66K80-I/PTVAO

PIC18F65K80-I/PTVAO

PIC18F45K80-I/PTVAO

DSPIC33EP64GS502T-I/MMC07

PIC24EP128MC206-H/MR

DSPIC33EP128MC204-H/ML

PIC18LF4320-I/ML

PIC18F4320-I/ML

PIC18F4410-I/ML

PIC18F25J50-I/ML

PIC16LF727-I/ML

PIC16LF819-I/ML

PIC16F722A-I/ML

PIC18F2331-I/MM

MCP73871-1CAI/ML

PIC18F24K20-I/ML

PIC10F200-I/MC

PIC10F202-I/MC

PIC16LF1826-I/ML

PIC16F1519-I/MV

PIC12F752-I/MF

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PIC18F4221-I/ML

PIC16F723A-I/ML

PIC16F727-I/ML

PIC16F1947-I/MR

MCP2515-I/ML

PIC12HV752-I/MF

PIC16LF1937-I/MV

PIC18LF2410-I/ML

PIC12F615-I/MF

PIC18F2480-I/MLC01

PIC16LF1934-I/ML

PIC18F46J13-I/ML

PIC18F45Q10T-I/PTC02

PIC18F45Q10T-I/PT

PIC24FJ128GL306T-I/PT

PIC24FJ64GL306T-I/PT

PIC18F46Q10T-I/PT

DSPIC33CH64MP508T-I/PT

PIC16LF15376T-I/PT

PIC18F25K83-I/SS

PIC18F26K83-I/SS

DSPIC33FJ12GP202-I/SO

AR1020-I/SS

AR1011-I/SS

AR1021-I/SS

DSPIC33EP32MC502-I/SS

PIC32CM2532LE00100T-E/PF

DSPIC33CH512MP506T-E/PT

DSPIC33CH512MP206T-E/PT

DSPIC33CH256MP506T-E/PT

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AVR32DA48T-E/PT

PIC32CM2532LS00100T-E/PF

DSPIC33CH256MP206T-E/PT

ATSAMD21G17A-AFT

ATSAMD21G18A-AFT

ATMEGA3208-AFR

PIC32MK0512MCJ064T-E/PT

PIC32MK0512GPG064T-E/PT

PIC32MK0256MCJ064T-E/PT

PIC32MK0256GPG064T-E/PT

DSPIC33CH128MP215T-E/PTC01

LE87612MQCT

RE354Q16T

RE355Q16T

PIC32MX174F256DT-V/ML

PIC32MX274F256DT-V/ML

PIC32MX370F512HT-V/MR

PIC32MX470F512HT-V/MR

PIC32MX220F032DT-V/ML

PIC32MX210F016DT-V/ML

PIC32MX254F128DT-V/ML

PIC32MX775F512HT-80V/MR

PIC32MX775F256HT-80V/MR

PIC32MX575F512HT-80V/MR

PIC32MX154F128BT-V/MM

PIC32MX575F256HT-80V/MR

PIC32MX695F512HT-80V/MR

PIC32MX675F512HT-80V/MR

PIC32MX675F256HT-80V/MR

PIC16F15323-I/JQ

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC18F14K50-I/MQ048

PIC32MX350F128H-I/MR

PIC32MX450F128H-I/MR

PIC32MK0256MCJ064-I/R4X

PIC18F46K40-I/ML

PIC18LF45K40-I/ML

DSPIC33EP64GS402-I/MMC02

PIC18LF26K40-I/MV

PIC18F45K40-I/MV

DSPIC33CK512MP305-I/M7

PIC18LF45K40-I/MV

PIC16F15274-I/MP

PIC16F15275-I/MP

PIC16F15276-I/MP

DSPIC33EP32GS402-I/MMC01

24LCS52-I/MC

24AA52-I/MC

PIC18LF24K42-I/ML

PIC18F24K40-I/ML

PIC18F25K42-I/MV

PIC18LF24K42-I/MV

PIC18LF25K42-I/MV

PIC16LF18325-E/JQVAO

PIC16F18855-E/MVVAO

PIC16F18324-E/JQVAO

PIC16F18857-E/MLVAO

ATSAMD51N19A-AUT-EFP

AT32UC3A1512-AUR

ATECC608A-MAH2B-T

ATECC608A-MAH2G-S

Date: Tuesday, July 22, 2025

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ATECC608A-MAH2G-T

ATECC608A-MAH2K-S

PIC18LF25K22-I/ML

SY89112UMY

DSPIC33EP128GP502-I/MM

PIC18LF24K22-I/ML

PIC16LF1508-I/ML

PIC16LF1509-I/ML

DSPIC33EP128MC202-I/MM

PIC32MX775F256L-80I/PF

PIC32MZ2048EFH100-250I/PT

PIC32MX150F128D-I/PT

PIC32MX120F032D-50I/PT

PIC32MX220F032D-50I/PT

PIC16F17174-E/MP

PIC16F18174-E/MP

PIC16F17175-E/MP

PIC16F18175-E/MP

AVR64DD28-E/STX

PIC16F17156-E/STX

PIC16F18156-E/STX

MCP4162-502E/MF

MCP4151-104E/MF

PIC12F615-E/MD

MCP4132-104E/MF

MCP4132-503E/MF

MCP3422A1-E/MC

MCP3422A2-E/MC

MCP4251-104E/ML

PIC18F44J11-I/PT

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PIC18F66K80-I/PTREL

PIC18F4580-I/PT

PIC18LF4685-I/PT

PIC18F4685-I/PT

PIC18F46J11-I/PT

PIC18F45J11-I/PT

MCP6494T-E/STVAO

MCP6484T-E/STVAO

MCP6474T-E/STVAO

PIC18LF46K42-E/PT

PIC18F46K42-E/PT

DSPIC33FJ32MC204-E/PT

PIC18F47K42-E/PT

PIC18LF47K42-E/PT

DSPIC33CK1024MP706-E/PT

DSPIC33CK1024MP705-E/PT

ATSAMD21E17D-AF

ATSAMD21E17D-AZ

DSPIC33CK1024MP406-E/PT

93C46BT-I/SN

AT24CM01-XHM-T

PIC16F1938T-I/SS038

93C46AT-I/SN

AT24CM01-XHD-T

PIC12F683T-I/SN101

PIC16LF18326T-I/ST

PIC16F18346T-I/SSC03

MCP4562T-502E/MF

MCP4562T-103E/MF

MCP4562T-104E/MF

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MCP4911T-E/MC

MCP4811T-E/MC

MCP4901T-E/MC

TC1301A-FHAVMFTR

MCP9804T-E/MCBBB

PIC32MX450F128H-V/MR

ATTINY1617-MN

ATTINY807-MN

ATTINY1607-MN

ATTINY3217-MN

RE46C422V32

ATTINY261A-MN

LE87511NQC

LE87502MQC

ATTINY417-MN

ATSAMD20E14A-MN

ATSAMD20E15A-MN

ATSAMD20E16A-MN

ATSAMD20E16A-MNA2

ATSAMD20E17A-MN

ATSAMD20E18A-MN

ATSAMD20J16B-MMN

ATSAMD20J14B-MMN

ATSAMD20J15B-MMN

ATSAMD20J14A-MMN

ATSAMD20J18A-MMN

AT89C5115-SISUM

ATMEGA8535L-8JU

PIC16F1579T-I/GZ

PIC16LF1826T-I/SS

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MCP3202T-CI/ST

PIC18F25K20T-I/SO

PIC18F24K20T-I/SO

PIC16F628AT-I/SO

PIC16LF1518T-I/SO

PS501T-I/SSC01

PIC16C622AT-04I/SO092

PIC18F25J10T-I/SO

PIC18F26J50T-I/SS

ATXMEGA32C3-ANR

ATXMEGA32D3-ANR

ATXMEGA64C3-ANR

PIC32MX350F256HT-V/PT023

ATSAMDA1J16B-ABT

ATSAMDA1J15B-ABT

ATSAMDA1J14B-ABT

ATSAMC20J17A-ANT

PIC32MX370F512HT-V/PT

PIC32MX470F512HT-V/PT

TC7106ACKW713

TC7107ACKW713

TC7116CKW713

TC7107CKW713

TC7106CKW713

TC7109CKW713

TC7117ACPT713

TC7107ACPT713

TC7117CPT713

TC7106CPT713

PIC32MX350F256H-I/PT

Date: Tuesday, July 22, 2025

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PIC32MX350F128H-I/PT

PIC24FJ256GA106-I/PT031

ATMEGA644A-AU

ATMEGA644PA-AU

PIC24FJ256GU405-I/PT

PIC24FJ512GU405-I/PT

PIC24EP256GU810-I/PF

PIC32MX564F064L-I/PF

DSPIC33FJ32MC104-I/PT

PIC24FJ32MC104-I/PT

PIC32MX664F128L-I/PF

PIC16F1716T-I/ML

PIC16F18855T-I/ML

PIC16F527T-I/ML

PIC16F689T-I/ML

PIC16F15275T-I/MP

PIC16F15276T-I/MP

ATECC608A-MAHDA-S

PIC16F677T-I/ML

PIC16F631T-I/ML

PIC16LF1559T-I/ML

PIC18LF14K22T-I/ML

PIC18LF13K22T-I/ML

PIC16F1503T-I/MG029

PIC16F1503T-I/MG030

PIC16F1503T-I/MG031

PIC16F1503T-I/MG032

PIC16F1503T-I/MG035

PIC18LF23K22T-I/ML021

PIC18LF23K22T-I/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F18855T-I/ML021

PIC16LF18855T-I/ML

LAN9252TI/ML

PIC16LF1554T-I/ML023

PIC16F18146T-I/6N

PIC16F18144T-I/6N

PIC16F18145T-I/6N

PIC16F18126T-I/7N

PIC16F18124T-I/7N

PIC16F636T-I/ML

PIC16F18125T-I/7N

PIC16F18114T-I/MD

PIC16F18115T-I/MD

ATSAMC20G17A-MUTS2

ATSAMC21G18A-MUT64

ATSAMC21E18A-MUT64

PIC16LF1827T-I/ML

PIC16LF1827T-I/MV

PIC16LF1454T-I/JQ

PIC16LF1455T-I/JQ

KSZ8081RNAIA-TR

KSZ8081RNDIA-TR

KSZ8091RNAIA-TR

KSZ8091RNDIA-TR

SPNY801142-TR

SPNY801143-TR

SPNY801147-TR

PIC16F18026T-I/ML

PIC16LF1823-I/JQ

SY58021UMG

Date: Tuesday, July 22, 2025

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PIC16F15345-I/GZ

PIC16LF15345-I/GZ

PIC16LF15325-I/JQ

PIC18LF26K22-I/ML

PIC32MX575F512LT-80I/PF

PIC16F18345-E/SS022

AVR128DA28-E/SS

PIC16LF15323-E/ST

PIC16LF1768T-I/ML

PIC32MX575F256HT-80I/PT

DSPIC33FJ256MC510T-I/PT

DSPIC33FJ256MC710T-I/PT

PIC16F18323T-E/JQ

PIC18F47Q84T-E/NHX

PIC18F26Q43T-E/STX

MCP2561T-E/MF

24LC64T-E/MNY

24AA64T-E/MNY

MCP2561FDT-E/MF

24LC64FT-E/MNY

MCP2562T-E/MF

PIC32MX320F032HT-40V/PT

PIC32MX340F512HT-80V/PT

PIC32MX440F512HT-80V/PT

PIC32MX440F128HT-80V/PT

SY89231UMG

SY89842UMG

ATECC608A-MAHMD-B

ATECC608A-MAHT2-B

PIC16F1829-I/ML

Date: Tuesday, July 22, 2025

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PIC32MK0512GPE100-E/PT

PIC32MK0512GPD100-E/PT

DSPIC33FJ64GS608-E/PT

DSPIC33FJ32GS608-E/PT

PIC24HJ64GP204-E/PT

PIC32MK0512MCF100-E/PT

PIC32MK1024MCF064-E/PT

PIC32MK1024GPE064-E/PT

PIC32MK1024GPD064-E/PT

DSPIC33FJ64GS610-E/PF

PIC24FJ512GU405-E/PT

PIC32MZ0512EFE100-E/PF

PIC32MZ0512EFF100-E/PF

PIC32MZ0512EFK100-E/PF

DSPIC30F4011-20E/PTA22

PIC32MZ1024EFE100-E/PF

PIC32MZ1024EFF100-E/PF

PIC32MZ1024EFG100-E/PF

PIC32MZ1024EFH100-E/PF

PIC32MZ1024EFK100-E/PF

PIC32MZ1024EFM100-E/PF

PIC32MZ2048EFG100-E/PF

93C56AT-E/ST

93C56BT-E/ST

MCP47FEB22A1T-E/ST

PIC18F25Q71T-I/SS

AVR64DA28T-I/SS

AVR64DA28T-I/SO

PIC16F1765T-I/ST

AVR16EA28T-I/SS

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PIC16F15256T-I/SSC01

PIC16F1764T-I/ST

PIC18F442-I/L

PIC16F74-I/L

AY0438-I/L

PIC32CM2532LE00064T-E/5LX

PIC32CM2532LS00064T-E/5LX

ATSAMD21G17A-MFT

ATSAMD21G18A-MFT

PIC32MK1024MCM064T-E/MR

PIC32MK0512MCM064T-E/MR

PIC32MK1024GPK064T-E/MR

ATSAMD21J18A-MMZT

PIC32MK0512GPK064T-E/MR

DSPIC33FJ16GS502T-E/MM

ATSAMD21J17D-MMZT

ATMEGA4809-MFR

ATSAMD21E18A-MFT

ATSAMD21E17A-MFT

ATSAMD21E15A-MFT

PIC18F26Q83T-E/5N

PIC18F27Q84T-E/5N

PIC16F15356T-E/MV

MCP23S08T-E/ML

24FC04T-E/Q4B

PIC16F876A-I/ML

SYA75603BTWLVAO

SYA75604BTWLVAO

ATTINY3217-MB-VAO

SYA75608TWLVAO

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SYA75612TWLVAO

EQCO510C0-V/REL

EQCO510C0-V/6NXVAO

PIC16F616-H/ST

DSPIC33EV128GM002-H/SS

PIC32MK0128MCA028-E/N2X

PIC16F1765-E/ST

PIC16F1764-E/ST

AVR128DB28-E/SO

AVR64DB28-E/SO

PIC16F17146-E/SS

DSPIC33EV128GM102-H/SS

DSPIC33EV64GM002-H/SS

DSPIC33EV64GM102-H/SS

PIC32MX250F256LT-V/PT

PIC32MX230F128LT-V/PT

PIC32MX270F512LT-V/PT

PIC32MX695F512HT-80V/PT

PIC32MX675F512HT-80V/PT

PIC32MX675F256HT-80V/PT

PIC32MX550F256LT-V/PT

PIC32MX250F256HT-V/PT

PIC32MX230F128HT-V/PT

PIC32MX270F512HT-V/PT

PIC32MX795F512HT-80V/PT

PIC32MX530F128LT-V/PT

PIC32MX570F512LT-V/PT

PIC32MX564F064LT-V/PT

PIC32MX664F128LT-V/PT

PIC32MX170F512LT-V/PF

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PIC32MX150F256LT-V/PF

PIC32MX664F064LT-V/PT

PIC32MX764F128LT-V/PT

PIC32MX130F128LT-V/PF

PIC32MX220F032DT-V/PT

PIC32MX210F016DT-V/PT

PIC32MX775F256HT-80V/PT

PIC32MX575F512LT-80V/PTC22

PIC32MX250F256LT-V/PF

PIC32MX230F128LT-V/PF

PIC16F18877-E/MVVAO

MCP3912A1-E/MQVAO

DSPIC33EP32GS502-E/MMVAO

PIC16F1519-E/MVVAO

PIC16F18856-E/STXVAO

PIC18F25K40-E/MLVAO

PIC16F1779-E/NHXVAO

PLA133-97QAVAO

MCP25625-E/MLVAO

DSPIC33EP32MC202-E/MMVAO

PIC18F26K42-E/MLVAO

DSPIC33EV256GM104-E/MLVAO

DSPIC33EP128GS804-E/MLVAO

PIC18F26K42-E/ML510

PIC18LF46K40-E/MVVAO

DSPIC33EV64GM102-E/MMVAO

PIC16F18326-E/7NVAO

SY89230UMG

SY58019UMG

SY58051AUMG

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PIC16F18326-I/JQ

SY88992LMG

SY54023RMG

SY58610UMG

SY58611UMG

SY56216RMG

SY56011RMG

SY56017RMG

SY56020RMG

SY56020XRMG

SY56023RMG

SY58022UMG

SY88422LMG

ATSAMG55J19B-MU

SY54023ARMG

SY89875UMG

SY89876LMG

SY89840UMG

SY89841UMG

SY58609UMG

SY89851UMG

SY89852UMG

SY89854UMG

SY89831UMG

SY89832UMG

SY89871UMG

SY89833ALMG

SY89872UMG

SY89833LMG

SY89873LMG

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PIC32MX150F128B-50I/SS

DSPIC33FJ32MC202-I/SS

PIC24HJ32GP202-I/SS

DSPIC33FJ32GP202-I/SS

DSPIC33FJ12MC202-I/SO

PIC32MX250F128B-50I/SS

93LC76AT-I/SN

93AA76AT-I/SN

93LC76BT-I/SN

93AA76BT-I/SN

MCP4161T-502E/MF

MCP3422A7T-E/MC

MCP4142T-503E/MF

MCP4162T-502E/MF

MCP4162T-104E/MF

MCP3422A6T-E/MC

MCP3423T-E/MF

MCP4151T-103E/MF

MCP4151T-104E/MF

MCP4151T-503E/MF

PIC18F2420T-E/ML

PIC12F629T-E/MD

MCP6033T-E/MC

PIC16LF19156T-I/MV

ATECC608C-TFLXTLSU

PIC16F19175T-I/MV

AVR16EB32T-I/RXB

AVR16EB28T-I/STX

PIC18F55Q43T-I/6LX

PIC18F45Q43T-I/MP

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ATECC608C-TNGTLSU-C

ECC608-TMNGTLSU

PIC16F19176T-I/MV

PIC16LF19175T-I/MV

PIC16LF19176T-I/MV

PIC18F25Q43T-I/STX

ATECC608C-TNGTLSU-G

ATSAMD21E18A-MUTDBG

DSPIC33EDV64MC205T-I/M7

MCP4231T-103E/ST

MCP4231T-104E/ST

MCP4231T-503E/ST

PIC18F2520T-E/SOC06

MCP9805T-BE/ST

MCP4241T-103E/ST

MCP4661T-502E/ST

MCP4661T-103E/ST

MCP4251T-502E/ST

MCP604T-E/ST

MCP6034T-E/ST

MCP6032T-E/SN

24LC128T-E/ST

24LC024HT-E/ST

24LC024HT-E/SN

MCP3422A1T-E/SN

MCP4661T-104E/ST

MCP4661T-503E/ST

MCP4922T-E/ST

ATSAME53N20A-AUT-EFP

ATSAME54N19A-AUT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATSAME54N20A-AUT

ATSAME54N20A-AUT-EFP

PIC16F1503-E/MGVAO

PIC16F1508-E/MLVAO

PIC18F26K42-E/SSVAO

PIC16F15323-E/STVAO

PIC16F18324-E/STVAO

PIC16F1704-E/STVAO

PIC16F1705-E/STVAO

PIC16LF1705-E/STVAO

PIC16F1824-E/STVAO

PIC16F753-E/STVAO

PIC16F1825-E/STVAO

PIC16F1788-E/SOVAO

PIC16F1773-E/SSVAO

PIC16F1776-E/SSVAO

PIC16F15324-E/STVAO

PIC16F18323-E/STVAO

24LC256-E/ST16KVAO

24FC256-E/ST16KVAO

PIC16F1613-E/STVAO

PIC16F1703-E/STVAO

PIC16F1615-E/STVAO

PIC16F616-E/STVAO

PIC16F1503-E/STVAO

PIC16F1824-E/STVAO-GM

PIC16F1614-E/STVAO

PIC16F616-E/STVAO-GM

DSPIC33CK64MP102-E/SSVAO

PIC16LF1784T-I/PT

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PIC24FJ128GA108T-I/PTC20

PIC18LF4550T-I/PT

PIC24FJ192GA108T-I/PTC21

PIC16F1787T-I/PT

PIC24FJ64GA306T-I/PT

DSPIC33CK64MP505T-E/PT

DSPIC33CK256MP205T-E/PT

DSPIC33CK256MP505T-E/PT

DSPIC33EV128GM106T-E/PT

PIC32CM2532LE00048T-E/Y8X

PIC32MX250F128B-V/ML

PIC32MX230F064B-V/ML

PIC32MX675F256H-80V/MR

PIC32MX695F512H-80V/MR

PIC32MX675F512H-80V/MR

PIC32MX795F512H-80V/MR

PIC32MX775F512H-80V/MR

PIC32MX775F256H-80V/MR

24CW1280-I/ST

93AA56B-I/ST

24LC256-I/SNRVE

ATMEGA3208-XF

DSPIC33FJ12MC201-E/SS

DSPIC33FJ12GP202-E/SO

PIC32MX340F256H-80I/MR

PIC32MX420F032H-40I/MR

34LC02T-I/SN

34AA02T-I/SN

24LC08BT-I/SNA23

24LC08BT-I/SNA27

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24LC16BT-I/SNRVE

PIC18LF26K22T-I/SOC01

24AA32AT-I/SNRVE

24AA128T-I/SN15KV08

24LC32AT-I/SNRVE

24LC128T-I/SNRVE

24AA128T-I/SN

24LC64T-I/SNRVE

PIC18F26K22T-I/SOC02

24LC32AT-I/SNA23

24LC32AT-I/SNA27

PIC16F819T-I/SSTSL

93AA56AT-I/SN

DSPIC33EP512GM306-E/PT

DSPIC33EP512GM706-E/PT

DSPIC33EP128GM306-E/PT

PIC24HJ32GP304-E/PTC02

PIC24HJ32GP304-E/PTA22

PIC16LF18877-E/PT

DSPIC33EP32MC204-E/PTA8

PIC16F1789-E/PT

DSPIC33EP32GS506-E/PT

DSPIC33EP16GS506-E/PT

PIC18F67K40-E/PT

PIC24FJ128GA705-E/PT

PIC24FJ64GA705-E/PT

PIC24FJ256GA704-E/PT

PIC24FJ128GA704-E/PT

PIC24FJ64GA704-E/PT

PIC24FJ256GA705-E/PT

Date: Tuesday, July 22, 2025

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PIC18F65K40-E/PT

PIC24FJ64GA106-E/PT

PIC24FJ256GA704-E/PTC02

DSPIC33EP256MU806-E/PT

PIC24FJ192GA106-E/PT

PIC24FJ64GA104-E/PT

PIC16LF1939-E/PT

ATSAMD21E16B-AF

ATSAMD21E15B-AF

PIC18F6622-E/PT

ATSAMD21E16L-AF

ATSAMD21E15L-AF

PIC18F45K80-E/PT

PIC18F46K80-E/PT

PIC16F1936-I/ML

PIC16F1936-I/MV

SY89113UMY

PIC24FJ64GA004-I/MLC13

PIC32CM5164LS60064-I/5LX-PROTO

PIC32CM5164LS60048-I/U5B-PROTO

PIC32CM1216MC00048-I/U5B

PIC32CM1216MC00048-I/U5BESU

DSPIC33EP256GP502-I/MM

DSPIC33EP256MC202-I/MM

DSPIC33EP256MC502-I/MM

PIC24EP256GP202-I/MM

PIC24EP256MC202-I/MM

PIC16F1823-I/ML029

KSZ8851SNLI

PIC18LF13K22-I/ML

Date: Tuesday, July 22, 2025

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KSZ8041NLI

PIC32CM5164SMT064-I/5LX

PIC16LF1937-I/ML

ATSAMD20J16B-MMU

ATSAMD20J15B-MMU

ATSAMD20J14B-MMU

KSZ8041RNLI

DSPIC33EP64MC206-I/MR

DSPIC33EP64MC506-I/MR

PIC32CM5164SMT048-I/U5B

ATMEGA48PA-MU

PIC18F27Q43-I/STX

OS81110AFR-D1A-010205-VAO

OS81110AFR-D1A-010207-VAO

OS81110AFR-D1A-010203-VAO

OS81110AFR-D1A-010204-VAO

OS81110AFR-D1A-010208-VAO

PIC16F18854T-I/MLVAO

PIC18F25K80T-I/MMVAO

PIC18F26K80T-I/MMVAO

PIC16F1788T-I/MLVAO

MCP79410T-I/MNYVAO

34LC02T-I/MNY16KVAO

PIC16F18325T-I/JQVAO

PIC16LF18324T-I/JQVAO

PIC18F45K42T-I/MVVAO

PIC16F1825T-I/JQVAO

25LC160DT-I/MNY16KVAO

PIC18F25K40T-I/MVVAO

PIC24FJ32MC102T-I/5NXVAO

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PIC18F2580T-I/MLVAO

MCP1722T-5010H/Q8BVAO

MCP1722T-5012H/Q8BVAO

MCP1722T-3312H/Q8BVAO

MCP1722T-3310H/Q8BVAO

PIC16F18876T-I/MVVAO

PIC16F1933T-I/MLVAO

PIC32MM0256GPM028T-I/MLVAO

PIC16LF18857T-I/MLVAO

KSZ8051MNLU-TRVAO

PIC18F26K40T-I/MVVAO

PIC16F1936T-I/MVVAO

25LC320AT-I/MNY16KVAO

OS81214AFR-B2B-010300-VAO

PIC16F1824T-E/JQ

MIC79110-4.2YML-TR

MIC79110YML-TR

PIC16F1503T-E/MV

DSPIC33AK128MC106T-E/M7

ATSAMD20G18A-ANT

ATSAMD20G16A-ANT

PIC32MX120F032DT-V/PT

PIC32MX110F016DT-V/PT

PIC32MX270F512LT-V/PF

PIC32MX575F512LT-80V/PF

PIC32CM2532LE00064T-I/5LX

PIC32CM2532LS00064T-I/5LX

PIC32CM2532LE00048T-I/U5B

PIC32CM2532LS00048T-I/U5B

LE79271AMQCT

Date: Tuesday, July 22, 2025

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LE79271MQCT

PIC16F1939T-I/MP

PIC18F25K83T-I/ML

PIC18F26K83T-I/ML

DSPIC33AK128MC103T-I/M7

DSPIC33AK64MC103T-I/M7

DSPIC33AK32MC103T-I/M7

AVR32DD32T-I/RXB

AVR16DD32T-I/RXB

AVR32DD28T-I/STX

AVR16DD28T-I/STX

ATSAMD20G16B-MUT

ATSAMD20G14B-MUT

DSPIC33AK128MC105T-I/M7

PIC16LF1789-I/ML

PIC12LF1501-I/MC

PIC24FJ128GB202-I/MM

PIC24FJ64GB202-I/MM

PIC12F1822-I/MF043

PIC24FJ128GB204-I/ML

PIC16F1828-I/GZ

PIC18LF27J13-I/ML

PIC18LF26J13-I/ML

PIC18LF47J13-I/ML

DSPIC33EP64GS502T-I/MMC12

DSPIC33EP32GS402T-I/MM

DSPIC33EP64GS502T-I/MM

DSPIC33EP32GS502T-I/MM

93AA76CT-I/SN

93LC86CT-I/SN

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93C86CT-I/SN

MCP41010T-I/SN

PIC12LF1552T-I/SN021

PIC12LF1552T-I/SN023

PIC12LF1552T-I/SN

PIC12F519T-I/SN047

PIC12F519T-I/SN

PIC16F1719-E/PT

PIC16LF1719-E/PT

PIC16LF1717-E/PT

DSPIC33EP256GM706-E/PT

MCP4261T-103E/ML

DSPIC33FJ64MC204T-E/ML042

DSPIC33FJ128GP802T-E/MM

DSPIC33FJ32GP302T-E/MM

PIC12F510T-E/MC

DSPIC33EP256MC204T-E/ML

DSPIC33FJ64MC202T-E/MM

MCP4261T-503E/ML

MCP4251T-104E/ML

PIC32MK1024GPE064T-E/MR

MCP4231T-103E/ML

PIC18F46J50-I/ML

PIC18F44J50-I/ML

DSPIC30F5015T-30I/PT

DSPIC30F5016T-30I/PT

PIC16F1509T-E/MLVAO-BW

PIC16F15225T-E/MGV AO-GM

PIC16F15325T-E/JQVAO-VW

PIC16F15345T-E/GZVAO-MB

Date: Tuesday, July 22, 2025

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PIC16F15345T-E/GZVAO-VW

PIC16F1704-E/MLVAO-MB

PIC16F18046T-E/MLVAO-VW

PIC16F18345T-E/6NVAO-BW

PIC18F14K22-E/MLVAO-MB

PIC18F14K22-E/MLVAO-VW

PIC18F25K22T-E/MLVAO-BW

PIC18F25K40T-I/MLVAO-BW

PIC18F25K80-E/MMVAO-MB

PIC16F726T-I/SS032

PIC16F726T-I/SS036

PIC16F726T-I/SS039

PIC16F726T-I/SSC06

24AA32AF-I/SN

MCP3204-CI/ST

11AA02E48-I/SN

PIC24FJ48GA002-I/SO

PIC24FV16KA302-I/SO

MCP6044-I/ST

PIC24FV08KM101-I/SS

PIC18LF24K50-I/SS

11AA02E64-I/SN

PIC18F24K50-I/SS

PIC18F25K50-I/SS

PIC18F2550-I/SO

PIC24FV16KM202-I/SS

PIC18LF25K50-I/SS

PIC32MX150F256LT-I/PF

PIC32MX130F128LT-I/PF

PIC32MX250F256LT-I/PF

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PIC32MX250F256LT-50I/PF

PIC32MX230F128LT-50I/PF

PIC32MX775F512HT-80I/PT

PIC16F1503-I/STVAO

25AA128-I/ST16KVAO

PIC16F1455-I/STVAO

PIC18F26Q83-I/SSVAO

PIC16F15225-I/STVAO

PIC16F17545T-I/ML

PIC16F17546T-I/ML

PIC16F15256T-I/STXC02

PIC32CM3204JH00048T-I/U5B

PIC32AK3208GC41048T-E/M7

AVR32DA48ST-E/6MX

ECE1117-Y3-1-TR

USB2422T/MJ

PIC32MX470F512HT-120/MR

24VL024HT/MNY

PIC32MZ0512EFK064-I/PT

PIC32MZ1024EFE064-I/PT

PIC32MZ1024EFF064-I/PTF21

PIC32MZ1024EFK064-I/PT

PIC32MX764F128H-I/PT

PIC32MX564F128H-I/PT

PIC32MZ1024EFM064-I/PT

PIC32MZ2048EFG064-I/PT

PIC32MZ2048EFH064-I/PT

PIC32MZ2048EFM064-I/PTN21

PIC16F884-I/PT

PIC32CM3204JH00032T-I/RTB

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PIC32CM6408JH00064T-I/5LX

PIC32CM6408JH00048T-I/U5B

PIC32CM6408JH00032T-I/RTB

PIC32CM3204JH00064T-I/5LX

PIC32MX550F256LT-V/PF

PIC32MX575F512LT-80V/PT

PIC32MX575F256LT-80V/PT

PIC32MX130F256DT-V/PT

PIC32MX350F256HT-V/PT

PIC32MX350F128HT-V/PT

PIC32MX450F256HT-V/PT

PIC32MX230F256DT-V/PT

PIC32MX150F128DT-V/PT

PIC32MX330F064LT-V/PF

PIC32MX430F064LT-V/PF

PIC32MX250F128DT-V/PT

PIC32MX430F064HT-V/PT

PIC32MX564F128LT-V/PT

PIC32MX534F064LT-V/PF

PIC32MX564F064LT-V/PF

PIC32MX664F128LT-V/PF

PIC32MX664F064LT-V/PF

PIC18LF442-I/L

PIC16F77-I/L

PIC18LF452-I/L

PIC18F452-I/L

PIC17C44-33I/L

PIC17C43-16I/L

PIC16F877-04I/L

PIC16F877-20I/L

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PIC16LF877-04I/L

PIC16LF74-I/L

PIC16F874A-I/L

PIC16LF874A-I/L

PIC16C65B-04I/L

PIC16C65B-20I/L

PIC16LC65B-04I/L

PIC17C42A-25I/L

PIC16LC74B-04I/L

PIC16C74B-20I/L

PIC16C74B-04I/L

PIC18C658-I/L

PIC17LC44-08I/L

PIC16C774-I/L

HV518PJ-G

HV5530PJ-G

HV5222PJ-G

HV5308PJ-B-G

HV5522PJ-G

MCP19119T-E/MQ

WP200TX01T-E/ML001

PIC24FJ16GA004T-E/ML

MCP6V17T-E/MNY

PIC16F15354T-E/ML

MCP9808T-E/MC

25LC160DT-E/MNY

25AA160DT-E/MNY

25LC160CT-E/MNY

DSPIC33EP16GS202T-E/MMC01

25LC080DT-E/MNY

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25LC080CT-E/MNY

MCP6V37T-E/MNY

PIC18LF43K22T-E/ML

PIC24FJ16GA002T-E/ML

PIC16F18854T-E/ML

EMC1412-1-AC3-TR

MCP6V62T-E/MNY

MCP6V67T-E/MNY

MCP47FEB14T-E/MQ

MCP47FEB24T-E/MQ

MCP47FVB08T-E/MQ

MCP47FVB18T-E/MQ

MCP47FVB28T-E/MQ

MCP47FEB08T-E/MQ

DSPIC33EP32GP502T-E/MM

DSPIC33EP32MC502T-E/MM

PIC24EP32GP202T-E/MM

DSPIC33EP512MC806T-E/MR

PIC16F18877T-E/MV

PIC24EP512GP806T-E/MR

24FC02T-E/MUY

24FC04T-E/MUY

PIC16F616T-E/MLC07

24FC04HT-E/MUY

DSPIC33FJ16GS404T-E/ML

ATXMEGA192A3U-AUR

ATXMEGA64B3-AUR

ATXMEGA128B3-AUR

PIC32MK0512GPK100T-I/PT

PIC32MK0512MCM100T-I/PT

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ATMEGA4808-MUR

PD69210R-035400-TR

PIC16F883T-I/ML031

PIC16F18875T-I/MV

TC1301A-NICVMFTR

TC1301B-AIAVMFTR

TC1301B-APAVMFTR

TC1301B-CCAVMFTR

TC1301B-DAAVMFTR

TC1301B-HWEVMFTR

DSPIC33FJ128GP710AT-I/PT

MCP4132-502E/MF

MCP4241-503E/ML

MCP4142-104E/MF

MCP4142-503E/MF

MCP4261-104E/ML

MCP4261-503E/ML

MCP4231-103E/ML

MCP4161-104E/MF

MCP4161-503E/MF

MCP4152-104E/MF

PIC32CM3204GV00048T-I/U5B

PIC32CM3204GV00032T-I/RTB

PIC32CM1602GV00064T-I/5LX

PIC32CM1602GV00048T-I/U5B

PIC32CM1602GV00032T-I/RTB

PIC32CM3204GV00064T-I/5LX

DSPIC33CK512MPT608T-E/PT

DSPIC33CK256MPT608T-E/PT

PIC32CX2051MTC128T-I/X9B

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32CX2051MTG128T-I/X9B

PIC32CX1025MTG128T-I/X9B

DSPIC33EP64GS504T-I/PT

ATSAMC20E17A-MUT

PIC32AK6416GC41048-I/PT

PIC32AK3208GC41048-I/PT

PIC32AK1216GC41064-I/PT

PIC32AK6416GC41064-I/PT

PIC32CM5164JH01048-I/Y8X-SL3

ATSAMC21G15A-AUT

ATSAMC21G16A-AUT

PIC16F916T-I/ML

PIC16F913T-I/ML

PIC24FJ128GA406T-I/PT

DSPIC33CK256MP306T-I/PT

PIC16LF15356-E/ML

PIC16LF15356-E/MV

UCS4003-E/8N

PIC16F19175-E/MV

DSPIC33CK256MP605-E/PT

HA7619-I/ML027

SY58011UMG-TR

SY58012UMG-TR

SY58013UMG-TR

SY58017UMG-TR

SY58018UMG-TR

SY58019UMG-TR

SY58606UMG-TR

SY58607UMG-TR

SY58608UMG-TR

Date: Tuesday, July 22, 2025

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SY89854UMG-TR

SY89851UMG-TR

SY89852UMG-TR

SY84113BUMG-TR

SY88303BLMG-TR

SY88353BLMG-TR

SY88403BLMG-TR

SY88773VMG-TR

AT24C512C-MAHMEU-T

AT24C01C-MAHM-T

AT24C01C-MAHM-E

PIC16LF1902T-I/MV020

SY54023RMG-TR

SY56020XRMG-TR

SY56023RMG-TR

SY56020RMG-TR

SY54017ARMG-TR

SY56017RMG-TR

SY54020RMG-TR

SY54020ARMG-TR

SY58022UMG-TR

SY54023ARMG-TR

KSZ8051RNLU-TRVAO

PIC16F18455T-I/STXVAO

ATA5702F1000M-WDQW

ATA5700F1000M-WDQW

ATA5702F1000M-WDQW-VAO

PIC16F690-I/SS

PIC16F690-I/SSC11

HA4412-I/SO

Date: Tuesday, July 22, 2025

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PIC24EP32MC202-I/SS

PIC16F886-I/SS

PIC16F689-I/SS050

DSPIC33FJ32MC202-I/SO

PIC16F886-I/SO

DSPIC33CH128MP505T-I/PTVAO

ATMXT1296M1T-ATRVAO

OS8104AATR-D1B-V01

DSPIC33CK32MC105T-I/PTVAO

DSPIC33CK64MC105T-I/PTVAO

AVR64DA32T-I/PTVAO

AVR64DA64T-I/PTVAO

PIC16F15376T-I/PTVAO

PIC16F15385T-I/PTVAO

DSPIC30F5011T-30I/PTVAO

DSPIC33EP64MC504T-I/PTVAO

PIC16F15376T-I/PTVAO-VW

PIC16F887T-I/PTVAO-VW

PIC18F56Q84T-I/PTVAO

PIC24EP128GP204T-E/PTVAO

AT28C256-15JU-043

AT28C256-15JU-323

SST39VF020-70-4I-NHE-T

ATMEGA8515-16JUR

ATMEGA8515L-8JUR

AT28C010-12JU-235

AT28C010E-12JU-235

AT28C010-15JU-235

AT28C010E-15JU-235

AT28LV010-20JU-235

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AT28LV010-20JU-630

ATMEGA8535-16JUR

ATF22V10CQZ-20JU-T

ATF1502AS-10JU44-113

PIC16LF1518T-I/MV

PIC16LF1517T-I/MV

PIC16LF1765T-I/ML

PIC16LF1764T-I/ML

PIC16F18345T-I/GZ

PIC16LF18345T-I/GZ

ATSAML21J18B-MMUT-SLL

ATSAML21J17B-MMUT-SLL

ATSAML22J16A-MMUT

ATSAML22J17A-MMUT

ATSAML22J18A-MMUT

PIC16LF1519T-I/MV

PIC18F45K22T-I/ML

PIC18F44K22T-I/ML

MTCH112T-I/MF

PIC12LF1840T-I/MF

PIC16F18446T-I/GZ

PIC18F43K22T-I/ML

PIC18F46K22T-I/ML

ATSAMD20J16B-MMUT

ATSAMD20J14B-MMUT

ATSAMD20J15B-MMUT

ATSAMD20J18A-MMUT

ATSAMD20J14A-MMUT

ATSAMD20J15A-MMUT

ATSAMD20J16A-MMUT

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PIC24FJ64GA702-I/ML

LAN9250I/ML

PIC16LF1829T-I/SS023

PIC16F18344T-I/SS

PIC16LF18344T-I/SS

PIC16F636T-I/ST

USX5044T-I/2G

PIC16F18074T-I/MP

PIC16F18075T-I/MP

PIC16F18054T-I/STX

PIC16LF1824T-I/ML

MCP47FEB02A3T-E/ST

MCP47FEB22A0T-E/ST

MCP47FEB11A3T-E/ST

MCP47FEB12A0T-E/ST

PIC16F15345T-I/GZ

PIC16LF15345T-I/GZ

PIC16LF15325T-I/JQ

ATECC608B-MAH2V-T

IS1871SF-102

PIC24HJ128GP506A-I/MR

PIC24HJ128GP206A-I/MR

DSPIC33EV64GM104-I/ML

DSPIC33EV128GM104-I/ML

DSPIC33EV64GM004-I/ML

DSPIC33EV32GM002-I/MM

DSPIC33EV32GM102-I/MM

PIC18F24K22-I/ML

PIC18F23K22-I/ML

PIC24FJ256GA406-I/MR

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PIC24FJ128GA406-I/MR

PIC24FJ64GA406-I/MR

PIC16LF1578-I/GZ

PIC16F1578-I/GZ

PIC12F1840-I/MF

PIC12LF1571-I/MF

MCP4141T-503E/MF

PIC16F723AT-E/SS

25LC640AT-E/SN

25LC640AT-E/ST

93C66CT-E/ST

93C46CT-E/ST

93C66BT-E/ST

25LC320AT-E/SN

25LC160DT-E/SN

MCP48FVB18-E/MQ

PIC18F25K80-E/MMC01

MCP48FVB28-E/MQ

24C00T-E/SN

MCP4352T-503E/ST

PIC16F73T-E/SO

MCP3426A6T-E/SN

24AA32AFT-I/SN

24LC16BT-I/SN

24LC024T-I/ST185

24LC024T-I/ST186

PIC16LF1459T-I/SS

PIC12C508AT-04I/SN

PIC12C508AT-04I/SN123

24LC32AT-I/SN

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PIC16F1512T-I/SS

24LC024T-I/ST187

PIC12LC508AT-04I/SN168

ATSAMD20J17A-AU

ATSAMD20J14A-AU

ATSAMD20J16A-AU

ATSAMD20J15A-AU

ATSAMD20J18A-AU

PIC18F65K40-I/PT

ATF1500AL-20AU

ATF1500A-10AU

ATF1504ASVL-20AU44

PIC24FJ256DA206-I/PT

PIC24FJ128DA206-I/PT

PIC24FJ256DA106-I/PT

PIC24FJ128DA106-I/PT

PIC16LF1527-I/PTC01

ATSAMD20J14A-AUA2

ATSAMD20J15A-AUA2

ATSAMD20J16A-AUA2

PIC18LF46J13-I/ML

PIC16LF1508-I/GZ

PIC16LF1509-I/GZ

PIC16F1507-I/GZ

PIC16F1829-I/GZ

PIC16LF1829-I/GZ

HCS301/SN

MCP6N11T-005E/SN

MCP6404T-E/ST

MCP6N11T-002E/SN

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MCP3426A1T-E/SN

DSPIC33EP256MC506-E/MR

PIC24EP256GP206-E/MR

MCP48FVB08-E/MQ

PIC18F45Q24-E/MP

PIC24EP128GP204-H/ML

PIC24EP128MC204-H/ML

DSPIC33EP256GP504-H/ML

DSPIC33EP256MC204-H/ML

DSPIC33EP256MC504-H/ML

PIC12F509T-I/SN047

PIC16LF1783T-I/SSC01

MCP79410T-I/SN

MCP79400T-I/SN

PIC12F675T-I/SN

PIC12F675T-I/SN195

PIC12F675T-I/SN166

PIC12F675T-I/SN172

PIC12F675T-I/SN049

93AA56BT-I/ST

93AA56BT-I/SN

PIC12F1501T-I/SN

24AA256T-I/SNRVE

25LC020A-E/ST

PIC18F26K40-E/SS

PIC24F08KA101-E/SS

PIC24F08KA102-E/SS

MCP6V19-E/ST

PIC18F85K90T-I/PTRSL

PIC18F85K22T-I/PT

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ENC424J600T-I/PT

ENC624J600T-I/PT

PIC18F4620T-I/PT

PIC18LF4620T-I/PT

PIC18LF4455T-I/PT

PIC18F4525T-I/PT

PIC18LF4525T-I/PT

PIC18F4550T-I/PT

PIC18F4455T-I/PT

PIC18F45K50T-I/PT

PIC18LF45K50T-I/PT

PIC18F46K20T-I/PT

PIC16F913-E/ML

PIC16F886-E/ML

PIC16F526-E/MG

MCP4331-503E/ML

DSPIC33CK128MP506-H/PT

DSPIC33CH512MP506-H/PT

DSPIC33CH512MP206-H/PT

DSPIC33CH256MP506-H/PT

DSPIC33CH256MP206-H/PT

DSPIC33CK32MP505-H/PT

DSPIC33CK128MP205-H/PT

DSPIC33CK128MP505-H/PT

DSPIC33CK64MP205-H/PT

DSPIC33CK64MP505-H/PT

DSPIC33CK32MP205-H/PT

DSPIC33CK256MP205-H/PT

DSPIC33EP128GS804T-E/PTVAO

AT32UC3C1256C-AZR

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AT32UC3C1512C-AZR

DSPIC33CK512MP605T-E/PTVAO

MCP4251-503E/ML

MCP4152-502E/MF

MCP4162-103E/MF

MCP4141-103E/MF

MCP4141-104E/MF

MCP4162-104E/MF

MCP4141-503E/MF

MCP4162-503E/MF

24LC16B-E/MC

MCP4131-104E/MF

MCP4131-503E/MF

MCP4142-502E/MF

MCP4142-103E/MF

MCP3422A0-E/MC

MCP652-E/MF

MCP4261-502E/ML

MCP3422A7-E/MC

MCP4132-103E/MF

PIC24FJ256GA606-I/PT

MCP1631T-E/MLVAO

24CW160T-E/Q4B66KVAO

24CW320T-E/Q4B66KVAO

24CW640T-E/Q4B66KVAO

PIC16LF18326T-E/7NVAO

PIC16F18346T-E/MLVAO

PIC32CM1216JH01032-E/PT

PIC32CM1216JH01048-E/Y8X

ATSAMC21N18A-AZ

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ATSAMC21N17A-AZ

DSPIC33CK512MP306-E/PT

PIC16F946-E/PT

DSPIC33FJ64GS406-E/PT

DSPIC33FJ64GS606-E/PT

MCP4151-103E/MF

TC1302B-PFVMF

MCP3422A3-E/MC

PIC32MX360F256LT-80V/PT

PIC32MX320F128LT-80V/PT

PIC32MX340F128LT-80V/PT

PIC32MX460F512LT-80V/PT

PIC32MX564F128LT-V/PF

PIC32MX764F128LT-V/PF

PIC32MX450F256LT-V/PF

PIC32MX350F256LT-V/PF

PIC32MX350F128LT-V/PF

PIC32MX450F128LT-V/PF

PIC32MX350F128LT-V/PT

PIC18LF47K42-E/ML

COMP_MCU_DGD_00034_V06

COMP_MCU_DGD_00098_V02

PIC16LF1906T-I/MV

PIC12LF1822T-I/MF

PIC10F322T-I/MC

93C46BT-I/MNY

PIC18F27J53T-I/ML

93C46AT-I/MNY

93C46AT-I/MC

MCP4631T-103E/ML

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PIC24HJ256GP206AT-E/MR

DSPIC33FJ128GP204T-E/ML

DSPIC33FJ128GP804T-E/ML

DSPIC33FJ32GP304T-E/ML

PIC16F1716T-E/ML

DSPIC33FJ64MC802T-E/MM

PIC16F18446T-E/GZ

DSPIC33FJ64MC804T-E/ML

DSPIC33FJ32MC304T-E/ML

DSPIC33FJ16MC102T-E/ML

DSPIC33FJ128MC204T-E/ML

IS1871SF-202

IS1870SF-102

IS1870SF-202

SY58020UMG-TR

SY58021UMG-TR

PIC12LF1822T-I/RF

PIC18LF26K22T-I/ML

PIC18LF26K22T-I/MLC03

PIC18LF26K22T-I/MLC04

PIC16F1765T-I/ML

PIC16F1764T-I/ML

PIC18F45K42T-I/MV

PIC18F46K42T-I/MV

24CSM01T-I/Q4B

PIC18F55Q24T-I/6LX

PIC18F56Q24T-I/6LX

PIC18F45Q24T-I/MP

PIC18F46Q24T-I/MP

PIC18F24Q24T-I/STX

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PIC18F25Q24T-I/STX

PIC18F26Q24T-I/STX

PIC16F15256T-I/STXC01

AT24C64D-MAHM-T-834

PD77020-011000-TR

ATECC608C-MAH7X-S

PIC16LF18326T-I/JQ024

24CS32T-I/Q4B

24CS64T-I/Q4B

PIC16F17574T-I/MP

PIC16F17575T-I/MP

PIC16F17576T-I/MP

PIC16F17554T-I/STX

PIC16F17555T-I/STX

PIC16F17556T-I/STX

PD77010-0100-0000-TR

MCP8027T-H/Q9X

PIC16LF18346T-I/GZ025

PIC16LF18346T-I/GZ026

ATSAMC21N17A-AZTVAO-GM

DSPIC33EP512GM710T-E/PTVAO

DSPIC33EP256GM604T-E/PTVAO

DSPIC33EP128GM604T-E/PTVAO

ATSAMC21G16A-AZTVAO

DSPIC33EP128GS808T-E/PTVAO

PIC18F47Q10T-E/PTVAO

AVR128DA32T-E/PTVAO

AVR128DA64T-E/PTVAO

AVR128DA48T-E/PTVAO

AVR64DA64T-E/PTVAO

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AVR64DA32T-E/PTVAO

AVR64DA48T-E/PTVAO

PIC18F46K40T-E/PTVAO

ATSAMC21N18A-AZT510

ATSAMC20N17A-AZTVAO

ATSAMD51N20A-AUT

ATSAMD51N20A-AUT-EFP

ATSAME51N19A-AUT

ATSAME51N20A-AUT

ATSAME51N20A-AUT-EFP

ATSAME53N19A-AUT

ATSAME53N19A-AUT-EFP

ATSAME53N20A-AUT

DSPIC33EV32GM102-I/SSVAO

DSPIC33EP32MC202-I/SSVAO

PIC32MZ2048EFG100-I/PF21

ATMEGA16A-AU

ATF1504AS-10JU44-T

ATF1504ASV-15JU44-T

ATF1504ASVL-20JU44-T

ATF22V10C-7JU-T

24LC64T-I/ST

25AA128XT-I/ST

PIC16F631T-I/SS

24FC512T-I/SN101

93AA66BT-I/ST

93AA66CT-I/ST

24LC32AXT-I/ST

24AA32AXT-I/ST

PIC16LF1517T-I/PT

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PIC18F45K20T-I/PT

PIC32MX330F064LT-I/PF

DSPIC33FJ128MC510AT-I/PTC27

PIC24FJ1024GA610T-I/PTC01

HA4584T-I/PT

DSPIC33EP128MC206T-I/PTA3

PIC32MX430F064LT-I/PF

DSPIC33EP256MC206T-I/PTA3

PIC32MX350F256HT-I/PT

PIC32MX320F128LT-80I/PT

PIC32MX340F128LT-80I/PT

DSPIC33EP256MU810T-I/PF

DSPIC33EP512MU810T-I/PF

PIC18LF24K40-I/SS

MT9172APR1

AT27C040-70JU-T

AT27C040-90JU-T

AT27C080-90JU-T

AT27LV040A-90JU-T

MT8808APR1

MT8816APR1

MT8806APR1

SY100E310LJY-TR

PIC32MZ1024EFH100T-I/PTVAO

ATECC608B-MAHAF-S

PIC16F1936T-I/MV

DSPIC33EP64GP502T-E/MM

MCP47FVB04T-E/MQ

MCP47FVB14T-E/MQ

MCP47FVB24T-E/MQ

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DSPIC33EP64GP506T-E/MR

AT89C51RC2-SLSUL

AT89C51CC03CA-SLSUM

AT89C51AC2-SLSUM

AT89C51CC01UA-SLSUM

AT89C51CC01CA-SLSUM

AT80C51RD2-SLSUM

AVR32DA32T-I/PT

DSPIC33EP32MC504T-I/PT

KSZ8041TLI-TR

PIC24EP32GP204T-I/PT

ATSAML21G16B-AUT

ATSAML21G17B-AUT

DSPIC33EP64GS506T-I/PTC07

93AA56CT-I/ST

PIC24FJ64GA104T-I/PT

PIC32MX575F512LT-80I/PT025

PIC24FJ64GB004T-I/PT

DSPIC33EP128GM306T-I/PT

PIC18LF2420-I/ML

MCP73838-NVI/MF

MCP73871-2CAI/ML

MCP73871-4CCI/ML

PIC18LF4523-I/ML

PIC16LF818-I/ML

AR1020-I/ML

MCP73831-2DCI/MC

MCP73831-3ACI/MC

MCP73831-4ADI/MC

MCP73831-5ACI/MC

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PIC18LF2520-I/ML

PIC32CM3204JH00032T-E/T5X

PIC32CM6408JH00064T-E/V2X

24AA025E48-I/SN

PIC24EP32GP202-I/SS

PIC16F685-I/SS

PIC24HJ32GP202-I/SO

DSPIC33FJ128MC506A-H/PT

PIC18F25K80T-E/MMCUI

MCP47CMD12T-E/MG

MCP47CMD21T-E/MG

MCP47CMD22T-E/MG

MCP47CVD01T-E/MG

MCP47CVD02T-E/MG

ATSAMC21E18A-MZT-SL1

ATSAMC21E18A-MZT-SL2

ATSAMC21E18A-MZT-SL3

ATTINY1627-MFR

MCP47CVD11T-E/MG

MCP47CVD12T-E/MG

MCP47CVD21T-E/MG

MCP47CVD22T-E/MG

MCP48CMD01T-E/MG

ATMEGA1284RFR2-ZFR

MCP48CMD02T-E/MG

MCP48CMD11T-E/MG

MCP48CMD12T-E/MG

MCP48CMD21T-E/MG

MCP48CMD22T-E/MG

ATMEGA2564RFR2-ZFR

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TC1301B-FDAVMFTR

TC1301B-EDAVMFTR

ATSAMD20J17A-AUA2

DSPIC33EP512MC806-I/PT022

PIC24FJ64GA106-I/PT

PIC24FJ192GA106-I/PTC22

PIC24FJ64GA106-I/PTC23

PIC24FJ192GA106-I/PT

ATF1508ASV-15AU100

PIC18F45K20-I/PTC07

ATF1508AS-10AU100

ATF1508ASVL-20AU100

ATSAMD20J18A-AUA2

PIC18F66J11-I/PT

MEC1418-I/NU

MEC1414-I/NU

PIC12HV752-E/MF

MCP4451-503E/ML

MCP4461-502E/ML

MCP4461-103E/ML

TC1302A-FFVMF

TC1301B-IECVMF

TC1301B-UWFVMF

TC1301A-APAVMF

TC1301A-AAAVMF

TC1301B-UUAVMF

TC1302B-AFVMF

TC1301B-DDAVMF

PIC12F629-E/MD

PIC12F675-E/MD

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TC1301A-UPBVMF

PIC16LC77-04/L

TC7117ACLW

PIC16C74A-04/L

PIC32MX575F256LT-80V/PF

PIC32MX695F512LT-80V/PF

PIC32MX675F512LT-80V/PF

PIC24HJ16GP304-E/PT

PIC24EP64GP204-E/PT

DSPIC33EP64GP506-E/PT

PIC24EP64GP206-E/PT

DSPIC33FJ256GP710A-E/PT

DSPIC33FJ256MC510A-E/PT

DSPIC33FJ256MC710A-E/PT

DSPIC33FJ32GP204-E/PT

DSPIC33AK64MC106T-E/M7

DSPIC33AK32MC106T-E/M7

AVR32EA28T-E/STX

PIC16F1509T-E/GZ

25CS320T-E/Q4B

LAN8650B1T-E/LMX

LAN8651B1T-E/LMX

AVR128DB64T-E/MR

AVR64DB64T-E/MR

PIC18F27K40T-E/ML020

ATSAMC20J18A-MMZT

MCP6N11T-010E/SN

MCP3426A7T-E/SN

MCP6N11T-100E/SN

MCP3422A3T-E/SN

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PIC16F628AT-E/SO

MCP3428T-E/ST

MCP4021T-103E/SN

PIC18F57Q43T-E/6LX

PIC18F56Q43T-E/6LX

24FC512T-E/Q4B

24FC256T-E/MNY

ATSAMD21G17D-MFT

ATSAMD21G17L-MFT

PIC16F723AT-E/ML

PIC18F25K50T-E/ML

PIC10F220T-E/MC

MCP1727T-5002E/MF

MCP1726T-1202E/MF

PIC18F2480-I/SO020

PIC18F25K22-I/SS

24LC128-I/ST

24AA128-I/ST

PIC24F04KA201-I/SS

PIC18F26J13-I/SO

24LC256-I/ST

PIC24EP512GP202-I/SO

PIC24EP512MC202-I/SO

PIC16F883-I/SS063

PIC16F883-I/SS079

PIC18F24Q10-I/SS

PIC18F26K80-I/SO

PIC18F25K80-I/SOC03

PIC16LC717-I/SS032

PIC18F27K40-I/SS

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DSPIC33FJ32MC302-I/SO

PIC24FV08KM202T-I/SS

PIC24FJ128GL302T-I/SO

ATMEGA3208-XUR

DSPIC30F3010T-20I/SO

PIC18LF65K80-I/PT

PIC18LF6722-I/PT

PIC18F6722-I/PT

PIC18LF6627-I/PT

PIC18F6627-I/PT

PIC18F6722-I/PTV04

PIC18F65K80-I/PT

PIC18F66K80-I/PT

PIC24FJ128GA106-I/PT041

ATSAM4LS2CA-AU

DSPIC33EP256MC206-I/PTA3

DSPIC33EP64MC206-I/PTA3

PIC24FJ1024GA610-I/PTC01

DSPIC33FJ32GS406-E/PT

DSPIC33FJ32GS606-E/PT

PIC24HJ32GP304-E/PT

PIC16F19196-E/PT

PIC16F19197-E/PT

PIC16LF19195-E/PT

PIC16LF19196-E/PT

PIC16LF19197-E/PT

PIC32MZ0512EFE064-E/PT

PIC32MZ0512EFF064-E/PT

PIC32MZ1024EFK064-E/PT

DSPIC33CK256MC505-H/PTVAO

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DSPIC33CK64MC105-H/PTVAO

DSPIC33CK128MC106-H/PTVAO

DSPIC33AK128MC105-H/PTVAO

DSPIC33AK64MC105-H/PTVAO

DSPIC33CK512MP608-H/PTVAO

DSPIC33CK512MP606-H/PTVAO

DSPIC33CK256MP606-H/PTVAO

MCP73833T-DZI/MF

MCP1725-1202E/MC

MCP1725-0802E/MC

PIC12F609-E/MD

MCP1725-1802E/MC

MCP4231-104E/ML

MCP4231-503E/ML

MCP4131-502E/MF

ATSHA204A-MAH1T-S

ATSHA204A-MAH1T-T

ATSHA204A-MAH2D-S

ATSHA204A-MAH2R-S

ATSHA204A-MAH3N-S

ATSHA204A-MAH3V-S

ATSHA204A-MAHLC-T

LE87286NQCT

DSPIC33EP128MC204T-I/ML

USB2514BT/M2

USX2064T/M2

KSZ9031RNXCA-TR

PIC32MX695F512L-80I/PF

ATMEGA328-AU

ATMEGA328P-AU

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PIC16F15256-I/SSVAO

PIC16F18056-I/SSVAO

LX34070-H/STVAO

PIC16F1825-H/STVAO

DSPIC33EP256GM604-E/PT

DSPIC33EP512GM604-E/PT

PIC32MM0064GPM064-E/PT

PIC32MM0128GPM064-E/PT

PIC32MM0256GPM064-E/PT

DSPIC30F6010A-20E/PTC02

DSPIC33CK256MP506-E/PTC01

DSPIC33CK64MP206-E/PTC02

DSPIC33CK64MP206-E/PTC03

DSPIC33CK256MP208-E/PTC01

DSPIC33CK256MP508-E/PTC02

DSPIC33CK128MP208-E/PTC05

PIC18F27Q84-E/5NVAO

DSPIC33CK128MC505-E/M7VAO

PIC32CM5164JH01048-E/U5B-SL3VAO

DSPIC30F5011-30I/PT

PIC18F46Q83-I/PT

DSPIC30F5013-20I/PT

DSPIC30F5013-30I/PT

ATSAMD21J18A-AU

ATSAMD21J17A-AU

PIC32CM2532JH00100-I/PF

PIC18F67J11-I/PTC06

PIC18LF66K80-I/PT

PIC18LF45K80-I/PT

PIC18LF46K80-I/PT

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PIC18F45Q10T-E/PTVAO

ATSAMD21E18A-AZT510

ATSAMD21E18A-AZTVAO

ATSAMD21J18A-AZT510

ATSAMD21G18A-AZT510

ATSAMD21E16B-AZTVAO

DSPIC33CK256MP206T-E/PTVAO

DSPIC33CK256MP506T-E/PTVAO

PIC16F1939T-E/MVVAO

PIC16LF18323T-E/JQVAO

PIC18F25Q10T-E/STXVAO

PIC16F15324T-E/JQVAO

PIC18F442-I/ML

PIC16F1517-I/MV

PIC12F617-I/MF

MCP73833-DZI/MF

PIC18LF2510-I/ML

PIC18F2510-I/ML

25LC320-I/SN

PIC16F18324-I/ST

DSPIC33FJ16GS504T-I/PT

PIC24HJ256GP610AT-I/PF

PIC32MX230F128LT-I/PT

PIC32MX270F512LT-I/PT

DSPIC33FJ128MC708T-I/PT

PIC32MX130F128LT-I/PT

DSPIC33FJ256GP710AT-I/PF

PIC32MX150F256LT-50I/PF

PIC32MX675F512HT-80I/PT

PIC32MX675F256HT-80I/PT

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PIC24FJ512GB610T-I/PT

PIC24HJ64GP506T-I/PT

PIC24HJ128GP206T-I/PT

PIC24HJ128GP506T-I/PT

PIC32MX795F512HT-80I/PT

PIC32MX575F256HT-80I/PTC22

PIC32MX695F512LT-80I/PTD21

PIC32MX530F128LT-I/PT

PIC32MX575F512HT-80I/PTC24

PIC32MX575F512HT-80I/PT

DSPIC33FJ16GS404T-I/PT

PIC32MX695F512HT-80I/PT

PIC16F688T-I/STVAO

PIC16F18325T-I/STVAO

PIC16F18323T-I/STVAO

PIC16F506T-I/STVAO

PIC16F630T-I/STVAO

PIC16F1825T-I/STVAO

24LC256T-I/ST16KVAO

PIC16F616T-I/STVAO

PIC16F1503T-I/STVAO

PIC16LF18324T-I/STVAO

MCP3004T-I/STVAO

PIC16F15245T-I/SSVAO

PIC16LF1503T-I/STVAO

MCP6024T-I/STVAO

24LC128T-I/ST16KVAO

MCP7940MT-I/STVAO

DSPIC33EV64GM002T-I/SSVAO

DSPIC33EV64GM102T-I/SSVAO

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DSPIC33EV32GM002T-I/SSVAO

PIC16F18426T-I/STVAO

PIC16LF15324T-I/STVAO

25AA128T-I/ST16KVAO

PIC16F1705T-I/STVAO-VW

PIC16F15256T-I/SSVAO

PIC16F18056T-I/SSVAO

MCP6022T-E/STVAO

MCP25625T-E/SSVAO

PIC16HV616T-E/STVAO

93LC46BT-E/ST15KVAO

24LC02BT-I/MNY

PIC16F1823T-I/ML

24AA16HT-I/MNY

PIC16F1825T-I/ML

24LC04BHT-I/MNY

24AA01HT-I/MNY

24AA04HT-I/MNY

24AA02HT-I/MNY

24LC01BHT-I/MNY

PIC18F44K22T-I/MV

DSPIC33EP256MU806-E/MR

MCP48FVB24-E/MQ

DSPIC33FJ64GS606-E/MR

DSPIC33FJ32GS606-E/MR

DSPIC33EP512MC204-E/ML

DSPIC33EP512MC504-E/ML

EQCO31X20C1T-I/3DW

PIC16LF721T-I/ML

24CS512T-I/Q4B

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PIC18F56Q43T-I/6LX

USB5806CT-I/KD

ATSAMC20E17A-MUTS2

ATSAMC21G18A-MUTN01

ATSAMC21G17A-MUTS2

DSPIC30F3010T-30I/SO

DSPIC33EP512GP502T-I/SO

PIC24FJ128GL302T-I/ML

PIC18LF4321-I/PT

PIC18F8410-I/PT

PIC18LF4510-I/PT

PIC18F4510-I/PT

PIC24FJ256GA108-I/PT

PIC24FJ192GA108-I/PT

PIC18F66J50-I/PT

PIC18F8490-I/PT

PIC24FJ128GA108-I/PT

PIC18F8622-I/PT

PIC18F8527-I/PT

PIC18F65J10-I/PT

PIC18F86J16-I/PT

PIC18F87J11-I/PT

PIC24FJ128GA110-I/PF

PIC24FJ256GA110-I/PF

PIC18LF8627-I/PT

PIC18LF44J10-I/PT

PIC18F8627-I/PT

PIC24FJ64GL302T-I/ML

PIC32MZ2048ECG064T-I/MR

DSPIC33EP256MU806T-I/MR

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PIC32MX370F512HT-I/MR

PIC32MX470F512HT-I/MR

PIC32MZ2048EFG064T-I/MR

PIC32MZ2048EFH064T-I/MR

PIC32MZ2048EFH064T-250I/MR

PIC32MZ0512EFK064T-I/MR

DSPIC33EP512MC806T-I/MR

PIC18F47K42T-I/ML

PIC32MZ2048EFH100-I/PF

PIC32MZ1024EFH100-I/PF

PIC32MZ1024EFK100-I/PF

DSPIC33FJ128MC510-I/PTC22

PIC24HJ128GP306-I/PT

DSPIC33FJ128MC506-I/PT

DSPIC33FJ16GS504-I/PT

PIC32MX130F064D-I/PT

PIC32MX130F064D-50I/PT

PIC32MX230F064D-I/PT

DSPIC33FJ64GP206-I/PT

DSPIC33FJ64GP306-I/PT

DSPIC33FJ64GP706-I/PT

PIC32MX150F256H-50I/PT

DSPIC33FJ128MC706-I/PT

PIC24HJ64GP210-I/PT

PIC24HJ64GP510-I/PT

DSPIC33FJ16GS404-I/PT

ATMEGA64L-8AURA3

ATMEGA64-16AURA1

ATXMEGA64A1-AUR

ATXMEGA128A1-AUR

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ATXMEGA32C4-AUR

ATXMEGA16D4-AUR

ATXMEGA32D4-AUR

PIC18LF8620-I/PT

PIC18F8620-I/PT

PIC18LF8720-I/PTC01

PIC24FJ64GA004-I/PT

PIC24FJ64GA004-I/PTC08

PIC18F46Q43-I/PT

PIC18F56Q43-I/PTC01

PIC18F56Q43-I/PT

DSPIC33EP128GS704-I/PT

DSPIC33EP128GS804-I/PT

DSPIC33EP64GS804-I/PT

PIC32MX270F512H-50I/PT025

DSPIC33CK512MPT608-I/PT

DSPIC33CK256MPT608-I/PT

PIC18LF47K40-I/PT

PIC18LF45K40-I/PT

PIC18LF46K40-I/PT

PIC32CX2051MTC128-I/X9B

25LC080DT-E/ST

25LC080CT-E/ST

25LC160CT-E/ST

PIC32AK3208GC41036-E/M7

PIC32AK1216GC41048-E/M7

PIC32AK6416GC41048-E/M7

PIC18LF47K40-E/PT

PIC18LF45K40-E/PT

PIC18LF46K40-E/PT

Date: Tuesday, July 22, 2025

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DSPIC33CK512MP408-E/PT

MCP14A0153T-E/MNY

MCP14A0154T-E/MNY

MCP14A0155T-E/MNY

MCP14A0601T-E/MNY

MCP14A0602T-E/MNY

MCP14A0453T-E/MNY

MCP14A0454T-E/MNY

MCP14A0455T-E/MNY

MCP14A0303T-E/MNY

MCP14A0304T-E/MNY

MCP14A0305T-E/MNY

PIC18F24K22T-E/ML

MIC2129T-E/U3BVAO

PIC18F25Q10T-E/5NVAO

PIC18F24Q10T-E/MVVAO

PIC16F18445T-E/GZVAO

PIC16LF18446T-E/GZVAO

PIC16LF15344T-E/MLVAO

PIC16LF15355T-E/5NVAO

DSPIC33CK128MC106T-E/MRVAO

PIC18F26K42T-E/ML510

TC1301B-IECVMFTR

TC1301B-UUAVMFTR

TC1302B-AFVMFTR

TC1301B-DDAVMFTR

TC1301A-UPBVMFTR

PIC18LF4450-I/PT

PIC18F4450-I/PT

PIC16C923-04I/PT

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PIC18F6520-I/PT

PIC18LF4431-I/PT

PIC18LF4420-I/PT

PIC18F4420-I/PT

PIC18F67J10-I/PTREL

PIC16LF747-I/PT

PIC16F747-I/PT

PIC18F87J10-I/PTREL

PIC16LC923-04I/PT

PIC16LC74B-04I/PQ

PIC16F777-I/PT

PIC18F8585-I/PTC06

PIC17C42A-16I/PQ

PIC16C74B-20I/PQ

PIC18LF46K22-I/PT

PIC18F66J94-I/PT

PIC18F67J94-I/PT

PIC18F95J94-I/PT

PIC18F96J94-I/PF

PIC18F96J94-I/PT

PIC18F97J94-I/PF

PIC16F1784-I/PT

PIC18F85J94-I/PT

PIC18F43K20-I/PT

PIC18LF4455-I/PT

PIC18F87K90T-I/PT026

PIC18F87K90T-I/PT031

PIC18F87K90T-I/PT032

DSPIC33FJ16GS504-I/PTD24

PIC32MK1024MCM064T-E/PT

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DSPIC33CK256MP306T-E/PT

DSPIC33CK256MP606T-E/PT

DSPIC33CK512MP306T-E/PT

DSPIC33CK512MP606T-E/PT

PIC24HJ32GP304T-E/PT

DSPIC33FJ128GP804T-E/PT

DSPIC33FJ128MC804T-E/PT

PIC32CM1216MC00032T-E/PT

PIC32CM6408MC00032T-E/PT

DSPIC33CK256MP308T-E/PT

DSPIC33CK256MP608T-E/PT

DSPIC33CK512MP308T-E/PT

PIC32CM6408MC00048T-E/Y8X

DSPIC33CK512MP608T-E/PT

DSPIC33CK256MP305T-E/PT

PIC32CM1216MC00048T-E/Y8X

DSPIC33CK64MP508T-E/PT

DSPIC33CK128MP206T-E/PT

DSPIC33CK128MP506T-E/PT

DSPIC33CK256MP508T-E/PT

DSPIC33CK256MP206T-E/PT

DSPIC33CK256MP506T-E/PT

DSPIC33CK256MP605T-E/PT

DSPIC33CK512MP305T-E/PT

DSPIC33CK512MP605T-E/PT

DSPIC33CK128MP208T-E/PT

DSPIC33CK128MP508T-E/PT

DSPIC33CK64MP208T-E/PT

PIC32MZ1024EFE064T-E/PT

PIC16LF767-I/ML

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MCP73834-G8I/MF

PIC16F627A-I/ML

MCP73834-6SI/MF

PIC16F884-I/ML

PIC12F615-I/MD

MCP73833-YAI/MF

MCP73833-FCI/MF

MCP73833-G8I/MF

MCP73833-GPI/MF

MCP73833-NVI/MF

MCP73837-FJI/MF

MCP73837-NVI/MF

MCP1602-250I/MF

DSPIC33CH512MP508-E/PT

AVR16DD28-E/SO

PIC18F06Q41-E/ST

PIC18F06Q40-E/ST

DSPIC33EP64GP502-E/SS

AVR64EA28-E/SS

24FC01-E/ST

AVR32EA28-E/SS

24FC02-E/ST

24FC04-E/ST

24FC04H-E/ST

AVR16EA28-E/SS

PIC16LF726-E/SS

PIC16LF722-E/SS

PIC12F1571-E/SN

PIC12F1572-E/SN

24FC128-E/SN

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PIC16LF18345-E/SS

PIC16LF1718-E/SS

PIC18LF27K40-E/SS

PIC16F18025T-E/ML

PIC18F27Q10T-E/STX

AVR32DB32T-E/RXB

AVR64DB32T-E/RXB

ATSAMD21J15B-MMZT

ATSAMD21J16B-MMZT

AVR64DA48T-E/6LX

AVR64DA64T-E/MR

93C76CT-I/MC

93C86CT-I/MNY

93C86CT-I/MC

PIC18F23K22T-I/MV

24AA02T-I/MNY

24LC02BT-I/MC

24AA02T-I/MC

24LC32AT-I/MNY

PIC16LF1907T-I/MV

PIC16F1784T-I/MV

PIC18F87K90T-I/PT038

PIC18F87K90T-I/PT042

PIC18F87K90T-I/PT043

PIC18F87K90T-I/PT

PIC18F87K22T-I/PT

ATSAML21G18B-AUT

PIC18F87K90T-I/PT039

PIC18F87K22T-I/PTRSL

ATSAMD21J16B-AUT

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ATSAMD21J15B-AUT

DSPIC33CH64MP506T-I/PT

DSPIC33CH128MP506T-I/PT

PIC18LF47K42T-I/ML

PIC32MK1024GPD064-I/PT

PIC32MK1024MCF064-I/PT

PIC32MK0512GPE064-I/PT

PIC32MX795F512H-80I/PT

DSPIC33EP256GP504-E/PT

DSPIC33EP256MC204-E/PT

24AA256-I/STRVE

PIC18F13K22-I/SS

PIC18F1330-I/SS

24LC01B-I/SN

24AA01-I/SN

PIC18F2585-I/SO

PIC18F1230-I/SS

PIC16F722-I/SO

PIC18LF1230-I/SS

24AA512-I/ST14

PIC16F1827-I/SO

PIC16F1826-I/SO

PIC18F23K20-I/SO

PIC24FJ64GA002-I/SO

PIC16F18854T-E/MLVAO

ATA6561-GBQW

AVR64DD32T-E/RXBVAO

ATA6628-GLQW

ATA6622C-PGQW-1

MCP23S17T-E/MLVAO

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ATA6626C-PGQW-1

PIC18F26K83T-E/5NVAO

PIC16F15356T-E/5NVAO

DSPIC33EV256GM002T-E/MMVAO

DSPIC33EV256GM102T-E/MMVAO

MCP16501TD-E/RMBVAO

MCP16501TE-E/RMBVAO

ATMEGA48PA-15MZ

MCP16501TA-E/RMBVAO

MCP16501TB-E/RMBVAO

MCP16501TC-E/RMBVAO

MCP19115T-E/MQVAO

MCP19114T-E/MQVAO

PIC16LF18325T-E/JQVAO

PIC16F18324T-E/JQVAO

24LC16BT-E/MNY16KVAO

PIC16F1825T-E/JQVAO

PIC24EP256MC204-E/PT

ATSAMD21G15B-AZ

PIC32MM0256GPM048T-I/PT033

DSPIC33EP32GS506T-I/PTC09

PIC18F57Q43T-I/PT

MCP1727T-1202E/MF

MCP1727T-0802E/MF

MCP1727T-1802E/MF

MCP1727T-3302E/MF

MCP1727T-ADJE/MF

MCP1725T-0802E/MC

MCP1725T-1202E/MC

TC1301A-ADAVMFTR

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MCP4131T-502E/MF

MCP4131T-103E/MF

MCP4131T-104E/MF

MCP4132T-502E/MF

MCP1727T-3002E/MF

MCP1727T-2502E/MF

MCP4141T-103E/MF

MCP1725T-3302E/MC

MCP4141T-502E/MF

MCP4162T-103E/MF

MCP1725T-1802E/MC

MCP1725T-5002E/MC

MCP1725T-ADJE/MC

MCP1725T-2502E/MC

MCP1725T-3002E/MC

MCP4131T-503E/MF

ATSAMC21G18A-MUT

PIC16F15344T-I/MLC01

ATSAMC20G17A-MUT

ATSAMC20G18A-MUT

PIC16F15344T-I/ML

PIC16LF15344T-I/ML

PIC16F15344T-I/GZ

PIC16LF15344T-I/GZ

PIC16LF15324T-I/JQ

PIC18F46Q83T-I/NHX

PIC18F46Q84T-I/NHX

AVR16EA48T-I/6LX

PIC16F18013T-I/MF

PIC16F18014T-I/MF

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PIC16F15355T-I/ML

PIC16LF15354T-I/ML

ATECC608C-MAHCZ-S

ATECC608C-MAHCZ-T

24AA024T-I/MNY

24LC025T-I/MNY

24AA025T-I/MNY

24LC025T-I/MC

24AA025T-I/MC

24LC024T-I/MC

24AA024T-I/MC

24LC014T-I/MNY

24AA014T-I/MNY

DSPIC33CK256MP305T-I/M7

DSPIC33CK256MP605T-I/M7

DSPIC33CK512MP305T-I/M7

DSPIC33CK512MP605T-I/M7

24LC014T-I/MC

TC1301B-EFAVMFTR

TC1301A-UWFVMFTR

TC1302B-GPVMFTR

TC1302B-DPVMFTR

TC1301A-FEAVMFTR

TC1301A-NSBVMFTR

TC1301A-PGAVMFTR

TC1301A-EDAVMFTR

DSPIC33CK256MP305-I/PT

DSPIC33CK256MP605-I/PT

AT89C51RC2T-RLTUM

PIC18F47K40-I/PT

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PIC16F1947-I/PT

UCS4003-E/8NVAO

PIC16F1615-E/MLVAO

MCP19061-E/RTBVAO

AVR32DD28-E/STXVAO

PIC16C62B-04/SO

PIC16C72A-04/SO

25LC080BT-I/ST

25AA080BT-I/ST

25LC080AT-I/ST

25AA160AT-I/ST

25LC160BT-I/ST

PIC16F913T-I/SS

PIC16F913T-I/SS025

24AA02UIDT-I/SN

PIC32MX120F064H-I/MR

PIC32MX120F064H-50I/MR

PIC32MX230F128H-I/MRJ21

PIC24EP64GP202-I/MM

PIC32MX530F128H-I/MR

PIC32MX230F128H-I/MR

PIC32MX230F128H-50I/MR

PIC32MX530F128H-50I/MR

PIC32MX254F128D-I/ML

PIC32CM5164JH01048-E/U5BVAO

PIC18F26Q24-E/STXVAO

PIC32CM1602GV00032-E/RTBVAO

DSPIC33CK512MP605-E/M7VAO

PIC32CM2532JH01048-E/U5BVAO

PIC32CM3204JH00032-E/RTBVAO

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PIC24HJ32GP202-E/MM

DSPIC33FJ32MC202-E/MM

DSPIC33EP32GP502-E/MM

PIC16F18126-I/ST

PIC16F17124-I/ST

PIC16F18124-I/ST

PIC16F17125-I/ST

AVR16DD28-I/SS

PIC16F18125-I/ST

PIC16F19155-I/SS

PIC16F18054-I/SS

PIC16F18054-I/SO

PIC16LF1824-I/ST

PIC16F15324-I/ST021

PIC16F15324-I/ST

PIC16F1829-I/SS

PIC18F27Q10-I/SS

PIC18F26Q10-I/SS

DSPIC33CK256MC502-I/SS

DSPIC33CK128MC502-I/SS

DSPIC33CK256MC102-I/SS

DSPIC33CK128MC102-I/SS

PIC16LF1938-I/SS029

PIC16F18345-I/SS

DSPIC33EV64GM002-I/SS

DSPIC33EV64GM102-I/SS

DSPIC33EV32GM002-I/SS

DSPIC33EP128GP502-I/SS

DSPIC33EP128MC202-I/SS

DSPIC33EP128MC502-I/SS

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PIC24EP128GP202-I/SS

PIC24EP128MC202-I/SS

PIC18F26Q71-I/SS

ECC204-MAVCZ-T

ECC204-MAVDA-T

PIC18F8720T-I/PT

PIC32MX174F256DT-I/PT

PIC32MX274F256DT-I/PT

PIC32MX154F128DT-I/PT

PIC32MX254F128DT-I/PT

PIC24FJ64GA004T-I/PT041

PIC24FJ64GA004T-I/PT042

PIC24FJ64GA004T-I/PT043

PIC24FJ64GA004T-I/PT

DSPIC33EP128GS704T-I/PT

DSPIC33EP128GS804T-I/PT

PIC24FJ128GA204T-I/PT

PIC18F56Q43T-I/PT

DSPIC33EP64GS804T-I/PT

DSPIC33FJ256GP506T-I/PT

PIC32MX340F512HT-80I/PT

PIC32MX340F128HT-80I/PT

PIC24FJ64GA006T-I/PT032

DSPIC33FJ64MC506T-I/PT

MCP4251T-503E/ML

PIC32MK1024GPD064T-E/MR

PIC32MK1024MCF064T-E/MR

DSPIC33EP256GP504T-E/ML

MCP4331T-502E/ML

MCP4331T-103E/ML

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MCP4331T-104E/ML

MCP4331T-503E/ML

PIC18F4680T-I/ML

PIC16F727T-I/ML

PIC16LF1937T-I/MV

MCP41HV31-503E/ST

MCP41HV31-104E/ST

PIC16LF1459-E/SS

MCP98243-BE/ST

PIC16F1512-E/SS

MCP6422-E/SN

MCP23017-E/SS

PIC24FV32KA302-E/SO

PIC24FV16KA302-E/SS

MCP6482-E/SN

MCP6492-E/SN

MCP6472-E/SN

ATSAMC20E16A-MZ

ATSAMC20E15A-MZ

PIC18F46K22-E/ML

DSPIC33FJ128MC802-H/SO

PIC24HJ64GP502-H/SO

DSPIC33EV256GM102-H/SO

DSPIC33EV256GM002-H/SO

DSPIC33FJ16GS502-H/SO

PIC24HJ32GP202-H/SO

DSPIC33FJ32MC202-H/SO

PIC16F18345-H/SS

PIC18F26K80-H/SS

PIC18F25K80-H/SS

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PIC24EP32GP204-E/PT

DSPIC33CK128MP205-E/PT

DSPIC33CK128MP505-E/PT

DSPIC33CK64MP205-E/PT

DSPIC33CK64MP505-E/PT

PIC32MX340F512H-80V/MR

PIC32MX340F128H-80V/MR

PIC32MX440F256H-80V/MR

PIC32MX320F032H-40V/MR

PIC32MX420F032H-40V/MR

PIC32MX154F128B-V/MM

PIC32MX254F128B-V/MM

PIC32MX174F256B-V/MM

PIC32MX274F256B-V/MM

PIC32MX550F256H-V/MR

PIC32MX220F032B-V/ML

PIC32MX210F016B-V/ML

ATSAMD20G14A-MN

ATSAMD20G15A-MN

ATSAMD20G16A-MN

ATSAMD20G17A-MN

ATSAMD20G18A-MN

PIC16F1825T-I/MLVAO

PIC16F1938T-I/MLVAO

PIC16LF1709T-I/MLVAO

PIC24FJ256GA108-E/PT

PIC18F4682-E/PT

PIC16F1946-E/PT

PIC24FJ128GA108-E/PT

PIC16LF1946-E/PT

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PIC16LF1947-E/PT

24LC64T-I/MC16KVAO

DSPIC33EV64GM006T-I/MRVAO

PIC16LF1454T-I/MLVAO

MCP2221AT-I/MLVAO

PIC16F1786T-I/MLVAO

PIC16F19197T-I/5LXVAO

PIC18LF46K22T-I/MLVAO

ATSAMHA1E14A-MBT-BVAO

ATSAMHA1E15A-MBT-BVAO

ATSAMHA1E15A-MBT-B510

RE46C400V28

RE46C401V28

PIC32MX350F128H-V/MR

HA4584-I/PT

PIC32MZ0512EFE064-I/PTA21

PIC32MZ0512EFE064-I/PTA22

PIC32MZ0512EFE064-I/PTA23

DSPIC33FJ128GP306A-I/PT

DSPIC33FJ128GP206A-I/PT

DSPIC33FJ128MC510A-I/PT

DSPIC33FJ128MC710A-I/PT

PIC18F44K22-I/PT

PIC17C756A-33I/PTC03

PIC24HJ128GP206A-I/PT

PIC24HJ64GP506A-I/PT

PIC24HJ64GP206A-I/PT

PIC24HJ128GP210A-I/PT

PIC24HJ128GP310A-I/PT

PIC12F615T-I/SN083

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC12F615T-I/SN

93AA86CT-I/SN

93C76CT-I/SN

93LC76CT-I/SN

PIC32CM3204GV00048T-E/Y8X

PIC32CM3204GV00032T-E/T5X

PIC32CM1602GV00064T-E/V2X

PIC32CM1602GV00048T-E/Y8X

PIC32CM1602GV00032T-E/T5X

MCP6054T-E/ST

MCP6064T-E/ST

DSPIC33CH64MP206T-I/PT

PIC16F1939T-I/ML

PIC16F1933T-I/ML

PIC18F25K22T-I/ML

TC1302B-DSVMF

TC1302B-DTVMF

TC1301B-EDAVMF

TC1301B-EFAVMF

TC1301A-DFAVMF

TC1301B-EGAVMF

TC1302A-DTVMF

TC1301A-EDAVMF

TC1301A-EFAVMF

TC1301A-EGAVMF

TC1301A-FDAVMF

TC1301A-FEAVMF

TC1301B-HWEVMF

TC1301A-UWFVMF

TC1301B-AIAVMF

Date: Tuesday, July 22, 2025

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TC1301B-APAVMF

TC1301B-CCAVMF

TC1301B-DAAVMF

TC1301B-GGDVMF

TC1302B-FFVMF

TC1301B-FFAVMF

TC1301A-SSBVMF

TC1301A-UFEVMF

TC1301A-PGAVMF

PIC16F18055-I/STX

ATECC608B-TNGLORAU-B

ATECC608B-TNGTLSU-B

ATECC608B-TFLXTLSU-PROTO

ATECC608A-TNGTLSU-B

ATECC608A-MAHA2-B

DSPIC30F5015-30I/PT

DSPIC30F5016-30I/PT

ATF1508ASL-25AU100

PIC24EP128GP204-I/PT030

PIC24EP128GP204-I/PT035

PIC24EP128GP204-I/PT037

DSPIC33CH512MP506-I/PT

DSPIC33CK64MP505-I/PT

DSPIC33CK32MP205-I/PT

DSPIC33CK32MP505-I/PT

DSPIC33CH512MP206-I/PT

DSPIC33CH256MP506-I/PT

ATSAMD20E16B-AU

ATSAMD20E15B-AU

ATSAMD20E14B-AU

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATMEGA8A-AU

ATMEGA8A-AU-HCM

AGL060V2-VQ100I

AGL060V2-VQG100I

AGL060V5-VQ100I

PIC24FJ128GA306-I/PT

PIC24FJ128GA306-I/PTC06

ATMEGA3208-AU

ATMEGA3209-AU

PIC18F47Q83-I/PT

24LC01BT-E/MNY

24LC01BT-E/MC

PIC16F1825T-E/ML

24LC02BHT-E/MNY

PIC18F46K20T-E/ML

24LC04BT-E/MNY

24LC04BT-E/MC

PIC12F1822T-E/MF

MCP6482T-E/MNY

MCP6492T-E/MNY

MCP6472T-E/MNY

MCP41HV31T-104E/MQ

24LC01BHT-E/MNY

PIC18F65K22T-E/MR

PIC18F46K22T-E/MV

MCP25625T-E/ML

MCP41HV31T-503E/MQ

MCP41HV31T-502E/MQ

MCP41HV31T-103E/MQ

EMC1413-A-AIA-TR

Date: Tuesday, July 22, 2025

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PIC16LF1786T-I/ML

93LC46BT-I/MC

ENC624J600-I/PT

PIC18LF4620-I/PT

PIC32CX1025SG41100T-I/E5X

PIC32MX764F128H-V/MR

PIC32MX534F064H-V/MR

PIC32MX220F032D-V/ML

PIC32MX210F016D-V/ML

PIC32MX564F128H-V/MR

PIC32MX120F032D-V/ML

DSPIC30F6015-30I/PT022

PIC32CM5164JH01100-I/PF511

PIC32CM5164JH01100-I/PF510

PIC32CM6408JH00048-I/Y8X

PIC32CM6408JH00032-I/T5X

PIC32CM3204GV00032-I/T5X

PIC32CM3204GV00064-I/V2X

PIC32CM3204GV00048-I/Y8X

PIC32CM3204JH00048-I/Y8X

PIC32CM3204JH00032-I/T5X

PIC32CM3204JH00064-I/V2X

PIC32CM1602GV00064-I/V2X

PIC32CM1602GV00048-I/Y8X

PIC32CM1602GV00032-I/T5X

93LC46A-E/SN

93LC46B-E/SN

93C46B-E/SN

PIC16F18424-E/ST

PIC16F18425-E/ST

Date: Tuesday, July 22, 2025

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25AA128T-E/ST

PIC16F18456T-E/SS

PIC24F16KL401T-E/SS

MCP7940NT-E/SN

25LC020AT-E/ST

25LC040AT-E/ST

PIC12F509T-E/SN

MCP42U83T-503E/ST

MCP42U83T-104E/ST

24FC128T-E/SN

24AA128T-E/ST

24FC128T-E/ST

MCP2200T-E/SS

AVR128DA28T-E/SS

AVR128DA28T-E/SO

PIC16F18345T-E/SS020

PIC16F18345T-E/SS021

PIC16F18345T-E/SS022

PIC32MK0128MCA028T-E/N2X

93LC46AT-E/SN

93LC46BT-E/SN

MCP3004T-E/ST

93C46BT-E/SN

93C46AT-E/SN

PIC16F18425T-E/ST

PIC32MZ1024EFF064T-E/PT

PIC32MZ1024EFG064T-E/PT

DSPIC33CH128MP508T-I/PT

DSPIC33CH64MP208T-I/PT

ATSAMC20E18A-AUT

Date: Tuesday, July 22, 2025

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ATSAMC21E18A-AUT

ATSAMC20E15A-AUT

PIC24EP256MC204T-I/PT

ATSAMC20G18A-AUT

ATSAMC20G15A-AUT

ATSAMC20E17A-AUT

ATSAMC21E15A-AUT

ATSAMC21E16A-AUT

ATSAMC21E17A-AUT

PIC18F66J16T-I/PT

ATSAMC20G16A-AUT

PIC18F4680-E/PTVAO

PIC18F8680-E/PTVAO

DSPIC33EP32GP504-E/PTVAO

DSPIC33EP32MC204-E/PTVAO

DSPIC33EP32MC504-E/PTVAO

AVR32DA32-E/PTVAO

DSPIC33CK64MP205-E/PTVAO

DSPIC33CK128MP206-E/PTVAO

AVR32DA48-E/PTVAO

PIC32MZ0512EFF064-E/PTVAO

DSPIC33CK256MP505-E/PTVAO

PIC18F26K22-I/SOC02

PIC12F675-I/SN102

PIC12F675-I/SN112

MCP79410-I/SN

PIC16F1516-I/SSC02

PIC12F675-I/SN

93AA56B-I/SN

93AA56C-I/SN

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93AA56C-I/ST

PIC18F24K42-I/SS

HCD0-00ESI/D0C4A

93AA56A-I/SN

34LC02-I/SN

34AA02-I/SN

24LC128-I/SN

24LC256-I/SN

PIC18F25K20-I/SOLPR

24LC64-I/SNRVE

24AA32A-I/SNRVE

PIC18LF26K22-I/SOC01

24CW160-I/ST

24CW640-I/ST

24CW320-I/ST

24LC32A-I/SNA27

24LC32A-I/SNRVE

MCP45HV31T-502E/MQ

MCP45HV31T-103E/MQ

MCP45HV31T-503E/MQ

MCP45HV31T-104E/MQ

MCP1632T-AAE/MC

MCP1632T-BAE/MC

PIC12LF1501T-E/MC

MCP6N16T-010E/MF

MCP6V32T-E/MNY

MCP6V12T-E/MNY

PIC16F18045-E/ML

DSPIC30F3012-20E/ML

DSPIC30F3013-20E/ML

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DSPIC30F2012-20E/ML

DSPIC33FJ64MC202-E/MMC04

PIC18F47Q43-E/MP

ATTINY3217-MF

DSPIC30F3011-20E/ML

PIC16LF1825-E/ML

MCP3911A0-E/ML

AVR32DA48-E/6LX

PIC18F67K22-E/MR

PIC24HJ128GP506A-I/PTVAO

PIC18F45Q10-I/PTVAO

ATMXT224S-AT

PIC32MZ1024EFH100-I/PTVAO

MCP3426A4T-E/SN

MCP3422A5T-E/SN

PIC24FJ16GA002T-E/SO

24C02CT-E/SN

MCP660T-E/ST

PIC18F2420T-E/SO020

24C01CT-E/ST

24LC64XT-E/ST

MCP624T-E/ST

MCP6N11T-001E/SN

MCP6L4T-E/ST

MCP6L74T-E/ST

MCP6072T-E/SN

93C56T-E/SN

MCP6074T-E/ST

DSPIC33FJ64GP206T-I/PT

DSPIC33FJ64GP306T-I/PT

Date: Tuesday, July 22, 2025

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DSPIC33FJ64GP706T-I/PT

ATSAMD20G16A-AUT

DSPIC33FJ64MC706T-I/PT

DSPIC33FJ128GP206T-I/PT

PIC32MZ1024ECG100T-I/PF

PIC32MZ2048ECG100T-I/PT

PIC24HJ256GP610T-I/PT

PIC32MZ2048ECG100T-I/PF

DSPIC33FJ256GP710T-I/PT

DSPIC33FJ64MC506AT-I/PT022

DSPIC33FJ64MC506AT-I/PT023

DSPIC33FJ64MC506AT-I/PT025

DSPIC33FJ64MC506AT-I/PT026

DSPIC33FJ64MC506AT-I/PT027

PIC24FJ128GL305T-I/PT

SY75604ATWL-TR

SY75603BTWL-TR

SY75604BTWL-TR

ECC204-TFLXAUTHU

ECC204-TFLXWPCU

PIC32MX170F256DT-V/ML

PIC32MX270F256DT-V/ML

ATECC608B-MAVHL-S

ATECC608B-MAVHL-T

ATSAMDA1E16B-MBT

ATSAMDA1E15B-MBT

HA7619T-I/ML027

PIC16LF1554T-I/ML

PIC16F1784T-I/ML

PIC16F1787T-I/ML

Date: Tuesday, July 22, 2025

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HA7617T-I/ML046

PIC16LF1705T-I/ML

PIC16F18877T-I/ML

PIC10LF322T-I/MC

PIC16F886T-I/ML

PIC16F1825T-I/JQ

MCP2200T-I/MQRVB

MCP2200T-I/MQ031

MCP2200T-I/MQ

MCP2210T-I/MQ

PIC16F616T-I/ML034

PIC24FJ16GA004T-I/MLC09

PIC16F1827T-I/MV040

PIC24FJ32GA104T-I/ML026

PIC18F24K22T-I/MV

PIC18F26K22T-I/MLC03

C0029QIC03T-I/ML042

PIC18F45K20T-I/MLC05

MTCH6301T-I/ML

ENC28J60T-I/ML

PIC16F1827T-I/MV039

PIC16LF1938T-I/MLC01

PIC16LF1938T-I/MV

PIC16LF1938T-I/MVC03

PIC24F16KA102T-I/ML

PIC24F16KA101T-I/MQ

PIC16F1933T-I/MV

PIC16F1938T-I/MLRA2

AT25640B-MAHL-E

AT25640B-MAHL-T

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DSPIC33EV32GM006-E/PT

ATSAML11E16A-AFKPH

DSPIC33EV256GM006-E/PT

DSPIC33EV256GM106-E/PT

PIC24FJ1024GB610-E/PT

24C00T-I/SN

24LC00T-I/SN

24AA00T-I/SN

PIC24F16KA101T-I/SS

PIC24F16KA102T-I/SS

PIC18F25K22T-I/SOC02

PIC18LF2455T-I/SO

PIC18F2455T-I/SO

PIC12F609T-I/SN027

PIC12F609T-I/SN

PIC16HV785T-I/SS

PIC24FJ128GA410-I/PT

PIC24FJ64GA410-I/PT

PIC16F19195-I/PT

PIC24FJ256GB410-I/PT

PIC24FJ128GB410-I/PT

PIC24FJ128GA204-I/PT

DSPIC33CK64MC105-I/PT

DSPIC33CK32MC105-I/PT

DSPIC33EP64GS506-I/PT020

DSPIC33EP64GS506-I/PTC08

DSPIC33EP64GS506-I/PT

ATTINY48-MUR

24AA014T-I/MC

24C02CT-I/MNY

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24C02CT-I/MC

24C01CT-I/MNY

25LC040AT-I/MNY

25AA040AT-I/MNY

25AA010AT-I/MC

PD39210R-011020-TR

DSPIC33EP32MC504T-E/ML

MCP6V82T-E/MNY

MCP6V92T-E/MNY

MCP4361T-503E/ML

PIC24EP32GP204T-E/ML

PIC24EP32MC204T-E/ML

PAC1921-1-AIA-TR

CAP1206-1-AIA-TR

CAP1296-1-AIA-TR

PIC18F25K80T-E/MM

PIC18F26K80T-E/MM

PIC18F25K80T-E/MMC01

MCP6V77T-E/MNY

CAP1293-1-AC3-TR

CAP1203-1-AC3-TR

EMC1444-A-AIA-TR

25AA160DT-E/MNY-PR

PIC24F16KA101T-E/MQ

MCP9903T-AE/9Q

MCP9904T-1E/9Q

MCP9904T-2E/9Q

MCP4261T-104E/ML

MCP4251T-502E/ML

MCP4251T-103E/ML

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24AA08HT-I/ST

PIC16LF1704T-I/ST

24LC16BT-I/ST

PIC16LF1503T-I/ST

PIC16LF1455T-I/ST

93C56CT-E/ST

93LC66AT-E/ST

93LC46CT-E/ST

MCP6002T-E/SN

MCP47FVB21A1T-E/ST

MCP47FVB21A2T-E/ST

25LC128XT-E/ST

PIC24EP512GP204-E/ML

DSPIC33FJ128GP804-E/ML

PIC16F15375-E/ML

PIC16F15376-E/ML

PIC16LF15375-E/ML

PIC16LF15376-E/ML

ATSAMC21G18A-MZ

ATSAMC20G17A-MZ

ATSAMC21G17A-MZ

ATSAMC21G16A-MZ

ATSAMC21G15A-MZ

PIC16F17146-E/6N

PIC16F18146-E/6N

PIC16F15375-E/MV

PIC16F15376-E/MV

PIC16LF15375-E/MV

ATSAMC20G18A-MZ

24LC02B-E/ST

Date: Tuesday, July 22, 2025

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34LC02-E/ST

MCP6004-E/ST

93C56A-E/ST

93C56B-E/ST

93C56C-E/ST

MCP47FEB22A1-E/ST

MCP47FEB22A2-E/ST

PIC16F1613-E/ST

24LC32AX-E/ST

PIC16LF1516-E/SS

PIC16LF1518-E/SS

PIC16LF1512-E/SO

93C46B-E/ST

PIC16F1707-E/SS

MCP47FEB22A3-E/ST

MCP47FVB22A0-E/ST

24LC014-E/ST

MCP6V64-E/ST

MCP4151T-502E/MF

MCP4162T-503E/MF

MCP4132T-103E/MF

MCP4132T-104E/MF

MCP4132T-503E/MF

MCP4161T-104E/MF

MCP9805T-BE/MC

MCP4161T-103E/MF

MCP4161T-503E/MF

MCP4142T-502E/MF

MCP4142T-103E/MF

MCP4142T-104E/MF

Date: Tuesday, July 22, 2025

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24LC16BT-E/MC

MCP3422A1T-E/MC

MCP3422A4T-E/MC

MCP4152T-502E/MF

MCP4152T-103E/MF

MCP4152T-104E/MF

MCP4152T-503E/MF

TC1302B-PFVMFTR

PIC16C924-08/L

PIC16C74A-10/L

PIC16C74A-20/L

PIC16LC74A-04/L

PIC16C77-04/L

PIC16C77-10/L

PIC16C64A-04/L

TC7106CLW

TC7106ACW

TC7107CLW

TC7107ACW

TC7117CLW

PIC16C924-04/L

PIC16C923-04/L

PIC17LC756A-08/L

PIC17C756A-33/L

PIC17C756A-16/L

PIC17C752-16/L

PIC17C752-33/L

TC850CLW

PIC32MZ1024EFG064-I/PTN22

PIC32MZ2048EFM064-I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F15275-I/PT

PIC16F15276-I/PT

PIC24FJ256GA106-I/PT

PIC18F45K40-I/PT

PIC18F46K40-I/PT

PIC24FV16KA302T-I/MLVAO

PIC16F1503T-I/MGVAO

PIC16F1824T-I/MLVAO

PIC16F886T-I/MLVAO

PIC16F1823T-I/MLVAO

PIC16F1704T-I/MLVAO

PIC16F1705T-I/MLVAO

PIC16F1718T-I/MLVAO

SY89840UMG-TR

SY89876LMG-TR

SY89841UMG-TR

SY89875UMG-TR

SY89831UMG-TR

SY89833LMG-TR

SY89871UMG-TR

SY88149HALMG-TR

SY89872UMG-TR

SY88063CLMG-TR

SY88073LMG-TR

SY88083LMG-TR

SY88953ALMG-TR

SY89228UMG-TR

SY89832UMG-TR

SY89834UMG-TR

SY89873LMG-TR

Date: Tuesday, July 22, 2025

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SY88992LMG-TR

AT24C256C-MAHL-E

PIC18F2580-I/ML

PIC18F2480-I/ML

MCP73832-2DCI/MC

MCP73832-3ACI/MC

MCP73832-4ADI/MC

MCP73832-5ACI/MC

AR1010-I/ML

PIC18F4520-I/ML

PIC18F4523-I/ML

PIC24F04KA201-I/MQ

PIC16F883-I/ML

MCP73832-2ACI/MC

MCP73832-2ATI/MC

TC7106ACPT713

TC7107CPT713

TC7116ACPT713

MCP6V74-E/ST

24LC04B-E/ST

PIC16LF1765-E/ST

PIC16LF1764-E/ST

PIC16LF1705-E/ST

PIC16LF1619-E/SS

PIC16LF1618-E/SS

PIC16F1709-E/SS

PIC16F1618-E/SS

PIC16F1615-E/ST

PIC16F1619-E/SS

PIC16LF1614-E/ST

Date: Tuesday, July 22, 2025

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24LC512-E/SN

PIC16LF1615-E/ST

PIC16LF1769-E/SS

PIC18LF25K22-E/SS

PIC16F1705-E/ST

PIC16F1718-E/SS

MCP3912A1-E/SS

MCP3919A1-E/SS

DSPIC33EV256GM002-E/SS

DSPIC33EV256GM102-E/SS

PIC16LF1579-E/SS

PIC16F1574-E/ST

PIC16F1575-E/ST

PIC16LF1574-E/ST

PIC16LF1575-E/ST

PIC16LF1578-E/SS

DSPIC33FJ12MC202-E/SO023

PIC16F1704-E/ST

PIC16F1708-E/SS

PIC18F2620-E/SO

PIC18F2525-E/SO

MCP602-E/SN

PIC24FJ1024GB606-I/PTC02

ATSAMD20G15A-AU

ATSAMC21E16A-MUT

PIC18LF24K40T-I/MV

PIC18LF25K40T-I/MV

PIC16F15356T-I/MV

ATMEGA88PA-MUR

PIC16F19155T-I/MV

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AVR32DA32T-I/RXB

PD69210R-035500-TR

ATSHA204A-MAHCZ-T

PIC32MK0512MCJ064T-I/R4X

PIC32MK0512GPG064T-I/R4X

PIC32MK0256MCJ064T-I/R4X

PIC16F874A-I/PT

PIC16F77-I/PT

TC1302B-DRVMF

DSPIC33EP64GS506-I/PTVAO

ATMXT641TD-AT

ATMXT449TD-AT

PIC18F46Q10-I/PTVAO

ATMXT641T-AT

ATMXT449T-AT

PIC18F45K20-I/PTVAO

OS81050AT-E1A-011007-V01

DSPIC33CH512MP506-I/PTVAO

ATMEGA324A-AU

ATMEGA165PA-AU

ATMEGA169PA-AU

ATMEGA169A-AU

ATMEGA325-16AU

ATMEGA3290P-20AU

ATXMEGA16A4-AU

ATXMEGA32D4-AUA0

ATXMEGA32A4-AU

ATXMEGA192A3U-AU

ATXMEGA256A3BU-AU

ATXMEGA256A3U-AU

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ATXMEGA128A3U-AU

ATXMEGA128B3-AU

ATMEGA165A-AU

AT89S8253-24AU

ATMEGA3250P-20AU

AT89C51RC-24AU

ATMEGA64A-AU

ATMEGA64-16AU

ATMEGA6450A-AU

PIC32MZ2048EFM100-I/PTBR2

PIC32MZ0512EFF100-I/PT

PIC32MZ1024EFK100-I/PT

PIC32MZ1024EFG100-I/PT

PIC32MZ1024EFH100-I/PTH21

PIC32MZ0512EFK100-I/PT

PIC32MZ1024EFE100-I/PTE21

PIC32AK3208GC41048-E/M7

AVR32DA48S-E/6MX

AVR64DA32S-E/QZB

AVR64DA48S-E/6MX

AVR64DA64S-E/5LX

AVR32DA32S-E/QZB

ATSAMC21E17A-OMZ

ATSAMC21J17A-OMMZ

ATSAMC21G17A-OMZ

MCP3912BA1-E/MQ

MCP3919BA1-E/MQ

MCP73853-I/ML

MCP1612-ADJI/MF

PIC12F675-I/MD

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PIC16F648A-I/ML

TC1302A-ISVMF

PIC16LF648A-I/ML

PIC10F204-I/MC

PIC32MX174F256DT-V/PT

PIC32MX274F256DT-V/PT

PIC32MX154F128DT-V/PT

MCP19111-E/MQ

MCP41HV31-502E/MQ

PIC16F1937T-I/PT

PIC18F45K22T-I/PT

PIC16F917T-I/PT

PIC16F914T-I/PT

PIC16F946T-I/PT

PIC16F946T-I/PTC02

PIC16F946T-I/PT024

PIC24FV16KA304T-I/PT

PIC16F1939T-I/PT

DSPIC33FJ128GP708AT-I/PT

DSPIC33FJ64GP710AT-I/PT

DSPIC33FJ128GP310AT-I/PT

PIC32MX340F512H-80I/PT

PIC32MZ1024EFE100-I/PTE22

PIC32MZ1024EFG100-I/PTG22

PIC32MZ1024EFG100-I/PTG23

PIC32MZ1024EFH100-I/PTH22

PIC32MZ1024EFH100-I/PT

PIC32MZ1024EFE100-I/PT

DSPIC33EV256GM106-I/PTC01

PIC32MZ1024EFF100-I/PT

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24LC08B-I/SNRVE

24LC08B-I/SNA27

ATSAML22G18A-MUT

ATSHA204A-MAHLE-T

24LC256T-I/MNY

24AA256T-I/MNY

ATSHA204A-MAHLH-T

ATSHA204A-MAHME-S

ATSHA204A-MAHMF-S

PIC24EP128GP206T-I/MR

24FC256T-I/MNY

ATSAMD21G16L-MUTN01

ATSHA204A-MAHMG-S

PIC16LF1503T-I/STC03

PIC16F689T-I/SS

ATMEGA4808-XUR

PIC12F675T-I/SN150

24LC04BHT-I/ST

24AA02HT-I/ST

24AA04HT-I/ST

PIC16LF1825T-I/ST027

24LC01BT-I/ST

PIC16F15223-E/MG

PIC16F15224-E/MG

24AA025E64-E/SN

DSPIC33FJ32MC202-E/SO

PIC24HJ32GP202-E/SO

DSPIC33FJ32MC202-E/SS

PIC16F1824-E/ST

PIC18F2580-E/SO

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PIC16F689-E/SS

PIC16F690-E/SS

PIC16F685-E/SS

PIC16F687-E/SS

24LC01BH-E/ST

24LC04BH-E/ST

24LC01B-E/ST

24LC02BH-E/ST

PIC16F15243-E/SS

PIC16F15244-E/SS

PIC16F1518-E/SS

PIC18LF24K42-E/SS

PIC18LF25K42-E/SS

PIC18LF26K40-E/SS

AT80C51RD2T-RLTUM

PIC18F67J60-I/PT

PIC18F66J65-I/PT

PIC18F66J60-I/PT

DSPIC33FJ128MC506A-I/PT

93C66AT-E/ST

93LC86AT-E/ST

25AA640AT-E/SN

PIC16LF1933T-E/SS

24LC01BHT-E/SN

MCP6272T-E/SN

PIC16F1829-H/SS

PIC16F1825-H/ST

DSPIC33CK64MP102-H/SS

DSPIC33CK32MP102-H/SS

DSPIC33CK64MC102-H/SS

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DSPIC33CK32MC102-H/SS

PIC16F1824-H/MLVAO

PIC16F1828-H/MLVAO

DSPIC33FJ64MC204-H/MLVAO

DSPIC33EP64MC204-H/MLVAO

DSPIC33EP32MC202-H/MMVAO

DSPIC33EP32MC204-H/MLVAO

DSPIC33EP256MC204-H/MLVAO

DSPIC33FJ32MC202-H/MMVAO

DSPIC33EP128MC204-H/MLVAO

DSPIC33EV64GM004-H/MLVAO

DSPIC33EV32GM002-H/MMVAO

DSPIC33EV128GM102-H/MMVAO

DSPIC33EV64GM104-H/MLVAO

DSPIC33EP64MC202-H/MMVAO

PIC18F26K80-H/MMVAO

PIC16F1829-H/MLVAO

PIC16F1503-H/MGVAO

MCP8021-3315H/9PXVAO

MCP8021-5015H/9PXVAO

MCP8022-3315H/NHXVAO

MCP8022-5015H/NHXVAO

MCP2561-H/MFVAO

PIC18F6520-E/PT

PIC18F6585-E/PT

PIC16F877-04E/PT

DSPIC33CK256MP306T-I/MR

DSPIC33CK256MP606T-I/MR

PIC16LF1459T-I/GZC04

DSPIC33CK512MP306T-I/MR

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DSPIC33CK512MP606T-I/MR

DSPIC33EP16GS202T-I/MM

PIC32MX270F512HT-50I/MR021

MCP7940MT-I/MNY

MCP79410T-I/MNY

MCP79400T-I/MNY

MCP7940NT-I/MNY

DSPIC33EP32MC202T-I/MM

PIC16F1789T-I/MV

24C01CT-I/MC

PIC32MX450F256LT-120/PF

PIC32MX450F256HT-120/PT

PIC32MX470F512LT-120/PT

PIC32MX470F512LT-120/PF

PIC32MX470F512HT-120/PT

HV2301TQ-G-M931

HV2601TQ-G-M931

DSPIC33FJ12MC202T-E/SO

DSPIC33FJ32MC202T-E/SO

PIC18F2520T-E/SO032

DSPIC33FJ16GP101T-E/SS

24AA02E48T-E/SN

24AA02E64T-E/SN

DSPIC33FJ32MC302T-E/SO

DSPIC33EP128MC502T-E/SS

PIC24EP128GP202T-E/SS

DSPIC30F2010T-20E/SO

PIC16F15323T-E/ST

MCP6V94T-E/ST

DSPIC33EP32MC502T-E/SS

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PIC16F677T-E/SS028

MCP6V64T-E/ST

MCP6V74T-E/ST

PIC24EP32GP202T-E/SS

PIC24EP32MC202T-E/SS

PIC16F883T-E/SO

PIC18F26K20-I/ML057

PIC16F18875-I/ML

PIC16LF18875-I/ML

PIC18F26Q84-I/5N

PIC16F15313-I/RF

PIC18F26Q83-I/5N

PIC16F15356-I/MV

PIC18F27Q83-I/5N

PIC18F27Q84-I/5N

PIC18LF65K40-I/MR

ATMEGA4808-MU

PD69210R-035400

PIC16LF18875-I/MV

ATSAMD20E14A-MU

ATSAMD20E14A-MUA2

ATSAMD20E15A-MU

ATSAMD20E15A-MUA2

ATSAMD20E16A-MU

ATSAMD20E16A-MUA2

PIC12F1571-I/MF

PIC12F1572-I/MF

PIC16LF1902-I/MV

PIC16LF1903-I/MV

ATSAMD20E17A-MU

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ATSAMD20E17A-MUA2

ATSAMD20E18A-MU

ATSAMD20E18A-MUA2

ATTINY1627-MU

ATTINY3227-MU

AVR32DD28-I/STX

AVR16DD28-I/STX

ATTINY427-MU

ATTINY827-MU

PIC18F57Q83-I/6MX

PIC18F57Q84-I/6MX

PIC16F18856-I/ML

PIC18F46Q43-I/MP

PIC32MX270F512H-50I/MR026

PIC16LF1765-I/ML

PIC16LF1764-I/ML

HV5624K7-G

ATSAMD20J14A-MMU

ATSAMD20J15A-MMU

ATSAMD20J16A-MMU

ATSAMD20J17A-MMU

ATSAMD20J18A-MMU

23LCV02M-I/ST

PIC18F26Q43-I/SS

ATMEGA6490A-AU

ATMEGA6490P-AU

AVR128DA32-I/PT

AVR128DA64-I/PT

AT89C55WD-24AU

ATMEGA64-16AUA0

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ATMEGA6450P-AU

ATMEGA329PV-10AU

ATMEGA325P-20AU

ATMEGA1280-16AU-HCM

PIC16F15386-I/PT

PIC16LF15385-I/PT

PIC16LF15386-I/PT

PIC16F17176-I/PT

PIC16F18176-I/PT

ATMEGA1284P-AU

ATMEGA1284-AU

ATMEGA649A-AU

ATMEGA645A-AU

ATMEGA645P-AU

ATMEGA1281V-8AU

ATXMEGA128A1-AU

ATXMEGA64A1-AU

ATXMEGA192D3-AU

ATXMEGA256C3-AU

ATMEGA645-16AU

ATMEGA645V-8AU

ATMEGA164A-AUA2

AVR64DB48-I/PT

AVR32DB48-I/PT

DSPIC33EP64GS708-I/PT

PIC32MK0128MCA048-I/Y8X

PIC24EP128GP204-I/PT039

LAN91C111I-NU

AVR128DB48-I/PT

DSPIC33EP128GS708-I/PT

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DSPIC33EP128GS808-I/PT

DSPIC33EP64GS808-I/PT

DSPIC33FJ64MC506A-I/PT

AVR64DA32-I/PT

AVR64DA64-I/PT

AVR64DA48-I/PT

DSPIC33AK512MPS508-I/PT

DSPIC33AK256MPS508-I/PT

ATSAMD21G17L-MNT

ATMEGA324P-20MQR

ATMEGA168PB-MNR

ATMEGA644PA-MNR

AT90PWM161-16MNR

ATTINY817-MNR

ATTINY417-MNR

ATMEGA644P-20MQR

ATMEGA644PV-10MQR

ATMEGA88PB-MNR

ATMEGA48PB-MNR

ATTINY3217-MNR

ATMEGA164PA-MNR

ATMEGA324PB-MNR

DSPIC33FJ64MC508-I/PT

DSPIC33FJ128MC708-I/PT

PIC32MX695F512L-80I/PTD21

PIC12LF1501-I/MC020

DSPIC33EV256GM106-I/MR

DSPIC33EV256GM006-I/MR

PIC16LF1829-I/ML

PIC16F1459-I/GZ

Date: Tuesday, July 22, 2025

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PIC16LF1459-I/GZ

PIC16F677-I/ML

MGC3130-I/MQ

DSPIC33CK512MP406T-E/MR

DSPIC33CK512MP706T-E/MR

DSPIC33CK256MP406T-E/MR

DSPIC33CK256MP706T-E/MR

DSPIC33CK256MC505T-E/M7

DSPIC33CK128MC505T-E/M7

ATSAMD21G15B-MFT

ATSAMD21G16B-MFT

DSPIC33CK256MC105T-E/M7

PIC18LF23K22-E/SS

MCP6292-E/SN

MCP45HV51-104E/ST

MCP6282-E/SN

25LC080A-E/ST

25LC160A-E/ST

MCP45HV51-502E/ST

MCP45HV51-103E/ST

MCP45HV51-503E/ST

PIC16F1783-E/SO

25LC080B-E/ST

PIC32MK0512GPE064T-I/PT

PIC32MK0512GPD064T-I/PT

PIC24FJ256GU408T-I/PT

PIC24FJ512GU408T-I/PT

TC7116CPT713

MEC1310-NU-TR

PIC32MZ2048EFM064-E/PTN24

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MZ2048EFM064-E/PT

PIC16F15274-E/PT

PIC16F15275-E/PT

PIC16F15276-E/PT

PIC18F45K40-E/PT

PIC18F46K40-E/PT

DSPIC33FJ128MC706A-E/PTC01

PIC24FJ128GA106-E/PT

PIC24FJ256GA106-E/PT

DSPIC33FJ128MC706A-E/PT

PIC24HJ128GP506A-E/PT

PIC32MZ2048EFG100-E/PT

PIC24EP512GP204T-H/PT

PIC24EP512MC204T-H/PT

PIC24EP512MC206T-H/PT

PIC18LF47K40-E/MV

PIC16F19196-E/MR

DSPIC33EV256GM004-E/MLC01

PIC16F19197-E/MR

PIC16LF19195-E/MR

PIC16LF19196-E/MR

PIC16LF19197-E/MR

24C01C-E/MC

ATTINY807-MF

24LC024-E/MC

24LC025-E/MC

24LC014-E/MC

ATTINY1607-MF

24C02C-E/MC

PIC18F47Q83-E/NHX

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MCP19117-E/STX

PIC16F18875-E/ML

PIC16LF18875-E/ML

MCP41HV51-502E/MQ

MCP41HV51-103E/MQ

MCP41HV51-503E/MQ

MCP41HV51-104E/MQ

MCP19123-E/MQ

MCP19061-E/RTB

PIC16F18456-I/STX

PIC16LF15324-I/JQ

PIC16F18013-I/MF

PIC16F18014-I/MF

93AA46AT-I/MNY

93LC46AT-I/MC

93AA46AT-I/MC

93LC86CT-I/MC

93AA86CT-I/MC

93LC76CT-I/MNY

93AA76CT-I/MNY

93LC76CT-I/MC

PIC16F15345-E/GZ

AVR128DB64-E/MR

LAN8650B1-E/LMX

LAN8651B1-E/LMX

AVR64DB64-E/MR

ATSAMC20J18A-MMZ

ATSAMC21J18A-MMZ

ATSAMC21J17A-MMZ

ATSAMC20J17A-MMZ

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ATSAMC21J16A-MMZ

ATSAMC20J16A-MMZ

PIC32MX120F032D-V/PT

PIC32MX350F128L-V/PT

PIC32MX450F128L-V/PT

PIC32MX350F256L-V/PT

PIC32MX350F256L-V/PF

PIC32MX350F128L-V/PF

PIC32MX330F064H-V/PT

PIC32MX430F064H-V/PT

PIC32MX450F256L-V/PF

PIC16F18346-E/GZ

PIC16LF18346-E/GZ

PIC16LF18326-E/JQ

PIC18F27K42-E/ML

PIC18LF27K42-E/ML

PIC16F17144-E/6N

PIC16F15256-E/STX

PIC16F15254-E/STX

PIC16F15255-E/STX

PIC32CM1216JH01032-E/RTB

PIC16F18044-E/ML

PIC18F26K22T-I/SS

PIC16F1783T-I/SS

93C86CT-I/ST

PIC16F1824T-I/STRA5

PIC18LF26K22T-I/SO

PIC16LF1902T-I/SS

PIC16LF1903T-I/SS

93LC76CT-I/ST

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PIC16F15376T-E/MLVAO

ATMEGA328P-15MZ

PIC24HJ64GP210-I/PF

PIC24HJ64GP510-I/PF

PIC32MX320F128H-80I/PT

PIC18F65K22-I/MR

A010201-I/MQ

PIC18F45K50-I/MV

PIC18LF27J53-I/ML

PIC18LF26J53-I/ML

PIC18LF47J53-I/ML

PIC18LF46J53-I/ML

PIC18F13K50-I/MQ

DSPIC33EP64MC206T-E/PT

DSPIC33EP64MC506T-E/PT

DSPIC33AK256MC505-I/PT

DSPIC33AK512MC205-I/PT

ATMEGA649P-AU

QT6C21-ASG-V3

QT60326-ASG

QT6C13-ASG

ATMEGA649V-8AU

ATMEGA649-16AU

ATMEGA6490V-8AU

ATMEGA640V-8AU

ATMEGA324PV-10AU

ATXMEGA64A4U-AU

ATXMEGA256D3-AU

ATXMEGA192C3-AU

AT89S51-24AU

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AT89LS51-16AU

ATMEGA168PB-AU

ATMEGA169PV-8AU

ATMEGA169P-16AU

ATMEGA2560-16AU

ATMEGA2560V-8AU

ATMEGA3250V-8AU

ATMEGA3250PV-10AU

ATTINY88-AU

ATMEGA8-16AUA4

ATMEGA325V-8AU

ATMEGA48V-10AU

ATMEGA48-20AU

ATMEGA640-16AU

PIC24HJ32GP204-E/PT

PIC32MZ1024EFG100-I/PTG21

PIC18F85J90-I/PT

MTR7208-I/PT

PIC18F83J90-I/PT

PIC18F85J11-I/PT

PIC18F84J11-I/PT

PIC18F83J11-I/PT

PIC18F84J90-I/PT

PIC24FJ32GP205-I/PT

DSPIC30F3010-30I/SO

PIC18F27Q43-I/SS

25LC040-I/SN

PIC18F27Q43-I/SO

25AA040-I/SN

25C040-I/SN

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MTCH112-I/SN

PIC12LF1840-I/SN

PIC16F72-I/SS085

PIC18F24K40-I/SS

PIC12F683-I/SN

PIC12F635-I/SN

PIC12LF1501-I/SN

93LC76A-I/SN

93AA86B-I/SN

93LC76C-I/SN

93C76C-I/SN

93AA76C-I/SN

93LC86C-I/SN

ATSAMD20G16A-MNT

ATSAMD20G17A-MNT

PIC32MX120F064HT-V/MR

ATSAMD20G14A-MNT

PIC32MX570F512HT-V/MR

25CS320-I/ST

AVR32DU28-I/SS

AVR16DU28-I/SS

AVR32DU20-I/SS

AVR16DU20-I/SS

PIC16F17156-I/SO

PIC16F18156-I/SO

AVR16EB14-I/ST

AVR16EB20-I/SS

AVR16EB28-I/SS

PIC18F25Q43-I/SS

PIC18F25Q43-I/SO

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PIC18F24K22-I/SS

PIC18F24K22-I/SO

PIC32MK1024MCM100-I/PT

PIC32MX695F512L-80I/PT

PIC32MX675F512L-80I/PT

PIC24EP64MC204-I/PTC06

PIC32MX150F256L-50I/PF

PIC32MX360F512L-80I/PTREL

ATSAMD20G16A-AU

ATSAMD20G17A-AU

ATSAMD20G18A-AU

PIC32MX795F512L-80I/PFE21

PIC32MX695F512L-80I/PTD22

PIC32MX230F256D-50I/PT

PIC32MX230F256D-I/PT

PIC32MX130F256D-50I/PT

HA3200D-I/PT

PIC32MX450F256H-I/PT

PIC32MX350F256L-I/PT

PIC32MX450F128H-I/PT

DSPIC33EP512MC504-I/PT

DSPIC33EP512MC204-I/PT

PIC32MX350F128L-I/PT

PIC32MX450F256L-I/PT

PIC24FJ128GL408-I/PT

PIC24FJ256GL408-I/PT

PIC24FJ256GU408-I/PT

PIC32MX450F128L-I/PT

24LC64T-E/SN

25AA640AT-E/ST

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PIC16F1827T-E/SO

25AA160DT-E/SN

MCP6424T-E/ST

MCP6044T-E/ST

93C86AT-E/ST

24LC32AT-E/SN

MCP6422T-E/SN

PIC16F1823T-E/STC07

24LC64FT-E/SN

24LC32AFT-E/SN

MCP23017T-E/SS

MCP6472T-E/SN

25AA320AT-I/MNYB23

11AA160T-I/MNY

11LC080T-I/MNY

11AA080T-I/MNY

PIC24HJ128GP206AT-I/MR

25AA320AT-I/MNY100

25AA320AT-I/MNY101

PIC16F724T-I/PT

PIC18F64J11T-I/PT

PIC24FJ96GA008T-I/PT

DSPIC30F6015T-30I/PT022

PIC18F43K20T-I/PT

PIC16LF1934T-I/PT

PIC18F65J94T-I/PT

PIC18F67J94T-I/PT

PIC18F95J94T-I/PT

PIC16F15224T-E/ST

PIC12F617T-E/SN078

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PIC12F617T-E/SN079

PIC16F1503-E/MV

DSPIC33AK128MC106-E/M7

DSPIC33AK64MC106-E/M7

DSPIC33AK32MC106-E/M7

PIC16F18056-E/STX

PIC16F18026-E/ML

PIC16F18046-E/ML

AVR32EA28-E/STX

DSPIC33CK64MP105T-I/PTC02

PIC32CX1025MTC128T-I/X9B

PIC32CX5112MTC128T-I/X9B

PIC32CX5112MTG128T-I/X9B

ATSAM4LC2CA-AU

PIC18LF45K42-I/PT

DSPIC33CK1024MP406-I/PT

DSPIC33FJ32MC204-I/PT

PIC18F45K42-I/PT

PIC16F18345-E/SS

DSPIC33EP128GP502-E/SS

DSPIC33EP128MC502-E/SS

DSPIC33EV32GM002-E/SS

MCP3913A1-E/SS

PIC16F15254-E/SS

PIC16F15255-E/SS

PIC18F06Q20-E/ST

PIC18F16Q20-E/SS

PIC18F26Q71-E/SS

PIC18F26Q71-E/SO

AVR128DB28-E/SS

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AVR64DB28-E/SS

AVR32DB28-E/SS

PIC32MZ1024EFF064-I/PTF22

PIC32MZ1024EFF064-I/PT

PIC32MZ1024EFG064-I/PT

PIC32MZ1024EFH064-I/PTH21

PIC32MZ1024EFH064-I/PT

AT89C51ED2T-RLTUMA0

AT89C51ED2T-RLTUMA1

AT89C51ED2T-RLTUMA2

AT89C51ED2T-RLTUM

AT89C51ID2T-RLTUM

AT89C51RD2T-RLTUM

ATA663254-GBQW-VW

ATA663454-GDQW-MB

ATMEGA88PA-15MZ-BW

ATMEGA88PA-15MZ-VW

ATTINY461-15MZ-BW

KSZ8081MNXIA-TR-VW

USB4925T-I/Y9XVAA-VW

PIC16F1459-ICE/SO

PIC16LF1459-ICE/SO

25LC080AT-H/SN

25CS640T-H/ST

PIC16F18345T-H/SS

MCP251863T-H/SS

25CS320T-H/ST

RE46C117S8TF

RE46C104S14TF

RE46C107S16TF

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RE46C145S16TF-AAA

MCP9801T-M/SN

RE46C144S16TF

RE46C143S16TF

RE46C140S16TF

RE46C141S16TF

RE298S16TF

RE299S16TF

RE320S16TF

RE321S16TF

RE280S16TF

RE46C167S16TF

RE46C168S16TF

RE46C165S16TF

RE46C166S16TF

RE46C180S16TF

RE46C145S16TF

RE297S16TF

RE46C191S16TF

RE296S16TF

PIC32MX230F256BT-V/SS

PIC32MX130F256BT-V/SS

PIC32MX170F256BT-V/SS

PIC32MX270F256BT-V/SS

PIC32MX150F128BT-V/SS

PIC32MX130F064BT-V/SS

PIC32MX250F128BT-V/SS

PIC32AK1216GC41048-I/PT

PIC16LC72A-04/SO043

24LC16B/SN

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24LC02B/SN

PIC12C508A-04/SN

PIC12LC508A-04/SN

PIC12C509A-04/SN

PIC12LC509A-04/SN

HCS201/SN

24LCS52/ST

93LC46A/ST

24AA08/SN

24LC08B/SN

24LC024/ST

24LC025/ST

93LC46B/ST

PIC16LF627-04/SS

93LC56A/ST

93LC66B/ST

34VL02/ST

PIC24FJ64GC010-I/PT

PIC24FJ128GC010-I/PT

ATSAMD20G16B-AU

ATSAMD20G15B-AU

ATSAMD20G14B-AU

ATECC608C-TNGTLSU-B

ECC608-TMNGTLSU-B

ATSAMD21E18A-MUDBG

DSPIC33EDV64MC205-I/M7

AVR32EA32-I/RXB

PIC32CM5164LE00048-I/U5B

EQCO5X31C0-I/6NX

PIC32CM5164LE00064-I/5LX

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PIC32CM5164LS00048-I/U5B

EQCO62X20C1TB-I/3DW

EQCO31X20C1TB-I/3DW

PIC32CM5164LS00064-I/5LX

PIC16LF721-I/ML

USB5806C-I/KD

USB5816C-I/KD

PIC16F15344-I/MLC01

PIC16F15344-I/ML

PIC16LF15344-I/ML

PIC16F15344-I/GZ

PIC16LF15344-I/GZ

93AA56AT-I/ST

24LC08BT-I/SNRVE

24LC256T-I/SN

24LC014HT-I/SN

24AA014HT-I/SN

24LC256T-I/SNRVE

24AA256T-I/SN

24LC128T-I/SN

93AA56CT-I/SN

24LCS52T-I/SN

24AA52T-I/SN

24LC014T-I/SN

24AA014T-I/SN

DSPIC33FJ16MC101-E/SS

PIC24FJ16MC102-E/SS

PIC24FJ16MC101-E/SS

PIC16F18323-E/ST

PIC16F15323-E/ST

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PIC16F883-E/SO

DSPIC33EP512MC502-E/SO

PIC24EP512GP202-E/SO

PIC18F26K80-E/SO

PIC18F25K80-E/SO033

PIC18F25K80-E/SO

ATSAMD20E16A-MNT

ATSAMD20E17A-MNT

ATSAMD20E18A-MNT

DSPIC33FJ32GP302T-E/MMC03

DSPIC33FJ64MC202T-E/MMC04

AVR32DA48T-E/6LX

MCP3911A0T-E/ML

ATECC508A-MAHWW-S

ATECC508A-MAHWW-T

ATECC608B-MAHAK-S

ATECC608B-MAHHL-S

ATECC608B-MAHHL-T

ATECC608B-MAHPA-T

ATECC608B-MAHSB-T

ATECC508A-MAHZC-S

ATECC508A-MAHZC-T

ATECC608B-MAHSC-T

ATECC608B-MAHZD-T

ATECC608B-MAHZN-S

PIC18F26Q10T-I/STX

PIC18F27Q43T-I/STX

PIC16F1938T-I/STXPAX

PIC16LF1847T-I/STX

24CW160T-I/Q4B

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24CW320T-I/Q4B

24CW640T-I/Q4B

PIC18F27Q43-E/SS

25C040-E/SN

PIC18F27Q43-E/SO

PIC16F18324-E/ST

PIC18F2523-E/SO

PIC12F1571-I/MF059

PIC32MX130F064B-I/ML

PIC18LF25K80-I/MM

MCP47FEB02A0T-E/ST

DSPIC33EP512GM304-E/ML

DSPIC33EP512GM604-E/ML

AVR64DA48-E/6LX

AVR64DA64-E/MR

AVR64DA32-E/RXB

PIC16F1454-E/ML

PIC16F1455-E/ML

PIC16F1455-E/JQ

PIC16F18074-E/MP

PIC32MZ0512EFK064T-E/PT

25LC080A-H/SN

RE46C117S8F

RE46C104S14F

RE46C107S16F

RE46C145S16F-AAA

MCP9801-M/SN

RE46C140S16F

RE46C143S16F

RE46C141S16F

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RE46C145S16F

RE46C167S16F

RE298S16F

RE299S16F

RE320S16F

RE321S16F

RE46C168S16F

RE46C165S16F

RE46C166S16F

RE46C180S16F

RE297S16F

RE296S16F

RE46C191S16F

RE46C144S16F

PIC32MX150F128B-V/SS

PIC32MX250F128B-V/SS

PIC32MX230F064B-V/SS

PIC32MX130F064B-V/SS

PIC32MX170F256B-V/SS

PIC32MX130F256B-V/SS

PIC32MX270F256B-V/SS

PIC32MX230F256B-V/SS

PIC32MX210F016B-V/SS

DSPIC30F2020-30E/SOB34

PIC32MX120F032B-V/SS

PIC32MX110F016B-V/SS

PIC32MX220F032B-V/SS

RE46C195S16

RE46C190S16F

RE46C101S8F

Date: Tuesday, July 22, 2025

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RE46C317S8F

RE46C318S8F

RE46C194S16

LX34070-H/ST

LX34050QPW

LX3302AQPW-EASY

RE46C600S16

ATTINY1616-XN

MTCH2120-V/SS

TC622EOA

TC1044SEOA

PIC18F2520-I/SO

PIC16C642-04I/SO

PIC16C745-I/SO

PIC18LF2685-I/SO

PIC18F2685-I/SO

PIC18LF2682-I/SO

PIC18F2682-I/SO

PIC16C642-20I/SO

PIC16F876A-I/SS

PIC18F2580-I/SO

PIC16F57-I/SS

PIC18F13K50T-I/SS020

PIC18F1330T-I/SS

24AA08T-I/ST

24LC08BT-I/STRVE

PIC16F610T-I/ST040

PIC18F27K40-E/SS

MCP6V79-E/ST

PIC18F25K83-E/SS

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PIC18F26K83-E/SS

24LC08BHT-I/MNY

PIC16LF1704T-I/ML023

PIC12F635T-I/MD073

LAN9253T-I/R4X

LAX9253T-I/R4X

ATECC608C-TCSMU

PD77020-020300-TR

PIC16F15223T-I/MG028

ATECC608C-MAHWG-T

PIC16LF1526T-I/MR

PD77010-0101-0000-TR

ATECC608C-MAH8M-S

PD77010-0102-0000-TR

DSPIC30F2023T-30V/MLD31

TC1301B-HPEVMFTR

TC1302B-ICVMFTR

TC1302B-IPVMFTR

TC1301B-GPDVMFTR

TC1301B-GWDVMFTR

TC1302B-HPVMFTR

TC1302A-IPVMFTR

TC1302B-SDVMFTR

TC1301B-EGAVMFTR

TC1302B-EIVMFTR

TC1301A-SSBVMFTR

TC1301A-UFEVMFTR

TC1302B-PHVMFTR

TC1301B-UPFVMFTR

TC1301B-UWFVMFTR

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TC1301B-GABVMFTR

TC1301B-FEAVMFTR

TC1302B-FFVMFTR

PIC18F45K42-E/PT

DSPIC33EV256GM006T-I/PT

PIC16F1779T-I/PTC01

MCP6474T-E/ST

24LC024T-E/ST

24LC025T-E/ST

93C76CT-E/ST

25LC160BT-E/ST

93LC86CT-E/ST

93LC46AT-E/ST

93C46AT-E/ST

TCN75AVOA713

PIC18LF25K22T-E/SO

MCP98243T-BE/ST

PIC18F23K22T-E/SS

MCP6492T-E/SN

MCP41HV31T-502E/ST

MCP6494T-E/ST

MCP41HV31T-103E/ST

MCP6V34T-E/ST

25LC080BT-E/ST

25LC080AT-E/ST

MCP41HV31T-503E/ST

MCP41HV31T-104E/ST

25LC160AT-E/ST

MCP45HV51T-104E/ST

PIC16F1575T-I/JQ

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PIC16F1575T-I/JQ024

PIC16LF1574T-I/JQ

KSZ8041NLI-TR

KSZ8041RNLI-TR

DSPIC33EP64MC206T-I/MR

DSPIC33EP64MC506T-I/MR

PIC24EP64MC206T-I/MR

ATMEGA48PA-MUR

PIC16LF1575T-I/JQ

KSZ8851SNLI-TR

PIC16F18324T-I/JQ

PIC16LF18324T-I/JQ

AGL125V2-VQ100

AGL125V2-VQG100

AGL125V5-VQ100

A3P060-VQG100XO69

A3P030-VQG100

A3P060-VQG100

DSPIC33EP128MC506T-E/PTVAO

DSPIC33EP64MC504T-E/PTVAO

DSPIC33EP128MC504T-E/PTVAO

DSPIC33EP128GP504T-E/PTVAO

ATTINY861A-MUR

PIC24FJ128GA406T-I/MR

PIC32MZ2048EFM100-I/PT

MCP47FEB22A2T-E/ST

MCP47FVB22A0T-E/ST

24LC02BT-E/ST

93C46BT-E/ST

MCP47FVB21A3T-E/ST

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MCP6L02T-E/SN

34LC02T-E/ST

24LC512T-E/SN

PIC16F1705T-E/ST

PIC18LF25K22T-E/SS

PIC16F1575T-E/ST

PIC16C63-10/SO

ATTINY88-15MZVAO

PIC18F47Q10T-E/MPVAO

PIC18F27Q10T-E/STXVAO

PIC16F15213T-E/MFVAO

PIC16F18025T-E/7NVAO

AVR128DA48T-E/6LXVAO

AVR128DA64T-E/MRVAO

AVR128DA32T-E/RXBVAO

ATA5293-GJQW-VAO

ATA5296-GJQW-VAO

AVR64DA48T-E/6LXVAO

AVR64DA32T-E/RXBL10

PIC16F15325T-E/JQVAO

PIC16LF1847-E/MV

PIC16F1508-E/GZ

AVR128DA32-E/RXBVAO

AVR64DA48-E/6LXVAO

PIC16LF1777T-I/ML

PIC16F1777T-I/ML

PIC18F65K80T-I/MR

ATXMEGA128A1U-AU

ATXMEGA64A1U-AU

AT89S52-24AU-HCM

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ATMEGA16-16AUA6

ATMEGA16L-8AU

ATMEGA3290V-8AU

ATMEGA3250PA-AU

ATMEGA3290A-AU

ATMEGA3250A-AU

ATMEGA128L-8AUA4

ATMEGA88V-10AU

ATMEGA88-20AU

ATMEGA168-20AU

ATMEGA168V-10AU

ATMEGA8515-16AU

ATMEGA8515L-8AU

AT89LP51-20AU

ATXMEGA64A3-AU

ATXMEGA128A3-AU

ATXMEGA16A4U-AU

ATXMEGA32A4U-AU

ATXMEGA64A3U-AU

ATMEGA88PB-AU

ATMEGA48PB-AU

ATA663431-GDQW-VAO

ATA663431-GDQW

PIC18F25K42-E/SS

MCP6V99-E/ST

24AA256-E/ST

24LC16B-E/ST

24LC16BH-E/ST

PIC16F1614-E/ST

PIC16F1503-E/ST

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PIC18F25K40-E/SS

PIC18LF24K40-E/SS

PIC18LF25K40-E/SS

PIC16F616-E/ST

PIC12F629-E/SN252

24LC04B/SN

24AA04/SN

24LC32A/SN

24AA02/SN

MCP6032T-E/SNEIE

MCP6V84T-E/ST

PIC18F25K80T-E/SO033

PIC18F25K80T-E/SO

PIC18F26K80T-E/SO

MCP6L92T-E/SN

MCP6V79T-E/ST

PIC16F1783T-E/SS

PIC16C773/SS

PIC16LC773/SS

PIC16C63-20/SO

TC622COA

PIC16C76-04/SO

PIC16C76-10/SO

TC7660COA

PIC16C55A-04/SS

PIC16C57C-04/SO

PIC16C57C-20/SO

PIC16F873-20/SO

PIC16LF873-04/SO

PIC16F876-04/SO

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PIC16F876-20/SO

PIC16C73A-04/SO

AVR32DA48ST-E/PT

DSPIC33CH256MP206T-E/PTC03

PIC32CM2532JH01048T-E/Y8X-SL3

ATSAMC21E15A-OAZT

PIC18F57Q84T-E/PT

PIC16F877-10E/PQ

PIC18F6680-E/PT

PIC18F8520-E/PT

PIC18F6525-E/PT

25LC160D-E/ST16KVAO

25LC080C-E/ST16KVAO

25LC320A-E/ST16KVAO

25LC640A-E/ST16KVAO

MCP6489-E/STVAO

AVR32DA28-E/SSVAO

DSPIC33CK32MP502-E/SSVAO

24LC64-E/ST16KVAO

24AA64-E/STVAO

PIC32MK0512GPD100T-I/PT

PIC32MK0512MCF100T-I/PT

ATMEGA4808-AUR

ATMEGA4809-AUR

PIC18F6720T-I/PT

ATSAMC21J18A-AUT-SL2

ATSAMC21J18A-AUT-SL3

PIC18F6620T-I/PT

24LC16B-E/SNA26

MCP2022A-500E/ST

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MCP2022A-330E/ST

PIC18LF4480-I/PT

PIC16LF707-I/PT

PIC18F67J93-I/PT

PIC16LF1782-E/ML

PIC18F23K22-I/SS

PIC16LF1713-I/SS

PIC16LF1716-I/SS

PIC18F23K22-I/SO

PIC18F23K22-I/SOV01

AVR64EA28-I/SS

PIC16LF15324-I/ST

PIC16F15344-I/SS

HV9308PJ-G

HV9408PJ-G

HV5408PJ-B-G

ATF750LVC-15JU

ATF750CL-15JU

ATF750C-10JU

MM5450YV

MM5451YV

MIC58P01YV

MIC59P50YV

MIC5801YV

ATF22V10C-7JU

ATF22V10C-10JU

ATF1502ASL-25JU44

ATF22V10C-15JU

ATF22LV10CQZ-30JU

ATF22V10CQZ-20JU

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AT27C040-90JU

AT27C080-90JU

USB2422T-I/MJ

PIC24FJ64GA202T-I/MM

PIC24EP512MC206T-I/MR

PIC24FJ128GA204T-I/ML

PIC24EP512GP204T-I/ML

DSPIC33EP512MC504T-I/ML

PIC32MX220F032DT-50I/ML

PD69210C-022319-TR

PD69210R-022320-TR

PIC24FJ64GA204T-I/ML

PIC32MX230F064BT-I/ML

PIC32MM0256GPM028T-I/ML

DSPIC33EP32MC504T-I/ML

PIC24EP32GP204T-I/ML

PIC24EP32MC204T-I/ML

ZL88701LDF1

PIC24EP512GP206T-I/MR

ZL88105LDF1

ZL88702LDF1

PIC24EP512MC204T-I/ML

LE9632RQCT

24FC04HT-I/MUY

LE9662WQCT

ZL88602LDF1

ZL88109LDF1

DSPIC33EV64GM004T-I/ML

DSPIC33EV64GM104T-I/ML

DSPIC33EP16GS202T-I/MMC01

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DSPIC33EV32GM004T-I/ML

DSPIC33EV32GM104T-I/ML

ZL88601LDF1

ZL88801LDF1

PIC18LF26K80T-I/MMC01

DSPIC33EP32GP504T-I/ML

24FC04T-I/Q4B

24FC04HT-I/Q4B

PIC16LF15323T-E/JQ

PIC12F1571T-E/MF

PIC12F1572T-E/MF

PIC16LF1903T-E/MV

MCP47CMD11T-E/MG

PIC18F46Q43T-I/PT

AVR128DA48T-I/PT

PIC24HJ64GP504T-I/PT

DSPIC33FJ64GP204T-I/PT

DSPIC33FJ64MC804T-I/PT

PIC16LF18875T-I/PT

PIC16LF1777T-I/PT

PIC16LF1779T-I/PT

PIC18F67J10T-I/PT020

PIC16F18074T-I/PT

PIC16F18075T-I/PT

PIC16LF1789T-I/PT

PIC32CM5164LE00048T-I/U5B

AVR32EA32T-I/RXB

PIC32CM5164LE00064T-I/5LX

PIC32CM5164LS00048T-I/U5B

ATSAMC21E18A-MUTN01

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ATSAMC21E16A-MUTN01

PIC32CM5164LS00064T-I/5LX

EQCO125X40C1T-I/3DW

EQCO125T40C1T-I/3DW

EQCO62X20C1T-I/3DW

ATSAM3S1AB-MU

PIC18F1320-I/ML

PIC18LF1220-I/ML

PIC18F1220-I/ML

PIC16F15354-I/ML

SY88349NDLMG

SY58606UMG

SY58607UMG

SY58608UMG

SY88149HALMG

SY88149NDLMG

SY88303BLMG

SY88353BLMG

SY88932LMG

SY88403BLMG

SY88773VMG

PIC18F26K40-I/MV

PIC16LF18455-I/STX

PIC16LF18456-I/STX

SY58052AUMG

PIC12F629-I/MD

PIC18F452-I/PT

PIC16F874-20I/PT

PIC16LF877A-I/PT

PIC16F877A-I/PT

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PIC16F74-I/PT

PIC16LF77-I/PT

DSPIC33CH256MP505T-I/PT

DSPIC33CH256MP205T-I/PT

PIC18LF55K42T-I/PT

PIC18F55K42T-I/PT

PIC18LF56K42T-I/PT

PIC18F56K42T-I/PT

PIC18F47Q43T-I/PT

PIC18F47Q10T-I/PTC01

PIC32MZ0512EFE100T-I/PT024

PIC18F44K20T-I/PT021

PIC24FJ128GA306T-I/PT025

PIC16F15324T-I/7NVAO

PIC16F1827T-I/MLVAO

KSZ8051RNLUB-TR-VAO

PIC24HJ256GP206A-E/PT

DSPIC33FJ256GP506A-E/PT

PIC16F1704T-I/STVAO

PIC16F1705T-I/STVAO

PIC16LF1554T-I/STVAO

MCP2221AT-I/STVAO

PIC16F1824T-I/STVAO

PIC16F526T-I/STVAO

PIC16F15244T-I/SSVAO

DSPIC33FJ64MC804T-H/ML

DSPIC33FJ128MC804T-H/ML

MCP2557FDT-H/MF

PIC24EP512GP206T-H/MR

MCP2558FDT-H/MF

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MCP2542FDT-H/MF

MCP2544FDT-H/MF

DSPIC33EP512MC506T-H/MR

DSPIC33EP512MC206T-H/MR

PIC24EP512MC206T-H/MR

DSPIC33EP512GP506T-H/MR

PIC18F25K80T-H/MM

PIC16F1829T-H/ML

MCP2561T-H/MF

MCP2561FDT-H/MF

MCP2562T-H/MF

24LC21T/SN

24LCS21AT/SN

93LC46AT/SN

93C46BT/SN

24LC02BT/SNA31

HCS301T/SN032

MCP6024T-I/ST

MCP3302T-BI/ST

MCP3302T-CI/ST

MCP601T-I/ST

MCP608T-I/ST

PIC32MZ1024ECH064T-I/PT

PIC32MZ2048ECH064T-I/PT

DSPIC30F4011T-20I/PT

DSPIC30F4011T-30I/PT

DSPIC33FJ32GP202T-E/MM

DSPIC33FJ32MC202T-E/MM

MCP9903T-1E/9Q

MCP9903T-2E/9Q

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DSPIC33CH64MP206-E/PT

DSPIC33CK128MP205-E/PTC05

DSPIC33EP128GM304-E/PT

DSPIC33EP128GM604-E/PT

DSPIC33EP512GP806T-E/MR

MCP4641T-103E/ML

MCP4641T-104E/ML

MCP4641T-503E/ML

MCP2515T-E/ML

MCP4631T-104E/ML

MCP659T-E/ML

MCP639T-E/ML

DSPIC33FJ16MC304T-E/ML

SST39VF020-70-4I-NHE

SST39VF010-70-4I-NHE

AT28C010E-12JU

AT28HC256-90JU-600

AT28C256EF-15JU-795

PIC16C925-I/L

AT89C51CC03UA-SLSUM

AT89C51CC02UA-SISUM

ATMEGA8515-16JU

ATMEGA8515L-8JU

AT32UC3C1128C-AUR

AT89C51RB2-SLRUM

AT89C51RC2-SLRUM

AT89C51IC2-SLRUL

AT89C51RB2-SLRUL

AT89C51RC2-SLRUL

AT89C51ED2-SLRUM

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

AT89C51ID2-SLRUM

AT89C51RD2-SLRUM

AT89C51CC03CA-SLRUM

AT80C51RD2-SLRUM

HV5812PJ-G-M904

PIC16C64A-04E/L

PIC18F6680-E/L

PIC17C756A-33E/L

PIC18F6585-E/L

24LC256T-I/ST

24AA256T-I/ST

24AA256T-I/STRVE

PIC18F25K22T-I/SS

24LC128T-I/ST

MCP607T-I/SNA21

PIC18F2221T-I/SS

PIC16C622AT-04I/SO093

PIC16C621AT-04I/SS082

24LC128T-I/STDLL

24AA128T-I/ST

PIC18F13K22T-I/SS

24LC04BHT-I/SN

24AA04HT-I/SN

MCP6549T-I/STBAA

PIC18F1230T-I/SS

PIC16F73T-I/SO165

PIC16F722T-I/SS

PIC16F73T-I/SO166

PIC18F2585T-I/SO

PIC16F1827T-I/SO

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PIC16F1826T-I/SO

MCP606T-I/ST

PIC16LF1516T-I/SO

24LC512T-I/ST14

24AA512T-I/ST14

PIC18F14K50T-I/SS032

PIC16F723T-I/SS

PIC16F723T-I/SO

PIC24FJ64GA002T-I/SO

93C46CT-I/ST

PIC24FJ64GL305T-I/PT

DSPIC33EP256MU806T-I/PT

DSPIC33EP512GP806T-I/PT

DSPIC33EP512MC806T-I/PT

PIC24EP512GP806T-I/PT

PIC32MX320F064HT-40I/PT

PIC32MX320F064HT-80I/PT

MCP47FEB02A1T-E/ST

MCP47FEB11A0T-E/ST

MCP47FEB11A1T-E/ST

MCP47FEB11A2T-E/ST

24LC64FT-E/ST

MCP47FEB22A3T-E/ST

MCP47FVB01A0T-E/ST

MCP47FEB12A3T-E/ST

MCP47FEB02A2T-E/ST

PIC24FJ64GA310-I/PTREL

PIC24FJ128GC006-I/PT

PIC18F45K50-I/PT

DSPIC33FJ64MC510A-I/PF

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PIC24F16KM104-I/PT

PIC18F86K22-I/PTRSL

DSPIC33EP128GM310-I/PF

PIC32MX360F256L-80I/PT023

PIC18F85K90-I/PT

PIC18F85K90-I/PTRSL

PIC18F85K22-I/PT

DSPIC33EP128GM710-I/PF

DSPIC33EP256GM310-I/PF

DSPIC33EP256GM710-I/PF

DSPIC33EP512GM310-I/PF

DSPIC33EP512GM710-I/PF

PIC18LF46J11-I/PT

ENC424J600-I/PT

PIC12F508T-I/MC

MCP73833T-YAI/MF

PIC16F914T-I/ML

PIC16F1827T-I/ML

MCP73834T-G8I/MF

MCP73834T-GPI/MF

PIC16F726T-I/ML

MCP73834T-6SI/MF

MCP73834T-B6I/MF

PIC18F26J11T-I/ML

PIC18F25J11T-I/ML

PIC16LF722T-I/ML

PIC18F26J50T-I/ML

PIC18F25J50T-I/ML

PIC18F24J11T-I/ML

MCP73834T-NVI/MF

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MCP73834T-YAI/MF

PIC12F509T-I/MC

PIC16LF727T-I/ML

PIC16F1517T-I/MV

PIC24FJ128GA006-I/PT

PIC24FJ96GA006-I/PT

PIC24FJ64GA006-I/PTC03

PIC24FJ64GA006-I/PT

PIC24FJ1024GA610-I/PT

PIC32CM5164JH01048T-E/U5B

PIC32CM2532JH00048T-E/U5B

PIC32CM5164JH00048T-E/U5B

PIC32CM2532JH01048T-E/U5B

DSPIC33FJ16GS502T-E/MMC03

MCP19123T-E/MQ

MCP98243T-BE/MNY

MCP98243T-BE/MNYAA

MCP98243T-BE/MNYAB

PIC32CM2532JH00064T-E/5LX

PIC32CM5164JH00064T-E/5LX

PIC32CM2532JH01064T-E/5LX

PIC32CM5164JH01064T-E/5LX

PIC16F1847-E/ML

PIC18LF46K22-E/ML

PIC18LF45K22-E/MV

PIC18F23K20-E/ML

PIC12HV615-E/MF

PIC12LF1501-E/MF

PIC18F13K22-E/ML

PIC16F1827-E/MV

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PIC16F1784-E/MV

PIC16F1787-E/MV

PIC12F1501-E/MC

DSPIC33CK512MP408-I/PT

DSPIC33CK512MP708-I/PT

DSPIC33CK256MP408-I/PT

DSPIC33CK256MP708-I/PT

DSPIC33CK1024MP405-I/PT

DSPIC33CK1024MP705-I/PT

DSPIC33CK512MP405-I/PT

DSPIC33CK512MP705-I/PT

DSPIC33CK256MP405-I/PT

DSPIC33CK256MP705-I/PT

ATMEGA1608-AU

ATMEGA808-AU

PIC16F18074-I/PT

DSPIC33CK256MC505-I/PT

DSPIC33CK128MC505-I/PT

DSPIC33CK256MC105-I/PT

MCP4021T-202E/SN

MCP664T-E/ST

PIC16C621A-04I/SS

PIC16C621A-20I/SS

PIC18F2685-I/SOREL

PIC16F785-I/SS

PIC18LF2331-I/SO

PIC18F2420-I/SO

PIC18LF2420-I/SO

PIC16LF818-I/SSTSL

PIC16F818-I/SSTSL

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PIC18F2431-I/SO

PIC18LF2431-I/SO

PIC18F2331-I/SO

PIC18LF2450-I/SO

PIC16F627A-I/SO

PIC18F2450-I/SO

PIC16LF627A-I/SO

PIC16LC554-04I/SS

MCP1725T-1802E/MCVAO

PIC24FJ256GA606-E/MR

PIC24FJ512GA606-E/MR

PIC24FJ1024GB606-E/MR

PIC24EP128GP202-E/MM

DSPIC33FJ06GS202-E/MM

DSPIC33FJ16GS404-E/ML

DSPIC33FJ16GS504-E/ML

PIC16F1788-E/ML

DSPIC33FJ12GP202-E/ML

PIC24HJ12GP202-E/ML

PIC32MZ2048EFM064T-E/PT

PIC32MZ0512EFK100T-E/PT

PIC32MZ0512EFE100T-E/PT

PIC32MZ0512EFF100T-E/PT

PIC32MZ1024EFM100T-E/PT

PIC32MZ2048EFG100T-E/PT

PIC32MZ2048EFH100T-E/PT

PIC32MZ2048EFM100T-E/PT

TC7107AIKW

TC7106AIKW

TC7106IKW

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PIC32CM2532JH00048T-E/Y8X

PIC32CM5164JH00048T-E/Y8X

PIC32CM2532JH01048T-E/Y8X

ATSAMD21J16B-AFT

ATSAMD21J15B-AFT

PIC16F19197T-E/PT

PIC16LF19197T-E/PT

ATSAMD21J17A-AFT

ATSAMD21J18A-AFT

DSPIC33CK256MP505T-E/PTC03

DSPIC33CK64MP206T-E/PTC03

DSPIC33CK256MP508T-E/PTC02

DSPIC33CK128MP208T-E/PTC05

DSPIC33CK32MP205T-E/PTC04

DSPIC33CK128MP205T-E/PTC05

PIC32CM2532LE00064T-E/PT

PIC32CM2532LS00064T-E/PT

DSPIC33CK32MP205T-E/PT

DSPIC33CK32MP505T-E/PT

DSPIC33CK128MP205T-E/PT

PIC18F4455-I/PT

PIC18F4458-I/PT

PIC18F97J94-I/PT

PIC16LF1784-I/PT

PIC18LF4553-I/PT

PIC18F4553-I/PT

HA5122-I/PT

PIC18LF4550-I/PT

PIC18F4550-I/PT

PIC24FJ128GA310-I/PF

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PIC24FJ64GA306-I/PTREL

PIC18LF4410-I/PT

PIC16F1787-I/PT

PIC18F66J11-I/PTC01

DSPIC33FJ64GS608-I/PTC03

PIC24F16KM204-I/PT

PIC24EP64GP204-I/PTC03

PIC18F86K90-I/PTRSL

PIC18F86K22-I/PT

PIC24F08KM204-I/PT

PIC24HJ64GP210A-I/PF

PIC24HJ64GP510A-I/PF

DSPIC33FJ64GP710A-I/PF

DSPIC33FJ128GP710A-I/PF

24LC04B-E/MC

PIC18F46K20-E/MV

PIC18F46K20-E/ML

PIC16F1828-E/ML

PIC32MX450F128LT-V/PT

PIC32MX330F064LT-V/PT

PIC32MX430F064LT-V/PT

PIC32MX320F064HT-40V/PT

PIC32MX320F064HT-80V/PT

AGL060V5-VQ100

DSPIC33CK256MP606T-I/PT

PIC32MZ2048ECG064-I/PT

PIC32MX550F256H-I/PT

DSPIC33EV64GM004-I/PT

DSPIC33EV64GM104-I/PT

PIC32MX570F512L-50I/PF

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PIC32MX270F512L-50I/PF

PIC32MX550F256L-50I/PF

PIC32MX154F128D-I/PT

DSPIC33FJ128GP310-I/PT

DSPIC33FJ256GP710-I/PT

DSPIC33FJ64MC510-I/PT

DSPIC33FJ32GS608-I/PT

DSPIC33FJ32GP304-I/PT

DSPIC33FJ64MC204-I/PT

PIC24FJ512GB606-I/PTC03

DSPIC33FJ64GS610-I/PT

DSPIC33FJ32GS610-I/PT

DSPIC33FJ64GS608-I/PT

PIC24HJ64GP204-I/PT

PIC16LF1769-E/ML

PIC16LF1768-E/ML

PIC16LF1566-E/MV

PIC16LF1619-E/ML

PIC16LF1618-E/ML

PIC16LF1618-E/GZ

PIC17C752-16/PT

PIC16LC67-04/PT

PIC24F16KA102-E/MLVAO

PIC18F14K22-E/MLVAO

MCP2050-330E/MQVAO

MCP2515-E/MLVAO

PIC16F883-E/MLVAO

DSPIC33FJ09GS302-E/MMVAO

DSPIC33FJ12MC202-E/MLVAO

DSPIC30F2010-20E/MMVAO

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DSPIC33EV128GM004-E/MLVAO

PIC16F1779-E/MLVAO

PIC16F1777-E/MLVAO

MCP19119-E/MQVAO

DSPIC33EV64GM104-E/MLVAO

MCP19125-E/MQVAO

DSPIC33EV32GM104-E/MLVAO

PIC18F26K40-E/MLVAO

PIC16F1769-E/6NVAO

DSPIC33EP128MC504-E/MLVAO

PIC16LF1559-E/MLVAO

PIC18F25K80-E/MMVAO

MCP6489-E/ST

DSPIC30F3010-20E/SO

DSPIC33FJ32GP304-E/ML

DSPIC33FJ64MC204-E/ML

MCP47FVB18-E/MQ

PIC16F887-E/ML

MCP47FEB08-E/MQ

MCP47FEB18-E/MQ

MCP47FEB28-E/MQ

MCP47FEB04-E/MQ

MCP47FEB14-E/MQ

MCP47FEB24-E/MQ

PIC18F66J93-I/PT

PIC18F87J93-I/PT

PIC18F86J93-I/PT

PIC18CR8627-I/PT

PIC24FJ256DA210-I/PT

ATSAMD20G15A-MU

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ATSAMD20G14A-MU

PIC18F47K42-I/MV

PIC18LF45K42-I/MV

PIC16F1938-I/MV

PIC16LF1947T-I/PTC02

PIC16LF1947T-I/PTC03

DSPIC33CK256MP206T-I/PT

PIC24FV16KM204-I/ML

PIC16LF1788-I/ML

PIC24FJ128GA202-I/MM

PIC24FJ64GA202-I/MM

24AA08-I/MC

PIC18LF26J11-I/ML

PIC16LF1503-I/MG

PIC18F54Q71-I/PT

PIC18F55Q71-I/PT

PIC16F1713T-E/MV

PIC16F1718T-E/MV

PIC18F26K40T-E/MV

AVR32DA32T-E/RXB

MCP19117T-E/MQ

PIC18F25K20T-E/ML

PIC24F16KA102T-E/MLC01

PIC32MK0512MCJ064T-E/R4X

PIC32MK0512MCM064T-E/PT

DSPIC33FJ64GS606T-E/PT

DSPIC33FJ64GS606T-E/PTD22

DSPIC33FJ64GS406T-E/PT

DSPIC33CH512MP505T-E/PT

DSPIC33FJ32GS406T-E/PT

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DSPIC33FJ32GS606T-E/PT

DSPIC33FJ64MC506AT-E/PT

DSPIC33FJ16GS504T-E/PTD22

PIC24HJ32GP304T-E/PTA22

PIC32MX320F032HT-40I/PT

ATSAMD20G14A-AUT

PIC32MX340F256HT-80I/PT

PIC32MX320F128HT-80I/PT

PIC32MX370F512LT-I/PF

PIC32MX470F512LT-I/PF

PIC32MZ1024EFE064T-I/MR

PIC32MZ1024EFF064T-I/MR

DSPIC33FJ32MC204T-I/ML

LE9652MPQCT

DSPIC33EP512GP506T-I/MR

DSPIC33FJ16GS404T-50I/ML

PIC32MM0256GPM028T-I/ML028

PIC32MX270F512HT-I/MR

PIC16LF1902T-I/MV021

PIC32MX130F128HT-I/MR

PIC32MX120F064HT-I/MR

PIC32MX250F256HT-I/MR

PIC32MX230F128HT-I/MR

PIC16F1779T-I/MP

PIC24HJ32GP202T-I/MM

DSPIC33FJ32GP202T-I/MM

DSPIC33FJ16GS504T-50I/ML

PIC32MX120F064HT-50I/MR

PIC32MX230F128HT-50I/MR

PIC32MX530F128HT-I/MR

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DSPIC33FJ16GS402T-50I/MM

PIC32MX130F128HT-50I/MR

MCP2515T-I/ML

PIC32MX250F128DT-I/ML

DSPIC33CK64MP506T-I/PT

DSPIC33CK32MP206T-I/PT

PIC32MX664F064HT-I/PT

PIC18LF26K22-I/MLC03

PIC18LF26K22-I/MLC04

PIC16F1765-I/ML

PIC16F1764-I/ML

PIC18F45K42-I/MV

PIC18F46K42-I/MV

TC1302B-GDV MF

TC1301B-GDDV MF

TC1301B-FEAV MF

TC1301B-UPFV MF

TC1302B-IPV MF

TC1302B-SDV MF

TC1301A-FGAV MF

TC1301A-FFAV MF

TC1301A-FFEV MF

TC1301A-FHAV MF

TC1301A-FSAV MF

24AA044-E/ST

MCP6V84-E/ST

MCP6V94-E/ST

34AA04-E/ST

PIC16LF1554-E/ST

PIC16F723A-E/SS

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PIC16F722A-E/SS

25LC640A-E/ST

25LC640A-E/SN

PIC16F1788-E/SS

PIC16F18344-E/SS

93C46C-E/ST

93C66A-E/ST

93C66B-E/ST

93C66C-E/ST

PIC16F1768-E/SS

PIC16F1769-E/SS

PIC16LF1788-E/SS

PIC16LF18854-E/SS

25LC320A-E/SN

25LC160D-E/SN

25LC080C-E/SN

PIC16LF1559-E/SS

PIC16F1827-E/SS

PIC16LF1829-E/SS

PIC16F18857-E/SS

PIC16F1826-E/SS

PIC12F617-E/SN

PIC16F1713-E/SO

PIC18F24K40-E/SS

PIC12LF1840-E/SN

PIC16F18325-E/ST

PIC12LF1501-E/SN

93LC76A-E/SN

93LC76B-E/SN

93LC76C-E/SN

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93C76C-E/SN

PIC16F18076-I/PT

PIC16F19175-I/PT

PIC16LF19175-I/PT

PIC16LF19176-I/PT

PIC16LF19186-I/PTC01

PIC16F19185-I/PT

PIC16F19186-I/PT

PIC18LF46K42-I/PT

PIC18F46K42-I/PT

DSPIC33CK1024MP706-I/PT

DSPIC33CK512MP406-I/PT

DSPIC33CK512MP706-I/PT

DSPIC33CK256MP406-I/PT

PIC18F47K42-I/PT

DSPIC33CK256MP706-I/PT

DSPIC33CK1024MP410-I/PT

DSPIC33CK1024MP710-I/PT

DSPIC33CK512MP410-I/PT

PIC18LF47K42-I/PT

DSPIC33CK512MP710-I/PT

DSPIC33CK256MP410-I/PT

DSPIC33CK256MP710-I/PT

DSPIC33CK1024MP408-I/PT

DSPIC33CK1024MP708-I/PT

MCP4361-103E/ML

MCP4361-502E/ML

PIC16LF1513-E/MV

PIC16F707-E/ML

PIC16LF1933-E/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F1936-E/MV

PIC16LF720-E/ML

PIC16LF1847-E/ML

MCP9804-E/MCBBB

MCP4542-103PE/MF

MCP4562-103PE/MF

MCP4801-E/MC

MCP4811-E/MC

PIC18F23K22-E/ML

PIC18LF24K22-E/MV

PIC12F1501-E/MF

PIC10LF320-E/MC

PIC10F320-E/MC

MCP639-E/ML

MCP659-E/ML

PIC12F1822-E/MF

PIC18F44K20-E/ML

PIC12F683-E/MD

PIC12LF1822-E/MF

PIC18F4585-E/ML

PIC12F615-E/MF

PIC16LF1823-E/ML

PIC18F14K22-E/ML

PIC16LF1507-E/ML

PIC18F66K40T-I/MR

PIC18LF65K40T-I/MR

MCP98244T-BE/MNYAB

ATSAMD21J15B-AZT

ATSAMD21G16B-AZT

ATSAMD21G15B-AZT

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DSPIC33EP64MC502-I/SS

PIC24EP64MC202-I/SS

PIC16LF18325-I/ST

PIC16LF18345-I/SS

PIC16LF18855-I/SS

PIC18LF13K22-I/SS

PIC16F1509-I/SSC02

PIC16LF1789T-I/MV

PIC16LF1789T-I/ML

PIC18LF45K50T-I/MV

A010201T-I/MQ

24AA08T-I/MNY

PIC18LF46J11T-I/ML

PIC18F14K50T-I/MQ

PIC24FJ128GC006T-I/MR

PIC16F17154-I/SS

PIC16F18154-I/SS

PIC16F17155-I/SS

PIC16F18155-I/SS

PIC16F17154-I/SO

25LC320AT-I/ST16KVAO

AVR32DA28T-I/SSVAO

24LC64T-I/ST16KVAO

DSPIC33EP512GP502T-I/SOVAO

PIC16LF1825T-I/STVAO

PIC18F14K22T-E/MLVAO

PIC12F617T-I/SN

PIC16F1713T-I/SO

PIC16F1934T-I/PTVAO

PIC18F65K22T-I/PTVAO

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PIC16F1527T-I/PTVAO

PIC16F1779T-I/PTVAO

DSPIC33CK128MP505T-I/PTVAO

DSPIC33CK64MP505T-I/PTVAO

PIC32MZ0512EFF064T-I/PTVAO

ATMXT225T-ATR

ATMXT641TD-ATR

ATMXT225TD-ATR

DSPIC33CK128MC105T-I/PTVAO

ATMXT449T-ATR-MB

ATMXT1296M1T-ATRVA1

PIC18F56Q43T-I/PTVAO

PIC18LF46K22T-I/PTVAO

ATMXT1067TD-ATRI2CCPVAO

ATMXT1067TD-ATRSPIVAO

ATMXT1067TD-ATRI2CVAO

PIC32CM6408JH00048T-E/Y8X

PIC32CM6408JH00032T-E/T5X

PIC32CM3204GV00064T-E/V2X

PIC16F18325T-I/ST

PIC12F1822T-I/SN

MTCH112T-I/SN

PIC12LF1840T-I/SN

PIC16F72T-I/SS085

PIC12F683T-I/SN

PIC12F635T-I/SN

PIC12LF1501T-I/SN

PIC16LF1459T-I/MLC05

PIC16F1708T-I/ML

PIC16LF1708T-I/ML

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PIC16F721T-I/ML

PIC16LF720T-I/ML

ATSAMC21J18A-MMUT

USB5807CT-I/KD

PIC16F1828T-I/ML

PIC16F1829T-I/ML031

PIC16F1829T-I/ML

PIC16LF1829T-I/ML

PIC18F87K90-I/PT042

PIC18F87K90-I/PT043

ATSAMC21E18A-ANT

ATSAMC20J15A-ANT

ATSAMC20J16A-ANT

ATSAMC21J15A-ANT

ATSAMC21J16A-ANT

ATSAMC21J17A-ANT

ATSAMC21J18A-ANT

ATSAMC20J17A-ANTS2

ATSAMC20J18A-ANTS2

PIC32MX170F256DT-V/PT

PIC32MX270F256DT-V/PT

ATXMEGA64D3-ANR

ATMEGA168PB-ANR

ATMEGA328P-ANR

ATMEGA644PA-ANR

ATMEGA16-16AQR

ATMEGA324P-20AQR

ATMEGA329P-20ANR

ATXMEGA128A1U-ANR

ATMEGA644P-20AQR

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ATXMEGA16A4U-ANR

ATXMEGA32A4U-ANR

ATMEGA165PV-8ANR

ATMEGA16L-8AQR

ATMEGA8A-ANR

ATMEGA644PV-10AQR

ATMEGA88PB-ANR

ATMEGA48PB-ANR

AT42QT1481-ANR

PIC16F18325-E/JQ

PIC16LF18323-E/JQ

PIC16F18323-E/JQ

MCP98243-BE/MC

PIC16F18877-E/ML

PIC16HV616-E/ML

PIC24EP32MC202-E/MM021

PIC10LF322-E/MC

PIC16LF1559-E/GZ

PIC16F18324-E/JQ

PIC16F18344-E/GZ

PIC32MM0064GPL020-E/ML

PIC32MM0016GPL028-E/ML

PIC32MM0032GPL028-E/ML

PIC32MM0064GPL028-E/ML

DSPIC33EP256MC206-E/MRRA3

PIC24F16KL402-E/MQ

PIC24F16KL401-E/MQ

PIC16F616-E/ML

PIC18LF25K83-E/ML

PIC18LF26K83-E/ML

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PIC16F1825-E/JQ

PIC16LF18345-E/GZ

MCP2200-E/MQ046

PIC32MM0016GPL020-E/ML

PIC32MM0032GPL020-E/ML

PIC18F24K22-E/MV

PIC16F18426-E/JQ

PIC16LF18426-E/JQ

MCP14A0453-E/MNY

MCP14A0454-E/MNY

MCP14A0455-E/MNY

PIC16F18425-E/JQ

PIC16LF18424-E/JQ

PIC16LF18425-E/JQ

MCP14A0303-E/MNY

MCP14A0304-E/MNY

LE79R79-1DJC

LE79R79-2DJC

LE79R79-3DJC

LE58QL031DJC

LE58QL021FJC

LE58QL02FJC

AT27C4096-55JU

SST39SF040-55-4I-NHE

SST39SF020A-55-4I-NHE

SST39SF010A-55-4I-NHE

SST39SF040-70-4I-NHE

SST39SF020A-70-4I-NHE

SST39SF010A-70-4I-NHE

SST39VF040-70-4I-NHE

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24AA16T-E/MNY16KVAO

93LC86C-E/SN

93C86C-E/SN

PIC16F1773T-I/SS

PIC24HJ32GP304T-E/PTC02

PIC16F1789T-E/PT

DSPIC30F5013T-20E/PTC01

PIC18F65K40T-E/PT

PIC18LF46K22T-E/PT

PIC18F46K80T-E/PT

DSPIC33EP512GP506T-H/PT

DSPIC33EP512MC206T-H/PT

DSPIC33EP512MC506T-H/PT

PIC24EP512GP206T-H/PT

DSPIC33EP64MC206T-H/PT

DSPIC33EP256GP504T-H/PT

PIC16F18125-I/7N

LAN8710AI-EZK-ABC

AVR32DB48-I/6LX

AVR128DA48-I/6LX

AVR128DA64-I/MR

PIC16F886T-I/SS

PIC18LF14K22T-I/SS

PIC18F43K22T-I/MV

PIC18F46K22T-I/MV

PIC12F519T-I/MC

PIC16LF1787T-I/MV

PIC18F46K20T-I/ML

PIC18F13K50T-I/MQ

PIC18F45K50T-I/MV

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24LC01BT-I/MNY

24AA01T-I/MNY

24LC01BT-I/MC

24AA01T-I/MC

24LC04BT-I/MNY

HA4315T-I/SS022

PIC24HJ12GP202T-I/SO

DSPIC33FJ12GP202T-I/SO

DSPIC33FJ12MC202T-I/SO

DSPIC33FJ32MC202T-I/SS

PIC16F685T-I/SS

HA2580T-I/SS

24FC16T-I/ST

24LC16BHT-I/ST

24LC08BT-I/ST

24FC08T-I/ST

24LC08BHT-I/ST

24AA16T-I/ST

24AA16HT-I/ST

PIC18LF2321-I/ML

PIC18F2321-I/ML

PIC12F509-I/MC

PIC12F508-I/MC

PIC16F1827-I/ML

PIC16F726-I/ML

ATSAMC21E17A-MUT

ATSAMC21E18A-MUT

DSPIC33EP256GP502T-I/MM

PIC24EP256GP202T-I/MM

PIC16LF1828T-I/ML025

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ATSAMD21J18A-MMUT

ATSAM4LC8AA-MUR

PIC16F18855T-I/MV

PIC16LF18855T-I/MV

PIC16LF1937T-I/ML

PIC16F1574T-I/JQ

ATMEGA809-MF

PIC16LF18877-E/MV

PIC32MZ2048EFH064-E/MR

PIC32MZ2048EFM064-E/MR

PIC32MK1024GPE064-E/MR

PIC32MK1024GPD064-E/MR

PIC16LF18323-E/ST

PIC18F14K22-E/SS

PIC16F15325-E/ST

25AA256-E/SN

25AA256-E/ST

PIC16F18854-E/SS

MCP6V39-E/ST

DSPIC33EP16GS202-E/SSC04

PIC18F26K80-E/SS

PIC18F25K80-E/SS

ATMEGA808-XF

ATMEGA1608-XF

23K256-E/ST

23K640-E/ST

PIC16F18444-E/SS

PIC16F18445-E/SS

DSPIC33EV128GM002-E/SS

DSPIC33EV128GM102-E/SS

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PIC16LF18324-E/ST

MCP6V69-E/ST

24AA044-E/SN

PIC16F1615-E/STVAO-MB

PIC16F1765-E/STVAO

PIC16F1764-E/STVAO

25LC080CT-E/SN

PIC16F1827T-E/SS

PIC16F1826T-E/SS

PIC12F617T-E/SN

ATSAMHA1E16A-MBT-B510

ATSAMHA1E14A-MBT-B510

MCP2200T-I/MQVAO

PIC16F1509T-I/MLVAO

PIC16F1508T-I/MLVAO

PIC16F1828T-I/MLVAO

PIC16LF1828T-I/MLVAO

PIC16LF1829T-I/MLVAO

93LC56CT-E/MC15KVAO

DSPIC33EP32GS504T-E/PTB3

PIC24EP512GP204-I/PT

DSPIC33EP512MC506-I/PT

PIC24EP512GU810-I/PF

DSPIC30F2020T-30I/SO

PIC32MX170F256BT-I/SS

PIC32MX270F256BT-I/SS

PIC32MX664F128L-V/PT

PIC32MX110F016D-V/PT

PIC32MX220F032D-V/PT

DSPIC33FJ32MC202T-I/SOC21

Date: Tuesday, July 22, 2025

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PIC24F08KL201T-I/SS

HA0130T-I/SS

PIC16LF1783T-I/SS

PIC24F16KL401T-I/SS

PIC24F08KL401T-I/SS

PIC24F08KL301T-I/SS

24FC64T-I/ST

24AA512T-I/ST

PIC24F08KL402T-I/SS

PIC24F16KL402T-I/SS

93LC66AT-I/ST

ATSAMC20J15A-MMUT

ATSAMC20J16A-MMUT

ATSAMC20J17A-MMUT

ATSAMC20J18A-MMUT

PIC16LF1507T-I/ML

PIC12F615T-I/SN071

PIC12F615T-I/SN076

PIC12F615T-I/SN079

ATSAMD21E15B-AFT

ATSAMD21E16B-AFT

AVR128DB32T-E/PT

AVR64DB32T-E/PT

AVR32DB32T-E/PT

ATSAMD21E16B-AZT

PIC16F18125T-E/7NVAO

PIC16F18877T-E/MLVAO

ATSAMC21E16A-MZT510

PIC18F47Q84T-E/NHXVAO

PIC16F18146T-E/6NVAO

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UCS4003T-E/8NVAO

PIC16F1615T-E/MLVAO

MCP19061T-E/RTBVAO

PIC18F26Q43T-E/STX510

AVR32DD28T-E/STXVAO

PIC16F15256T-E/STXVAO

PIC32CM5164JH01048T-E/U5BVAO

PIC18F26Q24T-E/STXVAO

PIC16F18026T-I/7NVAO

MCP7940NT-E/MNYVAO

PIC32CM3204GV00032T-E/RTBVAO

PIC18LF46J11-I/ML

PIC24FJ128GA204-I/ML

PIC16F1519T-E/PT

DSPIC33EP64MC504T-E/PT

PIC24EP64MC204T-E/PT

PIC18LF45K42-I/ML

PIC32MK1024MCM064-I/MR

PIC18LF46K42-I/MV

PIC18F45K42-I/ML

PIC32MX675F512H-80I/MR

PIC32MX795F512H-80I/MR

PIC24EP32GP202-I/MM

PIC18LF46K42-I/ML

PIC18F46K42-I/ML

PIC16F18857-I/ML

PIC16LF18857-I/ML

ATSAM4LS8AA-MU

ATSAM4LC8AA-MU

PIC18LF8527-I/PT

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PIC18F4580-I/PTC02

PIC18LF4221-I/PT

PIC16F1946-I/PT

MTR6853-I/PT

PIC18F44J10-I/PT

PIC18F45J10-I/PT

PIC24FJ64GB004-I/PTREL

PIC24FJ128GA008-I/PT

PIC18LF4580-I/PT

PIC16F727-I/PT

ATSAMD21E17D-OMZ

ATSAMD21G17D-OMZ

PIC16F17544-E/ML

PIC16F17545-E/ML

DSPIC33EP32MC204T-H/PT

DSPIC33EP32MC504T-H/PT

PIC24EP32GP204T-H/PT

PIC24EP32MC204T-H/PT

DSPIC33AK128MC106T-H/PT

DSPIC33AK64MC106T-H/PT

DSPIC33AK32MC106T-H/PT

DSPIC33AK128MC105T-H/PT

DSPIC33AK64MC105T-H/PT

DSPIC33AK32MC105T-H/PT

DSPIC33EP16GS202-E/SSC03

PIC12F1501-E/SN047

PIC12F1501-E/SN048

PIC12F1501-E/SN

PIC12F675-E/SN

93LC56B-E/SN

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93LC56A-E/ST

PIC16F1829T-I/MLVAO

PIC18F46K20T-I/MLVAO

TC1301A-PHEVMF

TC1301A-SFAVMF

TC1301A-SGBVMF

TC1302B-FPVMF

TC1302B-FSVMF

TC1302B-FTVMF

TC1301B-GABVMF

PIC32MZ2048EFG064T-E/PT

PIC32MZ2048EFH064T-E/PT

PIC18F8493-I/PT

PIC17LC756A-08I/PT

PIC17LC766-08I/PT

PIC18F87J60-I/PT

PIC18F97J60-I/PT

PIC18F4520-I/PTC05

PIC18F86J65-I/PT

PIC18F8621-I/PTC03

PIC17C752-16I/PT

PIC18C658-I/PT

PIC18F65J90-I/PTREL

PIC18F85J90-I/PTREL

PIC18LF4520-I/PT

PIC18F4520-I/PT

PIC18F67J60-I/PTREL

PIC18F6410-I/PT

PIC18F4520-I/PTB4

PIC18F96J65-I/PF

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PIC18F86J60-I/PT

PIC18F96J60-I/PT

PIC17C756A-16I/PT

PIC18F97J60-I/PF

PIC18LF4523-I/PT

PIC16LF724-I/PT

PIC16C924-08I/PT

PIC18F6493-I/PT

PIC18LF6723-I/PT

PIC16LC924-04I/PT

PIC18F6493-I/PTREL

PIC18F8493-I/PTREL

PIC18LF6680-I/PT

PIC18F6680-I/PT

PIC18LF6585-I/PT

PIC18F6585-I/PT

PIC18F6628-I/PT

PIC18LF6628-I/PT

PIC18F6723-I/PT

PIC18LC801-I/PT

PIC18F6621-I/PT

PIC18LF6525-I/PT

PIC18F6525-I/PT

PIC16LC925-I/PT

93LC86B-E/SN

MCP41010-E/SN

PIC12F519-E/SN

MCP41100-E/SN

93C66A-E/SN

93C66B-E/SN

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

93LC46C-E/SN

25LC160A-E/SN

25LC080B-E/SN

93C46C-E/SN

93C56A-E/SN

93C56B-E/SN

PIC12LF1571-E/SN

PIC12LF1572-E/SN

PIC16F627A-E/SS

25LC640-E/SN

25LC320-E/SN

PIC32MX320F032H-40I/MR

PIC32MX340F512H-80I/MR

93AA86C-I/SN

DSPIC33AK64MC105T-I/M7

PIC16F18876T-I/MV

ATSAMD20G15B-MUT

PIC16LF1776T-I/SS

PIC16F1776T-I/SS

PIC12LF1612T-I/SN

DSPIC33EP32GP502T-I/SS

HCS300T-I/SN047

HCS300T-I/SN053

PIC16F1513T-I/SS

PIC16F15245T-I/SS

PIC16F18855T-I/SS

24FC256T-I/SN

DSPIC33EP256GP502T-I/SS

PIC24EP256GP202T-I/SS

PIC16LF18855T-I/SS

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC18LF13K22T-I/SS

PIC12HV609T-I/SN

PIC16LF18444T-I/SS

PIC16LF18445T-I/SS

PIC16F18446T-I/SS

PIC16F688T-I/ST056

25LC080BT-E/SN

PIC18F2221-I/SS

PIC18F25J50-I/SS

PIC18F24K20-I/SSC03

PIC18F26J50-I/SS

PIC18F24J50-I/SS

PIC24FJ64GA102-I/SO

PIC24FJ64GB002-I/SO

PIC24FJ32GB002-I/SO

PIC18LF2480-I/SO

PIC24F32KA301-I/SS

PIC24F16KA301-I/SS

PIC16LF1827-I/SO

HSA2-040SIA/A2S23

PIC18F24K42-E/SS

34LC02-E/SN

24LC128-E/SN

24LC08B-E/SN

24LC02B-E/SN

24LC04B-E/SN

24LC16B-E/SN

PIC18F66K90-I/MR

PIC16F1825-I/ML

PIC18F66K22-I/MR

Date: Tuesday, July 22, 2025

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PIC18LF24J11-I/ML

PIC16F18054-I/STX

DSPIC30F4011-20I/ML

DSPIC30F4011-30I/ML

DSPIC30F4012-20I/ML

DSPIC30F4012-30I/ML

DSPIC30F2023-30I/ML

DSPIC30F3014-20I/ML

DSPIC30F3014-30I/ML

93LC66BT-I/ST

93AA66AT-I/ST

PIC16F1826T-I/SO027

93LC66CT-I/ST

93C56AT-I/ST

93C56BT-I/ST

PIC18LF25J10T-I/SS

PIC32MX210F016D-V/PT

PIC32MX350F256H-V/PT

PIC32MX350F128H-V/PT

PIC32MX450F256H-V/PT

PIC32MX450F128H-V/PT

TC7107AIPT713

RE341T-V/PTAAA

PIC16F727-ICE/PT

PIC16LF727-ICE/PT

PIC16LF1907-ICE/PT

PIC16F1789-ME2/PF

PIC16F1829-ME2/PF

PIC16F1719-ME2/PF

PIC16F1619-ME2/PF

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F1939-ME2/PF

DSPIC33EP512GP504T-H/PT

DSPIC33EP512MC204T-H/PT

DSPIC33EP512MC504T-H/PT

PIC24EP64GP206-I/PT

PIC32MZ1024ECH100-I/PF

DSPIC33FJ256MC710-I/PF

DSPIC33FJ64MC506-I/PT

DSPIC33FJ64MC706-I/PT

PIC24HJ128GP210-I/PF

PIC24HJ128GP310-I/PF

PIC32MZ1024ECH100-I/PT

DSPIC33FJ128GP306-I/PT

PIC32MX350F256L-I/PF

PIC32MX110F016D-I/PTF21

PIC32MX120F032D-I/PT

PIC32MK1024GPE064-I/PT

PIC32MX675F256H-80I/PT

PIC32MK0512GPD064-I/PT

PIC32MX575F256H-80I/PT

PIC18F56Q84-I/PTVAO

ATMXT641TD-AB

ATMXT449TD-AB

ATMXT641TD-ABVA2

ATMXT449TD-ABVA2

ATMXT225TD-ABVA2

DSPIC33FJ128MC506A-H/PTVAO

ATMXT449T-AB

ATMXT225T-AB

ATMXT641T-AB

Date: Tuesday, July 22, 2025

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ATMXT449T-AB074

ATMXT641T-AB074

ATMXT225TD-AB

ATMXT1296M1T-ABVA1

ATMXT1067TD-ABI2CCPVAO

ATMXT1067TD-ABSPIVAO

ATMXT1067TD-ABI2CVAO

ATMXT1296M1T-ABVAO

ATMXT1296M1E-AVAO

ATMXT1296M1E-AMKVAO

ATMXT1296M1T-AVA2

ATMEGA324PB-ABTVAO

DSPIC33EP128MC504-H/PTVAO

DSPIC33EP256MC506-H/PTVAO

PIC18F45K80-H/PTVAO

DSPIC33FJ256GP506A-H/PTVAO

DSPIC33EV32GM104-H/PTVAO

DSPIC33EV128GM004-H/PTVAO

DSPIC33EV128GM104-H/PTVAO

ATECC608B-MAH5V-T

MCP4231T-104E/ML

MCP4231T-503E/ML

EMC1464-A-AIA-TR

ATMEGA1608-MFR

PIC16F18345T-E/GZ

ATMEGA3209-MFR

DSPIC33FJ12GP202T-E/ML

DSPIC33EP64GP504T-E/ML

PIC24EP64GP204T-E/ML

MCP9904T-AE/9Q

Date: Tuesday, July 22, 2025

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DSPIC33EP512MC506-H/PT

ATSAMC21G17A-AZVAO

ATSAMC21G18A-AZVAO

ATSAMC20G17A-AZVAO

PIC16LF1847-I/SS

PIC18F25J11-I/SS

PIC18F24J11-I/SS

PIC18F26J11-I/SS

PIC18F27J53-I/SO

MCP3204-BAI/ST

PIC18F25J50-I/SS022

PIC18F25J50-I/SS024

PIC18F25J50-I/SS027

MCP2551-I/SN

RE46C108S8F

PIC16F628A-I/SO

PIC24F04KA200-I/ST

MCP2030-I/ST

PIC18F46K80-H/PT

DSPIC33CK64MP105-H/PT

DSPIC33CK32MP105-H/PT

DSPIC33CK256MP306-H/PT

DSPIC33CK256MP606-H/PT

DSPIC33CK512MP306-H/PT

DSPIC33CK512MP606-H/PT

DSPIC33EP512GP504-H/PT

DSPIC33EP512MC204-H/PT

DSPIC33EP512MC504-H/PT

PIC24EP512GP204-H/PT

PIC16F15356-I/SS

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PIC16LF767-I/SS

PIC16F767-I/SS

PIC24EP64GP202-I/SS

DSPIC30F3011-10I/MLB24

PIC32MX254F128B-I/MM

DSPIC33EP64GP502-I/MM

DSPIC33FJ06GS102-I/MM

DSPIC33FJ16GS402-I/MM

PIC16F1779-I/MP

PIC24HJ12GP202-I/ML

DSPIC33FJ64GS406-50I/MR

DSPIC33EP32GP502-I/MM

PIC32MX174F256B-I/MM

ATF22LV10C-10JU

ATF22V10CQ-15JU

AT27LV040A-90JU

AT27C040-70JU

AT89C51IC2-SLSUL

AT89C51RB2-SLSUM

ATSAMC21G15A-ANT

ATSAMC20N17A-ANT

ATSAMC21N17A-ANT

ATSAMC20N18A-ANT

ATSAMC21N18A-ANT

PIC32MK0256MCJ064T-I/PT

PIC32MK0256GPG064T-I/PT

DSPIC33EP128GS706T-I/PTC03

DSPIC33EP64GS506T-I/PTC10

DSPIC33AK32MC105T-I/M7

PIC16LF18326T-I/7N

Date: Tuesday, July 22, 2025

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PIC16F18346T-I/ML

PIC18LF46K40T-I/MVC02

PIC16F18346T-I/GZC01

PIC16F18346T-I/GZ

PIC16LF18346T-I/GZ

PIC16LF18326T-I/JQ

AVR64DD32T-I/RXB

AVR64DD28T-I/STX

PIC16F15225T-I/MG

MTCH1030T-I/MG

PIC16F15223T-I/MG

PIC18F27K42T-I/ML

PIC16F15224T-I/MG

PIC18LF27K42T-I/ML

PIC16F15256T-I/STX

PIC32CM1216JH01032T-I/RTB

PIC16F15254T-I/STX

PIC16F15255T-I/STX

PIC32CM1216JH01048T-I/U5B

USB2512BT-I/M2

USB2513BT-I/M2

PIC16F1518T-I/SO

24AA01T-I/ST

93AA76CT-I/ST

24LC64XT-I/STRVE

24AA02T-I/ST

24LC04BT-I/ST

MCP14A0305-E/MNY

PIC18F24K42-E/MV

MCP19114-E/MQ

Date: Tuesday, July 22, 2025

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PIC32MM0064GPM028-E/ML

PIC32MM0128GPM028-E/ML

PIC32MM0256GPM028-E/ML

MCP2050-500E/MQ

MCP2050-330E/MQ

PIC16F18424-E/JQ

PIC16F15354-E/MV

MCP47FEB01A0T-E/ST

MCP47FEB01A1T-E/ST

MCP47FVB21A0T-E/ST

PIC16F726-I/SS040

MCP2030A-I/ST

DSPIC33EV256GM002-I/SS

DSPIC33EV256GM102-I/SS

PIC16LF1708-I/SS

PIC16F1574-I/ST

MCP6N16T-100E/MF

MCP45HV51T-502E/MQ

11LC080T-E/MNY

11LC161T-E/MNY

11LC161T-E/MC

MCP45HV51T-103E/MQ

PIC16F1779-E/PT

PIC16F1777-E/PT

PIC18F65K80-E/PT

PIC18F66K80-E/PT

PIC18F6722-E/PT

PIC18F6627-E/PT

DSPIC33EV32GM106-E/PT

DSPIC33EV128GM006-E/PT

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DSPIC33EV128GM106-E/PT

DSPIC33FJ64MC204T-I/PTC05

DSPIC33EP256MU810T-I/PTC02

DSPIC33FJ128GP204T-I/PT

PIC32MX210F016DT-I/PT

PIC32MX450F256LT-I/PF

PIC32MX220F032DT-I/PT

PIC32MK0512MCF064T-I/PT

DSPIC33FJ128MC204T-I/PT

DSPIC33FJ32MC304T-I/PT

PIC32MM0256GPM064T-I/PT023

PIC24EP256GP204T-I/PT

DSPIC33EP128GS706T-I/PTC01

DSPIC33EP128GS706T-I/PTC02

DSPIC33EP128GS806T-I/PT

DSPIC33EP64GS806T-I/PT

DSPIC33EP128GS706T-I/PT

ATMEGA32A-AUR

PIC32MX550F256HT-I/PT

PIC32MX530F128HT-I/PT

PIC32MX570F512HT-I/PT

PIC24HJ256GP210T-I/PF

PIC24HJ256GP610T-I/PF

PIC32MX350F256LT-V/PT

PIC32MX120F064HT-V/PT

PIC32MX150F256HT-V/PT

PIC32MX170F512HT-V/PT

PIC32MX130F128HT-V/PT

ATSAMD20G16B-ANT

ATSAMD20G15B-ANT

Date: Tuesday, July 22, 2025

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ATSAMD20G14B-ANT

PIC32MX764F128HT-V/PT

ATSAML10E14A-MU

PIC18F46Q71-I/MP

PIC16F1503-I/MV

AVR32DD28-E/STX

AVR16DD28-E/STX

MCP47FEB21A0T-E/ST

MCP47FEB21A1T-E/ST

24LC32AFT-E/ST

93LC66BT-E/ST

93LC66CT-E/ST

ATTINY87-A15MZ

PIC18F47Q83T-I/PT

PIC18F47Q84T-I/PT

PIC24FJ128GL405T-I/PT

PIC24FJ256GL405T-I/PT

PIC24FJ512GL405T-I/PT

PIC24FJ512GU410T-I/PT

DSPIC33FJ128MC510AT-I/PTC30

PIC32CM1216MC00032T-I/PT

PIC16F874-04/PQ

PIC16F874-20/PQ

PIC17C44-16/PT

PIC17C44-33/PT

TC7106CKW

TC7106ACKW

PIC16C67-20/PQ

PIC16C65B-20/PQ

PIC16C64A-04/PQ

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PIC16C64A-10/PQ

PIC16C67-04/PQ

PIC16C65B-04/PQ

TC7109CKW

PIC16F877-04/PT

PIC16F874-04/PT

PIC16F877-20/PT

PIC16C65B-20/PT

PIC16LC65B-04/PT

PIC16C64A-10/PT

PIC16LC923-04/PT

PIC16LF877-04/PT

ATSAMC20J18A-AUT

ATSAMC20J15A-AUT

ATSAMC20J16A-AUT

ATSAMC20J17A-AUT

ATSAMC21J15A-AUT

ATSAMC21J16A-AUT

ATSAMC21J17A-AUT

ATSAMC21J18A-AUT-SL1

PIC16F884T-I/PTC02

PIC18F4580T-I/PTC01

PIC16LF1567T-I/PT

PIC16F1777T-I/PT

PIC16F1779T-I/PT

PIC16F18876T-I/PT

PIC16F18877T-I/PT

PIC16LF18877T-I/PT

DSPIC33EP128GS804T-E/MLVAO

MCP6282T-E/SN

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24LC512T-E/ST

MCP6292T-E/SN

ATSAMC21J17A-AZ510

ATSAMC21J18A-AZ510

ATSAMC21J16A-AZVAO

ATSAMC20J18A-AZVAO

ATSAMC20J17A-AZVAO

ATSAMD21J16B-AZVAO

DSPIC33EP512GM710-E/PTVAO

DSPIC33EP256GM710-E/PTVAO

PIC16F1459T-I/ML

PIC16LF1459T-I/MLC03

PIC18F46K80-I/ML

PIC18F26K42-I/ML

ATSAM3N0AA-MU

PIC16F1777-I/ML

PIC16LF1779-I/ML

PIC16LF1779-I/MV

PIC16F1779-I/MV

PIC16LF1777-I/ML

PIC16F1779-I/ML

PIC16LF1777-I/MV

PIC16F1777-I/MV

PIC18F65K80-I/MR

PIC18F66K80-I/MR

LE9662WQC

LE9672WQC

LE79272PQC

AT27C020-55JU-T

AT27C512R-45JU-T

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AT27C512R-70JU-T

AT27C020-90JU-T

COM20020I3V-DZD-TR

AT27LV256A-90JU-T

AT27LV512A-90JU-T

AT28HC256-12JU-T

AT28HC256E-70JU-T

AT28HC256E-90JU-T

AT28HC256E-12JU-T

AT28C256-15JU-T

AT28HC256F-90JU-T

PIC18F4580-E/PT

DSPIC33CK64MC105-E/PT

DSPIC33CK32MC105-E/PT

DSPIC33FJ128MC506A-E/PT

MCP3424T-E/ST

MCP3422A4T-E/SN

MCP3422A2T-E/SN

ZL88601LDG1

ZL88801LDG1

LE9643AQC

LE9651PQC

LE9652PQC

PIC18LF14K22-I/ML

PIC16F628AT-I/SS081

PIC16LF1508T-I/SS025

PIC16LF1509T-I/SS026

24LC024T-I/SN

24AA024T-I/SN

24LC025T-I/SN

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24AA025T-I/SN

24C02CT-I/SN

24C01CT-I/SN

25LC256T-I/SN

24LC024HT-I/SN

24AA024HT-I/SN

25LC080CT-I/SN

PIC16LF1788T-I/SS

PIC24FJ1024GB606-I/MR

PIC12F510T-I/SN

AT28C256E-15JU-T

AT28BV256-20JU-T

AT28C256EF-15JU-T

COM20019I-DZD-TR

COM20020I-DZD-TR

DSPIC33FJ16GS404-E/PT

PIC16F18876-E/PT

DSPIC33FJ16GS504-E/PT

24LC04BT-I/MC

24AA04T-I/MC

PIC16LF1788T-I/ML

24AA16T-I/MNY

PIC16F1827T-I/MV

24LC16BT-I/MNY

PIC18F45K22T-I/MV

MCP4261T-502E/ST

MCP4261T-103E/ST

MCP4261T-104E/ST

MCP4261T-503E/ST

MCP3422A7T-E/SN

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F785T-E/SS

MCP6L72T-E/SN

MCP4241T-502E/ST

MCP4011T-502E/SN

PIC18F25K80T-I/SO

DSPIC33FJ32MC101T-I/SS

PIC18F26K80T-I/SO

PIC16LF18323T-I/STC02

PIC16LF18323T-I/ST

PIC16F18323T-I/ST

PIC16LF18323T-I/ST028

PIC16LF18323T-I/ST024

PIC16LF18323T-I/ST025

PIC16F886T-I/SO

MCP4011T-503E/SN

MCP9843T-BE/ST

MCP2551T-E/SN

PIC32CM5164JH00100-I/PF

PIC32CM2532JH01100-I/PF

DSPIC33CK128MC105-I/M7

PIC32MZ2048EFM064T-E/MR

PIC32MZ1024EFG064T-E/MR

34AA04T-E/MNY

PIC18F24K42T-E/MV

DSPIC33EP128MC502T-E/MM

DSPIC33EP128GP504T-E/ML

DSPIC33EP128MC204T-E/ML

DSPIC33EP128MC504T-E/ML

MCP2544FDT-E/MF

PIC32MZ0512EFE064T-E/MR

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATSAMD21E16B-MU

24AA04H-I/ST

PIC18F25K42-I/SS

PIC16F15243-I/SS

PIC32MX564F064H-V/PT

A3PN250-VQG100I

PIC32CZ2051CA70100-V/E5X

A3PN060-2VQG100Q117

ATSAMC21N17A-AN

ATSAMC21N18A-AN

A3PN125-VQG100

A3PN060-VQG100IX94

PIC32MX130F128L-50I/PT

PIC32MX230F128L-I/PT

PIC16F1719-I/MP

ATECC608A-TNGACTU-B

ATECC608A-TNGLORAU-B

ATECC608A-TFLXTLSU-PROTO

PIC24F08KA102-I/ML

PIC24F08KA101-I/MQ

PIC18F25K20-I/ML

PIC18F25K20-I/MLC02

PIC18F25K20-I/MLC10

PIC16F18025-I/ML

DSPIC33FJ16GS502-I/MM

DSPIC33FJ64GP804T-I/PT

PIC24FJ128GU408T-I/PT

DSPIC33FJ128GP710-I/PF

DSPIC33FJ256GP510-I/PF

PIC32MZ2048ECM100-I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33EP64GP504-I/PT

PIC24EP64GP204-I/PT

PIC32MX170F512L-50I/PT

PIC32MX250F256L-50I/PT

PIC32MX530F128L-I/PT

PIC32MZ2048ECH100-I/PF

PIC32MX174F256D-I/PT

PIC32MX270F256D-50I/PT

DSPIC33EP64GP506-I/PT

DSPIC33CH512MP505-E/PT

PIC32MK0512MCJ064-E/PT

PIC32MK0512GPG064-E/PT

PIC32MK0512GPK100-E/PT

PIC18F43K22T-I/PT020

PIC32MK1024GPE064T-I/PT

PIC24FJ128GL408T-I/PT

PIC24FJ256GL408T-I/PT

PIC24FJ512GL408T-I/PT

PIC32MX450F128LT-I/PF

PIC32MK1024GPD064T-I/PT

PIC32MK1024MCF064T-I/PT

PIC18F14Q40T-I/SS

PIC18F15Q40T-I/SS

AVR128DA28T-I/SS

AVR128DA28T-I/SO

PIC12F1840T-H/MFVAO

MCP2561T-H/MFVAO

MCP2561FDT-H/MFVAO

PIC16F1507T-H/MLVAO

PIC18F24K42T-H/5NVAO

Date: Tuesday, July 22, 2025

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PIC18LF24K42-I/SS

PIC18LF25K42-I/SS

PIC16F15244-I/SS

PIC16LF1825-I/ST027

PIC18F2620-I/SOB4

TA010-MAYMD-BCZ

TA010-MAYMD-B

AVR128DA32S-E/QZB

AVR128DA48S-E/6MX

PIC18F46K22-E/MVC01

ATSAMD20E16B-OMZ

ATSAMD20J16B-OMZ

ATSAMD20G16B-OMZ

PIC18F25J50-I/SS029

93C86A-I/ST

93C86B-I/ST

93C76A-I/ST

93C76B-I/ST

MCP3208-BI/SL

24LC04B-I/SN

24AA04-I/SN

24LC04BH-I/SN

24AA02-I/SN

MCP2035-I/ST

24LC512-I/ST14

PIC24FJ32GA002-I/SO

24LC64F-I/SN

PIC32MX120F064HT-50I/PT

PIC32MX250F256HT-50I/PT

PIC32MX230F128HT-50I/PT

Date: Tuesday, July 22, 2025

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PIC24HJ32GP202-I/MM

DSPIC33FJ32GS606-50I/MR

24LC64T-E/ST

24LC32AT-E/ST

MCP47FEB21A2T-E/ST

MCP47FEB21A3T-E/ST

24AA044-I/SN

PIC16F1824T-I/ML

PIC18F47K40T-I/ML

25LC010AT-I/MC

25LC020AT-I/MC

25AA040AT-I/MC

25LC020AT-I/MNY

ATMEGA16L-8MURA5

PIC16F15375T-I/MV

PIC16F15376T-I/MV

PIC16LF15375T-I/MV

PIC16LF15376T-I/MV

PIC16F15376T-I/ML

PIC16LF15375T-I/ML

PIC16LF15376T-I/ML

PIC16F17126T-I/7N

ATMEGA16A-MUR

ATTINY167-MUR

KSZ9031RNXIA-TR

ATMEGA162-16MUR

ATMEGA162V-8MUR

ATMEGA324PB-MUR

PIC32MX575F512L-80V/PT

PIC32CM2532JH00064-I/5LX

Date: Tuesday, July 22, 2025

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PIC32CM5164JH00064-I/5LX

PIC32CM2532JH01064-I/5LX

ATSAMD21E18A-MU

ATSAMD21E18A-MU-SLL

ATSAMD21E18A-MUA1

ATSAMD21E17A-MUA1

ATSAMD21E17A-MU

USB5744-I/2G

PIC18F26K20-I/ML

PIC18F26K20-I/MLC03

PIC18F26K20-I/ML056

TC7662BEOA

TC7660SEOA

TC7660EOA

TC622EOA713

TC7660EOA713

TC7662BEOA713

TC1044SEOA713

TC7660SEOA713

TC7660SEOA713BAA

TC7660SEOA713BAB

PIC18F26K22T-I/ML027

DSPIC33CK256MC505T-I/M7

DSPIC33CK128MC505T-I/M7

DSPIC33CK256MC105T-I/M7

DSPIC33CK128MC105T-I/M7

PIC16F1826T-I/ML

PIC16F1826T-I/MV

DSPIC33CK256MC506T-I/MR

PIC32MK0256GPG064T-I/R4X

Date: Tuesday, July 22, 2025

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ATECC608B-MAHDA-T

ATECC608B-TCSMU

PD69101ILQ-TR

ATECC608B-MAHCZ-T

24CS256T-E/Q4B66KVAO

AVR128DA48T-E/6LXL10

AVR64DA48T-E/6LXL10

PIC18F26Q83T-E/5NVAO

MCP16501TD-E/RMB-D

MCP16502TAB-E/S8B-D

MCP16502TAD-E/S8B-D

PIC16F15255T-E/STX

PIC16F1503T-E/MG098

PIC10F320T-E/MC027

TC1301B-FAAVMF

TC1301B-GFDVMF

DSPIC33AK256MPS206-I/PT

DSPIC33AK512MC506-I/PT

DSPIC33AK256MC506-I/PT

DSPIC33AK512MC206-I/PT

DSPIC33AK512MPS205-I/PT

PIC12F683-I/MD

PIC18F4220-I/ML

PIC16F616-I/ML

PIC16F76-I/ML

MCP73831-2ATI/MC

PIC18LF65K80-I/MR

PIC18LF66K80-I/MR

PIC16F818-I/ML

PIC18LF46K80-I/ML

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PIC12F1572-E/RF

PIC16F1575-E/JQ

MCP9804-E/MC

PIC16F1704-E/ML

PIC16F1937-E/ML

PIC16F1618-E/GZ

PIC16F1619-E/ML

PIC16LF1613-E/ML

PIC12LF1612-E/MF

PIC16LF1709-E/ML

PIC16LF1615-E/ML

DSPIC33FJ12MC202-E/ML

PIC16LF1567-E/MV

MCP19117-E/MQ

MCP3422A2T-E/MC

MCP652T-E/MF

MCP4141T-104E/MF

PIC18LF25K42-I/ML

DSPIC33EP64GS502-I/MMC07

DSPIC33FJ16GS504-I/ML

PIC16F18875-E/PTVAO

DSPIC33CK256MP508-E/PTVAO

DSPIC33CK128MP508-E/PTVAO

DSPIC33CK64MP508-E/PTVAO

PIC16F1519-E/PTVAO

AT32UC3C1256C-AZT

AT32UC3C1512C-AZT

25AA010AT-I/MNY

PIC16LF1503T-I/MV

PD39210C-011019-TR

Date: Tuesday, July 22, 2025

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LE9551CMQCT

LE9551DMQCT

DSPIC33EP16GS502T-I/MM

ATMEGA16U2-MU

ATMEGA2564RFR2-ZU

ATSAMD21E15B-MU

MCP47FEB11A3-E/ST

MCP47FEB12A0-E/ST

MCP47FVB21A3-E/ST

PIC24FJ64GB202-E/SS

DSPIC33CH256MP505-I/PTVAO

DSPIC33EP32MC204-I/PTVAO

DSPIC33EP32MC504-I/PTVAO

PIC16F1939-I/PTVAO

PIC24FJ32MC104-I/PTVAO

DSPIC33CK128MP505-I/PTVAO

DSPIC33CK64MP505-I/PTVAO

DSPIC33EP128GM604-I/PTVAO

DSPIC33FJ64GS606-50I/PTVAO

PIC32MZ0512EFF064-I/PTVAO

PIC18F45K22-I/PTVAO-BW

ATMXT225T-AT

ATMXT225TD-AT

MCP6V14-E/ST

MCP23S17-E/SS

24AA02E64-E/SN

PIC16F1454-E/ST

11LC080-E/SN

24AA02E48-E/SN

MCP45HV31-502E/ST

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24LC32A-E/ST

24LC512-E/ST

24LC64-E/ST

MCP47FEB21A3-E/ST

PIC18LF27K40-I/SS

PIC16LF1554-I/STM10

PIC16LF1559-I/SSM10

24LC128-I/STRVF

PIC16F18145-I/SS

AVR128DA28-I/SS

MCP4642T-103E/MF

MCP3912A1T-E/MQ

MCP3919A1T-E/MQ

MCP4632T-502E/MF

MCP4632T-103E/MF

MCP4632T-104E/MF

MCP4632T-503E/MF

DSPIC33EP256MU810-E/PT

DSPIC33EP512GP806-E/PT

DSPIC33EP512MC806-E/PT

DSPIC33EP512GP506-E/PT

DSPIC33EP512MC506-E/PT

DSPIC33EP512MC206-E/PT

DSPIC33EV128GM004-E/PT

DSPIC33EV128GM104-E/PT

DSPIC33EV64GM004-E/PT

25LC256T-E/SN

25LC256T-E/ST

PIC16F648AT-E/SS

93LC76AT-E/SN

Date: Tuesday, July 22, 2025

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93LC76BT-E/SN

93LC86AT-E/SN

93LC86BT-E/SN

PIC12F510T-E/SN

ATSAMD20G18A-MU

PIC24FJ128GL302-I/ML

MCP6002-E/SN

PIC18F45K42-E/MV

PIC18F46K42-E/MV

MCP47FEB01A1-E/ST

PIC16LF1454-E/ST

MCP47FEB02A0-E/ST

MCP47FEB02A1-E/ST

MCP47FEB11A1-E/ST

MCP47FEB11A2-E/ST

MCP47FVB22A3-E/ST

MCP47FVB11A1-E/ST

PIC16F1847-E/SO

MCP47FVB01A0-E/ST

MCP47FVB01A1-E/ST

MCP47FEB12A1-E/ST

MCP47FEB02A2-E/ST

MCP47FEB02A3-E/ST

MCP47FEB21A2-E/ST

25LC080D-I/MNY

25AA080D-I/MNY

25AA160D-I/MNY

25LC080C-I/MNY

25AA080C-I/MNY

25LC160C-I/MNY

Date: Tuesday, July 22, 2025

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25AA160C-I/MNY

AT86RF215-ZU

PIC16F1769-I/ML

PIC16F1768-I/ML

ATSAML11E16A-MUKPH

25LC160D-I/MNY

LE9652MPQC

AT86RF215IQ-ZU

LE9541DUQC

PIC16LF18876-I/MV

PIC16F18856-I/STX

PIC24FJ64GA002-I/ML044

PIC24EP128GP202-I/MM038

PD69210R-034600

PD69210R-034900

PIC16F17576T-I/PT

PIC32CZ2051CA70100T-I/E5X

DSPIC33CK32MC102T-I/SS

PIC16F15254T-I/SS

MIC2568-0YSM-TR

MIC2568-1YSM-TR

PIC18F2423T-I/SO

PIC18F24J11T-I/SO

DSPIC33AK128MC102T-I/SS

DSPIC33AK64MC102T-I/SS

DSPIC33AK32MC102T-I/SS

PIC18F27Q83T-I/SS

PIC18F27Q84T-I/SS

PIC18F27Q83T-I/SO

PIC18F27Q84T-I/SO

Date: Tuesday, July 22, 2025

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AVR32DA28T-I/SS

PIC12F519T-I/SN049

PIC12F1840T-I/SN

PIC24F08KA101T-I/SS

DSPIC33EV64GM006T-I/PT

DSPIC33EP32MC502-E/SS

PIC24EP32GP202-E/SS

PIC24EP32MC202-E/SS

DSPIC33FJ12MC202-E/SO

PIC16F15356-E/SS

PIC16LF18446-E/SS

DSPIC33FJ64MC802-E/SO

DSPIC33FJ128MC202-E/SO

DSPIC33FJ128MC802-E/SO

DSPIC33FJ32MC302-E/SO

DSPIC33FJ16MC102-E/SS

DSPIC33FJ16GP101-E/SS

PIC16LF18445T-I/GZ

PIC16LF18446T-I/GZC01

PIC16LF18446T-I/GZ

EQCO5X31C0T-I/6NX

24LC024H-I/ST

24AA024H-I/ST

24LC024-I/ST

24AA024-I/ST

24LC025-I/ST

24AA025-I/ST

24AA16-I/SNB22

24FC64F-I/SN

24LC024-I/ST186

Date: Tuesday, July 22, 2025

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24LC024-I/ST187

25AA256-I/ST

PIC12LC508A-04I/SN

ATSAMC21G16A-MNT

ATSAMC21G17A-MNT

ATSAMC20J15A-MMNT

ATSAMC20J16A-MMNT

ATSAMC20J17A-MMNT

ATSAMC20J18A-MMNT

ATSAMC21J15A-MMNT

ATSAMC21J16A-MMNT

24FC16T-I/MUY

24FC08T-I/MUY

PIC32MX350F256HT-I/MR

DSPIC33FJ64GP202T-I/MM

DSPIC33FJ64GP802T-I/MM

DSPIC33CK256MP708-H/PT

DSPIC33CK1024MP405-H/PT

DSPIC33CK1024MP705-H/PT

DSPIC33CK512MP405-H/PT

DSPIC33CK512MP705-H/PT

DSPIC33CK256MP405-H/PT

DSPIC33CK256MP705-H/PT

DSPIC33FJ32MC204-H/PT

DSPIC33CK1024MP710-H/PT

DSPIC33CK64MC105-H/PT

DSPIC33CK32MC105-H/PT

DSPIC33CH64MP506-H/PT

DSPIC33CH128MP506-H/PT

DSPIC33EP32MC202T-E/MMVAO

Date: Tuesday, July 22, 2025

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PIC16F18877T-E/MVVAO

PIC18F26K42T-E/MLVAO

ATA6560-GBQW-VAO

PIC16F18857T-E/MLVAO

PIC16F18856T-E/STXVAO

PIC18F46K40T-E/MVVAO

DSPIC33CK256MP206-E/PT

DSPIC33CK256MP506-E/PT

PIC32MZ1024EFG100-E/PTG24

PIC32MZ1024EFG100-E/PT

PIC32MZ1024EFH100-E/PT

PIC18F47K40-E/PT

PIC18LF67K40-E/PT

PIC32MZ1024EFK100-E/PT

PIC32MZ1024EFM100-E/PT

PIC24FJ64GU205-E/PT

PIC24FJ64GP205-E/PT

PIC24FJ32GP205-E/PT

PIC24FJ32GU205-E/PT

DSPIC33CK256MP305-E/PT

PIC24F16KA102-E/SS

34AA02-E/SN

24AA64-E/SN

PIC18F25K20-E/SOC12

PIC12F609-E/SN

PIC16HV785-E/SS

PIC16LF18455-E/SS

PIC16LF18456-E/SS

MCP2003-E/SN

PIC16F18856-E/SS

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

24AA64-E/ST

PIC12F508-E/SN

PIC32MK0512MCF064T-I/MR

DSPIC33FJ128GP202T-I/MM

DSPIC33FJ128GP802T-I/MM

PIC24HJ64GP502T-I/MM

PIC24HJ128GP202T-I/MM

MCP3912A1T-E/SS

MCP3919A1T-E/SS

DSPIC33FJ12MC202T-E/SO023

MCP602T-E/SN

MCP6L2T-E/SN

34AA04T-E/ST

24AA044T-E/ST

PIC32MX220F032B-50I/SS

PIC24FJ64GL302-I/SO

DSPIC33FJ16GS502-50I/SO

34AA04-I/SN

PIC16LF737-I/SS

PIC16F737-I/SS

PIC16C620A-04/SS

PIC16C58B-20/SO

PIC16LC717/SS

PIC16LC58B-04/SS

PIC16LF84A-04/SS

PIC16C770/SS

PIC16F628-20/SS

PIC16LC620A-04/SS

PIC16LF628-04/SS

PIC16C621-04/SS

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PIC16C711-04/SS

PIC16C620A-40/SS

PIC16F628-04/SS

PIC16C771/SS

PIC16LC710-04/SS

PIC16LC711-04/SS

PIC16F84A-04/SS

PIC16F84A-20/SS

PIC16LC770/SS

PIC16C621A-04/SS

PIC16C621A-20/SS

PIC16C622A-04/SS

PIC16LC554-04/SS

PIC16C622A-04/SO

24AA64X/ST

PIC16LC642-04/SO

HCS301/SN024

PIC16C72A-04/SS

PIC16C72A-20/SS

PIC16C63A-04/SS

ENC28J60/SS

PIC16C622A-20/SO

PIC16C63A-20/SS

93LC56C-E/SN

24LC256-E/SN

PIC16F15354-E/SS

PIC16F17546-E/ML

MCP47FEB21A0-E/ST

MCP47FEB21A1-E/ST

DSPIC33FJ32MC202-E/SSC25

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MCP47FEB11A0-E/ST

24LC32AF-E/ST

93LC66C-E/ST

93LC66A-E/ST

93LC66B-E/ST

AVR64DA28-I/SS

AVR64DA28-I/SO

PIC16LF720-I/SS

24FC512T-I/SN

93C66CT-I/ST

93C66AT-I/ST

PIC16F677T-I/SS

93C66BT-I/ST

PIC18F14K22T-I/SS

93C76CT-E/SN

93C86CT-E/SN

MCP41010T-E/SN

PIC12F519T-E/SN

93C56AT-E/SN

93C56BT-E/SN

MCP41100T-E/SN

93C66AT-E/SN

LE9653AQC

LE9641PQC

LE9642PQC

PIC18F24K40-I/MV

PIC18F27K40-I/ML

AT91SAM7S32B-MU

PIC16LF1527-I/MR

PIC16LF1526-I/MR

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LE9541CUQC

DSPIC33EP128MC502-I/MM

PIC16F1578-I/SS

PIC16LF18344-I/SS

PIC16F1579-I/SS

DSPIC33EP64MC202-I/SS

ATSHA204A-MAHCZ-S

PIC16LF1508T-I/ML

PIC32MX170F512LT-50I/PF

PIC32MX130F128LT-50I/PF

PIC32MX550F256LT-I/PT

ATECC608C-MAHDA-S

ATECC608C-MAHDA-T

25CS640T-I/Q4B

PIC16LF15355T-I/MV020

PIC16F15355T-I/MV

PIC16LF15354T-I/MV

PIC16LF15355T-I/MV

PIC16F17156T-I/STX

PIC16F18156T-I/STX

USB5734T-I/MR

RE46C705IV32T

RE46C700IV28T

RE46C701IV28T

PIC18F26Q84T-I/5N

PIC18F56Q83T-I/6MX

PIC18F56Q84T-I/6MX

DSPIC33EV128GM102-H/SSVAO

DSPIC33CK32MC102-H/SSVAO

DSPIC33EV32GM002-H/SSVAO

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PIC16F1615-H/STVAO

25CS320-H/ST36KVAO

TC7117CLW713

PIC17C756AT-33/L

PIC16C67T-20/L

TC850CLW713

TC7109ACLW713

PIC16F877T-20/L

PIC16F877T-04/L

PIC16C74BT-20/L

AY0438T/L

HV20220PJ-G-M904

HV2201PJ-G-M904

MT8812APR1

MT093APR1

LE79R70-1DJCT

LE79R70DJCT

AVR64EA48T-E/6LX

AVR32EA48T-E/6LX

PIC16F18346T-E/GZ

PIC16LF18346T-E/GZ

AVR16EA48T-E/6LX

PIC18F66J90-I/PT

PIC18F6390-I/PT

PIC16LC774-I/PQ

PIC24FJ256DA210-I/PTREL

PIC16F727-I/MV

PIC18F44J11-I/ML

PIC18F46J11-I/ML

PIC18F45J11-I/ML

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PIC16F1938-E/SO

PIC12F1840-E/SN

PIC18F26Q10-E/SO

DSPIC33EP32MC202-E/SS

MCP6V89-E/ST

24AA16-E/SN

24LC16BH-E/SN

24LC08BH-E/SN

PIC18F16Q41-E/SS

PIC18F16Q40-E/SS

PIC18F27K42-E/SS

PIC18LF27K42-E/SS

24LC04BH-E/SN

PIC18F26K42-E/SS

PIC18LF26K42-E/SS

PIC16F15223-E/ST

PIC16F15224-E/ST

PIC16LF1566-E/SS

PIC16LF1936-E/SS

DSPIC33CK256MC502-E/SS

DSPIC33CK64MP102-E/SSC01

PIC18F26Q43-E/SS

PIC18F26Q43-E/SO

PIC16F17126-E/ST

PIC16F18126-E/ST

PIC18F97J94T-I/PT

PIC18LF46K22T-I/PT

PIC18F66J94T-I/PT

PIC18F85J94T-I/PT

PIC18F452-E/L

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PIC16F77-E/L

PIC16F74-E/L

HV5812PJ-G

PIC16F877A-E/L

PIC16LC923-04I/L

PIC16C64A-04I/L

PIC16C65A-20I/L

PIC16C765-I/L

PIC16C64A-10I/L

PIC16C67-20I/L

MCP48FEB24T-E/MQ

MCP48FEB28T-E/MQ

PIC32MZ0512EFE064T-E/MRA21

PIC16F1828T-E/ML

MCP48FEB04T-E/MQ

MCP48FVB04T-E/MQ

MCP48FVB08T-E/MQ

MCP48FVB14T-E/MQ

MCP48FVB18T-E/MQ

MCP48FVB24T-E/MQ

MCP47CVB08T-E/ML

MCP47CVB18T-E/ML

MCP47CVB28T-E/ML

MCP48CMB08T-E/ML

MCP48CMB18T-E/ML

MCP48FVB28T-E/MQ

OS81212AFR-B2B-010300-VAO

24LC16BT-I/MC16KVAO

PIC16F1513-I/MV

DSPIC33EV128GM106-I/MR

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PIC24FJ16GA004-I/ML

PIC24FJ48GA004-I/ML

HA7612-I/MM033

DSPIC33EP64GS504-I/ML

DSPIC33EP32GS504-I/ML

DSPIC33EP16GS504-I/ML

DSPIC33FJ64GP306A-I/PT037

DSPIC33FJ128MC510A-I/PTC31

PIC32MX320F064H-40I/PT

PIC32MZ1024ECG100-I/PT

PIC32MX570F512H-50I/PT

PIC32MX150F256L-50I/PT

PIC16F1829T-E/ML

MCP47CMB08T-E/ML

MCP47CMB18T-E/ML

MCP47CMB28T-E/ML

MCP48CMB28T-E/ML

MCP48CVB08T-E/ML

MCP48CVB18T-E/ML

MCP48CVB28T-E/ML

MCP47CMB04T-E/ML

MCP47CMB14T-E/ML

MCP47CMB24T-E/ML

MCP47CVB04T-E/ML

MCP47CVB14T-E/ML

MCP47CVB24T-E/ML

MCP48CMB04T-E/ML

MCP48CMB14T-E/ML

MCP48CMB24T-E/ML

MCP48CVB04T-E/ML

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MCP48CVB14T-E/ML

ATSAMD21J17A-MMFT

ATSAMD21J18A-MMFT

PIC32CM5164JH01064-I/PT-SL3

PIC32AK3208GC41064-I/PT

AVR64DA48S-I/PT

AVR64DA64S-I/PT

AVR32DA32S-I/PT

AVR64DA32S-I/PT

AVR32DA48S-I/PT

ATSAMD51N20A-AUN01

PIC32CM3204JH00064T-E/5LX

PIC32CM3204JH00048T-E/U5B

PIC32CM3204JH00032T-E/RTB

DSPIC33EP64GS502-I/MMC12

DSPIC33EP32GS402-I/MM

DSPIC33CK256MP305-I/M7

DSPIC33CK256MP605-I/M7

PIC18F25K42-I/ML

DSPIC33EP64GS502-I/MM

PIC18LF46K40-I/MV

PIC18F45K40-I/ML

PIC18F46K40-I/MV

PIC18LF26K40-I/ML

ATMEGA3208-MU

PIC18F46Q84-I/NHX

PIC18LF46K40-I/ML

24C02CT/ST

HCS301T/SN024

TC7660SCOA713

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24LC08BT/ST

PIC16F873T-20/SOV01

PIC16C770T/SS

24AA64T/SN

PIC16C622AT-20/SOC03

24LC04BT/SN

24AA04T/SN

24LC01BT/SN

24AA01T/SN

PIC12C509AT-04/SN

24LC32AT/SN

24LC02BT/SN

24AA02T/SN

HCS201T/SN017

HCS201T/SN021

24LC024T/ST

24LC16BT/SN

PIC12C508AT-04/SN

HCS201T/SN

24LCS52T/ST

93LC46AT/ST

24LC08BT/SN

PIC16F17545T-I/SS

PIC16F17546T-I/SS

AT25320B-XHL-T

A0001TIC03-I/ST047

PIC16F19156T-I/SS026

AT24C64D-XHM-T

AT24C32D-XHM-T

24FC512-I/ST16KVAO

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HCS362-I/STVAO

ATSAMD21G16B-AZTVAO

DSPIC33CK64MP206T-E/PTVAO

DSPIC33CK64MP506T-E/PTVAO

25LC160D-I/ST

25AA160D-I/ST

PIC16LF18456-I/SS

25AA160C-I/ST

PIC18F1320-I/SS

25AA320A-I/STB22

24LC21T-I/SN

PIC12F615T-I/SN085

PIC16F690T-I/SS038

PIC18F16Q41T-I/SS

PIC12LF1571T-I/SN028

PIC12LF1571T-I/SN031

PIC12LF1571T-I/SN029

PIC16F15223T-I/ST

PIC16F15224T-I/ST

PIC16LF1566T-I/SS

PIC16LF1936T-I/SS023

PIC12F1571T-I/SN042

PIC18LF25J10T-I/SS031

PIC18LF25J10T-I/SS035

MCP6042-I/SN

PIC16LF18856-I/SS

PIC12LF1840T39A-I/ST

PIC16F1703-I/ST

PIC16LF723A-I/SSC01

MCP2221-I/ST

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PIC12LC509A-04I/SN

MCP2221A-I/ST

PIC12LF1840T48A-I/ST

25LC040A-I/ST

25AA040A-I/ST

PIC12F509-I/SN

AVR128DA28-E/SSVAO

PIC16F18425-E/STVAO

PIC16F18424-E/STVAO

PIC16F18426-E/STVAO

AVR64DA28-E/SSVAO

MTCH1060-E/SSVAO

PIC16F1574-E/STVAO

PIC16F1823-E/STVAO

PIC16F1778-E/SSVAO

PIC18F27Q84-E/SSVAO

PIC18F25Q10-E/SSVAO

25LC128-E/ST16KVAO

PIC18F27Q83-E/SSVAO

PIC16F15243-E/SSVAO

PIC16F15255-E/SSVAO

PIC18F26Q83-E/SSVAO

PIC18F25Q43-E/SSVAO

DSPIC33EV64GM002-E/SSVAO

PIC16F18326-E/STVAO

MCP4251-503E/STVAO

PIC18F05Q40-E/STVAO

DSPIC33EV256GM002-E/SSVAO

AVR32DB28-E/SSVAO

PIC16F18046-E/SSVAO

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PIC18F27Q10-E/SSVAO

PIC16F15254-E/SSVAO

PIC18F24Q71-E/SOVAO

PIC16F18023-E/STVAO

PIC16F15244-E/SSVAO

MTR6677-I/PT

ATXMEGA128D4-AURA0

PIC32MZ2048ECG100T-I/PTD21

PIC32MZ1024EFG100T-250I/PT

PIC32MZ1024EFG100T-I/PTG23

ATMEGA329V-8AUR

ATXMEGA64D4-AUR

DSPIC33CK256MP305-E/PTVAO

24LC01B/SN

24AA01/SN

24AA64/SN

DSPIC33EV128GM004-E/ML

DSPIC33EV128GM104-E/ML

DSPIC33EV64GM004-E/ML

PIC16F1938-E/MV

PIC16F1718-E/ML

DSPIC33EV64GM104-E/ML

DSPIC33EV32GM004-E/ML

DSPIC33EV32GM104-E/ML

DSPIC33FJ16MC102-E/ML

PIC16F1713-E/MV

PIC16F1716-E/MV

PIC16LF1718-E/MV

PIC16LF18877-E/ML

PIC16F18876-E/ML

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PIC16LF18876-E/ML

PIC16F18854-E/MV

PIC16LF18854-E/MV

PIC16LF18324-E/JQ

PIC18F25K22-E/ML

PIC16LF1559-E/ML

PIC16F19155-E/MV

MCP8025A-115E/MP

PIC16LF15313-E/RF

PIC16F15356-E/ML

PIC16LF1554-E/ML

PIC16LF18325-E/JQ

PIC16LF1705-E/ML

PIC16F18345-E/GZ

DSPIC33EP512GP504-I/ML

DSPIC33EP512MC206-I/MR

DSPIC33EP512GP502-I/MM

DSPIC33EP512MC506-I/MR

PIC24FJ128GU406-I/MR

PIC24FJ256GU406-I/MR

PIC24FJ512GU406-I/MR

PIC24EP512MC202-I/MM

PIC32MZ1024EFM064T-E/PT

ATSAMC20N18A-AN

ATSAMC20E15A-ANT

ATSAMC20E16A-ANT

ATSAMC20E17A-ANT

ATSAMC20E18A-ANT

ATSAMC21E15A-ANT

ATSAMC21E16A-ANT

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ATSAMC21G17A-ANT

ATSAMC21G18A-ANT

ATSAMC21E17A-ANT

24AA08T/SN

93LC56BT/ST

24LC04BT/ST

24VL014T/ST

24VL024HT/ST

34VL02T/ST

24VL024T/ST

24VL014HT/ST

24VL025T/ST

24LC02BT/ST

PIC16C63AT-04/SS

24LC024T/SN

24LC025T/SN

MCP6549T-E/ST

MCP6544T-E/ST

MCP6274T-E/ST

PIC16F57T-E/SS

PIC16F876AT-E/SS

PIC16C622AT-04E/SO

PIC16F819T-E/SS

PIC16F818T-E/SS

MCP6294T-E/ST

MCP6G04T-E/ST

PIC16C621AT-04E/SO

PIC32MX174F256D-I/ML

PIC32MX274F256D-I/ML

PIC16F689-I/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F17525-I/ST

PIC16F17526-I/ST

PIC16F17544-I/SS

PIC16F17545-I/SS

PIC16F17546-I/SS

AT25320B-XHL-B

AT24C32D-XHM-B

DSPIC33EP256MC204T-H/PT

DSPIC33EP256MC504T-H/PT

PIC24EP256GP204T-H/PT

PIC24EP256MC204T-H/PT

DSPIC33EP256MC206T-H/PT

DSPIC33EP256MC506T-H/PT

DSPIC33EP32GP504T-H/PT

PIC32MZ2048EFH100-E/PT

PIC32MZ2048EFM100-E/PT

PIC32MM0064GPM048-E/PT

PIC16LF1509T-I/ML

PIC16F1459T-I/ML020

USB5807CT-I/KDH01

USB5816CT-I/KDH02

PIC16F1508T-I/ML

DSPIC33CH256MP506-I/PTC02

DSPIC33CH512MP206-I/PTC03

DSPIC33EP64MC204-I/PT

DSPIC33EP64MC504-I/PT

PIC24EP64MC204-I/PT

PIC12F617T-I/MF

MCP73834T-FCI/MF

MCP79411T-I/MNY

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MX575F512L-80V/PTC22

PIC16F1823-I/STC06

PIC12LF1822-I/SN

PIC16LF1773-I/SS

PIC16F1773-I/SS

PIC16LF1776-I/SS

PIC12F1612-I/SN

PIC16F636-I/ST

PIC16F1776-I/SS

DSPIC33EP32GP502-I/SS

PIC16F720-I/ML

PIC12F1822-I/MF

PIC16F1946-I/MR

PIC16LF723A-I/MV

AR1021-I/ML

AR1011-I/ML

PIC16LF1507-I/ML

PIC16LF1823-I/ML

PIC18F26J13-I/ML

PIC18LF45K22-I/MV

DSPIC33EP128MC506-E/PTVAO

DSPIC33EP128MC504-E/PTVAO

DSPIC33EP128GP504-E/PTVAO

DSPIC33EP512GP506-E/PTVAO

PIC24EP256GP204-E/PTVAO

DSPIC33EP64MC506-E/PTVAO

DSPIC30F4011-20E/PTVAO

DSPIC33FJ128GP804-E/PTVAO

PIC16LF1768T-I/SS

PIC16LF1578T-I/SS

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16LF1579T-I/SS

PIC16F1826T-I/SS032

PIC24FJ128GL406-E/MR

PIC16F18877-E/MV

DSPIC33FJ64MC804-E/ML

MCP48FEB08-E/MQ

MCP48FEB04-E/MQ

MCP48FEB14-E/MQ

MCP48FEB24-E/MQ

MCP48FVB04-E/MQ

MCP48FVB14-E/MQ

DSPIC33FJ128MC204-E/ML

DSPIC33FJ128MC804-E/ML

ATMEGA644PV-10MUR

ATMEGA644P-20MUR

ATMEGA88PB-MUR

ATMEGA48PB-MUR

KSZ8051MNLU-TRVAO-BW

MCP25625T-E/MLVAO-GM

MCP4151-103E/MFVAO-BW

MCP4151T-104E/MFVAO-GM

MCP6002-E/MCVAO-BW

PIC16F1503T-E/MVVAO-VW

PIC24HJ256GP210T-I/PT

SPNZ801143

USB5744/2GX01

LAN7800/Y9X

LE88262TQC

USX5044/2G

KSZ9031RNXCC

Date: Tuesday, July 22, 2025

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USB2514B/M2

KSZ8081MNXCA

KSZ8091MNXCA

KSZ8091RNBCA

USB5742B/2G

USB5742B/2GX01

USB5744B/2GX01

UTC2000/MG

USB4715/Y9X

USB5744/2G

USB5744/2GD02

USB5744/2GTB

SPNZ801174

KSZ8041NL

SPNZ801059

PIC24EP128MC206-I/PT

PIC32CM1216MC00048-I/Y8X

PIC32CM6408MC00048-I/Y8X

PIC32CX1025MTC128-I/X9B

PIC32CX5112MTC128-I/X9B

PIC32CX5112MTG128-I/X9B

ATF1504ASVL-20AU100

DSPIC33CK256MP208-I/PTC05

AT32UC3C1128C-AUT

PIC32MX460F256LT-80I/PT

PIC32MZ2048EFH100T-250I/PT

PIC32MX440F128LT-80I/PT

DSPIC33EV32GM006T-I/PT

DSPIC33EP32GP504T-I/PT

DSPIC33EV128GM104T-I/PT

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PIC32MX350F128LT-I/PF

DSPIC33EP512GP506T-I/PT

PIC24EP512GP204T-I/PT

DSPIC33EV64GM004T-I/PT

DSPIC33EV64GM104T-I/PT

DSPIC33EV32GM004T-I/PT

ATMEGA164A-AUR

PIC32MZ1024ECG064T-I/PT

PIC32MZ2048ECG064T-I/PT

HA4583T-I/PT

25LC320AT-E/ST

PIC24F16KL402T-E/SS

25LC160DT-E/ST

25AA160DT-E/ST

MCP6042T-E/SN

PIC12F617T-E/SN033

PIC12F617T-E/SN071

PIC12F617T-E/SN031

PIC12F617T-E/SN034

PIC12F617T-E/SN036

PIC12F617T-E/SN067

PIC16LF876AT-I/SS

PIC16F73T-I/SSC15

PIC18F2580T-I/SO

MCP6022T-I/STAAA

PIC16LF819T-I/SSTSL054

PIC16F1509T-I/ML

USB5926CT-I/KD

PIC18F4458-I/ML

PIC24FJ128GC006-I/MR

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PIC24FJ64GC006-I/MR

24LC04B-I/MC

24AA04-I/MC

PIC12F1501-I/MF

PIC18F46K20-I/MV

PIC18F46K20-I/ML

PIC16F1827-I/MV

PIC16LF1782-I/MV

ATECC608B-MAHA6-S

PIC16F18876T-I/MVC02

ATECC108A-MAHDA-T

PIC32MX270F512HT-50I/PT

PIC32MX550F256HT-50I/PT

DSPIC33CK256MP710T-E/PT

DSPIC33CK1024MP408T-E/PT

DSPIC33CK1024MP708T-E/PT

DSPIC33CK512MP408T-E/PT

ATSAMD21G17A-AZT

ATSAMD21G18A-AZT

DSPIC33CK512MP708T-E/PT

DSPIC33CK256MP408T-E/PT

DSPIC33CK256MP708T-E/PT

DSPIC33CK1024MP405T-E/PT

DSPIC33CK1024MP705T-E/PT

DSPIC33CK512MP405T-E/PT

PIC16C58B-04/SO

MCP25625T-E/SS

PIC16F1847T-E/SS

MCP6284T-E/ST

PIC18F45K20-I/MLC01

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PIC18F45K20-I/MLC05

SY54011RMG

PIC16F15324-I/JQ

PIC16LF1823-I/MLC04

ENC28J60-I/ML

PIC16F18455-I/STX

MCP4251-502E/ST

MCP4251-103E/ST

PIC16F631-E/SS

34AA02-E/ST

MCP4261-104E/ST

MCP4261-503E/ST

MCP4241-502E/ST

MCP4241-103E/ST

MCP6032-E/SN

MCP6034-E/ST

MCP4231-502E/ST

PIC18F25K40-E/ML

PIC18LF24K40-E/ML

PIC18LF25K40-E/ML

PIC16LF18875-E/MV

PIC18LF47K40-E/ML

PIC12F617T-I/SN028

PIC12F617T-I/SN030

PIC12F617T-I/SN032

PIC16C621AT-04I/SO088

PIC12LF1571T-I/SN

PIC12LF1572T-I/SN

PIC16LF648AT-I/SS

PIC16F627AT-I/SS

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PIC16LF627AT-I/SS

PIC16F18325-I/JQ

PIC18LF25K83-I/ML

PIC18LF26K83-I/ML

PIC16LF18323-I/JQ

PIC16F18323-I/JQ

PIC16F18877-I/ML

PIC16HV616-I/ML

MCP2200-I/MQ

PIC10LF322-I/MC

PIC16F18344-I/GZ

ATSAMG55J19A-MU

PIC16LF18426-I/JQ

HV5522K7-G-S344

PIC16LF1559-I/GZ

PIC16F18426-I/JQ

PIC16F18324-I/JQ

PIC16F886-I/ML

PIC32MM0128GPM048-E/PT

PIC32MM0256GPM048-E/PT

PIC32MZ0512EFE100-E/PT

PIC32MZ0512EFF100-E/PT

PIC32MZ0512EFK100-E/PT

PIC24HJ128GP202T-E/SO

DSPIC33FJ64GP802T-E/SO

DSPIC33FJ128GP202T-E/SO

DSPIC33FJ128GP802T-E/SO

DSPIC33FJ32GP302T-E/SO

PIC24FV16KM202T-E/SS

DSPIC33FJ128MC802T-E/SO

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DSPIC33FJ64MC202T-E/SO

DSPIC33FJ64MC802T-E/SO

DSPIC33FJ128MC202T-E/SO

PIC18F25K83T-E/SS

24AA025E64T-E/SN

24AA025E48T-E/SN

24FC16T-E/ST

24FC08T-E/ST

PIC16F1824T-E/ST

PIC16F1713T-E/SO

PIC16F689T-E/SS

PIC16F690T-E/SS

24LC02BHT-E/ST

24FC04T-E/ST

PIC16F685T-E/SS

MCP6V99T-E/ST

PIC16F687T-E/SS

MCP6009T-E/ST

MCP6479T-E/ST

24LC01BT-E/ST

24LC04BHT-E/ST

24FC04HT-E/ST

24LC16BHT-E/SN

24FC01T-E/ST

24LC01BHT-E/ST

24LC08BHT-E/SN

24FC02T-E/ST

24AA16T-E/SN

PIC16LF1579T-I/GZ

PIC16F18344T-I/GZ

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PIC16LF18344T-I/GZ

ATSAMD21J15B-MMUT

ATSAML21J16B-MMUT

ATSAML21J17B-MMUT

ATSAML21J18B-MMUT

PIC16LF1516T-I/MV

MCP6232-E/SN

PIC16F505-E/ST

MTCH1030-E/ST

PIC16F1508-E/SS

PIC16F677-E/SS

PIC16F1509-E/SS

PIC16F1936-E/SO

PIC18F04Q40-E/ST

PIC18F05Q40-E/ST

PIC18F04Q41-E/ST

PIC18F05Q41-E/ST

24LC16BT-E/ST

PIC12F629T-E/SN252

PIC12F629T-E/SN

PIC16F616T-E/ST

PIC12F629T-E/SN246

DSPIC33EP16GS202T-E/SS

PIC16F15323T-E/ST022

PIC16F15323T-E/ST025

DSPIC33EP32GS202T-E/SS

DSPIC33CK512MP705T-E/PT

DSPIC33CK256MP405T-E/PT

DSPIC33CK256MP705T-E/PT

DSPIC33EP32GS504T-E/PTC01

Date: Tuesday, July 22, 2025

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PIC18F4580-E/ML

PIC16F15274-E/MP

DSPIC33EP64GS502-E/MM

DSPIC33EP32GS502-E/MM

DSPIC33EP16GS502-E/MM

DSPIC33CK256MP305-E/M7

DSPIC33CK256MP605-E/M7

DSPIC33CK512MP305-E/M7

DSPIC33FJ32GS606T-50I/PT

24LC512T-E/ST14

MCP6569T-E/ST

MCP4352T-502E/ST

MCP4352T-103E/ST

MCP6022T-E/SN

MCP4921T-E/SN

MCP4352T-104E/ST

MCP3426A0T-E/SN

24C01CT-E/SN

PIC16F72T-E/SS

MCP3426A3T-E/SN

34AA02T-E/ST

MCP6052T-E/SN

MCP6062T-E/SN

PIC12F1501T-E/SN032

PIC12F1501T-E/SN033

PIC12F1501T-E/SN034

PIC12F1501T-E/SN035

PIC12F1501T-E/SN047

PIC12F1501T-E/SN048

PIC12F1501T-E/SN

Date: Tuesday, July 22, 2025

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PIC12F675T-E/SN073

PIC16LF1906-I/MV

PIC18F23K20-I/ML

PIC10F322-I/MC

PIC12F629-E/SN

DSPIC33EP16GS202-E/SS

PIC16F1713-E/SS

PIC16F1716-E/SS

PIC18F26Q10-E/SS

DSPIC33EP32GS202-E/SS

PIC16F1828-E/SS

24LC01B-E/SN

PIC16F1825T-E/MLVAO

PIC16F1938T-E/MLVAO

MCP19111T-E/MQVAO

PIC18F25K20T-E/MLVAO

PIC18F24K20T-E/MLVAO

PIC16LF1554T-E/MLVAO

PIC16LF1828T-E/MLVAO

DSPIC33FJ64GP202T-E/MMVAO

PIC16F1824T-E/MLVAO

PIC16F1783T-E/MLVAO

PIC18F26K22T-E/MLVAO

PIC18LF26K22T-E/MLVAO

DSPIC33FJ64GP802T-I/SO

PIC16F18456T-I/STX

PIC16F1503T-I/MG027

PIC16F1503T-I/MG028

SY89112UMY-TR

PIC18LF25K22T-I/ML

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PIC16F1713T-I/ML

PIC18LF2331-I/MM

AGL250V5-VQG100I

A3P125-2VQ100I

A3P125-2VQG100I

M1AGL250V2-VQ100I

DSPIC33EP128GM304-I/PT

DSPIC33EP128GM604-I/PT

DSPIC33EP256GM304-I/PT

DSPIC33EP256GM604-I/PT

PIC32MM0064GPM064-I/PT

PIC32MM0128GPM064-I/PT

PIC32MM0256GPM064-I/PT

M1AGL250V2-VQG100I

M1AGL250V5-VQ100I

M1AGL250V5-VQG100I

DSPIC33EP512GM304-I/PT

DSPIC33EP512GM604-I/PT

A3P125-VQ100I

A3P125-VQG100IPT72

DSPIC30F6011A-30I/PT

DSPIC33FJ32GP202-I/SO

PIC16F687-I/SS

AR1010-I/SS

24LC08B-I/ST

24FC08-I/ST

24FC16-I/ST

24LC16BH-I/ST

24LC08BH-I/ST

24AA08H-I/ST

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24AA16-I/ST

24AA16H-I/ST

PIC16LF1704-I/ST

HA4923-I/ST

PIC16LF1503-I/ST

PIC24FJ128GL302-I/SO

PIC16F689-I/SS

ATECC608A-MAH2M-S

ATECC508A-MAHGF-S

ATECC508A-MAHHL-S

ATECC508A-MAHHL-T

ATECC608A-MAH2U-T

ATECC608A-MAH2V-S

ATECC608A-MAH2X-S

ATECC608A-MAH2Y-S

ATECC608A-MAH3J-T

ATSAMC21E17A-MUT510

ATSAMC20G15A-MUT

ATSAMC20G16A-MUT

ATSAMC21G15A-MUT

PIC32MK1024MCM064-E/PT

PIC16LF1527-E/PT

PIC16LF1526-E/PT

DSPIC33EP64GS506-E/PTC01

DSPIC33EP64GS506-E/PT

ATSAMD21E17L-AF

AT28HC64BF-12JU-T

AT28BV64B-20JU-T

AT27C010-70JU-T

AT27BV256-70JU-T

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AT27BV010-90JU-T

AT28HC64B-90JU-T

AT28HC64B-12JU-T

AT28C64B-15JU-235

AT28C64B-15JU-T

AT28HC64B-70JU-T

AT27LV010A-70JU-T

AT27LV020A-12JU-T

AT27C256R-45JU-T

AT27C256R-70JU-T

ATSAMC21G16A-MUT

ATSAMC21G17A-MUT

PIC16F1613T-I/ML023

ATSHA204A-MAHDA-T

ATSHA204A-MAHDA-S

PIC16F17174-I/MP

PIC16F18174-I/MP

PIC16F17175-I/MP

PIC16F18175-I/MP

PIC16F17154-I/STX

PIC16F18154-I/STX

PIC16F17155-I/STX

PIC16F18155-I/STX

DSPIC30F1010-30I/MM

DSPIC30F2020-30I/MM

PIC16F1939-I/MV

PIC18F26Q10-I/ML

PIC24FJ256GA702-I/ML

MCP47FEB12A2-E/ST

MCP47FEB12A3-E/ST

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

11LC160-E/SN

11LC020-E/SN

11LC161-E/SN

PIC16LF18856-I/MV

PIC18F45K80-I/ML

AT28C010-12JU-T

AT28C010-15JU-T

AT28LV010-20JU-T

AT27C1024-45JU-T

AT27C1024-70JU-T

AT28C256F-15JU-T

AT28HC256-70JU-T

AT28HC256-90JU-T

AT27C010-45JU-T

PIC32MK1024MCM100-E/PT

PIC32MK0512MCM100-E/PT

PIC32MK1024GPK100-E/PT

PIC32MK0512MCM064-E/PT

PIC32MK1024GPK064-E/PT

PIC32MK0512GPK064-E/PT

PIC18F66K40-E/PT

PIC24FJ64GB004-I/ML

PIC24FJ32GB004-I/ML

PIC24FJ32GA102-I/ML

PIC24FJ64GA104-I/ML

PIC18F25K22-I/ML

PIC24F16KA302-I/ML

PIC24F32KA302-I/ML

PIC16F1939-I/ML

PIC24FV32KA302-I/ML

Date: Tuesday, July 22, 2025

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PIC18F2423-E/ML

PIC16F18155-E/STX

PIC16F15213-E/MF

PIC18F57Q43-E/6LX

PIC16F15214-E/MF

DSPIC33CK128MC505-E/M7

DSPIC33CK256MC105-E/M7

DSPIC33CK128MC105-E/M7

PIC18F56Q43-E/6LX

DSPIC33CK128MC506-E/MR

DSPIC33CK256MC106-E/MR

DSPIC33CK128MC106-E/MR

PIC16F1826-E/ML

PIC16F1826-E/MV

PIC16F1786-E/ML

PIC24EP128MC206-E/MR

DSPIC33EP128MC206-E/MR

DSPIC33EP128MC506-E/MR

DSPIC33EP128GP504-E/ML

DSPIC33EP128MC204-E/ML

DSPIC33EP128MC504-E/ML

PIC24EP128MC204-E/ML

PIC18LF25K22-E/ML

PIC16LF1508-E/ML

PIC18LF24K22-E/ML

PIC16LF1509-E/ML

PIC18F2523-E/ML

PIC16F1614-E/ML

ATSAMD20J16B-MZ

ATSAMD20J15B-MZ

Date: Tuesday, July 22, 2025

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PIC16LF1614-E/ML

PIC16LF1936-E/ML

PIC18F24K22-E/ML

PIC16F1829-E/ML

MCP19115-E/MQ

PIC18F27Q10-E/ML

PIC16F876A-E/ML

PIC18F47Q10-E/MP

PIC18F27Q10-E/STX

PIC16F877A-E/ML

PIC18F24Q10-E/ML

PIC18F25Q10-E/ML

PIC18F24Q10-E/STX

DSPIC33EP256GP502-E/MM

DSPIC33EP256MC502-E/MM

PIC24EP256GP202-E/MM

PIC18F25Q10-E/STX

PIC32MZ0512EFE064-E/MRA21

PIC16F688-E/ML

ATSAMD21E16B-MZ

ATSAMD21E15B-MZ

DSPIC33EP64MC206-E/MR

DSPIC33EP64MC506-E/MR

PIC24EP64MC206-E/MR

PIC16LF1937-E/ML

DSPIC33EP64MC202-E/MM

DSPIC33EP64MC502-E/MM

AVR128DB64T-E/PT

AVR64DB64T-E/PT

PIC32CM2532JH00032T-E/PT

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PIC32CM2532JH01032T-E/PT

PIC16F15375T-E/PT

ATSAMC21E18A-AZT-SL3

AVR16EB32T-E/PT

PIC18F26J53-I/ML

PIC18F27J13-I/ML

PIC18F27J53-I/ML

PIC16LF1904-I/MV

PIC12HV615-I/MF

PIC12HV615-I/MD

ATSAMC21N18A-AZTVAO

PIC16F18855T-E/MVVAO

MCP3912A1T-E/MQVAO

DSPIC33EP32GS502T-E/MMVAO

PIC16LF1824T-E/JQVAO

PIC16F1784T-E/MVVAO

PIC16F1519T-E/MVVAO

PIC16F18326T-E/JQVAO

ATA6663-FAQW-1

MCP2542FDT-E/MFVAO

PIC16F1779T-E/NHXVAO

PLA133-97QA-RVAO

MCP25625T-E/MLVAO

ATSAMC20G17A-AUT

DSPIC33CK64MP102-E/SS

PIC32MX250F128D-50I/ML

PIC32MZ1024EFG064-I/MR

PIC32MK0512MCJ064-I/R4X

PIC32MK0512GPG064-I/R4X

PIC32MZ1024EFH064-I/MR

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PIC32MZ1024EFK064-I/MR

PIC32MZ1024EFM064-I/MR

PIC24EP32GP204-I/ML

PIC16LF1518T-I/ML

ATSAMD21G16B-MUT

ATSAMD21G15B-MUT

ATSAMD21G16L-MUT

ATSAML22G16A-MUT

ATSAML22G17A-MUT

DSPIC33CK256MP208T-I/PTC05

AT8UA084CDB-5LRU

ATSAML22N16A-AUT

ATSAML22N17A-AUT

ATSAML22N18A-AUT

PIC18F57Q43T-I/PTC01

PIC24EP256GP206T-I/PT

ATSAMD20G16A-MUA2

PIC18LF27K40-I/ML

PIC32MX270F512H-50I/MR021

ATSAMD20G17A-MUA2

MCP79410-I/MNY

DSPIC33EP32MC202-I/MM

ATSAMD21E16B-MU-SLL

PIC18LF47K40-I/MV

ATMEGA168PA-MU

24C01C-I/MC

PIC16F19196-I/MR

PIC16F19197-I/MR

PIC16LF19195-I/MR

PIC16LF19196-I/MR

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PIC16LF19197-I/MR

PIC18F47Q84-I/NHX

PIC18F26K80-E/MMVAO

PIC16F1788-E/MLVAO

PIC16F18325-E/7NVAO

PIC16F18854-E/MLVAO

DSPIC33EV128GM102-E/MMVAO

DSPIC33EV64GM002-E/MMVAO

DSPIC33EV32GM002-E/MMVAO

PIC16LF15323-E/7NVAO

MCP23S17-E/MLVAO

PIC18F26K83-E/5NVAO

TC1301A-AHAVMF

PIC16F1824-E/ML

MCP629-E/ML

PIC16F723A-E/ML

MCP3426A1-E/MC

ATTINY424-XU

ATTINY824-XU

PIC32MX695F512L-80I/PT023

PIC24HJ64GP510A-I/PT

PIC24HJ64GP210A-I/PT

PIC32MX695F512L-80I/PT020

DSPIC33AK256MPS205-I/PT

DSPIC33AK512MC505-I/PT

PIC18F8680-I/PTGVAO

DSPIC33EP256MC504-I/PTVAO

PIC16C925-I/PTVAO

DSPIC33EP64GP504-I/PTVAO

DSPIC33EP64GP506-I/PTVAO

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PIC24EP128GP206-I/PTVAO

PIC24HJ128GP510A-I/PTVAO

PIC24FJ64GB004-I/PTVAO

DSPIC33FJ128GP804-I/PTVAO

PIC18F452-I/PTVAO

PIC18F6585-I/PTVAO

PIC24FV32KA304-I/PT

PIC24FV16KA304-I/PT

PIC24F32KA304-I/PT

PIC24F16KA304-I/PT

PIC18F47J53-I/PT

PIC18F4680-I/PT

PIC18LF4680-I/PT

PIC18F46J53-I/PT

PIC24FJ128GA010-I/PT

PIC18F4585-I/PT

PIC18LF4585-I/PT

PIC24FJ192GA110-I/PT

PIC24FJ256GA110-I/PT

PIC32MK0256MCJ064-I/PT

PIC32MX150F256L-I/PT

PIC24EP64MC206T-E/PT

DSPIC33CH512MP508T-E/PT

DSPIC33CH512MP208T-E/PT

DSPIC33CH256MP208T-E/PTC04

DSPIC33CH512MP208T-E/PTC05

ATMEGA165PV-8AU

ATMEGA16-16AU

AT42QT2640-AU

AT42QT1481-AU

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ATMEGA88A-AU

ATMEGA329PA-AU

ATMEGA325A-AU

ATMEGA325PA-AU

ATMEGA162-16AU

ATMEGA644-20AU

AT89LP6440-20AU

AT89LP3240-20AU

ATXMEGA128C3-AU

ATXMEGA128D3-AUA1

ATXMEGA128D3-AU

DSPIC33CH256MP508T-E/PT

DSPIC33CH256MP208T-E/PT

PIC18F14K22T-E/ML

MCP16501TD-E/RMB

MCP16501TE-E/RMB

PIC18F26K40T-E/ML

PIC16F687T-E/ML

PIC18F25K40T-E/ML

PIC16F1769T-E/ML

PIC16F1768T-E/ML

PIC16F785T-E/ML

PIC16HV785T-E/ML

MCP2200T-E/MQ046

MCP14A0901T-E/MNY

MCP14A0902T-E/MNY

MCP14A1201T-E/MNY

MCP14A1202T-E/MNY

AVR16EA32-I/RXB

AVR128DB32-I/RXB

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PIC16LF1503-I/ARC

LAN9252I/ML

LAN9353I/ML

PIC16LF1936-I/ML

WP300TX01-I/ML02C00

PIC16F636-I/ML

PIC16LF1827-I/ML

PIC16LF1827-I/MV

ATSAMC21G17A-MU

PIC16LF1454-I/JQ

PIC16LF1455-I/JQ

ATSAMD21G18A-MU-SLL

ATSAMD21E17A-MU-MB

PIC32CM2532LE00064-I/5LX

PIC32CM2532LS00064-I/5LX

PIC32CM2532LE00048-I/U5B

25C320-E/SN

PIC16LF1828-E/SS

25LC128-E/ST

PIC16F628A-E/SS

25LC160B-E/SN

25LC080A-E/SN

PIC12LF1552-E/SN

PIC12F683-E/SN084

PIC12F683-E/SN

ATSAM3N00AA-MU

DSPIC33CK512MP708-E/PT

DSPIC33CK256MP408-E/PT

DSPIC33CK256MP708-E/PT

ATSAMD21E18A-AZ

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ATSAMD21E17A-AZ

ATSAMD21G17A-AZ

ATSAMD21G18A-AZ

DSPIC33EP64GS504-E/PTB3

DSPIC33EP64GS504-E/PTC13

DSPIC33EP64GS504-E/PT

DSPIC33EP32GS504-E/PT

DSPIC33EP16GS504-E/PT

DSPIC33CK1024MP405-E/PT

DSPIC33CK512MP405-E/PT

DSPIC33CK512MP705-E/PT

DSPIC33CK256MP405-E/PT

DSPIC33CK256MP705-E/PT

PIC18LF45K42-E/PT

PIC16F1503T-I/MV

PIC18F46Q71T-I/MP

DSPIC33AK128MC106T-I/M7

DSPIC33AK64MC106T-I/M7

DSPIC33AK32MC106T-I/M7

PIC16F18076T-I/MP

PIC16F18056T-I/STX

PIC18F54Q71T-I/6LX

PIC16F1939T-I/MPC03

AVR32EA28T-I/STX

PIC16LF1847T-I/ML

PIC16LF1847T-I/MV

PIC16F1508T-I/GZ

PIC16F1509T-I/GZ

25CS320T-I/Q4B

PIC16C716-04I/SS

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PIC16C716-20I/SS

PIC16F19176T-E/PT

25LC128-E/SN

MCP2200-E/SS

25LC256-E/ST

25LC256-E/SN

PIC16F648A-E/SS

93LC66C-E/SN

PIC12F1840T-E/RF

EMC1412-A-AC3-TR

25LC320AT-E/MNY

93LC46CT-E/MNY

PIC24F32KA302T-E/ML

PIC24FJ256GA106T-E/MR

DSPIC33EP64GS504T-E/ML

DSPIC33EP32GS504T-E/ML

PIC24FJ128GB610-E/PT

PIC24FJ256GA606-E/PT

PIC24FJ512GA606-E/PT

PIC24FJ1024GB606-E/PT

PIC24FJ128GB606-E/PT

PIC24FJ256GB606-E/PT

PIC24FJ128GA610-E/PT

PIC16F1946-E/PTVAO

DSPIC33EP256MC504-E/PTVAO

DSPIC33EV128GM106-E/PTVAO

DSPIC33EV64GM106-E/PTVAO

DSPIC33EV32GM106-E/PTVAO

DSPIC33EV64GM104-E/PTVAO

DSPIC33EV32GM004-E/PTVAO

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DSPIC33EV128GM104-E/PTVAO

DSPIC33EV64GM004-E/PTVAO

PIC18F66K40-E/PTVAO

DSPIC33EP128GS806-E/PTVAO

DSPIC33EV256GM106-E/PTVAO

LAN8650B1T-E/LMXVAO

ATSAMC21N17A-AZTVAO

ATSAMC21N18A-AZTVAO-GM

AVR64DA48T-E/PTL10

AVR128DA48T-E/PTL10

PIC16F15375T-E/PTVAO

PIC16F884T-E/PTVAO

DSPIC33CK256MC506T-E/PTVAO

DSPIC33CK128MC506T-E/PTVAO

DSPIC30F5011T-20E/PTVAO

PIC24FJ256GA704T-E/PTVAO

PIC18F47Q84T-E/PTVAO

93AA66C-I/SN

93LC66A-I/SN

93AA66A-I/SN

93LC66B-I/SN

93LC66B-I/SN15K

93AA66B-I/SN

93LC56A-I/SN

93LC56B-I/SN

93LC56C-I/SN

PIC16LF18323-I/ST025

PIC16LF18323-I/ST024

PIC16F1788-I/SSC01

PIC16F1827-I/SOC06

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PIC16F1826-I/SSC03

PIC18F26K22-I/SS025

25LC256-I/SNRVB

PIC16LF18323-I/STC02

MCP7940N-I/SN

MCP7940M-I/SN

PIC16LF1509-I/SSC01

MCP2210-I/SS

MCP2200-I/SSRVB

MCP2200-I/SS040

PIC12F1501-I/SN

PIC12F1501-I/SNH3A

PIC16LF1783-I/SSC01

MCP79400-I/SN

AVR16EB14T-I/ST

AVR16EB20T-I/SS

AVR16EB28T-I/SS

PIC18F25Q43T-I/SS

PIC18F25Q43T-I/SO

PIC18F24K22T-I/SS

PIC18F24K22T-I/SO

PIC16LF1713T-I/SS

PIC18F23K22T-I/SS

PIC18F23K22T-I/SO

PIC16F13123T-I/ST

PIC16F13124T-I/ST

PIC16F13125T-I/ST

PIC16F13143T-I/SS

PIC16F13144T-I/SS

PIC16F13145T-I/SS

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24LC02BT-I/STA31

24CS512T-I/ST

AVR64EA28T-I/SS

PIC16LF15324T-I/ST020

PIC16LF15324T-I/ST

PIC16F15344T-I/SS

PIC16LF15344T-I/SS

MCP602T-I/STAAA

PIC18F26Q83T-I/SS

PIC18F26Q84T-I/SS

DSPIC33AK512MPS208-I/PT

PIC18F26Q43-I/SO

PIC16F882-I/SO

MTCH1060-I/SS

AVR64DD28-I/SS

PIC16LC716-04I/SS

PIC16C56A-04I/SS

PIC18LF1320-I/SS

PIC16LF628-04I/SS

PIC16C715-04I/SS

PIC16C715-20I/SS

PIC16F628-04I/SS

PIC16F628-20I/SS

MCP2140-I/SS

MCP23016-I/SO

PIC16LC771-I/SS

PIC16LF819-I/SS

PIC16C712-20I/SS

PIC16C622A-20I/SS

PIC16LC622A-04I/SS

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PIC16F88-I/SS

PIC16F87-I/SS

PIC16LC58B-04I/SO

PIC16C58B-04I/SO

PIC16C770-I/SS

PIC16LC770-I/SS

PIC16C711-20I/SS

PIC16C711-04I/SS

PIC16LC711-04I/SS

PIC16F819-I/SS

PIC16LF818-I/SS

PIC16F84A-04I/SS

PIC16F84A-20I/SS

PIC16LF84A-04I/SS

PIC16C622A-04I/SS

MCP2140-I/SSRVB

PIC16LC620A-04I/SS

PIC16LF628A-I/SO

PIC16C58B-04I/SS

PIC16C57C-04I/SOC05

ENC28J60-I/SO

MCP2155-I/SSRVC

PIC16LF88-I/SS

PIC16LF87-I/SS

PIC16F18455-E/STX

PIC16F18456-E/STX

PIC16LF18455-E/STX

PIC16LF18456-E/STX

PIC16F18856-E/ML

DSPIC33CK256MC505-E/M7

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33CK256MC506-E/MR

PIC18F46Q43-E/MP

ATSAMD21E18A-MZ

ATSAMD21E17A-MZ

PIC16LF1765-E/ML

PIC16LF1764-E/ML

ATSAMC21E18A-MZ

PIC12F529T39AT-I/ST

24AA32AT-I/ST

24AA32AFT-I/ST

24LC512T-I/ST

24LC32AFT-I/ST

PIC16F1936T-I/SS

HA1839T-I/SS

93AA46BT-I/ST

PIC16F1847T-I/SO

PIC16F570T-I/SS

PIC24F04KL101T-I/SS

AVR64DA64T-I/PT

AVR64DA48T-I/PT

PIC24HJ256GP206T-I/PT

PIC32MX350F256HT-I/PT024

DSPIC33AK512MPS508T-I/PT

DSPIC33AK256MPS508T-I/PT

DSPIC33AK512MPS208T-I/PT

DSPIC33AK256MPS208T-I/PT

DSPIC33AK512MPS512T-I/PT

DSPIC33AK512MC508T-I/PT

DSPIC33AK256MC508T-I/PT

DSPIC33AK512MC208T-I/PT

Date: Tuesday, July 22, 2025

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DSPIC33AK256MC208T-I/PT

AVR16EA32T-I/PT

PIC18F46K22T-I/PT

PIC18F46K22T-I/PT020

PIC18F46K22T-I/PT022

DSPIC33AK256MPS512T-I/PT

25LC010A-I/ST

25AA010A-I/ST

25LC020A-I/ST

25AA020A-I/ST

AR1100-I/SS

ATXMEGA64D3-AURA7

DSPIC33FJ128MC510T-I/PTC22

PIC24HJ64GP510AT-I/PF

PIC24HJ128GP510AT-I/PF

DSPIC33FJ128MC710AT-I/PF

PIC24FJ64GA010T-I/PF

PIC32MX460F512LT-80I/PT026

PIC18F26K20T-I/ML052

PIC18F26K20T-I/ML053

PIC32MK1024GPK064T-I/MR

PIC32MK0512GPK064T-I/MR

PIC24F08KA101T-I/MQ

PIC24F08KA101T-I/MQC02

PIC18F26K20T-I/ML055

PIC18F26K20T-I/ML056

PIC18F26K20T-I/ML057

PIC18F65K40T-I/MR

PIC18F25K20T-I/ML

PIC16LF1579-E/GZ

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PIC16F753-I/ST

PIC16HV753-I/ST

AVR32DD28-I/SS

PIC16F17126-I/ST

LX34070AT-H/ST

ATTINY1616-XNR

MTCH2120T-V/SS

PIC16C62BT-04/SO047

HCS300T/SN

HCS301T/SN

PIC16F873T-04/SO

PIC32MZ1024EFF100T-I/PF

ATMEGA48A-AUR

ATMEGA48PA-AUR

PIC32MZ1024EFG100T-I/PF

PIC32MZ1024EFH100T-I/PF

PIC32MZ1024EFK100T-I/PF

PIC32MZ1024EFM100T-I/PF

PIC32MX170F256DT-50I/PT

PIC32MX270F256DT-50I/PT

DSPIC33FJ64GS608T-50I/PT

PIC24FJ1024GA606T-I/PT

PIC24FJ128GA606T-I/PT

PIC24FJ256GA606T-I/PT

PIC24FJ512GA606T-I/PT

PIC32MX695F512LT-80I/PTD22

PIC24FJ1024GB606T-I/PT

PIC32MX230F256DT-50I/PT

PIC32MX230F256DT-I/PT

PIC24FJ128GB606T-I/PT

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PIC24FJ256GB606T-I/PT

PIC24FJ512GB606T-I/PT

PIC24FJ1024GA610T-I/PT

ATECC508A-MAH3A-S

ATECC508A-MAH3A-T

ATECC508A-MAH3B-S

ATSAM3N1AB-MUR

ATSAM3N0AA-MUR

ATSAM3S4AA-MUR

ATSAM3S2AA-MUR

DSPIC33CH256MP508T-I/PT

DSPIC33CH256MP208T-I/PT

DSPIC33EP64MC204T-I/PT

DSPIC33EP64MC504T-I/PT

PIC24EP64MC204T-I/PT

PIC32CM5164JH01064T-E/PTVAO

PIC24EP128GP204-E/PTVAO

DSPIC33EP64MC504-E/PTVAO

AT89C51RD2T-RLTUMA0

PIC16F15274-I/PT

AT89C51AC3T-RLTUM

AT89C51CC03UAT-RLTUM

AT89C51CC03CAT-RLTUM

ZL30291BLDF1

AVR32DA32ST-I/QZB

AVR64DA64ST-I/5LX

AVR64DA32ST-I/QZB

AVR32DA48ST-I/6MX

AVR128DB64T-I/MRC01

PIC18F26Q10T-I/ML022

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LAX8710AT-I/S8X

PIC16F15223T-I/MG027

DSPIC33FJ128GP206-I/PT

PIC32MZ2048ECM100-I/PF

PIC32MX530F128L-50I/PT

PIC32MX170F512H-50I/PT

AVR64DD32T-E/RXB

AVR64DD28T-E/STX

MTCH1030T-E/MG

TC1301B-GDDVMFTR

TC1301B-GFDVMFTR

TC1301B-GGDVMFTR

TC1302B-GDVMFTR

TC1301A-AAAVMFTR

TC1301A-APAVMFTR

PIC16F876AT-E/ML

TC1301B-FAAVMFTR

DSPIC33CH256MP205-E/PT

DSPIC33CH512MP205-E/PT

DSPIC33CH256MP505-E/PT

PIC24HJ256GP210A-E/PF

93AA46BT-I/MC

PIC12F1501T-I/MC

PIC18LF45K22T-I/MV

PIC12F519T-I/MC034

24LC16BHT-I/MNY

24AA16T-I/MC16KVAO

93LC56CT-I/MC15KVAO

PIC24FJ128GU405T-I/PT

PIC24FJ256GU405T-I/PT

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PIC24FJ512GU405T-I/PT

TC7109AILW

TC14433ELI

TC14433AELI

TC14433AELI713

TC14433ELI713

PIC16LC923-04/L

PIC16C662-04/L

PIC16LC924-04/L

PIC16C64A-20/L

PIC16LC64A-04/L

PIC16C65A-04/L

PIC16C65A-10/L

PIC16C65A-20/L

PIC16F1716-E/ML

PIC16F1718-E/MV

PIC16LF1719-E/MV

PIC16LF1717-E/MV

PIC16F1516-E/MV

PIC16F1518-E/MV

ATECC608B-MAHCZ-S

ATECC608B-MAHDA-S

ATECC608B-MAHA5-S

MT8816AP1

MT8808AP1

MT8806AP1

ATF1504AS-10JU44

ATF1504ASVL-20JU44

ATF1504ASL-25JU44

ATF1500A-10JU

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ATF1504ASV-15JU44

AT28C010-15JU

AT28C010E-15JU

AT28C010-12JU

AT28LV010-20JU

HV5122PJ-G

AT27C1024-45JU

AT27C1024-70JU

AT27C4096-90JU

AT28HC256-70JU

AT28HC256-90JU

AT28HC256-12JU

AT28HC256E-70JU

AT28HC256E-90JU

AT28C256F-15JU

AT28HC256E-12JU

MCP3426A2T-E/MC

MCP3426A5T-E/MC

MCP3426A1T-E/MC

MCP622T-E/MF

MCP4262T-503E/MF

MCP4252T-502E/MF

MCP4252T-103E/MF

MCP4252T-104E/MF

MCP9843T-BE/MNY

MCP9843T-BE/MC

MCP4552T-103E/MF

MCP4552T-104E/MF

MCP4552T-503E/MF

MCP4562T-503E/MF

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PIC18LF2480-I/ML

PIC18F47J53-I/ML

PIC16LF1946-I/MR

34AA02T-I/MNYB21

PIC18LF4525-I/ML

PIC12F1571-I/RF

PIC12F1572-I/RF

PIC16F1704-I/ML

PIC16F1575-I/JQ

PIC16LF723A-I/ML

DSPIC33EV256GM004-I/ML

DSPIC33EV256GM104-I/ML

PIC16F1937-I/ML

MCP4562T-503QE/MF

MCP4562T-104QE/MF

93LC76CT-E/MNY

93C46BT-E/MNY

93LC46AT-E/MNY

93LC86CT-E/MNY

PIC12F1501T-E/MF

PIC12F615T-E/MF

93C86CT-E/MNY

93C76CT-E/MNY

25AA640AT-E/MNY

93LC46BT-E/MNY

93C46AT-E/MNY

PIC18F23K22T-E/ML

24LC02BT-E/MNY

24LC02BT-E/MC

PIC16F1823T-E/ML

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24LC32AT-E/MNY

24LC32AT-E/MC

MCP19111T-E/MQ

24LC04BHT-E/MNY

PIC16LF1554T-E/MLM10

PIC32MX795F512LT-80I/PT

PIC32MX530F128LT-50I/PF

PIC24HJ256GP610AT-I/PT

PIC32MX270F512LT-50I/PF

PIC32MX775F512LT-80I/PT

PIC32MX775F256LT-80I/PT

PIC32MX330F064LT-I/PT

PIC32MX430F064LT-I/PT

DSPIC33FJ256GP710AT-I/PT

DSPIC33FJ256MC510AT-I/PT

PIC32MX130F064DT-I/PT

TC1302A-HPVMF

PIC12LF1571-E/RF

PIC12LF1572-E/RF

MCP3912A1-E/MQ

MCP3919A1-E/MQ

PIC16F1719-E/ML

PIC16F1782-E/MV

PIC16LF1718-E/ML

PIC16LF1719-E/ML

PIC16LF1717-E/ML

PIC16F1708-E/ML

PIC16F1579-E/GZ

PIC16F1574-E/JQ

PIC16F1783-E/ML

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PIC18F4620-E/ML

PIC16F1782-E/ML

DSPIC33EV256GM104-E/ML

PIC16LF1578-E/GZ

PIC16F1578-E/GZ

PIC12F1571-E/RF

AT27C010-70JU

AT27BV256-70JU

AT27LV256A-90JU

AT28HC64B-12JU

AT28HC64BF-12JU

PIC32CM1602GV00032T-E/RTBVAO

DSPIC33CK512MP605T-E/M7VAO

PIC16F15223T-E/MGV AO

34AA02T-E/MNY16KVAO

PIC32CM3204JH00032T-E/RTBVAO

PIC32CM6408JH00032T-E/RTBVAO

DSPIC33CK256MP705T-E/M7VAO

DSPIC33FJ64GP804-E/MLVAO

DSPIC33EP32GP502-E/MMVAO

DSPIC30F4011-20E/MLVAO

DSPIC33EP128GP502-E/MMVAO

DSPIC33EP256GP502-E/MMVAO

PIC16F1936-E/MLVAO

PIC16LF1829-E/MLVAO

PIC16F1825-E/MLVAO

PIC16F1938-E/MLVAO

PIC18F25K22-E/MLVAO

PIC16LF1554-E/MLVAO

PIC16F1828-E/MLVAO

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PIC16F1824-E/MLVAO

PIC16F1823-E/MLVAO

PIC16F1704-E/MLVAO

PIC16LF1559T-I/MLVAO

PIC24F16KA102T-I/MLVAO

PIC16LF1938T-I/MLVAO

DSPIC30F2010T-20I/MMVAO

MCP2210T-I/MQVAO

PIC16F1518T-I/MLVAO

PIC16F1847T-I/MLVAO

PIC16LF18445-E/SS

PIC16F18446-E/SS

PIC16F688-E/ST

DSPIC33EV32GM102-E/SS

PIC32MM0016GPL028-E/SS

PIC32MM0032GPL028-E/SS

PIC32MM0064GPL028-E/SS

PIC16LF18344-E/SS

PIC16F1578-E/SS

PIC16F1579-E/SS

MCP4341-503E/ML

MCP4441-502E/ML

MCP4441-103E/ML

MCP4901-E/MC

MCP4821-E/MC

MCP4911-E/MC

MCP4351-502E/ML

MCP4351-103E/ML

MCP4351-104E/ML

MCP4351-503E/ML

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DSPIC33CK512MP605-E/M7

PIC16F15275-E/MP

DSPIC33EP16GS502-E/MMC03

24LC08B-E/MC

PIC16F15276-E/MP

PIC18F24K40-E/ML

PIC18F46K40-E/ML

PIC18LF45K40-E/ML

PIC18LF46K40-E/ML

ATMEGA3208-MF

PIC18F46K40-E/MV

PIC18LF45K40-E/MV

PIC18LF46K40-E/MV

PIC18F25K42-E/ML

PIC18LF24K42-E/ML

PIC18LF25K42-E/ML

PIC18F25K42-E/MV

PIC18LF24K42-E/MV

PIC18LF25K42-E/MV

PIC18LF26K40-E/MV

PIC18F45K40-E/ML

PIC18F45K40-E/MV

PIC18LF26K40-E/ML

DSPIC33EP64GS402-E/MMC02

PIC18F46Q83-E/NHX

PIC18F46Q84-E/NHX

PIC18F47K40-E/MV

PIC16LF1503-E/MV

PIC18F47K40-E/ML

25AA128T-I/SNRVA

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PIC18F26K20T-I/SS

HA1127T-I/SS

PIC18F25K20T-I/SS

PIC18F25K20T-I/SSC01

TC1302A-IAVMF

TC1302A-IPVMF

TC1302B-GPVMF

TC1301B-HOEVMF

MCP4461-104E/ML

24AA128-E/ST

24FC128-E/ST

PIC16LF18326-E/ST

PIC16F18346-E/SS

PIC16LF18346-E/SS

AVR128DA28-E/SO

PIC16F17144-E/SS

PIC16F18144-E/SS

PIC16F17145-E/SS

PIC16F18145-E/SS

PIC16F18345-E/SS020

PIC16F18345-E/SS021

MCP8021T-5015H/9PXVAO

MCP8022T-3315H/NHXVAO

MCP8022T-5015H/NHXVAO

PIC18F66J10T-I/PTC01

PIC24FV16KM204T-I/PT

PIC18F85J50T-I/PT

PIC24FV32KA304T-I/PT

PIC18F86K90T-I/PT

PIC18F86K90T-I/PTRSL

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PIC18F4410T-I/PT

PIC24FJ64GC006T-I/PT

DSPIC33EP256GM310T-I/PT

DSPIC33EP512GM310T-I/PT

93C86AT-I/ST

93C86BT-I/ST

ATSAMD21E15L-MNT

PIC32MX450F128HT-V/MR

ATSAMD21E17L-MNT

ATA8515-GHQW

ATA8215-GHQW

ATSAMD21E16L-MNTB7

ATECC608B-MAVDA-T

ATECC608B-MAVDA-S

RE46C422V32T

ATTINY261A-MNR

ATA8210-GHQW

ATA8510-GHQW

ATSAMC21E18A-MNTDY

LE87402MQCT

LE87511NQCT

LE87502MQCT

ATTINY1617-MNR

ATA8535-GHQW

PIC16LF1938T-I/SS022

PIC16LF1938T-I/SS029

PIC16F753T-I/ST

PIC16F18124T-I/ST

PIC16F19155T-I/SS

PIC16LF1824T-I/ST

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MTCH1060T-I/SS

PIC16F1829T-I/SS040

PIC16F15324T-I/ST021

PIC16F15324T-I/ST

PIC16F1829T-I/SS

PIC16LF1829T-I/SSC03

PIC16F1619T-I/SS

PIC16LF1619T-I/SS

LE79R79-1DJCT

LE79R79-2DJCT

LE79R79-3DJCT

LE58QL031DJCT

LE58QL021FJCT

LE58QL02FJCT

PIC16F18456T-I/SS

PIC16LF18455T-I/SS

PIC16LF18456T-I/SS

PIC18F27K40T-I/SS

PIC18F24K42T-I/SS

PIC18F25K42T-I/SS

PIC18LF24K42T-I/SS

PIC18LF25K42T-I/SS

PIC18F26K40T-I/SSC03

PIC18F26K40T-I/SS

PIC32MZ2048ECM100T-I/PT

PIC32MX230F064DT-I/PT

PIC32MX440F256HT-80I/PT

PIC32MX440F512HT-80I/PT

PIC32MX440F128HT-80I/PT

DSPIC30F3011T-30I/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATSAMD20G15A-AUT

DSPIC33FJ128GP306T-I/PT

DSPIC33FJ128GP706T-I/PT

25AA160AT-I/SN

93LC66AT-I/SN

93AA66AT-I/SN

93LC66BT-I/SN

25LC080BT-I/SN

25AA080BT-I/SN

93LC66BT-I/SN15K

93AA66BT-I/SN

93C46CT-I/SN

ATSAMC21E17A-MZ

PIC18F45K22-E/ML

ATSAMC21E16A-MZ

ATSAMC21E15A-MZ

ATSAMC20E18A-MZ

ATSAMC20E17A-MZ

PIC18F44K22-E/ML

PIC18F56Q83-E/6MX

PIC18F56Q84-E/6MX

PIC12LF1840-E/MF

DSPIC33EV32GM002T-E/SSVAO

PIC16F1614T-E/STVAO

PIC18F25K20T-I/SSC15

DSPIC33EP32MC202T-I/SS

PIC18F25K20T-I/SSC17

PIC18F24K20T-I/SS

PIC18F24K20T-I/SSC01

PIC16F1938T-I/SO

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC18F16Q40T-I/SS

24LC22AT-I/SN

ATSAMC21E18A-OAZ

ATSAMC21J18A-AZ-SL3

ATSAMC21E18A-AZ-SL3

PIC16C77-20/L

PIC18F45K20-E/PT

PIC18F44K20-E/PT

DSPIC30F3011-20E/PT

DSPIC33CK64MP105-E/PT

DSPIC33CK32MP105-E/PT

PIC18F57Q43-E/PT

DSPIC33CK256MP505-E/PT

DSPIC33EP32MC504-E/PT

ATMEGA809-AF

ATMEGA1609-AF

PIC32MX130F064DT-50I/PT

PIC32MX550F256LT-50I/PF

PIC32MX570F512LT-50I/PF

PIC32MX570F512LT-I/PT

DSPIC33FJ256MC710AT-I/PT

ATTINY1607-MNR

ATTINY807-MNR

AT90PWM81OS-B16MNR

ATMEGA324PA-MNR

RE370V28T

SHA104-TFLXAUTHU

SHA105-TFLXAUTHU

ECC204-TFLXAUTHU-CZ

PIC16F1947-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16F1939-E/PT

PIC24F32KA304-E/PT

PIC18F8622-E/PT

PIC18F4680-E/PT

PIC24FJ256GA110-E/PT

PIC24FJ128GA110-E/PT

PIC16F724-E/PT

PIC24FV32KA304-E/PT

PIC18F4585-E/PT

PIC18F46K22-E/PT

PIC18F45K22-E/PT

PIC18F43K22-E/PT

PIC24F16KM204-E/PT

PIC16F1784-E/PT

PIC16C73A-20/SO

PIC16C63A-04/SO

PIC16C63A-20/SO

PIC14000-04/SO

PIC14000-20/SO

TC7660SCOA

TC7662BCOA

PIC16C57C-04/SS

PIC16C55A-04/SO

PIC16C55A-20/SO

PIC16C55A-20/SS

PIC16C62A-04/SS

PIC16C66-04/SO

PIC16C66-10/SO

PIC16C66-20/SO

PIC16C73B-04/SO

Date: Tuesday, July 22, 2025

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PIC16C73B-20/SO

PIC16LC73B-04/SO

PIC16C63-04/SO

PIC16F1618T-I/ML

PIC16LF1618T-I/ML

PIC16F1769T-I/ML

PIC16F1768T-I/ML

PIC16LF1769T-I/ML

SY89842UMG-TR

DSPIC33AK512MPS212T-I/PT

DSPIC33AK256MPS212T-I/PT

PIC16F726-I/MV

PIC18LF4680-I/ML

PIC18F45J50-I/ML

PIC18F44K20-I/ML

PIC16LF1783-I/ML

PIC16LF1783-I/MV

PIC18F46J53-I/ML

PIC16LF1513-I/MV

PIC16LF1512-I/MV

PIC16F721-I/ML

PIC18F2431-I/MM

PIC18LF24K22-I/MV

PIC10F320-I/MC

PIC18F4585-I/ML

PIC16F1847-I/ML

PIC16LF1933-I/MV

PIC16LF1947-I/MR

PIC16F616T-E/ML

PIC16LF1705T-E/ML

Date: Tuesday, July 22, 2025

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MCP2050T-330E/MQ

MCP2050T-500E/MQ

ATA6561-GBQW-N

A3PN060-VQ100

A3PN060-VQG100

A3PN125-1VQ100

A3PN125-1VQG100

A3PN125-2VQ100

A3PN125-2VQG100

A3PN125-VQ100

A3PN060-2VQ100I

A3PN060-2VQG100I

A3PN060-VQ100I

A3PN060-VQG100I

A3PN125-2VQG100I

A3PN125-VQ100I

A3PN125-VQG100I

A3PN125-VQG100IQ153

A3PN125-VQG100IQ157

AGLN060V2-VQG100

AGLN060V2-VQ100

PIC32CM2532LS00048-I/U5B

PIC18F66K22-E/PT

PIC18F4525-E/PT

ATSAMC21G18A-AZ-SL3

PIC32AK1216GC41048-E/PT

PIC32AK6416GC41048-E/PT

PIC32AK3208GC41048-E/PT

PIC32AK1216GC41064-E/PT

PIC32AK6416GC41064-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32AK3208GC41064-E/PT

ATSAME54N20A-AZ-SL3

AVR32DA48S-E/PT

AVR64DA32S-E/PT

AVR64DA48S-E/PT

AVR64DA64S-E/PT

AVR32DA32S-E/PT

ATSAMC21J17A-OAZ

ATSAMC21G17A-OAZ

ATSAMC21E17A-OAZ

PIC32CM2532JH00064-E/PTS2

PIC32CM2532JH00048-E/Y8XS2

PIC32CM1216JH01048-E/Y8XS2

DSPIC33CK128MP205-E/PTC07

A3P250-1VQ100M

A3P250-1VQG100M

A3P250-VQ100M

A3P250-VQG100M

A3P250-VQ100MX3

A3P250-VQ100MX45

DSPIC33EP128GS808-ETM/PT-HP_ASSY

PIC16C765-I/PT

PIC16LC65B-04I/PQ

PIC17LC44-08I/PT

PIC17C44-16I/PQ

PIC16F877-04I/PQ

PIC16F877-20I/PQ

ATSAMC21G18A-AZ510

AT24C32E-XHM-B

AT24C64D-XHM-B

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AGL125V5-VQG100I

DSPIC33CK32MP105-I/PT

AVR32DA32-I/PT

DSPIC33EP32MC504-I/PT

PIC16F15274-I/PT020

ATMEGA1609-AU

AGL125V2-VQ100I

AGL125V2-VQG100I

AGL125V5-VQ100I

PIC24EP32GP204-I/PT

PIC32MK1024MCF100-I/PTA21

KSZ8041TLI

PIC18F87K90-I/PT

PIC18F87K22-I/PT

PIC18F87K90-I/PTRSL

PIC18F87K22-I/PTRSL

PIC18F87K90-I/PT035

PIC18F87K90-I/PT038

DSPIC33CK256MP505-I/PT

PIC18F87K90-I/PT025

PIC18F87K90-I/PT026

PIC18F87K90-I/PT031

PIC18F87K90-I/PT039

PIC32MX695F512L-80I/PT021

PIC18F45K20-I/PT

PIC24FJ16GA004-I/PT

PIC24FJ48GA004-I/PT

DSPIC33FJ64GP706A-I/PT

DSPIC33FJ64GP306A-I/PT

DSPIC33FJ64GP206A-I/PT

Date: Tuesday, July 22, 2025

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PIC24HJ128GP306A-I/PT

PIC24FJ128GA106-I/PT026

DSPIC33FJ128GP706A-I/PT

PIC16F1765T-E/STVAO

PIC16F1764T-E/STVAO

MCP251863T-E/SSVAO

PIC16F18425T-E/STVAO

PIC16F18424T-E/STVAO

PIC16F18426T-E/STVAO

AVR128DA28T-E/SSVAO

SY58013UMG

SY58016LMG

SY58017UMG

SY58018UMG

SY88022ALMG

PIC12LF1840T-E/SN

PIC12LF1501T-E/SN

PIC12F615T-E/SN

93LC86CT-E/SN

93LC76CT-E/SN

DSPIC30F2010T-30I/MM

PIC32MX534F064HT-I/MR

PIC32MX130F064DT-I/ML

DSPIC33FJ128GP804T-I/ML

PIC18F26Q84-I/SO

DSPIC30F4012-20I/SO

DSPIC30F4012-30I/SO

PIC16F15225-I/ST

DSPIC30F1010-30I/SO

DSPIC30F2020-30I/SO

Date: Tuesday, July 22, 2025

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DSPIC33AK32MC102-I/SS

DSPIC33CK128MP508T-I/PT

DSPIC33CK64MP208T-I/PT

DSPIC33CK256MP508T-I/PT

DSPIC33CK128MP208T-I/PT

PIC32MZ0512EFF100T-I/PT

DSPIC33EP128GM710-E/PF

DSPIC33EP256GM310-E/PF

DSPIC33EP512GM310-E/PF

DSPIC33EP512GM710-E/PF

PIC18F4620-E/PT

DSPIC33EP512MU810-E/PF

PIC16F1519-E/PT

MCP6482T-E/SN

DSPIC33CK128MC502T-I/SS

DSPIC33CK256MC102T-I/SS

DSPIC33AK256MPS208-I/PT

DSPIC33AK512MC508-I/PT

PIC24HJ256GP206-I/PT

DSPIC33AK256MC508-I/PT

DSPIC33AK512MC208-I/PT

DSPIC33AK256MC208-I/PT

PIC32CM1216JH01048-I/Y8X

PIC32CM1216JH01032-I/PT

DSPIC33AK256MPS512-I/PT

DSPIC33AK512MPS212-I/PT

DSPIC33AK256MPS212-I/PT

AVR16EA32-I/PT

PIC18F46K22-I/PT

DSPIC33AK512MPS512-I/PT

Date: Tuesday, July 22, 2025

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AVR128DA48-I/PT

PIC24HJ64GP504-I/PT

DSPIC33FJ64GP204-I/PT

DSPIC33FJ64MC804-I/PT

PIC16LF1777-I/PT

PIC16LF1779-I/PT

PIC16LF18875-I/PT

PIC16LF1789-I/PT

DSPIC33EP16GS504T-E/ML

93C46CT-E/MNY

93C66CT-E/MNY

93C66BT-E/MNY

93LC66BT-E/MNY

93LC56CT-E/MNY

93LC56AT-E/MNY

93LC56CT-E/MC

93LC56BT-E/MNY

ATMXT1296M1T-ARVA2

DSPIC33EP64GP504T-I/PTVAO

DSPIC33EP256MU810T-I/PTVAO

PIC24EP128GP206T-I/PTVAO

DSPIC33FJ128GP804T-I/PTVAO

PIC16F1947T-I/PTVAO

PIC16F1946T-I/PTVAO

PIC16F1517T-I/PTVAO

PIC16LF1937T-I/PTVAO

PIC16LF1934T-I/PTVAO

PIC16F1937T-I/PTVAO

PIC16F1518T-I/SS

PIC12F1822T-I/SN039

Date: Tuesday, July 22, 2025

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24VL014HT/SN

24VL024HT/SN

24LCS52T/SN

24VL024T/SN

24VL025T/SN

24VL014T/SN

24C00T/SN

24LC00T/SN

24AA00T/SN

PIC16LC642T-04/SO

24LC16BT/ST

24LC01BT/ST

93LC46BT/SN

93LC46T/SN

93AA46T/SN

93LC56T/SN

93LC66T/SN

93AA56T/SN

93AA66T/SN

HCS301T/SN022

25LC040T/SN

25C040T/SN

25LC320T/SN

25C320T/SN

24LC21AT/SN

PIC12F1822T-I/SN049

PIC16LF1559T-I/SS

PIC16LF1829T-I/SS

PIC16LF1829T-I/SSC01

PIC16F1827T-I/SS

Date: Tuesday, July 22, 2025

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HA2022T-I/SS

PIC16F1827T-I/SS026

PIC16F1826T-I/SS

HA2525T-I/SS

11LC040-E/SN

PIC16F883-E/SS

MCP47FEB01A3-E/ST

PIC16F570-E/SS

MCP47FVB22A1-E/ST

MCP47FVB22A2-E/ST

MCP47FVB12A0-E/ST

MCP47FVB12A1-E/ST

11LC010-E/SN

MCP47FVB02A0-E/ST

PIC16F15256-I/SSC01

AVR128DB28-I/SO

MCP79411-I/SN

MCP79412-I/SN

AVR64DB28-I/SO

AVR32DB28-I/SO

PIC16F17146-I/SS

PIC16F18146-I/SS

MCP79401-I/SN

MCP79402-I/SN

PIC24FJ256GA702-I/SS

PIC24FJ128GA702-I/SS

PIC24FJ64GA702-I/SS

DSPIC33EP32GS504T-I/MLC09

DSPIC33EP32GS202T-I/MM

ATSAMC21E18A-MUTDY

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PIC32MX150F256HT-I/MRN21

DSPIC33EP32GS402T-I/MMC01

DSPIC33EP64GS402T-I/MMC02

ATMEGA808-MUR

PIC24FJ64GU202T-I/ML

ATSAMD20G14A-MUTA2

PIC12LF1612-I/SN

24LC08BH-E/ST

24LC02BH-E/SN

PIC16F684-E/ST

24FC16-E/ST

24FC08-E/ST

HA4986-E/ST

PIC16F18326-E/ST

MCP41HV51-502E/ST

MCP41HV51-103E/ST

MCP41HV51-503E/ST

MCP41HV51-104E/ST

ATTINY424-XF

ATTINY824-XF

DSPIC30F3013-20E/SO

PIC16F18044-E/SS

PIC16F18045-E/SS

PIC32MX695F512H-80I/PT

ATSAMG55J19B-MUC21

PD69210R-034400

PIC16F18854-I/ML

DSPIC33FJ32GS606T-I/PTD23

DSPIC33FJ64GS406T-I/PT

DSPIC33FJ64GS606T-I/PT

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PIC18F86J90T-I/PT

DSPIC33FJ32GS406T-I/PT

DSPIC33FJ32GS606T-I/PT

DSPIC33CK32MP506T-I/PT

DSPIC33CK64MP508T-I/PT

DSPIC33CK128MP506T-I/PT

DSPIC33CK64MP206T-I/PT

PIC24HJ128GP504T-I/PT

MCP607T-I/ST

MCP609T-I/ST

MCP6544T-I/ST

MCP602T-I/ST

MCP42100T-I/ST

MCP42010T-I/ST

MCP6549T-I/ST

MCP6543T-I/SN

MCP6542T-I/SN

HCS300T-I/SN

MCP6022T-I/SN

HCS301T-I/SN

PIC16F876AT-I/SO

TC622COA713

PIC16LF876T-04/SO

PIC16LF1613-E/MLVAO

DSPIC33EV256GM002-E/MMVAO

DSPIC33EV256GM102-E/MMVAO

MCP19114-E/MQVAO

PIC18F46K42-E/MVVAO

PIC16F18326-E/JQVAO

PIC16F1509-E/MLVAO

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PIC16F1509-E/GZVAO

ATSAMD21E15B-MZVAO

PIC16LF1503-E/MVVAO

ATSAMD21E18A-MZVAO

ATSAMC21E15A-MZ510

PIC12LF1840T48AT-I/ST026

PIC16F18346-I/GZC01

PIC16F18346-I/GZ

PIC16LF18346-I/GZ

PIC16LF18326-I/JQ

AVR64EA32-I/RXB

DSPIC33AK128MC102-I/M7

DSPIC33AK64MC102-I/M7

DSPIC33AK32MC102-I/M7

DSPIC33FJ256GP710T-I/PF

DSPIC33FJ256MC710T-I/PF

ATSAML11E14A-AU

ATSAML11E15A-AU

ATSAML11E16A-AU

ATSAML10E16A-AU

DSPIC33EP512MU810-I/PFC04

ATF1504ASL-25AU44

ATF1504AS-10AU44

ATF1502ASV-15AU44

ATSAML10E14A-AU

ATSAML10E15A-AU

PIC16F917-I/PT

MEC1428-I/NU-C1

MPL360B-I/Y8X

PIC16F1517-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC24FJ32GA004-E/PT

DSPIC33EP256MU810-E/PF

PIC16F884-E/PT

PIC24FJ16GA004-E/PT

DSPIC33FJ128MC708A-E/PT

PIC24HJ64GP206A-E/PT

DSPIC33FJ64GP708A-E/PT

DSPIC33FJ64GP206A-E/PT

ATSAMD20G17A-AUTA3

ATSAMD20G16A-AUTA2

ATSAMD20G18A-AUTA2

ATSAMD20G17A-AUTA2

ATSAMD20G15A-AUTA2

PIC32MM0256GPM048T-I/PT027

PIC32MM0256GPM048T-I/PT029

PIC32MZ0512EFE100T-I/PT

PIC32MZ2048EFM100T-I/PTBR2

TC7129CKW713

PIC32MX450F256LT-120/PT

PIC18F1220-I/SS

25LC320A-I/ST

PIC18F65K90-I/PTRSL

PIC24FJ64GA310-I/PT

PIC24FJ128GA310-I/PT

PIC18F67K90-I/PTRSL

PIC18F67K22-I/PTRSL

SY89834UMG

SY84782UMG

SY89874AUMG

SY89874UMG

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CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

MCP4241T-104E/ST

MCP4241T-503E/ST

25LC010AT-E/ST

PIC18F26K40T-E/SS

PIC24F08KA101T-E/SS

MCP6V19T-E/ST

PIC18F24K42T-E/SS

PIC18F14K22T-E/SS

25AA256T-E/SN

25AA256T-E/ST

MCP6V39T-E/ST

23K256T-E/ST

23K640T-E/ST

PIC18F25K80T-E/SS

ATMEGA808-XFR

PIC18F26K80T-E/SS

ATMEGA1608-XFR

PIC16LF18324T-E/ST

MCP6V69T-E/ST

24AA044T-E/SN

ATMEGA3208-XFR

DSPIC33FJ16GS502T-E/SO

PIC18LF23K22T-E/SS022

34AA04T-E/SN

PIC16F15356T-E/SS

DSPIC33FJ16MC101T-E/SS

PIC24FJ16MC101T-E/SS

DSPIC33FJ12GP202T-E/SO

DSPIC33EP128MC206-E/PT

PIC16F19195-E/PT

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DSPIC33EDV64MC205T-H/M7VAO

PIC16F1508T-H/MLVAO

MCP4441T-103H/6NVAO

MCP4441T-103H/MLVAO

PIC16F17156T-I/SS

PIC16F18156T-I/SS

PIC18F06Q20T-I/ST

PIC18F16Q20T-I/SS

PIC16LF15323T-I/ST

PIC32MK0128MCA028T-I/N2X

AVR32EA28T-I/SS

93AA46AE48T-I/SN

PIC16LF1936T-I/SO

PIC16F18424T-I/ST

PIC16F18425T-I/ST

PIC16LF18424T-I/ST

PIC16LF18425T-I/ST

PIC18F26Q71T-I/SS

PIC18F26Q71T-I/SO

PIC16F18426T-I/ST

PIC16LF18426T-I/ST

PIC18F24Q71T-I/SS

DSPIC33CH512MP506-E/PT

DSPIC33CH512MP206-E/PT

ATMEGA649P-AUR

ATMEGA128L-8AURA5

ATMEGA324P-20AUR

ATMEGA324P-20AURA0

ATXMEGA64A4U-AUR

ATMEGA88V-10AUR

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ATMEGA88-20AUR

ATMEGA3290P-20AUR

ATMEGA3250P-20AUR

ATMEGA640-16AURA0

ATXMEGA192A3-AUR

ATXMEGA64A3U-AUR

ATXMEGA192D3-AUR

ATXMEGA256D3-AUR

ATXMEGA256C3-AUR

ATXMEGA192D3-AURA1

ATMEGA1280-16AUR

ATMEGA1280V-8AUR

ATMEGA165P-16AUR

DSPIC33CH256MP506-E/PT

DSPIC33CH256MP206-E/PT

ATMEGA3208-AF

ATMEGA3209-AF

ATSAMD21J17A-AF

PIC32CM2532JH00100-E/PF

PIC32CM5164JH00100-E/PF

PIC32CM2532JH01100-E/PF

ATSAMD21J18A-AF

ATSAMD21G17A-AF

ATSAMD21G18A-AF

PIC18F86K22-E/PT

PIC18F44K22-E/PT

DSPIC33FJ128GP710A-E/PT

DSPIC33FJ128GP708A-E/PT

PIC24EP256GP204-H/ML

PIC24EP256MC204-H/ML

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DSPIC33EP32MC202-H/MM
DSPIC33EP128GP506-H/MR
DSPIC33EV128GM106-H/MR
DSPIC33AK64MC105-H/M7
DSPIC33AK32MC105-H/M7
DSPIC33AK128MC105-H/M7
DSPIC33AK32MC102-H/M7
DSPIC33AK32MC103-H/M7
DSPIC33AK128MC102-H/M7
DSPIC33AK64MC102-H/M7
DSPIC33AK128MC103-H/M7
DSPIC33AK64MC103-H/M7
DSPIC33AK32MC106-H/M7
DSPIC33AK128MC106-H/M7
PIC32MX270F256B-50I/SS
DSPIC33FJ12MC201-I/SS
PIC18F4331-I/PT
PIC17C752-33I/PT
PIC24HJ128GP510A-I/PT
DSPIC33FJ64GP310A-I/PT
DSPIC33FJ64GP710A-I/PT
DSPIC33FJ64MC706A-I/PT
DSPIC33FJ128GP310A-I/PT
DSPIC33FJ128GP710A-I/PT
DSPIC33FJ64MC510A-I/PT
PIC16LF1527-I/PT
PIC18F4515-I/PT
MEC1322I-NU-C0
PIC16LF1526-I/PT
PIC24FJ128GA106-I/PT038

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PIC18F44K20-I/PT

PIC16LF1904-I/PT

PIC16LF1907-I/PT

PIC16LF1567-I/PT

HA4012-I/PT

PIC18LF4610-I/PT

PIC24HJ128GP504-I/PTC26

PIC16LF1937-I/PT

PIC32MX575F512L-80I/PT024

PIC16F1934-I/PT

PIC16F1517-I/PT

PIC16LF1719-I/PT

PIC16LF1717-I/PT

PIC18F4610-I/PT

PIC18LF4515-I/PT

PIC16F1719-I/PT

PIC16F1717-I/PT

PIC16F1519-I/PT

DSPIC33EP128GM306-I/PT

PIC24FJ32GA104-I/PT

DSPIC33EP128GM706-I/PT

DSPIC33EP256GM306-I/PT

DSPIC33EP256GM706-I/PT

DSPIC33EP512GM306-I/PT

DSPIC33EP512GM706-I/PT

PIC24FJ64GB004-I/PT

PIC24FJ32GB004-I/PT

PIC24FJ64GA104-I/PT

PIC32MX575F512L-80I/PT025

PIC18F87J50-I/PT025

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PIC18LF6410-I/PT

PIC18LF6310-I/PT

PIC24FJ128GA705-I/PT

PIC24FJ64GA705-I/PT

PIC24FJ256GA705-I/PT

PIC18F66K90-I/PTRSL

PIC18F66K22-I/PTRSL

PIC18F65K22-I/PTRSL

PIC18LF6490-I/PT

PIC18LF8490-I/PT

PIC18LF8410-I/PT

PIC18LF6390-I/PT

PIC18LF8390-I/PT

PIC18LF8310-I/PT

PIC16F59-I/PT

MTCH6301-I/PT

MTCH6303-I/PT

HA6580-I/PT

PIC18F66K22-I/PT

PIC18F65K22-I/PT

PIC24FJ128GA310-I/PTC04

PIC24FJ64GA308-I/PT

PIC24FJ128GA308-I/PT

PIC18F67K90-I/PT

PIC18F67K22-I/PT

PIC18F67K90-I/PTC05

ATECC508A-MAHKN-S

ATECC508A-MAH1A-T

ATECC508A-MAH1A-S

PIC16LF1554T-I/MLM10

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ATECC608A-MAH4K-T

PIC16LF1559T-I/MLM10

PIC16F1937T-I/MP

MCP45HV51T-503E/MQ

MCP45HV51T-104E/MQ

MCP6002T-E/MC

PIC18F47Q83-E/PT

PIC18F47Q84-E/PT

DSPIC30F5011-20E/PT

DSPIC30F5013-20E/PT

PIC32CM2532JH01048-E/Y8X

ATSAMD21E17A-AF

ATSAMD21E18A-AF

PIC32CM5164JH01100-E/PF

PIC18F46Q83-E/PT

PIC18F46Q84-E/PT

PIC32CM2532JH00064-E/PT

PIC32CM5164JH00064-E/PT

PIC32CM2532JH01064-E/PT

PIC32MX470F512LT-I/PT022

PIC32MX564F128HT-I/PT

PIC32MX534F064HT-I/PT

PIC32MX564F064HT-I/PT

PIC32MX664F128HT-I/PT

PIC16LF1947T-I/PT

DSPIC33CH512MP505T-I/PT

DSPIC33CH512MP205T-I/PT

ATMEGA324PB-AU

ATMEGA32L-8AUA3

PIC16LF19176-E/MV

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PIC16LF721-E/ML

PIC16F15355-E/ML

PIC16LF15354-E/ML

PIC16LF15355-E/ML

PIC16F19156-E/MV

PIC16LF19155-E/MV

PIC16LF19156-E/MV

PIC16F15355-E/MV

PIC16LF15354-E/MV

DSPIC33CK256MC105T-E/PT

ATSAMD21E17D-AZT

ATSAMD21E16L-AFT

PIC16F18875-I/MV

PIC16F1508-I/ML

PIC16F1509-I/ML

PIC16LF1936-I/MV

ATMEGA4808-XU

24AA01H-I/ST

24AA02H-I/ST

PIC18LF26K40-I/SS

24FC02-I/ST

24LC01B-I/ST

24FC01-I/ST

24LC01BH-I/ST

24FC04-I/ST

24LC04BH-I/ST

24FC04H-I/ST

24LC02BH-I/ST

11LC010T-E/MNY

11LC020T-E/MNY

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11LC040T-E/MNY

PIC16F1824T-E/ML

PIC18F46K22T-E/MV028

PIC18F46K22T-E/MV029

PIC18F46K22T-E/MV030

PIC12F1840-E/MF

PIC12LF1571-E/MF

PIC12LF1572-E/MF

PIC16F1709-E/ML

MCP2544WFD-E/MF

MCP2544FD-E/MF

MCP2542WFD-E/MF

PIC24FJ16GA002-E/ML

PIC16F1705-E/ML

PIC16LF18313-E/RF

MCP19125-E/MQ

PIC18F26K22-E/ML

MCP8025-115E/MP

PIC16LF1939-E/MV

PIC16F1939-E/MV

PIC24FJ32GA002-E/ML

DSPIC33AK64MC106-H/M7

DSPIC33EDV64MC205-H/M7

AK2157T-M/NCA

PIC32MX450F256H-120/MR

USB2512B/M2

USB2513B/M2

MCP73871-2CC/ML

USB2422/MJ

USX2064/M2

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PIC32MX470F512H-120/MR

KSZ8081RNACA

PIC32MX250F256L-V/PF

PIC32MX150F256H-V/PT

ATA5294-GJQW-VAO

AVR64DA32T-E/RXBVAO

PIC18F46Q43T-E/MPVAO

ATA663201-GBQW

PIC16F18426T-E/JQVAO

ATSAML11E16A-MZTVAO

ATSAML10E16A-MZTVAO

PIC16F1579T-E/GZVAO

93LC56CT-I/SN

93LC56AT-I/SN

93LC86BT-I/SN

PIC12F617T-I/SN059

25AA256T-I/ST

25AA256T-I/SN

PIC16F648AT-I/SS

93LC56BT-I/SN

93AA86AT-I/SN

93LC86AT-I/SN

93LC66CT-I/SN

93AA66CT-I/SN

PIC16F18055-I/SO

AVR64DD28-I/SO

PIC16LF15356-I/SS

25LC320AX-I/ST

25AA320AX-I/ST

PIC16F19156-I/SS

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PIC16LF19155-I/SS

PIC16LF19156-I/SS

MIC68200-2.5YML-TR

PIC32MK0128MCA048T-E/6MX

PIC16F15325T-E/JQ

MIC68200-3.3YML-TR

MIC68200YML-TR

PIC32MK0128MCA032T-E/RTB

PIC24HJ256GP206A-I/PT

DSPIC33FJ32GP204-I/PT

DSPIC33FJ16MC304-I/PT

DSPIC33FJ64GP710-I/PF

DSPIC33FJ128GP310-I/PF

PIC24HJ128GP506-I/PT

PIC32MX130F128L-50I/PF

PIC32MX230F128L-I/PF

PIC24HJ256GP210A-I/PT

PIC32MX530F128L-I/PF

PIC24HJ64GP506-I/PT

PIC24HJ128GP206-I/PT

PIC32MX530F128L-50I/PF

PIC32MX230F128L-50I/PF

DSPIC33FJ16GS504-50I/PT

AVR128DB32T-E/RXB

TC1301A-SGBVMFTR

TC1301A-DFAVMFTR

TC1302A-DTVMFTR

TC1302B-FSVMFTR

TC1302B-FTVMFTR

TC1301A-PHEVMFTR

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TC1301A-SFAVMFTR

MCP4131-103E/MF

MCP4152-503E/MF

MCP4161-502E/MF

MCP9805-BE/MC

MCP4161-103E/MF

MCP4151-503E/MF

MCP4151-502E/MF

PIC24FJ128GA610-I/PT

PIC24FJ256GA610-I/PT

PIC24FJ512GA610-I/PT

PIC24FJ1024GB610-I/PT

PIC24FJ128GB610-I/PT

PIC24FJ256GB610-I/PT

PIC24FJ512GB610-I/PT

PIC24FJ128GA704-I/PT

PIC24FJ64GA704-I/PT

PIC16LF18425T-I/JQVAO

AVR32DA32T-I/RXBVAO

PIC12LF1822T-I/MFVAO

PIC12LF1840T-I/MFVAO

PIC12F1572T-I/MFVAO

ATA5702F1000M-WDQW-VA1

ATA5700F1000M-WDQW-VA1

ATSAMHA1G16A-MBT-BVAO

PIC12F615T-I/MFVAO

PIC18F25Q10T-I/MLVAO

ATSAMHA1G15A-MBT-BVAO

ATSAMHA1G14A-MBT-BVAO

PIC16F1518T-I/MVVAO

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PIC16LF1516T-I/MVVAO

PIC16LF1518T-I/MVVAO

PIC16F15344T-I/MLVAO

PIC16LF15344T-I/MLVAO

ATSAMHA1G16A-MBT-B510

ATTINY1627-MURVAO

PIC16F18456T-I/STXVAO

DSPIC33FJ64GP804T-E/MLVAO

DSPIC33EP32GP502T-E/MMVAO

DSPIC33EP128MC202T-E/MMVAO

DSPIC33EP64MC204T-E/MLVAO

PIC18F25K22T-E/MLVAO

DSPIC33AK512MPS206T-I/PT

DSPIC33AK256MPS206T-I/PT

DSPIC33AK512MC506T-I/PT

DSPIC33AK256MC506T-I/PT

DSPIC33AK256MPS505T-I/PT

DSPIC33AK512MPS205T-I/PT

DSPIC33AK256MPS205T-I/PT

DSPIC33AK512MC505T-I/PT

DSPIC33AK256MC505T-I/PT

PIC32CM1216JH01032T-I/PT

DSPIC33AK512MC206T-I/PT

DSPIC33AK256MC206T-I/PT

DSPIC33AK512MC205T-I/PT

DSPIC33AK256MC205T-I/PT

PIC32CM1216JH01048T-I/Y8X

PIC18F46Q71T-I/PT

PIC18F44Q71T-I/PT

PIC18F45Q71T-I/PT

Date: Tuesday, July 22, 2025

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PIC32MX170F256DT-I/PT

PIC32MX270F256DT-I/PT

ATSAM4LC4AA-AUR

ATSAM4LS4AA-AUR

ATSAM4LC2AA-AUR

ATSAM4LS2AA-AUR

DSPIC33AK512MPS510T-I/PT

DSPIC33AK256MPS510T-I/PT

DSPIC33AK512MPS210T-I/PT

DSPIC33AK256MPS210T-I/PT

DSPIC33AK512MC510T-I/PT

DSPIC33AK256MC510T-I/PT

ATSAMD51N20A-AUTN01

25AA080BT-I/SNB21

PIC16LF1827T-I/SS

PIC16LF1828T-I/SS

PIC12F1822T-I/SN052

MCP2200T-I/SS

PIC32MZ0512EFF100T-E/PF

PIC32MZ0512EFK100T-E/PF

PIC32MZ1024EFE100T-E/PF

DSPIC33FJ256MC710AT-E/PT

DSPIC30F6012AT-20E/PT

DSPIC33EV32GM104T-E/PT

PIC24FJ256GA704T-E/PTC02

PIC24HJ128GP204T-E/PT

PIC24HJ128GP504T-E/PT

DSPIC33FJ128MC204T-E/PT

DSPIC33FJ32MC304T-E/PT

PIC24HJ64GP204T-E/PT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC30F4011T-20E/PTA22

DSPIC33EP64MC206-I/PT

DSPIC33EP64MC506-I/PT

PIC24EP64MC206-I/PT

PIC24FJ128GU406-I/PT

PIC24FJ256GU406-I/PT

PIC24FJ512GU406-I/PT

PIC16F17174-I/PT

PIC16F18174-I/PT

PIC16F17175-I/PT

PIC16F18175-I/PT

AVR64DD32-I/PT

DSPIC33CK256MP205-I/PTC05

PIC24FJ128GL406-I/PT

PIC24FJ256GL406-I/PT

PIC18F23K22T-I/ML

11LC010T-I/MNY

PIC24HJ256GP610A-E/PF

DSPIC33FJ256GP510A-E/PF

PIC16F1516T-I/ML

PIC16F1518T-I/ML

PIC16F18856T-I/STX

PIC16LF18856T-I/STX

PIC16F18455T-I/STX

PIC18LF2480T-I/ML

PIC12F615T-I/MD029

PIC18LF2321T-I/ML

PIC16LF1934T-I/ML

PIC10LF320T-I/MC

PIC18F46J50T-I/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC12F1822T-I/MF

PIC12F615T-I/MF

PIC18F43K20T-I/ML

PIC16F1947T-I/MR

PIC18F46J11T-I/ML

PIC18F44K20T-I/ML

PIC16LF1783T-I/ML

PIC16LF1933T-I/ML

PIC18LF24K22T-I/MV

PIC10F320T-I/MC

PIC16F1847T-I/ML

PIC18F45K20T-I/ML

PIC16F722T-I/ML

PIC18F45K20T-I/MLC01

PIC16F1938-E/ML

PIC16LF1938-E/ML

PIC24FJ64GA002-E/ML

DSPIC33EP128GS702-E/MM

DSPIC33EP128GS704-E/ML

DSPIC33EP128GS804-E/ML

DSPIC33EP64GS804-E/ML

DSPIC33EP64GS504-E/MLC06

MCP23008-E/ML

PIC24EP128GP202-I/MM

PIC18LF23K22-I/ML

PIC18LF2523-I/ML

PIC18F2523-I/ML

PIC16F1614-I/ML

DSPIC33EP128GP506-I/MR

DSPIC33EP128MC206-I/MR

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MX150F128DT-I/PT

PIC32MX230F128LT-50I/PT

PIC32MX575F512LT-80I/PT

PIC32MX575F256LT-80I/PT

PIC32MX530F128LT-50I/PT

DSPIC33FJ256MC710AT-I/PF

DSPIC30F5011T-20I/PT

DSPIC33FJ128MC706T-I/PT

PIC24HJ64GP510T-I/PT

PIC16F18054T-I/SS

PIC16F18055T-I/SS

PIC16F18054T-I/SO

PIC16F18055T-I/SO

PIC16F18056T-I/SS

PIC16F18056T-I/SO

DSPIC30F5015-20E/PT

DSPIC30F5016-20E/PT

PIC32MK1024GPK100-I/PT

PIC32MK0512GPK100-I/PT

DSPIC33FJ64GP708-I/PT

DSPIC33FJ128GP708-I/PT

PIC24HJ256GP610A-I/PF

DSPIC33FJ256GP510A-I/PF

PIC32MX675F256L-80I/PT

SHA104-MAVCZ-T

SHA104-MAVDA-T

SHA105-MAVDA-T

RNG90-MAVDA-T

PIC12F617T-I/SN022

PIC12F617T-I/SN038

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC18LF25J10T-I/SS042

PIC18LF25J10T-I/SS043

PIC18LF25J10T-I/SS046

PIC12F617T-I/SN044

PIC12F675T-I/SN164

PIC16F19156T-I/SS025

PIC16F17524T-I/ST

PIC16F17525T-I/ST

PIC16F17526T-I/ST

PIC16F1937T-I/MV

ATSAMD21G17L-MUT

ATMEGA32L-8MURA2

PIC16F17146T-I/6N

ATMEGA644PA-MUR

ATMEGA644A-MUR

PIC16F17144T-I/6N

ATMEGA324PV-10MUR

ATMEGA324P-20MUR

ATMEGA168PB-MUR

PIC16F17145T-I/6N

PIC16F17124T-I/7N

PIC16F17125T-I/7N

ATMEGA644V-10MUR

ATMEGA32L-8MUR

PIC16F15376T-I/MP

PIC16LF15356T-I/MV

ATMEGA8515L-8MUR

ATMEGA8515-16MUR

ATMEGA16L-8MUR

ATTINY87-MUR

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATMEGA644-20MUR

DSPIC33EP512GP506T-E/PTVAO

PIC24EP256GP204T-E/PTVAO

DSPIC33EP64MC506T-E/PTVAO

MCP41U83T-503E/7N

MCP41U83T-104E/7N

MCP3460RT-E/2LX

MCP3919BA1T-E/MQ

MCP3912BA1T-E/MQ

PIC16F1513-I/SS

PIC16F15245-I/SS

PIC16F1619-I/ML

PIC16LF1768-I/ML

PIC16LF1618-I/ML

PIC16LF1618-I/GZ

PIC16LF1615-I/ML

PIC16F1718-I/MV

PIC16LF1713-I/ML

PIC16LF1716-I/ML

MCP3901A0-I/ML

PIC16LF1566-I/MV

PIC16LF1567-I/MV

PIC16F1708-I/GZ

PIC16F1708-I/ML

PIC16LF1718-I/ML

PIC16F1516-I/MV

PIC16F1518-I/MV

PIC12LF1571-I/RF

PIC24FV16KA302T-I/SOC01

PIC32MX220F032BT-I/SS

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC32MX210F016BT-I/SS

PIC18F26K83T-I/SS020

PIC32MX120F032BT-I/SS

PIC32MX110F016BT-I/SS

PIC24EP64GP202T-I/SS

DSPIC33FJ32GP202T-I/SS

PIC32MX250F128BT-50I/SS

HA4412T-I/SO

DSPIC33FJ12MC201T-I/SS

AR1010T-I/SS

AR1020T-I/SS

AR1011T-I/SS

AR1021T-I/SS

PIC18F85K90T-I/PT

MCP16501TA-E/RMB-D

AT89C55WD-24AUR

ATMEGA324PA-AUR

ATMEGA325-16AUR

ATMEGA329-16AUR

ATXMEGA256A3BU-AUR

ATXMEGA256D3-AURA1

ATXMEGA128A3U-AUR

ATXMEGA256A3U-AUR

PIC32MK1024GPK100T-I/PT

PIC32MK1024MCM100T-I/PT

ATMEGA324A-AUR

ATMEGA64A-AUR

ATMEGA165PA-AUR

ATMEGA165A-AUR

ATMEGA169A-AUR

Date: Tuesday, July 22, 2025

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ATMEGA169PA-AUR

ATMEGA164PV-10AUR

ATMEGA164P-20AUR

ATXMEGA16D4-AURA2

ATXMEGA32D4-AURA4

ATXMEGA16C4-AUR

AVR128DA32T-I/PT

AVR128DA64T-I/PT

ATMEGA645V-8AUR

ATMEGA6450-16AUR

ATMEGA1284P-AUR

ATMEGA1284-AUR

ATMEGA164A-AURA2

AVR64DB48T-I/PT

PIC18F86K22T-I/PT

PIC24EP128GP206-I/PT

ATA5833-WNQW

ATA5830N-WNQW2

ATA5831-WNQW

ATA5782-WNQW

KSZ8051MNLV-TR

ATA5781-WNQW

ATA5781-WNQW-VAO

ATSAMHA0G17A-MZT-BVAO

93AA86BT-I/SN

DSPIC33CH128MP208-I/PT

93LC76BT-I/ST

PIC12LF1572-I/RF

PIC16F1719-I/ML

PIC16F1782-I/MV

Date: Tuesday, July 22, 2025

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PIC16LF1719-I/MV

PIC16LF1719-I/ML

PIC16LF1708-I/ML

PIC16F1782-I/ML

PIC16LF1717-I/MV

PIC16LF1713-I/MV

PIC16LF1716-I/MV

PIC18LF4515-I/ML

PIC16F1713-I/ML

PIC16F1716-I/ML

PIC16F1783-I/ML

PIC18F4620-I/ML

PIC18LF4620-I/ML

PIC18F4525-I/ML

PIC16LF18326-E/JQVAO

ATSAMD20E16B-MZVAO

PIC12F1822-E/MFVAO

PIC12F1840-E/MFVAO

PIC16F15214-E/MFVAO

PIC24EP256GP202-E/SS

PIC16F18855-E/SS

DSPIC33EP64MC202-E/SS

DSPIC33EP64MC502-E/SS

PIC24EP64MC202-E/SS

PIC16C73B-04E/SO

PIC16C73B-20E/SO

PIC16C63A-04E/SO

PIC12HV609-E/SN

PIC16LF18444-E/SS

PIC16F15223T-E/MG

Date: Tuesday, July 22, 2025

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PIC16F15224T-E/MG

PIC18F27K42T-E/ML

PIC18LF27K42T-E/ML

PIC32CM1216JH01048T-E/U5B

MCP6V74T-E/STVAO

MCP4922T-E/STVAO

MCP45HV31T-103E/STVAO

MCP6234T-E/STVAO

25AA020AT-I/MNY

25LC040AT-I/MC

PIC18LF47K40T-I/ML

25AA020AT-I/MC

PIC18F47Q83T-I/NHX

ATSAMD21E17D-MUT

ATSAMD21E15B-MUTN01

PIC16F724T-I/ML

PIC18F27J13T-I/ML

MCP79401T-I/MNY

MCP79402T-I/MNY

PIC16LF1947T-I/MR

DSPIC33FJ06GS202-E/SO

DSPIC33FJ06GS102-E/SO

DSPIC33FJ16GS402-E/SO

DSPIC33FJ16GS502-E/SO

34AA04-E/SN

PIC32MX120F032BT-50I/SS

PIC32MX220F032BT-50I/SS

PIC24FJ64GB202T-I/SS

PIC24FJ128GA202T-I/SS

PIC24FJ64GA202T-I/SS

Date: Tuesday, July 22, 2025

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PIC32MX150F128BT-I/SS

DSPIC33FJ16GP101T-I/SS

DSPIC33FJ16MC101T-I/SS

PIC24FJ16MC101T-I/SS

HA4581T-I/SO

HA1930T-I/SS

PIC16F883T-I/SO

HA4582T-I/SO

PIC12F675T-I/SN208

PIC16F883T-I/SS079

PIC16F883T-I/SS

DSPIC30F3013T-30I/SO

DSPIC33FJ32GP302T-I/SO

DSPIC33FJ128MC202T-I/SO

PIC24EP512MC204-H/PT

DSPIC33EP512GP506-H/PT

DSPIC33EP512MC206-H/PT

PIC16C621A-20E/SO

PIC16C622A-04E/SS

PIC16F88-E/SS

PIC16F506-E/ST

PIC16C712-20E/SS

MCP6G04-E/ST

PIC18F2331-E/SO

PIC18F2520-E/SO

PIC18F2431-E/SO

MCP604-E/ST

MCP4261-502E/ST

MCP4261-103E/ST

TC7660SVOA

Date: Tuesday, July 22, 2025

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PIC18F2420-E/SO

MCP9805-BE/ST

MCP4231-103E/ST

PIC16F1516T-E/SS

MCP45HV31T-104E/ST

PIC18F26K22T-E/SS

93C86CT-E/ST

PIC16LF73T-I/SS

MCP3304T-BI/SL

MCP3304T-CI/SL

PIC16F57T-I/SS024

PIC16F57T-I/SS025

PIC16F872T-I/SS

PIC16LF872T-I/SS

PIC16LF76T-I/SS

PIC16F76T-I/SS

PIC16LF873AT-I/SS

PIC16C62BT-20I/SS

PIC18LF14K50T-I/SS

PIC16F57T-I/SS027

PIC16F57T-I/SS

PIC18F2320T-I/SO

RE46C100S8TF

PIC16F876AT-I/SS

PIC18F2480T-I/SO

MCP2140AT-I/SO

PIC18F2431T-I/SO

PIC18F14K50T-I/SS

MCP2140AT-I/SS

RE46C119S16TF

Date: Tuesday, July 22, 2025

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PIC18LF2680T-I/SO

PIC18F25K20-E/SO

MCP4352-103E/ST

MCP6N11-100E/SN

PIC16LF1823-E/ST

MCP664-E/ST

MCP4631-502E/ST

PIC16F628A-E/SO

25LC256T-I/STRVA

MCP6004T-I/STAAA

PIC24HJ64GP202T-I/SO

PIC24HJ128GP202T-I/SO

25LC256T-I/SNRVB

PIC24HJ128GP502T-I/SO

PIC24HJ32GP302T-I/SO

PIC24HJ64GP502T-I/SO

HSA0-040SDA/A0SA10TR

PIC24FJ32GA104T-E/ML

PIC16F1783-E/SS

MCP45HV31-103E/ST

MCP45HV31-503E/ST

MCP45HV31-104E/ST

PIC18F26K22-E/SS

93LC46A-E/ST

MCP25625-E/SS

PIC16LF1903-E/SS

PIC18F24K22-E/SS

PIC18F23K22-E/SS

93LC76C-E/ST

PIC16LF1902-E/SS

Date: Tuesday, July 22, 2025

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MCP6284-E/ST

93LC86C-E/ST

MCP6V34-E/ST

93AA76BT-I/ST

24LC02BT-I/SN

24LC02BT-I/SNA32

24AA02T-I/SN

MCP6044T-I/ST

PIC18F24K50T-I/SO

PIC18F25K50T-I/SO

11AA02E64T-I/SN

PIC24FV16KM202T-I/SS

PIC18F24K50T-I/SS

PIC18F25K50T-I/SS

PIC18LF25K50T-I/SS

PIC24FV08KM101T-I/SS

HCS201T-I/SN

24LC024HT-I/ST

24AA024HT-I/ST

PIC16F916T-I/SS028

24FC64T-I/SN

DSPIC33EP128GS708T-I/PT

DSPIC33EP128GS808T-I/PT

DSPIC33EP128GS708T-I/PTC01

AVR32DB48T-I/PT

DSPIC33EP128GS708T-I/PTC02

DSPIC33EP64GS808T-I/PT

DSPIC33EP64GS708T-I/PT

PIC32MK0128MCA048T-I/Y8X

DSPIC33FJ128MC506AT-I/PT061

Date: Tuesday, July 22, 2025

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PIC24HJ256GP206AT-I/PT027

PIC18F56Q71T-I/PT

AVR128DB48T-I/PT

DSPIC33FJ128GP306AT-I/PT

DSPIC33FJ128MC706AT-I/PT

AVR64DA32T-I/PT

DSPIC33EV128GM106T-I/PT

HV5630PJ-G

COM20019I-DZD

COM20020I-DZD

24LC32AFT-I/SN

PIC16F18857-E/ML

PIC16F873A-E/SO

PIC18F24Q10-E/SS

PIC18F25Q10-E/SS

PIC18F24Q10-E/SO

PIC18F25Q10-E/SO

PIC16F15245-E/SS

DSPIC33EP256MC502-E/SS

ATMEGA4808-MF-VAO

TC1302B-PFVMF-VAO

MCP1726-ADJE/MFVAO

MCP1727-ADJE/MFVAO

MCP2562-E/MFVAO

MCP2562FD-E/MFVAO

PIC18F26K83-E/MLVAO

PIC18F25K83-E/MLVAO

PIC18F47Q10-E/MPVAO

PIC18F27Q10-E/STXVAO

MCP1602T-180I/MF

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MCP1602T-250I/MF

MCP1602T-330I/MF

MCP1602T-ADJI/MF

MCP1602T-FIXI/MF

AT89CC01UAEDT-RLRUM

PIC32MX270F512HT-50I/PT020

PIC24HJ32GP304T-I/PT

DSPIC33FJ128GP804T-I/PT

DSPIC33CK512MP305T-I/PT

DSPIC33CK512MP605T-I/PT

PIC16F18025-E/7NVAO

AVR128DA48-E/6LXVAO

AVR128DA64-E/MRVAO

PIC16LF648AT-I/ML

MCP1612T-ADJI/MF

PIC10F204T-I/MC

PIC10F220T-I/MC

PIC10F206T-I/MC

PIC16F628AT-I/ML

PIC16LF628AT-I/ML

PIC18F4685T-I/ML

PIC10F222T-I/MC

PIC16LF88T-I/ML

PIC16F88T-I/ML

PIC12F615T-I/MD

PIC18F2450T-I/ML

MCP1602T-120I/MF

MCP1602T-150I/MF

PIC24HJ128GP202-I/SO

PIC24HJ128GP502-I/SO

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC24HJ32GP302-I/SO

DSPIC33FJ32MC102-I/SO

PIC24FJ32MC102-I/SO

PIC24HJ64GP502-I/SO

PIC32MX350F128HT-I/MR

PIC32MX450F128HT-I/MR

ATSAMD20E15B-MUTDY

ATSAMD20E16B-MUTDY

PIC18LF14K50T-I/MQ

24LC014HT-I/MNY

24AA014HT-I/MNY

24LC024HT-I/MNY

24AA024HT-I/MNY

34LC02T-I/MNY

34AA02T-I/MNY

ATSAMD51N20A-AUT-EFP-RB

PIC16LF18876T-I/PT

PAC1710-1-AIA-TR

PAC1720-1-AIA-TR

PIC16LF1825T-I/ML

PIC32CM1216JH01032T-E/RTB

AVR64EA32T-E/RXB

AVR32EA32T-E/RXB

24LC128T-E/MNY

MCP42U83T-502E/7N

MCP42U83T-103E/7N

MCP42U83T-203E/7N

MCP42U83T-503E/7N

MCP42U83T-104E/7N

DSPIC33AK128MC102T-E/M7

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DSPIC33AK64MC102T-E/M7

DSPIC33AK32MC102T-E/M7

AT86RF233-ZFR

AVR128DA48T-E/6LX

AVR128DA64T-E/MR

AVR128DA32T-E/RXB

ATTINY817-MFR

ATTINY417-MFR

ATTINY3217-MFR

ATSAMC21G18A-MZT

PIC12LF1501T-I/MC021

PIC16F18044T-I/ML

PIC16F18045T-I/ML

PIC18F47Q10T-I/MP

PIC18F47Q43T-I/MP

PIC16LF1554T-I/ML030

PIC16LF1554T-I/ML031

MGC3130T-I/MQ024

MGC3130T-I/MQ

DSPIC33EP32GS202T-I/MMC02

PIC32MX550F256HT-50I/MR

PIC32MX250F256HT-50I/MRJ21

PIC32MX250F256HT-50I/MR

PIC32MX570F512HT-50I/MR

ATECC608B-TNGACTU-G

ATECC608B-TNGLORAU-G

ATECC608B-TNGTLSU-G

ATSAMC20G17A-MZT

ATSAMC21G17A-MZT

ATSAMC21G16A-MZT

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ATSAMC21G15A-MZT

ATSAMC20G18A-MZT

ATSAMC20G16A-MZT

ATSAMC20G15A-MZT

ATSAMC21G17A-MZT-SL1

PIC18F26J50T-I/SS033

PIC18F26J50T-I/SS034

DSPIC33FJ16GS402T-50I/SO

DSPIC33FJ16GS502T-50I/SO

34AA04T-I/SN

PIC24EP32GP202T-I/SS

ATSAMD20G14A-AUTA2

ATSAMD20G18A-AUTA3

DSPIC33FJ128MC804T-I/PT

PIC24FJ32GP205T-I/PT

DSPIC33CK256MP608T-I/PT

DSPIC33CK512MP308T-I/PT

DSPIC33CK512MP608T-I/PT

DSPIC33CK256MP305T-I/PT

DSPIC33CK256MP605T-I/PT

PIC24FJ256GA406T-I/PT

ATSAMD20E16B-MUT

ATSAMD20E14B-MUT

ATSAMD20E15B-MUT

11LC010-I/SN

DSPIC33EP128MC506-I/MR

UTC2000-I/MG

PIC16LF1454-I/ML

PIC24EP128GP206-I/MR

PIC16F1713T-I/MV

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PIC16F1716T-I/MV

PIC16LF1718T-I/MV

PIC24FJ64GA306T-I/MR024

PIC18F25K50T-I/ML

PIC16F18876T-I/ML

PIC16LF18876T-I/ML

DSPIC33EP256MC504T-E/PTVAO

DSPIC33CH128MP505-H/PT

DSPIC33CH64MP205-H/PT

DSPIC33CH128MP205-H/PT

DSPIC33FJ256GP710A-H/PF

DSPIC33FJ256MC710A-H/PF

PIC32MZ0512EFF064-E/MR

PIC12F510-E/MC

PIC32MK1024MCF064-E/MR

PIC32MK0512GPE064-E/MR

ATMEGA1608-MF

PIC18F46K42-E/ML

PIC18F45K42-E/ML

PIC18LF46K42-E/ML

PIC18LF45K42-E/MV

PIC18LF26K42-E/ML

PIC18F47K42-E/MV

PIC18LF47K42-E/MV

PIC18F47K42-E/ML

PIC16F726T-I/SS027

24FC128T-I/ST

PIC16F1933T-I/SS

24AA64T-I/ST

DSPIC33FJ32MC202T-I/SO023

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PIC12F1571-I/SN035

24LC128-I/SNRVF

24FC128-I/SN

PIC16LF1718-I/SS

PIC12F1571-I/SN038

PIC12F1571-I/SN063

PIC12F1571-I/SN

PIC12F1572-I/SN

PIC18F2525T-E/SO

TC7660SVOA713

PIC18F2420T-E/SO

PIC16LF73T-E/SO

PD69210C-022619-TR

PD69210R-022620-TR

AVR128DB64T-I/MR

AVR64DB64T-I/MR

AVR32DU28T-I/STX

AVR16DU32T-I/RXB

AVR16DU28T-I/STX

AVR32DU32T-I/RXB

PIC16F18444T-I/GZ

PIC16F18445T-I/GZ

PIC16LF18444T-I/GZ

MCP4661-103E/ST

24LC01BH-E/SN

PIC16LF1516-E/SO

PIC16F726-E/SS

PIC18F26K20-E/SO

ATMEGA16U4-AU

ATMEGA32U4-AU

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ATMEGA32U4RC-AU

ATMEGA16U4RC-AU

ATMEGA329P-20AU

ATMEGA8535-16AU

ATMEGA8535L-8AU

ATMEGA2561-16AU

ATMEGA2561V-8AU

AT90USB646-AU

AT90USB647-AU

ATXMEGA64B3-AU

ATXMEGA32D4-AUA4

ATXMEGA16D4-AUA2

PIC16F15375-I/PT

ATMEGA3250-16AU

AT89LP51ED2-20AU

AT89LP51ID2-20AU

AT89LP51RD2-20AU

ATXMEGA16C4-AU

ATXMEGA32C4-AU

ATXMEGA32D4-AU

ATXMEGA16D4-AU

ATXMEGA64D3-AUA4

ATXMEGA64D3-AU

ATMEGA32-16AU

ATMEGA3290-16AU

ATMEGA164PV-10AU

AT90CAN128-16AU

ATXMEGA64C3-AU

ATXMEGA32C3-AU

ATXMEGA32D3-AU

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ATMEGA328PB-AU

ATMEGA168A-AU

ATMEGA329V-8AU

ATMEGA329-16AU

ATMEGA164P-20AU

ATXMEGA32D4-AUA5

ATXMEGA16D4-AUA1

ATXMEGA128D4-AU

ATXMEGA128A4U-AU

ATXMEGA64D4-AU

PIC16F15376-I/PT

PIC16F15385-I/PT

ATMEGA324PA-AU

MCP6072-E/SN

MCP3426A4-E/SN

PIC16F72-E/SS

24C00-E/SN

MCP4921-E/SN

MCP3426A3-E/SN

PIC18F2682-E/SO

PIC18F2685-E/SO

MCP3422A5-E/SN

MCP4352-502E/ST

PIC24FJ16GA002-E/SO

PIC24FJ48GA002-E/SO

PIC16F610-E/ST

24LC64X-E/ST

MCP660-E/ST

24C01C-E/ST

MCP3426A6-E/SN

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MCP624-E/ST

MCP6N11-001E/SN

93C56-E/SN

PIC16LF726-E/SO

MCP3422A4-E/SN

MCP6N11-005E/SN

MCP6074-E/ST

MCP6404-E/ST

PIC16F627A-E/SO

MCP6N11-002E/SN

MCP6N11-010E/SN

PIC16LF19185-I/PT

PIC16LF19186-I/PT

AVR64DA48-I/6LX

ATSAML11E16A-MU

ATECC608B-MAHMD-B

PIC16F1824-I/JQ

PIC16LF1824-I/ML

PIC16LF1824-I/JQ

AVR32DD32-I/RXB

AVR16DD32-I/RXB

PIC18F55Q24-I/6LX

PIC18F56Q24-I/6LX

PIC18F45Q24-I/MP

PIC18F46Q24-I/MP

PIC18F24Q24-I/STX

PIC18F25Q24-I/STX

PIC18F26Q24-I/STX

AVR32EB32-I/RXB

PD77020-011000

Date: Tuesday, July 22, 2025

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PIC32CM5164JH01048-I/U5B-SL3

PIC16F17556-I/STX

PIC16F17574-I/MP

PIC16F17575-I/MP

PIC16F17576-I/MP

PIC16F17554-I/STX

PIC16F17555-I/STX

PD77010-0100-0000

PIC32CM5164LS00048-I/U5B-SL3

OS81210AM-B2B-010200

DSPIC33AK32MC105-I/PT

ATSAMD51N20A-AU-EFP-RB

ATSAMD51N19A-AU

ATSAMD51N19A-AU-EFP

ATSAMD51N20A-AU

ATSAMD51N20A-AU-EFP

AVR16EA48-I/PT

ATSAME51N19A-AU

ATSAME51N19A-AU-EFP

ATSAME51N20A-AU

ATSAME51N20A-AU-EFP

ATSAME53N19A-AU

ATSAME53N19A-AU-EFP

ATSAME53N20A-AU

ATSAME53N20A-AU-EFP

ATSAME54N19A-AU

ATSAME54N20A-AU

ATSAME54N20A-AU-EFP

PIC32CX1025SG41100-I/E5X

AT32UC3A1512-AUT

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PIC16LF18876-I/PT

DSPIC33AK256MC206-I/PT

DSPIC33AK256MC205-I/PT

PIC18F46Q71-I/PT

ATSAMD51N20A-AF

ATSAME51N19A-AF

ATSAME51N20A-AF

ATSAME53N19A-AF

ATSAME53N20A-AF

ATSAME54N19A-AF

AVR64DD32-E/PT

ATSAME54N20A-AF

PIC16F1937-E/PT

PIC16F1934-E/PT

PIC24FJ128GL406-E/PT

PIC24FJ256GL406-E/PT

PIC24FJ512GL406-E/PT

PIC24FJ128GU406-E/PT

PIC24FJ256GU406-E/PT

PIC32AK1216GC41064T-I/M7

PIC32AK6416GC41064T-I/M7

PIC32AK3208GC41064T-I/M7

PIC32AK1216GC41036T-I/M7

PIC32AK6416GC41036T-I/M7

PIC32AK3208GC41036T-I/M7

PIC32AK1216GC41048T-I/M7

PIC32AK6416GC41048T-I/M7

PIC32AK3208GC41048T-I/M7

AVR64DA48ST-I/6MX

24AA256-I/SN

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24LC014H-I/SN

24AA014H-I/SN

24AA256-I/SNRVE

PIC16F15354-I/SS

24LC128-I/SNRVE

24AA128-I/SN

93AA56A-I/ST

24LCS52-I/SN

24AA52-I/SN

24LC014-I/SN

24AA014-I/SN

PIC24F16KA101-I/SS

PIC16LF18857-I/SS

24C00-I/SN

24LC00-I/SN

PIC24F16KA102-I/SS

24AA00-I/SN

PIC18F25K22-I/SOC02

PIC18LF25K22-I/SSC02

PIC16F1847-I/SOC02

PIC16F18455-I/SS

PIC16F18456-I/SS

PIC12F609-I/SN

PIC16F1933-I/SSC01

PIC16HV785-I/SS

PIC12F1822-I/SNC08

PIC16F1933-I/SS024

PIC16LF18455-I/SS

MTCH6102-I/SS

PIC16F18856-I/SS

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PIC12F508-I/SN

PIC24FJ64GA705T-I/PT

DSPIC33FJ32GP304T-I/PT

PIC32MX350F256LT-I/PF

PIC32MZ2048EFM100T-I/PF

PIC32MX564F064LT-I/PF

PIC32MX664F128LT-I/PF

PIC32MX664F064LT-I/PF

DSPIC33FJ64MC204T-I/PT

PIC32MZ2048EFG100T-I/PF

PIC32MZ2048EFH100T-I/PF

ATMEGA328-AUR

ATMEGA328P-AUR

PIC32MZ0512EFE100T-I/PF

PIC32MZ0512EFF100T-I/PF

PIC32MX564F128LT-I/PF

PIC32MX534F064LT-I/PF

PIC32MZ2048EFH100T-250I/PF

PIC32MZ0512EFK100T-I/PF

PIC32MZ1024EFE100T-I/PF

DSPIC33CK32MP206T-E/PT

DSPIC33CK32MP506T-E/PT

DSPIC33CK256MP208T-E/PT

DSPIC33CK128MC102T-I/SS

HSA2-040SIA/A2S23TR

24CS256T-I/ST

DSPIC33EP128GM604-E/PTVAO-BW

PIC32MX130F128LT-V/PT

PIC32MX775F512LT-80V/PF

PIC32MX775F256LT-80V/PF

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PIC32MX575F256LT-80V/PFC21

PIC32MX550F256HT-V/PT

PIC32MX775F512HT-80V/PT

PIC16LF19155T-I/MV

ATECC608A-MAHHL-S

ATECC608A-MAHHL-T

ATECC608A-MAHLG-T

PIC16F1936T-I/ML

SY89113UMY-TR

AT91SAM7S32B-MU-999

24CS256T-I/Q4B

ATECC608A-MAHVL-T

ATECC608A-MAHVM-T

ATECC608A-MAHZN-S

ATECC608B-MAH3F-T

ATECC608B-MAH3S-T

ATECC608B-MAH3W-T

AT86RF233-ZUR

AT24C256C-MAHL-T

ATECC508A-MAHPH-S

ATECC508A-MAHUW-T

ATECC608B-MAH4I-S

ATECC608B-MAH5O-T

PIC16LF15354-I/MV

PIC16LF15355-I/MV

ATECC608C-MAHMD-B

PIC16F17156-I/STX

PIC16F18156-I/STX

USB5734-I/MR

RE46C705IV32

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RE46C700IV28

RE46C701IV28

ATSAMDA1E14B-MBT

NI32DA14-MBT

ATA8520E-GHQW

ATA8520E-GHPW

NI32DA16-MBT

ATSAMC20E15A-MNT

ATSAMC20E16A-MNT

ATSAMC20E17A-MNT

RE46C420V28T

RE46C421V28T

ATSAMC20E18A-MNT

ATSAMC21E15A-MNT

ATSAMC21E16A-MNT

PIC18F24K20-I/SO

PIC18LF2410-I/SO

PIC18F2410-I/SO

PIC16LC770-I/SSHLF

PIC18F13K50-I/SS

PIC18LF2221-I/SO

ENC28J60-I/SS

PIC18F26K20-I/SO024

MCP2150-I/SS

MCP2155-I/SS

PIC16LF1518-I/SO

PIC16F1934-I/ML

DSPIC33CK1024MP405-I/M7

DSPIC33CK1024MP705-I/M7

DSPIC33CK512MP405-I/M7

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PIC16LF1704-I/ML

DSPIC33CK512MP705-I/M7

DSPIC33CK256MP405-I/M7

DSPIC33CK256MP705-I/M7

DSPIC33CK1024MP406-I/MR

DSPIC33CK1024MP706-I/MR

DSPIC33CK512MP406-I/MR

DSPIC33CK512MP706-I/MR

DSPIC33CK256MP406-I/MR

DSPIC33CK256MP706-I/MR

PIC16F753-I/ML

PIC16HV753-I/ML

PIC16F630-I/ML

PIC16F676-I/ML

PIC16F684-I/ML

PIC16LF18855-I/ML

PIC16F17114-I/MD

PIC16F18114-I/MD

PIC16F17115-I/MD

PIC16F18115-I/MD

PIC16F1615-I/ML

PIC16LF18856-I/ML

PIC16LF18854-I/ML

PIC16F18074-I/MP

MCP2221-I/ML

MCP2221A-I/ML

PIC16F1454-I/ML

PIC16F1455-I/ML

PIC16F1454-I/JQ

HV5524K7-G

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC16LF1516-I/ML

PIC16LF1518-I/ML

PIC16LF1516-I/MV

PIC32MX274F256D-V/PT

PIC32MX154F128D-V/PT

PIC32MX695F512L-80V/PF

PIC32MX675F512L-80V/PF

PIC32MX675F256L-80V/PF

PIC32MX795F512L-80V/PF

PIC32MX775F512L-80V/PF

PIC32MX775F256L-80V/PF

PIC32MX130F128L-V/PF

PIC32MX230F128L-V/PF

PIC32MX575F512H-80V/PT

PIC32MX575F256H-80V/PT

PIC32MX575F256H-80V/PTC21

PIC32MX575F256L-80V/PT

PIC32MX254F128D-V/PT

PIC32MX695F512H-80V/PT

PIC32MX675F512H-80V/PT

DSPIC33FJ128MC510A-I/PF

DSPIC33FJ128MC710A-I/PF

PIC24HJ128GP210A-I/PF

PIC24HJ128GP310A-I/PF

PIC24HJ128GP510A-I/PF

DSPIC33FJ128GP310A-I/PF

PIC18F86K90-I/PT

PIC24FJ128GA310-I/PTREL

PIC18LF47J53-I/PT

MT093AP1

Date: Tuesday, July 22, 2025

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ATF1504AS-7JX44

LE79R70-1DJC

LE79R70DJC

SST39SF040-55-4C-NHE

SST39SF020A-55-4C-NHE

SST39SF010A-55-4C-NHE

SST39SF040-70-4C-NHE

SST39SF020A-70-4C-NHE

SST39SF010A-70-4C-NHE

SST39LF020-55-4C-NHE

SST39LF010-55-4C-NHE

SST39LF040-55-4C-NHE

SST39LF040-55-4C-NHE-RVL

SST39VF040-70-4C-NHE

SST39VF020-70-4C-NHE

PIC16F747-I/ML

PIC12F609-I/MF

AT24C64D-MAHM-E

PIC16LF1527T-I/MR

A3P125-VQG100T

PIC16F19197-E/PTVAO

ATSAMD21J18A-AZVAO

A3P250-VQG100T

PIC32MZ2048EFM100-E/PTVAO

DSPIC33CK512MP608-E/PTVAO

DSPIC33CK256MP606-E/PTVAO

PIC18F46Q10-E/PTVAO

DSPIC33CK256MP608-E/PTVAO

DSPIC33CK256MC505-E/PTVAO

PIC18F45Q10-E/PTVAO

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DSPIC33CK1024MP710-E/PTVAO

DSPIC33CH128MP506-E/PTVAO

DSPIC33CH128MP508-E/PTVAO

DSPIC33CH128MP505-E/PTVAO

DSPIC33CK64MP105-E/PTVAO

DSPIC33CK256MP508-E/PT510

PIC32MZ2048EFH100-E/PTVAO

DSPIC33CK64MC105-E/PTVAO

DSPIC33CK32MC105-E/PTVAO

PIC24HJ12GP202-I/SO

PIC24FJ32MC102-I/SS

PIC32MX170F256B-I/SS

DSPIC33FJ32GP101-I/SS

DSPIC33FJ06GS001-I/SS

DSPIC33FJ06GS101A-I/SS

DSPIC33FJ32MC101-I/SS

PIC24FJ32MC101-I/SS

DSPIC33FJ06GS202A-I/SO

PIC32AK1216GC41048T-E/PT

PIC32AK6416GC41048T-E/PT

PIC32AK3208GC41048T-E/PT

PIC32AK1216GC41064T-E/PT

PIC32AK6416GC41064T-E/PT

PIC16LF627AT-I/SO

PIC16F785T-I/SS

MCP604T-I/ST

PIC16F628AT-I/SO051

PIC16F73T-I/SO150

PIC16F73T-I/SS155

24LC64XT-I/ST

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PIC16F73T-I/SS

PIC18F2685T-I/SO

PIC16C67-20/L

PIC16LC67-04/L

TC7116ACLW

TC7116CLW

TC7109CLW

TC7109ACLW

PIC17C44-16/L

PIC16C65B-04/L

PIC16C65B-20/L

PIC16LC65B-04/L

PIC16LF877-04/L

PIC17C43-25/L

AY0438/L

PIC16F877-20/L

PIC16F877-04/L

PIC17C44-25/L

PIC17C44-33/L

PIC17C43-16/L

PIC16F874-04/L

PIC16F874-20/L

PIC17C42A-16/L

PIC17C42A-25/L

PIC16LC74B-04/L

PIC16C74B-04/L

PIC16C74B-20/L

PIC18F47K40T-I/PT

PIC18LF47K40T-I/PT

PIC18F45K40T-I/PT

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PIC18F46K40T-I/PT

PIC18LF45K40T-I/PT

PIC18LF46K40T-I/PT

DSPIC30F4013-20I/ML

DSPIC30F4013-30I/ML

ATECC608B-TNGACTU-B

PIC32CM3204GV00064-I/5LX

PIC32MX170F256D-50I/ML

PIC32MX270F256D-50I/ML

PIC32MZ2048ECM064-I/MR

DSPIC33FJ64GS606-50I/MR

ATMEGA809-MU

PIC16F1788-I/ML

DSPIC33FJ32MC202-I/MM

PIC32MZ1024ECG064-I/MR

DSPIC30F2010T-20E/MM

PIC24FJ32GA004T-E/ML

MCP4461T-502E/ML

PIC24EP512GP204T-E/ML

PIC24EP512MC204T-E/ML

PIC24EP512MC206T-E/MR

PIC24EP512GP206T-E/MR

DSPIC33EP512MC506T-E/MR

DSPIC33EP512MC206T-E/MR

MCP4461T-103E/ML

MCP4461T-104E/ML

MCP4461T-503E/ML

DSPIC33EP512GP506T-E/MR

24FC08T-E/MUY

PIC24FJ64GA104T-E/ML

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MCP4351T-104E/ML

DSPIC33EP128MC202T-E/MM

MCP4351T-503E/ML

24AA04T-E/MC

93C66AT-E/MNY

93C56CT-E/MNY

93C56AT-E/MNY

93C56BT-E/MNY

93LC66CT-E/MNY

93LC66AT-E/MNY

25LC640AT-E/MNY

MCP23017T-E/ML

AT89C51RB2-SLSUL

MCP6N16T-001E/MF

ATMEGA328PB-MNR

ATMEGA32A-MNR

PIC24FJ64GB002T-I/SO

PIC18F24K20T-I/SSC03

PIC24FJ32GA102T-I/SO

PIC24F04KA201T-I/SS

PIC24F04KA200T-I/ST

PIC18LF2480T-I/SO

PIC24F32KA301T-I/SS

PIC18LF2321T-I/SS

PIC16LF1827T-I/SO

PIC18LF2321T-I/SO

PIC18F25J50T-I/SS

PIC18F24J50T-I/SS

PIC18F26J11T-I/SS

PIC18F25J11T-I/SS

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PIC18F24J11T-I/SS

MCP3204T-BAI/ST

MCP2551T-I/SN

RE46C108S8TF

ENC28J60T-I/SS

PIC16C621AT-04I/SO081

PIC16F616T-I/ST045

MCP2030T-I/ST

AGL030V2-VQ100

AGL030V2-VQG100

AGL030V5-VQ100

AGL030V5-VQG100

ATF1502AS-7AX44

HV209TQ-G

AVR64DA32ST-E/QZB

AVR64DA48ST-E/6MX

AVR64DA64ST-E/5LX

AVR32DA32ST-E/QZB

MCP41U83T-502E/7N

MCP41U83T-103E/7N

MCP41U83T-203E/7N

PIC18F46J50T-I/PT031

PIC18F46J50T-I/PT032

PIC16LF1717T-I/PT

PIC16F1517T-I/PT

PIC16LF1719T-I/PT

PIC16F1519T-I/PT

DSPIC33EP512GM306T-I/PT

PIC32MZ1024ECM100T-I/PT

DSPIC33CK128MC106T-E/PT

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PIC32CM5164JH01048T-E/Y8X-SL3

AVR32SD32T-E/PT

PIC24FJ256GA804T-E/PT

DSPIC33CK128MP206T-E/PTC01

AVR128DA32ST-E/PT

AVR128DA48ST-E/PT

AVR128DA64ST-E/PT

PIC24FJ256GA704T-E/PT020

PIC24FJ64GA006T-I/MR

DSPIC33EV128GM004T-I/ML

DSPIC33EV128GM104T-I/ML

PIC32MX450F256HT-I/MR

DSPIC33EV32GM006T-I/MR

DSPIC33EV32GM106T-I/MR

PIC24EP256MC206T-I/MR

ZL88107LDF1

DSPIC30F3012T-20I/ML

ATTINY88-MUR

PIC24EP256GP206T-I/MR

PIC32MM0064GPM028T-I/ML

PIC32MM0128GPM028T-I/ML

PIC24FJ64GA002T-I/ML044

PIC24FJ64GA004T-I/MLC13

DSPIC33FJ32MC304T-I/ML

LE9642PQCT

DSPIC33AK64MC105-I/M7

DSPIC33AK32MC105-I/M7

PIC16F18876-I/MV

PIC18LF46K40-I/MVC02

PIC18F56Q71-I/6LX

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MTCH1030-I/MG

PIC16F15223-I/MG

PIC24FJ512GB606T-I/PTC01

DSPIC33EV256GM106T-I/PT

DSPIC33EV128GM006T-I/PT

PIC16LF1784-E/MV

PIC16LF1784-E/ML

PIC18F2321-E/ML

PIC16LF1459-E/ML

PIC18F14K50-E/MQ

PIC18F4321-E/ML

PIC18F2221-E/ML

DSPIC33FJ64GP310-I/PF

DSPIC33FJ256GP710-I/PF

DSPIC33FJ64MC710-I/PF

PIC32MZ2048ECM064-I/PT

PIC32MX130F128L-I/PT

PIC18F26K40-I/MVVAO

PIC16F1936-I/MVVAO

PIC32MM0064GPL020-I/MLVAO

PIC32MZ1024EFM100T-I/PT

PIC32MZ1024EFG100T-I/PT

PIC16F1823T-E/MLVAO

PIC16F1704T-E/MLVAO

PIC16LF1559T-E/MLVAO

PIC16C72A-20/SO

TC1044SCOA

24LC08B/ST

PIC16F873-04/SO041

PIC18F25K20T-I/MLC10

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PIC16LF19197T-I/MR

PIC18F67K40T-I/MR

PIC18LF67K40T-I/MR

PIC16LF1716T-I/MV

PIC32CM3204JH00064T-E/V2X

PIC32CM3204JH00048T-E/Y8X

MCP4431T-503E/ML

MCP4441T-502E/ML

MCP4441T-103E/ML

MCP4441T-104E/ML

MCP4441T-503E/ML

DSPIC33EP512MC502T-E/MM

DSPIC33EP512GP502T-E/MM

MCP4361T-103E/ML

MCP4361T-104E/ML

MCP4451T-502E/ML

MCP4451T-103E/ML

24FC16T-E/MUY

MCP4561T-503E/MFOPP

MCP4451T-104E/ML

MCP4451T-503E/ML

PIC16LF1579-I/GZ

PIC16F1579-I/GZ

PIC16LF1574-I/JQ

PIC16F1574-I/JQ

PIC16LF1575-I/JQ

PIC24EP256GU810T-I/PF

PIC24EP512GU810T-I/PF

PIC32MX330F064HT-I/PT

PIC32MX420F032HT-40I/PT

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PIC16F1847-E/SS

24LC64-E/SN

93C86A-E/ST

93C86B-E/ST

93LC76A-E/ST

PIC24F32KA301-E/SS

PIC24F16KA301-E/SS

93LC76B-E/ST

93C76B-E/ST

PIC16LF1906-E/SS

MCP6272-E/SN

25AA640A-E/SN

25AA640A-E/ST

PIC16LF1825-E/ST

24LC32A-E/SN

PIC18LF26K22-E/SS

93C76A-E/ST

PIC24FV08KM101-E/SS

PIC16LF1503-E/ST

PIC24F32KA302-E/SO

PIC24F32KA302-E/SS

PIC24F16KA302-E/SS

25AA160D-E/SN

PIC16F1459-E/SS

MCP6424-E/ST

PIC32MX764F128L-I/PT

DSPIC33EP512GP504-I/PT

DSPIC33EP256MC206-I/PT

ATMEGA164PA-AU

PIC32MX564F128L-I/PF

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LE9621AQC

PIC32CM2532LS00048-E/Y8X

PIC32CM2532LE00100-E/PF

PIC32CM2532LS00100-E/PF

DSPIC30F6011A-20E/PT

DSPIC30F6012A-20E/PT

DSPIC30F6011A-20E/PF

DSPIC30F6012A-20E/PF

DSPIC30F6013A-20E/PT

DSPIC30F6014A-20E/PT

PIC32MX120F032B-50I/SS

HSA2-040SAA/A2323

93C66C-I/ST

93C66A-I/ST

24LC024-I/SN

24AA024-I/SN

PIC16F18344-I/SS

PIC16F677-I/SS

93C46C-I/ST

PIC16F1769-I/SS

PIC16F1768-I/SS

93C66B-I/ST

PIC18F14K22-I/SS

PIC16LF1508-I/SS025

PIC16LF18854-I/SS

24LC025-I/SN

24AA025-I/SN

24C02C-I/SN

24C01C-I/SN

24LC024H-I/SN

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24AA024H-I/SN

25LC080C-I/SN

PIC16LF1788-I/SS

25LC256-I/ST

25AA320A-I/SN

25AA160D-I/SN

25AA080C-I/SN

25LC320A-I/SN

25LC160D-I/SN

PIC16LF1508-I/SS

PIC16LF1509-I/SS

PIC12F1822-I/SN

PIC12F1822-I/SNC11

PIC16F1518-I/SS

PIC16LF1559-I/SS

PIC12C509A-04I/SN

PIC16F1827-I/SS

PIC16LF1829-I/SS022

PIC16LF1829-I/SS

PIC16LF1829-I/SSC03

HA2022-I/SS

PIC16F18857-I/SS

PIC16F1826-I/SS

HA2525-I/SS

PIC12F510-I/SN

PIC12F617-I/SN

PIC16F1713-I/SO

PIC32CM6408JH00032-E/RTBVAO

DSPIC33CK256MP705-E/M7VAO

PIC16F1825-I/MLVAO

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PIC16LF1709-I/MLVAO

PIC16LF1554-I/MLVAO

PIC16LF1828-I/MLVAO

PIC16F1503-I/MGVAO

PIC24FV16KA302-I/MLVAO

PIC16F1828-I/MLVAO

PIC16F1824-I/MLVAO

PIC16F1823-I/MLVAO

PIC16F1704-I/MLVAO

PIC16F1705-I/MLVAO

PIC16F1718-I/MLVAO

PIC16LF1938-I/MLVAO

DSPIC30F2010-20I/MMVAO

MCP2210-I/MQVAO

PIC16F1518-I/MLVAO

OS81110AF-D1A-010203-VAO

OS81110AF-D1A-010204-VAO

OS81110AF-D1A-010205-VAO

OS81110AF-D1A-010207-VAO

OS81110AF-D1A-010208-VAO

PIC18F25K80-I/MMVAO

PIC16F1788-I/MLVAO

MCP2515-I/MLVAO

MCP79410-I/MNYVAO

DSPIC33EV256GM104-I/MLVAO

PIC16F18325-I/JQVAO

PIC16F1825-I/JQVAO

PIC16F15323-I/JQVAO

PIC16F15324-I/JQVAO

25LC020AT-E/MC16KVAO

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PIC18F57Q84T-E/6MXVAO

ATA663203-GBQW

ATA663211-GBQW

ATA663232-GBQW

ATA663255-GBQW

ATMEGA4809-MFR-VAO

PIC16F15354T-E/5NVAO

PIC16F1503T-E/MVVAO

PIC16F1503T-E/MGVAO

PIC16F1509T-E/GZVAO

PIC16F753T-E/MLVAO

PIC16HV753T-E/MLVAO

DSPIC33EV64GM102T-E/MMVAO

PIC18F4320-I/PT

PIC24FJ64GA008-I/PT

PIC24FJ64GA108-I/PT

PIC32MX695F512L-80V/PT

PIC32MX675F512L-80V/PT

PIC32MX675F256L-80V/PT

PIC32MX795F512L-80V/PT

PIC32MX775F512L-80V/PT

PIC32MX775F256L-80V/PT

PIC32MX675F256H-80V/PT

PIC32MX230F256D-V/PT

PIC32MX130F256D-V/PT

PIC32MX564F128L-V/PT

PIC32MX534F064L-V/PT

PIC32MX564F064L-V/PT

PIC18F26Q71-I/SO

PIC16F1936-I/SSC03

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AVR128DB28-I/SS

AVR64DB28-I/SS

LAN8651B1T-E/LMXVAO

PIC16F18046T-E/MLVAO

PIC16F18026T-E/MLVAO

DSPIC33EDV64MC205T-E/M7VAO

PIC16F1764T-E/MLVAO

PIC16F15385T-E/6MXVAO

PIC16LF15376T-E/NHXVAO

PIC16F15376T-E/MPVAO

PIC16LF15356T-E/MVVAO

ATA5293-GJQW-VA1

PIC16F15376T-E/MVVAO

PIC18F24K42T-E/5NVAO

DSPIC33CK128MC505T-I/PT

DSPIC33CK256MC105T-I/PT

DSPIC33CK128MC105T-I/PT

PIC24FJ128GL410T-I/PT

PIC18F96J94T-I/PF

PIC18F97J60T-I/PF

ATUC64D4-AUR

PIC24FJ64GU202-I/ML

PIC24FJ32GU202-I/ML

PIC24FJ64GP202-I/ML

PIC24FJ32GP202-I/ML

PIC18F14K50-I/MQ054

PIC16F916T-I/SS031

PIC16C621AT-20I/SO086

PIC18LF24K22T-I/SS

PIC16F616T-I/ST076

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24LC512T-I/SN

24AA512T-I/SN

24FC512T-I/SNC21

93C76CT-I/ST

25AA160BT-I/ST

24LC025T-I/ST

24AA025T-I/ST

24AA02E48T-I/SN

24LC02BHT-I/SN

24AA02HT-I/SN

93LC86CT-I/ST

93AA86CT-I/ST

24LCS52T-I/ST

24AA52T-I/ST

93AA46AT-I/ST

93LC46AT-I/ST

PIC16LF18875T-I/MV

PIC12F1571T-I/RF

PIC16LF18876T-I/MV

PIC16F18877T-I/MV

PIC16LF18877T-I/MV

PIC18F47K40T-I/MV

PIC18LF47K40T-I/MV

PIC16F18424T-I/JQ

PIC16F18425T-I/JQ

PIC16LF18424T-I/JQ

PIC16LF18425T-I/JQ

PIC16F18426T-I/JQ

PIC18F45K40T-I/MV

PIC18F46K40T-I/MV

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PIC18LF45K40T-I/MV

PIC18LF46K40T-I/MV

PIC16LF18426T-I/JQ

PIC16F18326T-I/JQ

PIC16F15324T-I/JQ

PIC16F15323T-I/JQ

PIC16LF15323T-I/JQ

PIC12F1571T-I/MF

PIC12F1572T-I/MF

PIC18LF2331T-I/MM

PIC18F25K80T-I/MMC04

PIC16LF1902T-I/MV

PIC16LF1903T-I/MV

PIC18LF45K42T-I/MV

PIC18LF46K42T-I/MV

PIC18F47K42T-I/MV

PIC18LF47K42T-I/MV

AT86RF215-ZUR

AT86RF215IQ-ZUR

AT86RF215M-ZUR

ATMEGA644RFR2-ZUR

ATTINY1627-MUR

ATSAMD20E14A-MUT

ATSAMD20E14A-MUTA2

ATSAMD20E15A-MUT

ATMEGA2564RFR2-ZUR

ATMEGA1284RFR2-ZUR

ATSAMD20E15A-MUTA2

ATSAMD20E16A-MUT

ATSAMD20E16A-MUTA2

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ATSAMD20E17A-MUT

ATSAMC21E17A-MNT

ATSAMC21E18A-MNT

ATSAMC20G15A-MNT

ATSAMC20G16A-MNT

ATSAMC20G17A-MNT

ATSAMC20G18A-MNT

ATSAMC21G15A-MNT

DSPIC33EP64GS504T-I/ML

93AA66CT-I/MNY

93LC66AT-I/MNY

93AA66AT-I/MNY

93LC66BT-I/MNY

PIC16F1783T-I/MV

HA7612T-I/MM033

DSPIC33EP32GS504T-I/ML

PIC24FJ128GA106T-I/MR

93LC66BT-I/MC

93AA66BT-I/MC

93C56AT-I/MNY

25LC640AT-I/MNY

25AA640AT-I/MNY

PIC24FJ256GA106T-I/MR

PIC24F04KL101T-I/MQ

11LC020T-I/MNY

11AA020T-I/MNY

PIC24F08KL301T-I/MQ020

PIC24FJ48GA004T-I/ML022

11AA161T-I/MNY

PIC16F15224-I/MG

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PIC16F877-10E/PT

PIC18F8680-E/PT

PIC18F8585-E/PT

PIC16F77-E/PT

PIC18F4431-E/PT

PIC18F4331-E/PT

PIC18F452-E/PTC34

PIC18F4420-E/PT

PIC18F6310-E/PT

PIC18F448-E/PT

PIC18F8490-E/PT

PIC18F442-E/PT

PIC18F8723-E/PREL

PIC18F4520-E/PT

PIC18F458-E/PT

PIC16LF724-E/PT

PIC18F6723-E/PREL

PIC18F8410-E/PT

PIC18F6410-E/PT

PIC18F452-E/PT

PIC18F8722-E/PT

PIC18F6628-E/PT

PIC18F8723-E/PT

PIC18F6723-E/PT

PIC24FJ256GA110-E/PF

PIC24FJ128GA110-E/PF

PIC18F4423-E/PT

PIC18F4523-E/PT

PIC18F4685-E/PT

PIC32MX530F128HT-V/PT

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PIC32MX570F512HT-V/PT

PIC32MX150F256LT-V/PT

PIC32MX170F512LT-V/PT

PIC18F26Q83T-I/SO

PIC18F26Q84T-I/SO

PIC16F15355T-I/SS

PIC16F18023T-I/ST

PIC16F18024T-I/ST

PIC16LF15354T-I/SS

PIC16LF15355T-I/SS

PIC16LF1778T-I/SS

ATTINY3226-XUR

PIC16F1778T-I/SS

PIC16F1778T-I/SSC02

ATTINY426-XUR

ATTINY826-XUR

ATTINY1626-XUR

PIC16LF15325T-I/ST

PIC16F15345T-I/SS

PIC16LF15345T-I/SS

PIC18F04Q20T-I/ST

PIC18F05Q20T-I/ST

PIC18F14Q20T-I/SS

PIC18F15Q20T-I/SS

PIC16LF1786T-I/SS

24CSM01T-I/ST

PIC18F25Q24T-I/SS

PIC18F26Q24T-I/SS

93LC46AT-I/SN

93AA46AT-I/SN

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93AA46BT-I/SN

DSPIC33FJ32GP102-I/SO

PIC16F526-I/ST

AVR32DB28-I/SS

24AA256UID-I/ST

PIC24EP256MC206T-I/PT

PIC16F18875T-I/PT

DSPIC33CK256MP206T-I/PTC05

DSPIC33CH512MP508T-I/PT

DSPIC33CH512MP208T-I/PT

DSPIC33CH256MP508T-I/PTC01

DSPIC33CH512MP208T-I/PTC02

DSPIC33AK32MC102T-I/M7

ATECC508A-MAHKN-T

DSPIC33FJ128MC804T-E/ML

PIC24FJ16MC102T-E/ML

PIC16LF1559-E/MLM10

ATSAMC21J18A-AUT64

ATSAMC21G18A-AUT64

DSPIC33EP256MC506T-I/PT

DSPIC33CK512MP306T-I/PT

DSPIC33CK512MP606T-I/PT

PIC24FJ128GA306T-I/PT026

ATSAML21G18B-AUT-SLL

DSPIC33CK64MP105T-I/PT

DSPIC33CK32MP105T-I/PT

PIC18F25J11-I/SO

PIC18F24J11-I/SO

PIC12F1840-I/SN

PIC24F08KA101-I/SS

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PIC24F08KA102-I/SS

PIC18F26K20-I/SS

HA1127-I/SS

PIC18F25K20-I/SS

PIC18F25K20-I/SSC01

PIC18F25K20-I/SSC15

DSPIC33EP32MC202-I/SS

PIC18F24K20-I/SS

PIC16F1938-I/SO

24LCS21A-I/SN

24LC21A-I/SN

PIC18F26K22-I/SO029

24LCS22A-I/SN

24LC22A-I/SN

PIC18F27K42-I/SS

PIC18LF27K42-I/SS

PIC12F615-I/SN085

24LC21-I/SN

PIC18LF26K42-I/SS

PIC18F16Q41-I/SS

PIC18F26K42-I/SS

PIC18F16Q40-I/SS

PIC12F510-I/SNC06

MCV08A-I/SN

PIC16F15223-I/ST

PIC16F15224-I/ST

PIC16LF1566-I/SS

23AA02M-I/ST

PIC16LF723-I/SS

PIC16F72-I/SS

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PIC18LF2321-I/SS

PIC16LF722-I/SS

MCP3008-I/SL

25AA320A-I/SNB22

MCP3202-CI/ST

MCP3004-I/ST

PIC16LF726-I/SO

PIC18LF2580-I/SO

PIC16LF1826-I/SS

PIC18F2221-I/SO

PIC18F2510-I/SO

PIC18LF2221-I/SS

PIC16LF1826-I/SO

PIC18LF2510-I/SO

PIC18F2321-I/SS

ATSAMC21J17A-MMNT

ATSAMC21J18A-MMNT

LAN9250TV/ML

LAN9252TV/ML

ATSAMD20E16B-MNT-SG

ATSAMDA1G16B-MBT

ATSAMDA1G15B-MBT

ATSAMDA1G14B-MBT

SY75608TWL-TR

SY75612TWL-TR

ATSAMD20G16B-MNT

ATSAMD20G14B-MNT

ATSAMD20G15B-MNT

ATSAMD21E16L-MNTA7

ATSAMD21E16L-MNTP01

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DSPIC33EP64GS504T-E/PTVAO

PIC18F46K80T-E/PTVAO-MB

PIC16LF19197T-E/PTVAO

PIC32MX270F256B-I/SS

DSPIC33FJ64GP202-I/SO

DSPIC33FJ64GP802-I/SO

DSPIC33FJ128GP202-I/SO

DSPIC33FJ128GP802-I/SO

DSPIC33FJ32GP302-I/SO

DSPIC33FJ16GP102-I/SS

PIC32MX230F256B-50I/SS

PIC32MX230F256B-I/SS

PIC32MX130F256B-50I/SS

PIC16F18323-I/ST

PIC16F1823-I/ST042

PIC16F883-I/SS

HA1930-I/SS

PIC32MX150F128B-I/SS

PIC32MX130F064B-I/SS

PIC32MX120F032B-I/SS

PIC16F883-I/SO

PIC32MX250F128B-I/SS

93LC46C-E/ST

PIC16F1518-E/SO

PIC16F1516-E/SO

24LC64F-E/ST

MCP47FVB21A1-E/ST

MCP47FVB21A2-E/ST

PIC16F1512-E/SO

PIC16F1513-E/SO

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25LC128X-E/ST

PIC18F27Q10T-I/SS

PIC18F26Q10T-I/SS

DSPIC33CK256MC502T-I/SS

DSPIC33FJ16GS402-50I/MM

DSPIC33AK128MC106-I/M7

ATSAML10E15A-MU

ATSAML10E16A-MU

ATSAML11E14A-MU

ATSAML11E15A-MU

DSPIC33AK64MC106-I/M7

DSPIC33AK32MC106-I/M7

PIC18F54Q71-I/6LX

PIC18F55Q71-I/6LX

PIC18F44Q71-I/MP

PIC18F45Q71-I/MP

AVR32EA28-I/STX

PIC16LF1847-I/ML

PIC16LF1847-I/MV

PIC16F1508-I/GZ

PIC16F1509-I/GZ

ATMEGA16L-8MUA6

PIC16F19156-I/MV

PIC16LF19155-I/MV

PIC16LF19156-I/MV

PIC16F19175-I/MV

PIC16F19176-I/MV

PIC16LF19175-I/MV

PIC16LF19176-I/MV

PIC32CM6408JH00048-I/U5B

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PD69210C-022619

PD69210R-022620

AVR128DB64-I/MR

AVR64DB64-I/MR

AVR32DU28-I/STX

AVR16DU32-I/RXB

AVR16DU28-I/STX

AVR32DU32-I/RXB

PIC16F18444-I/GZ

PIC16F18445-I/GZ

PIC16LF18444-I/GZ

PIC16LF18445-I/GZ

PIC16LF18446-I/GZ

EQCO125X40C1-I/3DW

EQCO125T40C1-I/3DW

EQCO62X20C1-I/3DW

EQCO31X20C1-I/3DW

EQCO125X40C1TB-I/3DW

EQCO125T40C1TB-I/3DW

LAN9253-I/R4X

PIC16F914-I/PTVAO

ATMXT641TD-AT-GM

AVR64DA64-I/PTVAO

PIC18F46K40-I/PTVAO

DSPIC33CK32MP105-I/PTVAO

PIC16F15385-I/PTVAO

DSPIC30F5011-30I/PTVAO

MCP47FVB08-E/MQ

DSPIC33FJ128GP802-E/MM

DSPIC33FJ32GP302-E/MM

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PIC12LF1572-I/MF

PIC32MM0064GPL020-I/ML

PIC24FJ64GA306-I/MR

PIC24FJ128GA306-I/MR

PIC16LF18313-I/RF

PIC16F1709-I/ML020

PIC16F1709-I/ML

PIC24FJ64GA002-I/ML

PIC24FJ16GA002-I/ML

MTCH810-I/MF

PIC24FJ128GA006-I/MR

PIC24FJ96GA006-I/MR

PIC24FJ64GA006-I/MR

PIC16F1705-I/ML

PIC32MM0016GPL020-I/ML

PIC32MM0032GPL020-I/ML

PIC32MM0064GPL028-I/ML

PIC16LF1938-I/ML

PIC16LF1939-I/MV

PIC16LF1939-I/ML

PIC16F1938-I/ML

PIC32MM0016GPL028-I/ML

PIC32MM0032GPL028-I/ML

PIC24FJ32GA002-I/ML

PIC24FJ48GA002-I/ML

DSPIC33EP128GS702-I/MM

DSPIC33EP128GS704-I/ML

DSPIC33EP128GS804-I/ML

DSPIC33EP64GS804-I/ML

PIC16F1718-I/ML

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PIC18F25K80-I/MM030

HA7617-I/ML035

PIC16F1713-I/MV

PIC16F1716-I/MV

PIC12F1840-I/RF

PIC16LF1718-I/MV

DSPIC33FJ16GS504T-E/ML

MCP4661T-104E/ML

MCP629T-E/ML

MCP98244T-BE/MNYAC

MCP4661T-103E/ML

MCP4661T-503E/ML

MCP4661T-104QE/ML

MCP4661T-503QE/ML

24FC01T-E/MUY

DSPIC33FJ256GP506AT-E/MR

PIC24HJ16GP304T-E/ML

PIC24HJ32GP204T-E/ML

PIC16F18124-E/STVAO

MCP3208-CI/SLVAO

PIC24FJ256GA705-I/PTC03

PIC32MX250F128D-I/PT

PIC16C774/L

PIC16LC774/L

HV20220PJ-G

HV20220PJ-G-S323

HV2301PJ-G

HV2201PJ-G

HV219PJ-G

TC7129CLW

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATF22V10C-5JX

ATF750C-7JX

ATF1502AS-7JX44

MT8812AP1

ATMEGA128-16ANR

ATMEGA128L-8ANR

ATMEGA128A-ANR

ATMEGA88PA-ANR

ATMEGA164PA-ANR

ATMEGA325A-ANR

ATMEGA64L-8AQR

ATMEGA164P-20AQRA1

ATMEGA32A-ANR

ATMEGA328PB-ANR

ATMEGA168PA-ANR

ATMEGA48PA-ANR

ATMEGA16L-8AQRA5

ATXMEGA192A3U-ANR

ATXMEGA256A3U-ANR

ATXMEGA32D4-ANR

ATMEGA324PA-ANR

ATMEGA169PA-ANR

ATMEGA165P-16ANR

ATMEGA64A-ANR

ZL30291LDG1

ZL30292LDG1

ATMEGA324PB-ANR

AT89C51RC2-SLSUM

AT89C51IC2-SLSUM

AT89C51ED2-SLSUM

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AT89C51ID2-SLSUM

AT89C51RD2-SLSUM

AT89C51AC3-SLSUM

MCP4912-E/ST

MCP4641-502E/ST

93C66-E/SN

MCP4801-E/SN

MCP4811-E/SN

24LC256-E/ST

24LC256-E/STRVE

PIC24FV16KA301-E/SS

MCP6242-E/SN

PIC24FV32KA301-E/SS

PIC18F13K22-E/SS

MCP634-E/ST

PIC16F722-E/SS

PIC16F722-E/SO

PIC18F1230-E/SS

PIC18F1330-E/SS

PIC18F1330-E/SSC02

PIC16F723-E/SS

PIC16F723-E/SO

PIC16F1827-E/SO

PIC16F1826-E/SO

PIC18F2585-E/SO

93LC86B-E/ST

93LC86A-E/ST

MCP6H74-E/ST

PIC16LF1933-E/SS

MCP4661-103PE/ST

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PIC24EP512GP206-H/PT

PIC24EP512MC206-H/PT

DSPIC33CK1024MP406-H/PT

DSPIC33CK1024MP706-H/PT

DSPIC33CK512MP406-H/PT

DSPIC33CK512MP706-H/PT

DSPIC33CK256MP406-H/PT

DSPIC33CK256MP706-H/PT

DSPIC33CK1024MP410-H/PT

DSPIC33CK512MP410-H/PT

DSPIC33CK512MP710-H/PT

DSPIC33CK256MP410-H/PT

DSPIC33CK256MP710-H/PT

DSPIC33CK1024MP408-H/PT

DSPIC33CK1024MP708-H/PT

MTD6508T-ADJE/JQ

MCP4551T-104E/MF

MCP4551T-503E/MF

PIC16F1825T-E/JQ

PIC32CM5164JH01100-I/PF

ATSAMD21E17A-AU

PIC18F46Q84-I/PT

AGL030V2-VQ100I

AGL030V2-VQG100I

AGL030V5-VQ100I

AGL030V5-VQG100I

ATSAMD21G18A-AU

ATSAMD21G17A-AU

ATSAMD21G17A-AUA1

PIC16LF1554T-I/MLVAO

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A3P125-VQG100

AGL060V2-VQ100

PIC18LF4220-I/PT

PIC18F6520-I/PTC08

PIC18F4523-I/PT

PIC18F4220-I/PT

PIC18F86J50-I/PT

93C56CT-I/SN

93C56AT-I/SN

93C56BT-I/SN

MCP41100T-I/SN

93LC46CT-I/SN

93AA46CT-I/SN

93C66CT-I/SN

93C66AT-I/SN

93C66BT-I/SN

25AA160BT-I/SN

25LC160AT-I/SN

PIC18F26K22T-I/ML030

PIC18F43K22T-I/MP

MCP73838-FJI/MF

PIC16F72-I/ML

MCP73871-1AAI/ML

24AA16-I/MC

MCP73834-GPI/MF

MCP73834-NVI/MF

PIC18F2420-I/ML

PIC16LF72-I/ML

MCP73871-1CCI/ML

MCP73871-2AAI/ML

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MCP73871-3CAI/ML

MCP73871-3CCI/ML

MCP73871-4CAI/ML

ATSAMD20J15A-MMN

ATSAMD20J16A-MMN

ATSAMD20J17A-MMN

SY75603ATWL

SY75604ATWL

SY75603BTWL

SY75604BTWL

PIC32MX170F256D-V/ML

PIC32MX270F256D-V/ML

LAN9250V/ML

LAN9252V/ML

ECC204-MAVMD-B

PIC32MX270F512H-V/MR

PIC32MX570F512H-V/MR

SY75612TWL

ATSAMD20G16B-MN

ATSAMD20G14B-MN

ATSAMD20G15B-MN

SY75608TWL

ATMEGA644PA-MN

AT90PWM161-16MN

ATMEGA324P-20MQ

ATMEGA168PB-MN

ATTINY817-MN

ATMEGA16-16MQ

ATMEGA644PV-10MQ

ATMEGA644P-20MQ

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ATMEGA88PB-MN

PIC16LF18324-I/JQVAO

PIC18F25K40-I/MVVAO

MCP1722-5012H/Q8BVAO

MCP1722-3312H/Q8BVAO

MCP1722-5010H/Q8BVAO

MCP1722-3310H/Q8BVAO

PIC16F1933-I/MLVAO

PIC32MM0256GPM028-I/MLVAO

PIC16LF18857-I/MLVAO

KSZ8051MNLU-VAO

PIC32MX664F128H-V/PT

PIC32MX664F064H-V/PT

PIC24FJ128GA106-I/PT

PIC24FJ128GA106-I/PTA5

ATSAMD20E18A-AU

AVR128DB48-I/6LX

AVR128DA32-I/RXB

ATMEGA1284P-MU

ATMEGA1284-MU

ATSAMD21G17D-MU

ATSAMD21G17L-MU

PIC16F15325-I/JQ

PIC32MZ1024EFE100-E/PT

PIC32MZ1024EFF100-E/PT

PIC32MZ1024EFH064T-E/PT

PIC32MZ1024EFK064T-E/PT

ATSAMD21G16B-AFT

ATSAMD21G15B-AFT

DSPIC33CK32MP506-H/PT

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DSPIC33CK256MP208-H/PT

DSPIC33CK256MP508-H/PT

DSPIC33CK128MP208-H/PT

DSPIC33CK128MP508-H/PT

DSPIC33CK64MP208-H/PT

DSPIC33CK64MP508-H/PT

DSPIC33CH512MP205-H/PT

DSPIC33CH256MP505-H/PT

DSPIC33CH512MP505-H/PT

DSPIC33CH256MP205-H/PT

DSPIC33FJ128GP804-H/PT

DSPIC33FJ128MC804-H/PT

DSPIC33CK256MP206-H/PT

DSPIC33CK256MP506-H/PT

DSPIC33CK128MP206-H/PT

DSPIC33CK64MP206T-E/PTC02

DSPIC33EP32GS506T-E/PT

ATMEGA1609-AFR

ATMEGA809-AFR

DSPIC33CK64MP105T-E/PT

DSPIC33CK32MP105T-E/PT

AVR32DA32T-E/PT

PIC24EP32GP204T-E/PT

DSPIC33EP64GS506T-E/PTRB3

PIC16F17574-E/MP

PIC16F17575-E/MP

PIC16F17576-E/MP

PIC16F17554-E/STX

PIC16F17555-E/STX

PIC16F17556-E/STX

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AVR32SD32-E/QZB

TA010-TFLXUCZ-VU

93C66BT-E/SN

25LC160BT-E/SN

93LC66CT-E/SN

93C46CT-E/SN

PIC12LF1572T-E/SN

25LC640T-E/SN

25LC320T-E/SN

25C320T-E/SN

25LC080AT-E/SN

PIC18F26K40-I/SSC03

PIC18F26K40-I/SS

25A512-I/ST

PIC16F870-I/SO

PIC16LF18323-I/ST028

ATMEGA808-XU

HSA2-040SAA/A2320A

PIC16F15325-I/ST

PIC16F18854-I/SS

23K256-I/ST

23K640-I/ST

PIC16F1823-I/ST041

ATMEGA1608-XU

PIC18F26K80-I/SS

23A256-I/ST

DSPIC33FJ16GP102-I/ML

PIC32MX675F256H-80I/MR

DSPIC33FJ16MC102-I/ML

PIC24FJ16MC102-I/ML

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DSPIC30F2010-20I/MM

DSPIC30F2010-30I/MM

DSPIC33EP32MC504-I/ML

PIC24EP32MC204-I/ML

PIC32MX210F016D-I/ML

DSPIC33EP256GP504-I/ML

PIC32MX575F512H-80I/MR

PIC32MX575F256H-80I/MR

PIC32MX695F512H-80I/MRD21

PIC24HJ64GP204T-I/ML

PIC24HJ64GP504T-I/ML

PIC32MX564F064HT-I/MR

PIC24FJ32MC102T-I/ML

PIC32MX130F064BT-I/ML

PIC32MX270F256DT-50I/ML

34AA04T-I/MNY

DSPIC33EV32GM102T-I/MM

DSPIC33EV128GM006T-I/MR

PIC24FJ1024GA606T-I/MR

PIC32MX250F128BT-I/ML028

DSPIC33FJ16MC102T-I/ML

PIC24FJ16MC102T-I/ML

DSPIC33EV128GM106T-I/MR

DSPIC33FJ16MC304-E/ML

DSPIC33FJ32MC204-E/ML

DSPIC33EP64GP504-E/ML

PIC24EP64GP204-E/ML

PIC18F65K22-E/MR

PIC16F1787-E/ML

PIC16F1823-E/ML

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MCP3910A1-E/ML

MCP3918A1-E/ML

PIC16F1459-E/ML

PIC16LF1788-E/ML

PIC16LF1789-E/MV

PIC16LF1789-E/ML

MCP25625-E/ML

PIC16LF1503-E/MG

PIC16F1825-E/ML

DSPIC30F3011T-20E/PT

DSPIC33EP256MU806T-E/PT

HA7619T-I/ML025

PIC32MX150F128DT-50I/ML

PIC32MX250F128DT-50I/ML

PIC24EP64GP204T-I/ML

DSPIC33FJ06GS202T-I/MM

PIC32MX575F512HT-80I/MR

DSPIC33FJ06GS102T-I/MM

PIC32MX575F256HT-80I/MR

PIC32MX274F256DT-I/ML

PIC32MX154F128DT-I/ML

DSPIC33FJ32MC202T-I/MM

PIC24EP256GP204T-I/ML029

SYCUSTDIP1-TR

PD69210R-022420-TR

PD69210C-022419-TR

AT24C08C-MAHM-T

AT24C08C-MAHM-E

PIC18F14K50T-I/MQ045

PIC18F14K50T-I/MQ047

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PIC18F14K50T-I/MQ048

PIC18F14K50T-I/MQ051

PIC24EP256GU810T-E/PF

PIC24EP512GU810T-E/PF

PIC24EP256GU810T-E/PT

PIC24EP512GU810T-E/PT

DSPIC33FJ16GS504T-E/PT

24C02CT/SN

24C01CT/SN

93LC66AT/SN

93LC66BT/SN

93LC56AT/SN

93LC56BT/SN

34VL02T/SN

24LC08BT/SNRVE

24LC16BT/SNRVE

DSPIC33EV64GM104-E/PT

DSPIC33EV32GM004-E/PT

DSPIC33EV256GM004-E/PT

DSPIC33EV256GM104-E/PT

DSPIC33FJ256GP710A-E/PF

DSPIC33FJ256MC510A-E/PF

DSPIC33FJ256MC710A-E/PF

DSPIC33EP128GS706-E/PT

DSPIC33EP128GS806-E/PT

DSPIC33EP64GS806-E/PT

ATMXT1296M1E-ARVAO

ATMXT1296M1E-ARMKVAO

MCP47FEB22A0-E/ST

MCP47FEB01A2-E/ST

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MCP47FVB12A2-E/ST

MCP47FEB01A0-E/ST

MCP47FVB12A3-E/ST

MCP47FVB21A0-E/ST

MCP47FVB01A2-E/ST

MCP47FVB01A3-E/ST

93LC46B-E/ST

MCP47FVB02A1-E/ST

MCP47FVB02A2-E/ST

AVR128DA28-I/SO

PIC16F18156-I/SS

PIC18F16Q20-I/SS

PIC16F17144-I/SS

PIC16F18144-I/SS

PIC16F17145-I/SS

PIC16F17156-I/SS

PIC18F06Q20-I/ST

PIC16LF15323-I/ST

MIC2179-3.3YSM

AVR32EA28-I/SS

93AA46AE48-I/SN

PIC16LF1936-I/SO

PIC16F18424-I/ST

DSPIC33CK128MC105-I/PTVAO

PIC16LC620A-04/SO

PIC16C62B-20/SO

PIC16LC62B-04/SO

PIC16C621A-04/SO

PIC16C621A-20/SO

PIC16LC621A-04/SO

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CF775-04/SO

PIC16F1716T-I/SS

HS12-100P0/12PS0FTR

PIC16F18425-I/ST

PIC16LF18425-I/ST

PIC16LF18424-I/ST

PIC16F18426-I/ST

PIC16LF18426-I/ST

PIC32MK0128MCA028-I/N2X

PIC16F1765-I/ST

PIC16F1764-I/ST

AVR16EA28-I/SS

PIC16F505T-I/ST061

PIC16LF1554T-I/ST

PIC16LF723AT-I/SS

MCP602T-I/SN

25AA640AT-I/SN

25AA640AT-I/SNB23

25LC640AT-I/ST

25AA640AT-I/ST

25LC640AT-I/SN

PIC16F1786T-I/SS

PIC18F14K50T-I/SS042

HSA0100SI/A0SS0BTR

HSA0-040SIA/A0SS10TR

PIC16F1828T-I/SS027

PIC16F1828T-I/SS023

PIC16F1828T-I/SS024

MCP47FVB02A3-E/ST

MCP47FVB11A0-E/ST

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MCP47FVB11A2-E/ST

MCP47FVB11A3-E/ST

PIC24HJ256GP610A-H/PT

DSPIC33FJ256GP710A-H/PT

DSPIC33FJ256MC710A-H/PT

DSPIC33CH64MP508-H/PT

DSPIC33CH128MP508-H/PT

DSPIC33CH64MP208-H/PT

DSPIC33CH128MP208-H/PT

PIC24HJ256GP610A-H/PF

DSPIC33CH512MP508-H/PT

DSPIC33CH512MP208-H/PT

DSPIC33CH256MP508-H/PT

DSPIC33CH256MP208-H/PT

DSPIC33EV256GM004-H/PT

DSPIC33EV256GM104-H/PT

DSPIC33EV128GM004-H/PT

DSPIC33EV128GM104-H/PT

DSPIC33EV64GM004-H/PT

DSPIC33EV64GM104-H/PT

DSPIC33EV256GM006-H/PT

DSPIC33EV256GM106-H/PT

DSPIC33EV128GM006-H/PT

DSPIC33EV128GM106-H/PT

DSPIC33EV64GM006-H/PT

DSPIC33EV64GM106-H/PT

DSPIC33EV32GM004-H/PT

DSPIC33EV32GM104-H/PT

PIC16F870-I/SS

MCP2140A-I/SS

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PIC16C781-I/SS

RE46C119S16F

RE46C100S8F

PIC16LC620A-04I/SS070

PIC18F24J10-I/SS

PIC16LF870-I/SS

24FC512-I/ST14

PIC18LF13K50-I/SS

PIC18LF25J10-I/SO

PIC18F2220-I/SOC03

PIC18LF25J10-I/SS

PIC18F25J10-I/SS

PIC18LF25K80-I/SS

PIC18LF26K80-I/SS

PIC16LF72-I/SS

PIC18LF2320-I/SOC08

PIC18F25J10-I/SO

24C02C-I/ST

MCP3208-CI/SL

MCP23016-I/SS

PIC16F873A-I/SS

25AA640AX-I/ST

25LC640AX-I/ST

PIC18F2320-I/SOC07

PIC18LF2553-I/SOHLF

25LC128X-I/ST

PIC18F27J13-I/SO

MCP3202-BI/SN

MCP3202-CI/SN

PIC16F610-I/ST

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24AA64X-I/ST

PIC16C622A-20I/SSHXX

ATSAML10E16A-AUT

ATSAML11E14A-AUT

ATSAMD20E18A-AUT

ATSAML11E15A-AUT

ATSAML11E16A-AUT

ATSAML11E16A-AUTKPH

ATSAMD20E15A-AUTA2

ATSAMD20E14A-AUTA2

ATSAMD20E17A-AUTA2

PIC18F43K22T-I/PT

AVR128DB32T-I/PT

ATSAMD20E18A-AUTA2

ATSAMD20E16A-AUTA2

MCP4011-502E/SN

MCP4011-503E/SN

MCP4342-103E/ST

MCP2551-E/SN

MCP4641-104E/ST

MCP4641-503E/ST

MCP4641-103E/ST

25LC640AX-E/ST

PIC18F14K50-E/SS

PIC16LF1847-E/SO

MCP4901-E/SN

PIC16F1933-E/SS

PIC16F1933-E/SO

MCP4911-E/SN

MCP6071-E/SN

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC12LF1822-E/SN

MCP4342-104E/ST

MCP4342-503E/ST

MCP6H04-E/ST

MCP6061-E/SN

PIC16LC717-E/SS

24LC08B-E/ST

PIC18F25K22-E/SS

MCP4902-E/ST

MCP654-E/ST

MCP6444-E/ST

MCP4332-502E/ST

MCP4332-103E/ST

MCP4332-104E/ST

MCP4332-503E/ST

PIC16F1508-E/ML

PIC16F1509-E/ML

PIC16F18126-E/7N

ATSAMD20E16B-MZ

ZL88109LDG1

ZL88105LDG1

ZL88107LDG1

PIC32MX220F032B-I/ML

PIC18LF24K50-I/ML

PIC18LF25K50-I/ML

PIC18F25Q10-I/ML

LE9632RQC

ZL88701LDG1

DSPIC33FJ128GP204-I/ML

DSPIC33FJ128GP804-I/ML

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CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

DSPIC33FJ32GP304-I/ML

DSPIC33FJ64MC204-I/ML

ATTINY88-MU

PIC32MX564F128H-I/MR

PIC32MK0512MCF064-I/MR

PIC24EP512GP206-I/MR

ATMEGA4809-AFR

PIC32MK0512GPK100T-E/PT

PIC32MK0512MCM100T-E/PT

PIC32MK1024GPK100T-E/PT

DSPIC33FJ16GP304T-E/ML

DSPIC33EP256MU806T-E/MR

PIC16F628AT-I/SS

PIC16LF628AT-I/SS

PIC16LF1828T-I/SS020

PIC16LF1828T-I/SS021

25LC080AT-I/SN

25AA080AT-I/SN

25LC160BT-I/SN

PIC18LF67K40-E/MR

PIC18F25K40-E/MV

PIC10F322-E/MC

MCP47CMB14-E/ML

MCP47CVB04-E/ML

MCP47CMB24-E/ML

MCP47CVB14-E/ML

MCP47CVB24-E/ML

MCP48CMB28-E/ML

PIC32MZ2048ECG064-I/MR

ATSAMC21E17A-MZT

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

ATSAMC21E16A-MZT

ATSAMC21E15A-MZT

DSPIC33CK512MP405T-E/M7

DSPIC33CK512MP705T-E/M7

DSPIC33CK256MP405T-E/M7

DSPIC33CK256MP705T-E/M7

DSPIC33CK1024MP406T-E/MR

PIC16LF18854T-E/ML

ATSAMD21E17D-MZT

34AA02T-I/MNYB22

24FC16T-I/Q4B

24FC08T-I/Q4B

PIC16F18875T-I/ML

24LCS52T-I/MNY

PIC18F46J13-I/PT

PIC24FJ128DA210-I/PT

PIC24FJ256DA110-I/PT

PIC24FJ128DA110-I/PT

PIC16F707-I/PT

PIC24FJ64GA010-I/PF

PIC18F44J50-I/PT

DSPIC33CK512MP406-E/PT

DSPIC33CK512MP706-E/PT

DSPIC33CK256MP406-E/PT

DSPIC33CK256MP706-E/PT

DSPIC33CK1024MP410-E/PT

DSPIC33CK512MP410-E/PT

ATMEGA808-AF

ATMEGA1608-AF

DSPIC33CK512MP710-E/PT

Date: Tuesday, July 22, 2025

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DSPIC33CK256MP410-E/PT

DSPIC33CK256MP710-E/PT

DSPIC33CK1024MP408-E/PT

A3P250-1VQG100T

A3P060-1VQG100T

A3P060-VQG100T

A3P125-1VQG100T

PIC18F8720-E/PT

PIC18F8620-E/PT

PIC18F4580-I/ML

PIC16F882-I/ML

MCP23016-I/ML

PIC16LF76-I/ML

MCP73833-6SI/MF

MCP73833-AMI/MF

MCP73833-B6I/MF

MCP73833-BZI/MF

PIC16LF73-I/ML

PIC16F73-I/ML

MCP73834-YAI/MF

MCP73837-FCI/MF

LAN7800T-I/Y9X

ATTINY461A-MUR

ATTINY261A-MUR

ATSAMD21E16B-MUT

ATSAMD21E15B-MUT

24LC024T-I/MNY

DSPIC33FJ06GS202A-I/SS

DSPIC33FJ06GS102A-I/SO

PIC18LF14K22-I/SS

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PIC12F1572T-I/RF

PIC12LF1571T-I/RF

PIC12LF1572T-I/RF

PIC16F18313T-I/RF

PIC16LF1786-I/ML

PIC16F1828-I/ML

PIC16LF1787-I/MV

PIC16F1823-I/ML

PIC18LF4455-I/ML

24LC08B-I/MC

PIC18F44K22-I/MV

PIC16F1789-I/ML

PIC18F43K22-I/MV

PIC18F46K22-I/MV

PIC18F14K22-I/ML

PIC12F519-I/MC

PIC16LF1787-I/ML

PIC18F14K50-I/MQ

PIC16LF18313T-I/RF

PIC16F15313T-I/RF

PIC16LF15313T-I/RF

PIC16LF1567T-I/MV

PIC16F1777T-I/MV

PIC16F1507-H/MLVAO

DSPIC33EDV64MC205-H/M7VAO

PIC16F1508-H/MLVAO

PIC16F1615-H/MLVAO

DSPIC33CK128MC105-H/M7VAO

DSPIC33CK256MC505-H/M7VAO

DSPIC33AK64MC102-H/M7VAO

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DSPIC33AK128MC102-H/M7VAO

MCP2557FD-H/MFVAO

DSPIC33CK512MP606-H/MRVAO

DSPIC33CK256MP606-H/MRVAO

DSPIC33CK1024MP405-H/M7VAO

93LC56CT-E/MC15KVAO-GM

ATA5293-GJQW-VAO-BW

PIC16F17124-E/ST

PIC16F18124-E/ST

PIC16F17125-E/ST

PIC16F18125-E/ST

AVR64DD28-E/SS

PIC16F1938-E/SS

PIC16F753-E/ST

PIC16HV753-E/ST

AVR32DD28-E/SS

AVR16DD28-E/SS

PIC16F19155-E/SS

PIC12F635-E/SN

PIC16F1829-E/SS

PIC16LF1824-E/ST

MTCH1060-E/SS

PIC16F15324-E/ST

PIC16F17155-E/SS

PIC16F18155-E/SS

PIC16F17156-E/SO

PIC16F18156-E/SO

PIC16F17154-E/SO

PIC16F18154-E/SO

PIC16F17155-E/SO

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PIC16F18155-E/SO

DSPIC33CK128MC502-E/SS

DSPIC33CK256MC102-E/SS

DSPIC33CK128MC102-E/SS

PIC16F17156-E/SS

PIC16F18156-E/SS

PIC16F17154-E/SS

PIC16F18154-E/SS

24FC256-E/ST

PIC16LF1508-E/SS

PIC16LF1509-E/SS

DSPIC33EV64GM002-E/SS

DSPIC33EV64GM102-E/SS

ATTINY3227-MUR

PIC24FJ256GA702T-I/ML

PIC24FJ128GA702T-I/ML

PIC24FJ64GA702T-I/ML

ATSAMG55J19B-MUTC21

LAN9250TI/ML

ATSAML10E14A-AF

ATSAML10E15A-AF

ATSAML10E16A-AF

ATSAML11E14A-AF

ATSAML11E15A-AF

ATSAML11E16A-AF

ATSAML10E16A-AZ

ATSAML10E15A-AZ

ATSAML11E15A-AZ

ATSAML11E16A-AZ

PIC16F18076-E/PT

Date: Tuesday, July 22, 2025

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PIC18F45K50-E/PT

PIC16LF15375-E/PT

PIC16LF15376-E/PT

ATSAME54N20A-AZ-RB

ATSAMD51N20A-AZ

AVR128DB64-E/PT

AVR64DB64-E/PT

ATSAMC20J18A-AZ

ATSAMC21J17A-AZ

ATSAMC20J17A-AZ

ATSAMC21J16A-AZ

ATSAMC20J16A-AZ

ATSAMC20J15A-AZ

ATSAMC21J15A-AZ

ATSAMC21J18A-AZ

AVR16EB32-E/PT

PIC18F45Q43-E/PT

PIC18F55Q43-E/PT

PIC32CM2532JH00032-E/PT

PIC32CM2532JH01032-E/PT

DSPIC33CH512MP508-E/PTC01

PIC16F19175-E/PT

PIC16F19176-E/PT

PIC16LF19175-E/PT

PIC16LF19176-E/PT

PIC16F19185-E/PT

PIC16F19186-E/PT

PIC16LF19185-E/PT

PIC16LF19186-E/PT

DSPIC33CK256MC506-E/PT

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DSPIC33CK128MC506-E/PT

DSPIC33CK256MC106-E/PT

DSPIC33CK128MC106-E/PT

DSPIC33CK512MPT608-E/PT-TCSM

DSPIC33CK256MPT608-E/PT-TCSM

PIC18F45Q24-E/PT

PIC18F46Q24-E/PT

PIC18F55Q24-E/PT

PIC18F56Q24-E/PT

PIC18F57K42-E/PT

PIC18LF57K42-E/PT

PIC32CM5164JH01048-E/Y8X-SL3

PIC16F1769T-I/SS

PIC16F1768T-I/SS

PIC16LF1769T-I/SS

PIC18F27Q10-I/SO

PIC16F630-I/ST

PIC16F676-I/ST

PIC16F18044-I/SS

PIC16F18045-I/SS

DSPIC30F3013-20I/SO

DSPIC30F3013-30I/SO

PIC24HJ64GP502-I/SOA21

PIC16F18056-I/SO

PIC18F26Q10-I/SO

DSPIC30F3010-20I/SO

DSPIC33FJ12GP202-I/ML

DSPIC33FJ12MC202-I/ML

DSPIC33FJ06GS202A-I/MM

PIC32MX170F256B-I/ML

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PIC32MX270F256B-I/MLG21

DSPIC33EP256GP506-I/MR

PIC32MX270F256B-I/ML

DSPIC33EP256MC204-I/ML

ATTINY861A-MU

DSPIC33FJ128MC804-I/ML

DSPIC33FJ32MC304-I/ML

DSPIC33EP256MC504-I/ML

DSPIC30F4013-30I/MLB31

DSPIC33FJ64MC802-I/MM

DSPIC33FJ128MC202-I/MM

DSPIC33FJ128MC802-I/MM

DSPIC33FJ32MC302-I/MM

DSPIC33FJ06GS102A-I/MM

DSPIC33FJ09GS302-I/MM

HA7619-I/MM028

DSPIC33FJ128GP202-I/MM

DSPIC33FJ128GP802-I/MM

DSPIC33FJ32GP302-I/MM

DSPIC33FJ64MC202-I/MM

PIC24HJ128GP502-I/MM

PIC24HJ32GP302-I/MM

DSPIC33FJ64GP202-I/MM

DSPIC33FJ64GP802-I/MM

PIC24HJ64GP202-I/MM

PIC24HJ64GP502-I/MM

PIC24HJ128GP202-I/MM

DSPIC33FJ32MC102-I/ML

ATMEGA3209-MU

PIC32MX450F256H-I/MR

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ATMEGA328P-MU

PIC12F510-I/MC

DSPIC33FJ64MC804-I/ML

DSPIC33FJ128MC204-I/ML

PIC24FJ32MC102-I/ML

PIC18LF47K42-I/MV

PIC18F47K42-I/ML

PIC18LF47K42-I/ML

ATSAMD20G16A-MU

ATSAMD20G17A-MU

PIC24FJ32GA102T-I/ML

PIC12F1822T-I/RF

PIC12F1840T-I/RF

PIC12LF1840T-I/RF

93C66CT-I/MNY

93C66AT-I/MNY

93C66BT-I/MNY

93C66CT-I/MC

93C66AT-I/MC

25LC320AT-I/MNY

25AA320AT-I/MNY

PIC16F688-I/ML

MCP73838-FCI/MF

ATA8520-GHQW

ATSAML21J18B-MMNT

ATSAML21J17B-MMNT

ATSAMD20J16B-MMNT

ATSAMD20J14B-MMNT

ATSAMD20J15B-MMNT

ATA8710-GHQW

Date: Tuesday, July 22, 2025

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ATSAMD20J18A-MMNT

ATSAMD20J14A-MMNT

ATSAMD20J15A-MMNT

ATSAMD20J16A-MMNT

ATSAMD20J17A-MMNT

ATSAML21J16B-MMNT

ATSAMD21G16L-MNT

ATSAMD21G16L-MNTA7

ATSAMD21G16L-MNTP01

SY75603ATWL-TR

PIC24HJ128GP510-I/PF

PIC24HJ256GP210-I/PF

MCP79412T-I/MNY

PIC16LF1826T-I/MV

PIC16F722AT-I/ML

PIC16F723AT-I/ML

PIC10F200T-I/MC

PIC10F202T-I/MC

PIC16LF1826T-I/ML

PIC12F752T-I/MF

PIC16F1519T-I/MV

PIC18F24K20T-I/ML

MCP73833T-CNI/MF

PIC16C620AT-04/SS

PIC16C56AT-20/SS021

PIC16F84AT-20/SS

PIC16F628T-04/SS

PIC16C771T/SS

PIC16LC711T-04/SS

PIC16LC554T-04/SS

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PIC16C622AT-04/SO

24AA64XT/ST

ENC28J60T/SS

PIC16C72AT-04/SS

HS12-100P0S/12PS30TR

PIC16C72AT-04/SO

PIC12F508-I/SN080

PIC18LF1220-I/SS

DSPIC33EV64GM006T-E/MRVAO

ATSAMC21E18A-MZTVAO

ATSAMC21E16A-MZTVAO

ATSAMC21E17A-MZTVAO

PIC16F876T-20/SO

ATSAMC20N18A-AZ

ATSAMC20N17A-AZ

PIC24HJ64GP504-E/PT

DSPIC33FJ64GP204-E/PT

DSPIC33FJ64MC804-E/PT

AVR64DA64-E/PT

AVR64DA32-E/PT

AVR64DA48-E/PT

PIC18LF55K42-E/PT

PIC18F55K42-E/PT

PIC18LF56K42-E/PT

PIC18F56K42-E/PT

PIC16LF1777-E/PT

PIC16LF1779-E/PT

PIC16LF18875-E/PT

PIC16F18074-E/PT

PIC16F18075-E/PT

Date: Tuesday, July 22, 2025

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PIC16LF1789-E/PT

PIC16F18855T-I/MLC01

PIC16F18856T-I/ML

PIC16LF18856T-I/ML

PIC16F15274T-I/MP

PIC16F690T-I/ML

AR1020T-I/ML

AR1011T-I/ML

AR1021T-I/ML

PIC18F14K22T-I/ML

PIC18F13K22T-I/ML020

PIC18F13K22T-I/ML

PIC16F1503T-I/MG043

PIC16F1503T-I/MG048

PIC16F18854T-I/ML

PIC16LF18854T-I/ML

PIC16F18857T-I/ML

PIC16LF18857T-I/ML

PIC18F27K40T-I/ML

ATSAMD20E16B-MUTN01

PIC18LF27K40T-I/ML

PIC18F24K42T-I/ML

PIC18F25K42T-I/ML

PIC18LF24K42T-I/ML

PIC18LF25K42T-I/ML

PIC16F1614T-I/ML

PIC18F2523T-I/ML

ATSAMD21E17D-MUT-SLL

PIC18F26K40T-I/ML

PIC18LF26K40T-I/ML

Date: Tuesday, July 22, 2025

CENO-16EGCZ399 - CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

PIC18F24K40T-I/ML

PIC16F1709T-I/ML020

PIC16F1709T-I/ML

MCP73871T-4CCI/ML

MCP73871T-1AAI/ML

MCP73871T-1CAI/ML

MCP73871T-1CCI/ML

MCP73871T-3CCI/ML

PIC32MX664F064L-I/PT

MCP47FVB11A3T-E/ST

MCP47FVB12A2T-E/ST

MCP47FVB12A3T-E/ST

MCP47FVB01A2T-E/ST

PIC24FJ32GA104-I/ML026

PIC16F1825-I/JQ

MCP2200-I/MQ031

PIC16LF18345-I/GZ

MCP2200-I/MQRVB

MCP2210-I/MQ

PIC16F1847-I/SO

24FC128-I/ST

PIC16F1933-I/SS

PIC24F16KL401-I/SS

PIC24F08KL401-I/SS

PIC24F08KL301-I/SS

PIC24F08KL201-I/SS

DSPIC33FJ32MC202-I/SO023

DSPIC33FJ32MC202-I/SOC21

PIC16LF1783-I/SS

PIC24F04KL101-I/SS

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24AA32AF-I/ST

24AA64-I/ST

24FC64-I/ST

24LC32A-I/ST

24LC512-I/ST

24AA64F-I/ST

24FC512-I/ST

HA0130-I/SS

93AA66A-I/ST

93LC66B-I/ST

93LC66C-I/ST

93C56A-I/ST

93C56B-I/ST

PIC24F08KL302-I/SS

PIC24F08KL402-I/SS

PIC24F16KL402-I/SS

93LC46C-I/ST

93LC56A-I/ST

93LC56B-I/ST

93LC56C-I/ST

MCP6002-I/SN

93C46B-I/ST

PIC16F1516-I/SO

PIC16F1518-I/SO

24LC64F-I/ST

24FC64F-I/ST

24LC64-I/ST

PIC16F631-I/SS

PIC16LF876A-I/SS

93AA46C-I/ST

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25AA128X-I/ST

93LC86A-I/ST

93AA86A-I/ST

93LC86B-I/ST

93AA86B-I/ST

PIC16LF1778-E/SS

ATTINY3226-XF

PIC16F1778-E/SS

ATTINY426-XF

ATTINY826-XF

93LC56A-E/SN

ATTINY1626-XF

93C56C-E/SN

93C66C-E/SN

PIC16F18023-E/ST

DSPIC33CK64MP102-E/SSC02

PIC16LF15325-E/ST

PIC16LF15345-E/SS

PIC18F04Q20-E/ST

PIC18F05Q20-E/ST

PIC18F14Q20-E/SS

PIC16LF1786-E/SS

PIC18F26Q24-E/SS

PIC18F26Q24-E/SO

PIC18F15Q20-E/SS

AVR32SD28-E/SS

AVR32SD20-E/SS

PIC18F24Q24-E/SS

PIC18F25Q24-E/SS

PIC18F66K80T-E/PT

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PIC18F6722T-E/PT

DSPIC33FJ256GP506AT-E/PT

DSPIC33EP256MU810T-E/PT

DSPIC33EP512MU810T-E/PT

DSPIC33EP256MU810T-E/PF

DSPIC33EP512MU810T-E/PF

ATMEGA64-16AURA0

ATMEGA6450A-AUR

ATMEGA6490A-AUR

ATMEGA6490P-AUR

ATMEGA649V-8AUR

ATMEGA64L-8AURA1

MCP73871T-3CAI/ML

PIC16F785T-I/ML

PIC16HV785T-I/ML

MCP2200T-I/MQ046

ATECC608B-MAH6K-T

PIC16F15356T-I/ML

PIC18LF25K83T-I/ML

PIC18LF26K83T-I/ML

PIC18F26K42T-I/ML

PIC18LF26K42T-I/ML

DSPIC33EP128GP502T-I/MM

DSPIC33EP128MC202T-I/MM

DSPIC33EP128MC502T-I/MM

PIC32MX270F256BT-I/MLG21

PIC18F27Q10T-I/STX

PIC18F24Q10T-I/STX

MCP73871T-4CAI/ML

PIC16LF1828T-I/ML

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ATSAMD21G17D-MUTN01

PIC18F25K40T-I/ML

PIC18LF24K40T-I/ML

PIC18LF25K40T-I/ML

PIC16F15354T-I/ML

PIC16LF1454T-I/ML

PIC16LF1709T-I/ML

PIC16F1619T-I/ML

PIC16LF1619T-I/ML

24LC256T-I/ST15KVAO

DSPIC33EV32GM102T-I/SSVAO

DSPIC33EP32MC202T-I/SSVAO

PIC18F26Q10T-I/SSVAO

PIC18F24Q10T-I/SSVAO

PIC18F25Q10T-I/SSVAO

PIC18F26K83T-I/SSVAO

24LC04BT-I/ST16KVAO

PIC16F1828T-I/SS

MTCH105T-I/ST

PIC18F26Q10T-I/SSC01

PIC16F627AT-I/SO035

24FC256T-I/ST

PIC18F25K80T-I/SS

PIC16F1718T-I/SS020

PIC16F15243T-I/SS

PIC16F15244T-I/SS

PIC16F722T-I/SO

PIC12LF1571T-I/SN026

PIC12F510T-I/SN079

PIC12F510T-I/SN064

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PIC12F510T-I/SN073

PIC16F1503T-I/ST

PIC12F510T-I/SN075

PIC16F684T-I/ST

PIC16F684T-I/ST110

ATTINY424-XUR

ATTINY824-XUR

PIC16F18326T-I/ST

AA614C-01-1416-GLF/TR

PIC16F630T-I/ST052

PIC16F630T-I/ST

PIC16F630T-I/STC04

PIC16F18857T-I/SS

PIC16LF18857T-I/SS

PIC16F676T-I/ST

C0042TIC01T-I/ST021

PIC16F18455T-I/SS

PIC18F26K22-E/SO

PIC16F1455-E/ST

PIC24FV16KM202-E/SS

PIC24FV16KM202-E/SO

PIC16C55AT-04/SO

PIC16C55AT-20/SO

PIC16C55AT-20/SS036

PIC16C621AT-20/SO

PIC16F628T-20/SS

PIC16C620AT-04/SO

ATA5781-WNQW-VAO-GM

ATA663254-GBQW-VAO-GM

ATA663254-GBQW-VAO-MB

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ATA663431-GDQW-VAO-GM

ATA663431-GDQW-VAO-VW

ATA663454-GDQW-VAO-GM

ATA663454-GDQW-VAO-SG

ATSAMHA0G17A-MZT-BVAO-GM

DSPIC33EP128MC206T-H/MRVAO-VW

DSPIC33EV128GM102T-H/MMVAO-VW

ATSAMC21G18A-OMZ

ATSAMC21E18A-OMZ

ATSAMC21E18A-MZ-SL3

ATSAMC21G18A-MZ-SL3

PIC32AK1216GC41064-E/M7

PIC32AK6416GC41064-E/M7

PIC32AK3208GC41064-E/M7

PIC32AK1216GC41036-E/M7

PIC32AK6416GC41036-E/M7

DSPIC33FJ128GP206AT-I/PT

PIC18F44K22T-I/PT

DSPIC33FJ128MC510AT-I/PT

DSPIC33FJ64MC706AT-I/PT

PIC16C621AT-20I/SS

PIC16C711T-04I/SS

PIC16F88T-I/SS

PIC16F87T-I/SS

ENC28J60T-I/SO

PIC16LF628T-04I/SS

PIC16LF87T-I/SS

PIC18F2420T-I/SO

PIC18LF2420T-I/SO

PIC16LF818T-I/SSTSL

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HCS301T-I/SN028

PIC16F818T-I/SSTSL

PIC16LC554T-04I/SS

PIC18F2520T-I/SO

PIC18LF2520T-I/SO

PIC16F628AT-I/SO052

DSPIC33FJ64MC506AT-I/PT

PIC18F6410T-I/PTC01

PIC16LF1526T-I/PT

PIC18F44K20T-I/PT

11LC040T-I/MNY

11AA040T-I/MNY

11AA010T-I/MNY

PIC24FJ16GA004T-I/ML

PIC24FJ48GA004T-I/ML

PIC16LF1459T-I/GZ

93AA56CT-I/MNY

93LC56AT-I/MNY

93AA56AT-I/MNY

93LC56BT-I/MNY

93AA56BT-I/MNY

HV5623K7-G-M933

93LC56CT-I/MC

PIC24FJ64GB002T-I/ML

PIC24FJ32GB002T-I/ML

PIC24FJ64GB004T-I/ML

PIC24F16KA302T-I/ML

PIC24F32KA302T-I/ML

93LC46CT-I/MC

93AA46CT-I/MC

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93LC56CT-I/MNY

93AA56BT-I/MC

PIC24FV32KA302T-I/ML

PIC24FV32KA304T-I/ML

93AA56CT-I/MC

93LC56AT-I/MC

93AA56AT-I/MC

93LC56BT-I/MC

93C56CT-I/ST

24LC014T-I/ST

24AA014T-I/ST

PIC16F723AT-I/SS

PIC18F27Q83-I/SS

PIC18F27Q84-I/SS

PIC18F27Q83-I/SO

PIC24FJ64GA006T-I/PTC08

PIC24FJ64GA006T-I/PT

PIC24FJ96GA006T-I/PTV01

PIC24FJ64GA006T-I/PT036

PIC24FJ64GA006T-I/PT037

PIC24FJ128GA006T-I/PTC2

PIC24FJ128GA006T-I/PT

ATECC108A-MAHZU-T

PIC32CM5164LS60064T-I/5LX-PROTO

ATECC508A-MAH1B-S

ATECC508A-MAH1C-S

ATECC508A-MAH1Q-S

ATECC508A-MAH1Q-T

ATSAM3S1AB-MUR

ATSAM3N00AA-MUR

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ATECC608A-MAH1G-S

ATECC608A-MAH1G-T

ATECC608A-MAH1K-S

PIC16F688T-I/ST061

AR1100T-I/SS

PIC16F688T-I/ST062

PIC16F688T-I/ST

PIC12F519T-I/SN048

PIC32MM0016GPL028T-I/SS

PIC32MM0032GPL028T-I/SS

PIC32MM0064GPL028T-I/SS

PIC16LF1554T-I/ST039

PIC16F1578T-I/SS

PIC16F1579T-I/SS

PIC16LF18325T-I/ST

DSPIC33EP64MC202T-I/SS

DSPIC33EP64MC502T-I/SS

PIC24EP64MC202T-I/SS

PIC16LF18323T-I/ST026

PIC16F1509T-I/SS023

PIC16F1508T-I/SS031

PIC16F1508T-I/SS

PIC16F1509T-I/SS

PIC16F1509T-I/SSC02

PIC18F27Q10T-I/SO

PIC18F24Q10T-I/SO

PIC18F25Q10T-I/SO

PIC18F26Q10T-I/SO

PIC16F17154T-I/SS

PIC16F18154T-I/SS

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PIC16F17155T-I/SS

PIC16F18155T-I/SS

PIC16F17154T-I/SO

PIC18F25K80T-I/SOC03

PIC16F18154T-I/SO

PIC16F17155T-I/SO

PIC16F18155T-I/SO

ATTINY3224-XUR

PIC24HJ12GP202T-I/SS

PIC16F676T-I/ST043

DSPIC33FJ12GP202T-I/SS

DSPIC33FJ12MC202T-I/SS

HSA2-040SAA/A2320ATR

HSA2-040SAA/A2324TR

PIC12F629T-I/SN138

PIC16LF1938T-I/SS024

PIC16LF1938T-I/SS025

PIC16F505T-I/ST

PIC12F629T-I/SN211

PIC12F629T-I/SN233

PIC16F506T-I/ST

PIC16LF1938T-I/SS026

PIC16LF1938T-I/SS030

PIC16LF1938T-I/SS

PIC18F25Q10T-I/STX

PIC32MK0512MCJ064T-I/PT

PIC32MK0512GPG064T-I/PT

PIC32CM2532JH01048T-E/Y8XVAO

DSPIC33CK256MP206T-E/PTVAO-VW

PIC32MK0128MCA048T-E/Y8XVAO

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DSPIC33CK512MPT608T-E/PTVAO

ATSAME51N19A-AZT510

ATSAME51N19A-AZTVAO

ATSAMD51N19A-AZTVAO

PIC32CM5164JH00048T-E/Y8XVAO

PIC32CM5164JH01100T-E/PF510

DSPIC33FJ32GP202-E/MM

PIC16F1779-E/MP

MCP6424T-E/STVAO

MCP6V14T-E/STVAO

MCP6V34T-E/STVAO

MCP6V84T-E/STVAO

MCP6V94T-E/STVAO

MCP6V64T-E/STVAO

ATSAMD21E18A-AU

ATSAMD21G18A-AUA1

PIC18F67J10-I/PTXXX

DSPIC33AK128MC106-I/PT

DSPIC33AK64MC106-I/PT

PIC18F87J10-I/PT

PIC18F86J15-I/PT

PIC18F86J10-I/PT

PIC18F85J15-I/PT

PIC18F85J50-I/PT

PIC18F65J50-I/PT

PIC16LC926-I/PT

PIC16C926-I/PT

PIC18F66J10-I/PT

PIC18F65J15-I/PT

PIC16F877A-I/PTV03

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PIC18F86J55-I/PT

PIC18F87J50-I/PT

PIC18F66J55-I/PT

PIC18F67J50-I/PT

PIC18F67J90-I/PT

PIC18LF4682-I/PT

PIC18F4682-I/PT

PIC18F4423-I/PT

PIC18F8390-I/PT

PIC18F46J50-I/PT

PIC32CM3204JH00032-I/RTB

PIC32CM3204JH00064-I/5LX

24LC04BT-E/ST

24LC32AXT-E/ST

24LC014T-E/ST

MCP6004T-E/ST

MCP6L04T-E/ST

HCS300/SN

PIC16LF876-04/SO

PIC16C56A-04/SO

PIC16LC63A-04/SO

ATSAMC20E17A-MZTVAO

ATA663454-GDQW-VAO

ATA663454-GDQW

ATSAMD21E17D-MZTVAO

ATSAMD21J18A-MMZTVAO

ATA6625-GBQW

PIC18F56Q43T-E/6LXVAO

PIC18F24K22T-E/MLVAO

ATSAMC21J17A-MMZTVAO

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ATSAMC21J16A-MMZTVAO

ATSAMC21G16A-MZTVAO

24AA64T-E/MNYVAO

24LC64T-E/MC16KVAO

DSPIC33EV256GM006T-E/MRVAO

PIC18F45Q43T-E/MPVAO

PIC16F685T-E/MLVAO

PIC18F46Q10T-E/MPVAO

PIC18F47Q83T-E/NHXVAO

PIC18F26Q84T-E/5NVAO

PIC16F1786T-E/MLVAO

ATSAMD21E15B-MZTVAO

ATSAMD21G18A-MZT510

ATSAMC21E15A-MZT510

ATSAMC21E17A-MZT510

PIC16LF19196T-E/5LXVAO

ATSAMC21E15A-MZTVAO

ATSAMC20E16A-MZTVAO

ATA663231-GBQW-VAO

ATA663254-GBQW

ATA663254-GBQW-VAO

MCP2200T-E/MQVAO

PIC16F1508T-E/MLVAO

PIC16F1509T-E/MLVAO

PIC16LF1936T-E/MLVAO

PIC16F1829T-E/MLVAO

PIC16LF1829T-E/MLVAO

ATA663231-GBQW

UTC2000T-E/MG042

ATTINY3217-MZT-VAO

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PIC16F15325T-E/7NVAO

PIC16F1828T-E/MLVAO

DSPIC33EP128GP502T-E/MMVAO

MCP23017T-E/MLVAO

PIC16F1718T-E/MVVAO

PIC16F15355T-E/5NVAO

PIC18F45Q10T-E/MPVAO

ATA6582-GUQW1-VAO

ATA6583-GUQW1-VAO

ATA6587-GUQW1-VAO

ATA6588-GUQW1-VAO

MCP1725T-3302E/MCVAO

MCP2050T-500E/MQVAO

ATA6570-GCQW1

ATA6571-GCQW1-VAO

PIC16F15224T-E/MGVAO

PIC16F15225T-E/MGVAO

ATSAMC21G18A-MZT510

ATSAMC21G17A-MZTVAO

LAN8670C2T-E/LMXVAO

ATA8287-GHQW

ATSAMD20E14A-MNT

ATSAMD20E15A-MNT

MCP2200-I/MQ046

PIC16F1827-I/MV039

PIC16F1827-I/MV040

MCP6484T-E/ST

ATA6847T-5050E/NHX

ATA6847T-3333E/NHX

ATA6847T-5033E/NHX

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PIC32AK1216GC41064T-E/M7

PIC32AK6416GC41064T-E/M7

PIC32AK3208GC41064T-E/M7

PIC32AK1216GC41036T-E/M7

PIC32AK6416GC41036T-E/M7

PIC32AK3208GC41036T-E/M7

PIC32AK1216GC41048T-E/M7

PIC32AK6416GC41048T-E/M7

A3P030-1VQ100

A3P030-1VQG100

A3P030-2VQ100

A3P030-2VQG100

A3P030-VQ100

A3P030-VQG100PX87

A3P030-VQG100PY10

AGL250V2-VQ100

AGL250V2-VQG100

AGL250V5-VQ100

93C46A-I/SN

AT24CM01-XHM-B

AT24CM01-XHD-B

PIC16F18854-I/MV

PIC16LF18854-I/MV

PIC18F24K50-I/ML

PIC18F25K50-I/ML

PIC16F819-I/MLTSL

PIC16LF18324-I/JQ

PIC16LF1559-I/ML

PIC16LF18877-I/ML

PIC16F18876-I/ML

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PIC16LF18876-I/ML

PIC32MM0064GPM028-I/ML

PIC32MM0128GPM028-I/ML

PIC32MM0256GPM028-I/ML

PIC18F25K80-I/MM032

PIC16F610T-I/ST038

RE46C105S14TF

PIC16LF73T-I/SO

ATECC608A-TNGACTU-C

ATECC608A-TNGLORAU-C

ATECC608A-TNGACTU-G

ATECC608A-TNGLORAU-G

PIC16F1719T-I/MP

ATECC608B-TFLXTLSU

ATECC608A-TCSMU

DSPIC33EV128GM006-I/PT

DSPIC33EV128GM106-I/PT

DSPIC33EV64GM006-I/PT

PIC32MX775F512L-80I/PT

PIC32MX775F256L-80I/PT

PIC32MX795F512L-80I/PTE22

PIC32MX795F512L-80I/PT

PIC18F55K42-I/PT

PIC18LF55K42-I/PTC01

PIC18LF56K42-I/PT

PIC32MX570F512L-I/PF

DSPIC33FJ256GP710A-I/PF

DSPIC33FJ256MC510A-I/PF

PIC32MK0512MCM100-I/PT

DSPIC33CK512MP305-E/PT

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DSPIC33CK512MP605-E/PT

PIC32CM1216MC00048-E/Y8X

PIC32CM6408MC00048-E/Y8X

PIC32CM1216MC00032-E/PT

PIC32CM6408MC00032-E/PT

DSPIC33CK512MP606-E/PT

DSPIC33CK256MP308-E/PT

DSPIC33CK256MP608-E/PT

DSPIC33CK512MP308-E/PT

DSPIC33CK512MP608-E/PT

DSPIC33CK256MP306-E/PT

PIC32MX764F128HT-I/PT

PIC16F1947T-I/PT

PIC16F1947T-I/PTC02

DSPIC33CK256MP208T-I/PT

PIC16F15355-I/ML

PIC16LF15354-I/ML

PIC16LF15355-I/ML

AVR16EA48-I/6LX

C0001RIC00T-I/SS

PIC16LF1823T-I/ST

PIC16LF1823T-I/STC05

MTCH1030T-I/ST

HCS301T-I/SN029

MIC2179-3.3YSM-TR

MIC2179-5.0YSM-TR

PIC16F18126T-I/ST

PIC16F18125T-I/ST

PIC16F18146T-I/SS

PIC16F18144T-I/SS

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MIC2179YSM-TR

PIC18F04Q41T-I/ST

PIC18F05Q41T-I/ST

PIC18F14Q41T-I/SS

PIC18F15Q41T-I/SS

MCP79400T-I/ST

MCP79401T-I/ST

MCP79402T-I/ST

PIC16F1933T-I/SO

PIC16LF1933T-I/SO

MCP7940MT-I/ST

PIC16F18025T-I/ST

PIC16F18026T-I/ST

PIC18F24Q71T-I/SO

PIC18F25Q71T-I/SO

PIC16F15256T-I/SO

PIC16F15254T-I/SO

PIC16F15255T-I/SO

MCP79410T-I/ST

MCP79411T-I/ST

MCP79412T-I/ST

AVR32DD28T-I/SS

AVR16DD28T-I/SS

AVR32DD28T-I/SO

AVR16DD28T-I/SO

PIC16F873T-20/SO

PIC16LF1827-E/SS

MCP4362-104E/ST

MCP4342-502E/ST

MCP4362-502E/ST

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MCP4362-103E/ST

MCP4362-503E/ST

MCP4011-103E/SN

MCP4011-202E/SN

MCP47CVD02-E/MG

MCP48CMD22-E/MG

MCP47CVD11-E/MG

MCP48CVD01-E/MG

ATTINY417-MF

MCP47CVD12-E/MG

MCP48CVD02-E/MG

PIC18F25K20-E/ML

MCP48CVD11-E/MG

MCP47CMD01-E/MG

PIC18F26K20-E/ML

MCP47CVD21-E/MG

MCP47CMD02-E/MG

MCP47CMD11-E/MG

MCP47CVD22-E/MG

MCP48CVD12-E/MG

MCP47CMD12-E/MG

MCP48CMD01-E/MG

MCP48CVD21-E/MG

MCP47CMD21-E/MG

MCP48CMD02-E/MG

MCP48CVD22-E/MG

MCP48CMD11-E/MG

DSPIC30F4011-20E/ML

DSPIC30F4012-20E/ML

DSPIC30F2023-20E/ML

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DSPIC30F3014-20E/ML

DSPIC30F4013-20E/ML

DSPIC30F2010-20E/MM

PIC32CM2532LE00064-E/5LX

PIC32CM2532LS00064-E/5LX

PIC32CM2532LE00048-E/U5B

PIC32CM2532LS00048-E/U5B

DSPIC33EV256GM002-E/MM020

ATSAMD21E18A-MF

ATSAMD21E17A-MF

PIC32CM5164JH01048-E/U5B

PIC32CM2532JH00048-E/U5B

PIC32CM5164JH00048-E/U5B

ATSAMD21G15B-MF

ATSAMD21G16B-MF

ATSAMD21G17A-MZ

PIC16F716-E/ML

ATSAMD21J18A-MMZ

ATSAMD21G18A-MZ

PIC16F18025-E/ML

ATSAMD21G17D-MF

ATSAMD21G17D-MZ

PIC18F26Q10-E/ML

DSPIC33FJ16GS502-E/MMC03

DSPIC33FJ16GS502-E/MM

ATSAMD21J17D-MMZ

ATSAMD21G17A-MF

ATSAMD21G18A-MF

ATMEGA4809-MF

PIC32CM2532JH01064-E/5LX

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PIC32CM5164JH01064-E/5LX

PIC24HJ128GP202-E/MMC01

PIC18F25K50-E/ML

PIC32CM2532JH00064-E/5LX

PIC32CM5164JH00064-E/5LX

PIC32CM2532JH01048-E/U5B

PIC16F15313-E/RF

PIC18F26Q83-E/5N

PIC18F26Q84-E/5N

PIC18F27Q83-E/5N

PIC18F27Q84-E/5N

ATMEGA4808-MF

PIC16F15356-E/MV

MCP23S08-E/ML

PIC16F18313-E/RF

PIC18LF65K40-E/MR

PIC18LF66K40-E/MR

PIC18LF14K22-E/ML

PIC12F1571-E/MF

PIC12F1572-E/MF

PIC16LF1902-E/MV

PIC16LF1903-E/MV

ATTINY1627-MF

ATTINY3227-MF

PIC18F57Q83-E/6MX

PIC18F57Q84-E/6MX

ATTINY427-MF

ATTINY827-MF

ATECC608A-MAH1U-S

ATECC608A-MAH1W-T

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PIC32CM5164LS60048T-I/U5B-PROTO

PIC16F18154-I/SO

PIC16F17155-I/SO

PIC16F18155-I/SO

PIC24HJ12GP202-I/SS

DSPIC33FJ12GP202-I/SS

DSPIC33FJ12MC202-I/SS

PIC16LF1938-I/SS025

PIC16LF1938-I/SS026

PIC12F629-I/SN206

PIC12F629-I/SN209

PIC16LF1938-I/SS

C0001RIC00-I/SS

PIC16F505-I/ST

PIC16LF1823-I/ST

PIC16F506-I/ST

PIC16LF1823-I/STC05

MTCH1030-I/ST

PIC16F1508-I/SS

PIC16F1509-I/SS

PIC18F04Q40-I/ST

PIC18F05Q40-I/ST

PIC18F04Q41-I/ST

PIC18F05Q41-I/ST

PIC18F14Q40-I/SS

PIC18F15Q40-I/SS

PIC18F14Q41-I/SS

PIC18F15Q41-I/SS

MCP79402-I/ST

PIC16F1933-I/SO

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PIC16LF1933-I/SO

MCP7940M-I/ST

PIC16F18025-I/ST

PIC16F18026-I/ST

PIC18F24Q71-I/SO

PIC18F25Q71-I/SO

PIC18F24Q71-I/SS

PIC18F25Q71-I/SS

PIC16F15256-I/SO

PIC16LF1773T-I/SS

PIC18F2450T-I/SO

PIC16F627AT-I/SO

DSPIC33FJ128MC804-E/PTVAO

PIC16F1719-E/PTVAO

PIC18F46K22-E/PTVAO

PIC18F66K90-E/PTVAO

DSPIC33EP256MC506-E/PTVAO

PIC16LF1519-E/PTVAO

PIC16F1527-E/PTVAO

PIC16F1526-E/PTVAO

PIC18F45K22-E/PTVAO

DSPIC30F5015-20E/PTVAO

PIC16F1937-E/PTVAO

DSPIC33FJ32MC204-E/PTVAO

DSPIC33EP64GS506-E/PTVAO

DSPIC33EP32GS506-E/PTVAO

DSPIC33FJ16GS402T-I/MM

PIC16F887T-I/ML

PIC32MX150F128BT-50I/ML

PIC32MX250F128BT-50I/ML

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DSPIC33FJ16GS504T-I/ML

DSPIC33EP32MC502T-I/MM

PIC24EP32GP202T-I/MM

MCP6544-E/ST

PIC16F819-E/SS

PIC16F818-E/SS

PIC16F57-E/SS

PIC16F872-E/SO

PIC16F73-E/SO

PIC16LC770-E/SS

PIC16F870-E/SO

PIC16LC771-E/SS

PIC16F870-E/SS

MCP6294-E/ST

MCP6274-E/ST

PIC16C622A-20E/SO

PIC16F76-E/SO

PIC16LC622A-04E/SO

PIC16F72-E/SO

PIC18F242-E/SO

PIC16C622A-04E/SO

PIC16C621A-04E/SO

PIC16F15355-I/MV

DSPIC33CK256MP205-I/PT

DSPIC33EP64GS506-I/PTC07

PIC18F87K90-I/PT032

PIC18F87K90-I/PT034

ATMEGA809-AU

DSPIC33CK128MP205-I/PT

DSPIC33CK128MP505-I/PT

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DSPIC33CK64MP205-I/PT

DSPIC33CH128MP205-I/PT

AVR64DU32-I/PT

A3P030-1VQ100I

A3P030-1VQG100I

A3P030-2VQ100I

A3P030-2VQG100I

PIC32CM2532JH00064-I/PT

PIC32CM5164JH00064-I/PT

A3P030-VQ100I

A3P030-VQG100I

PIC32CM2532JH01064-I/PT

PIC32CM5164JH01064-I/PT

DSPIC33EP128GS808-E/PT

DSPIC33EP64GS808-E/PT

DSPIC33EP64GS708-E/PT

AVR128DB48-E/PT

AVR64DB48-E/PT

PIC32MK0128MCA048-E/Y8X

PIC24HJ128GP206AT-I/PT

PIC24HJ64GP506AT-I/PT

PIC24HJ64GP206AT-I/PT

DSPIC33FJ64GP706AT-I/PT

PIC24HJ64GP210AT-I/PT

PIC24HJ64GP510AT-I/PT

DSPIC33FJ128GP706AT-I/PT

PIC18F2321-E/SO

24LC024-E/ST

MCP41HV31-502E/ST

MCP41HV31-103E/ST

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ATTINY461A-MU

ATTINY261A-MU

ATTINY48-MU

HV5622K7-G-S343

PIC18LF66K40-I/MR